

JEDEC STANDARD

DDR5RCD05 Registering Clock Driver

JESD82-515

November 2025

JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



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DDR5RCD05 Registering Clock Driver

(From JEDEC Board Ballot JCB-25-61, formulated under the cognizance of the JC-40.4 subcommittee on Registered and Fully Buffered Memory Support Logic, item 711.99E).

1 Scope

This document defines standard specifications of DC interface parameters, switching parameters, and test loading for definition of the DDR5 Registering Clock Driver (RCD) with parity for driving address and control nets on DDR5 RDIMM applications. The DDR5RCD05 Device ID is DID = 0x0055.

The terms ‘Registering Clock Driver’, ‘RCD’, ‘register’ or ‘device’ are used interchangeably to refer to this device in the remainder of this specification.

The purpose is to provide a standard for the DDR5RCD05 (see Note) logic device, for uniformity, multiplicity of sources, elimination of confusion, ease of device specification, and ease of use. DDR5RCD05 is backwards compatible with DDR5RCD04, DDR5RCD03, DDR5RCD02, and DDR5RCD01.

NOTE: The designation DDR5RCD05 refers to the part designation of a series of commercial logic parts common in the industry. This designation is normally preceded by a series of manufacturer specific characters to make up a complete part designation.

2 Mechanical Outline

Package options include a 264-ball Flip-Chip Fine-Pitch BGA with 0.60 mm/0.675 mm ball pitch, 14 x 21 grid. The package has a number of depopulated balls. Package size is 8.70 mm x 14.40 mm as defined in MO-361A¹. The device pinout supports outputs on the top and outer left and right columns to support easy DIMM signal routing. Corresponding inputs are placed in a way to match the corresponding pin location on the connector.

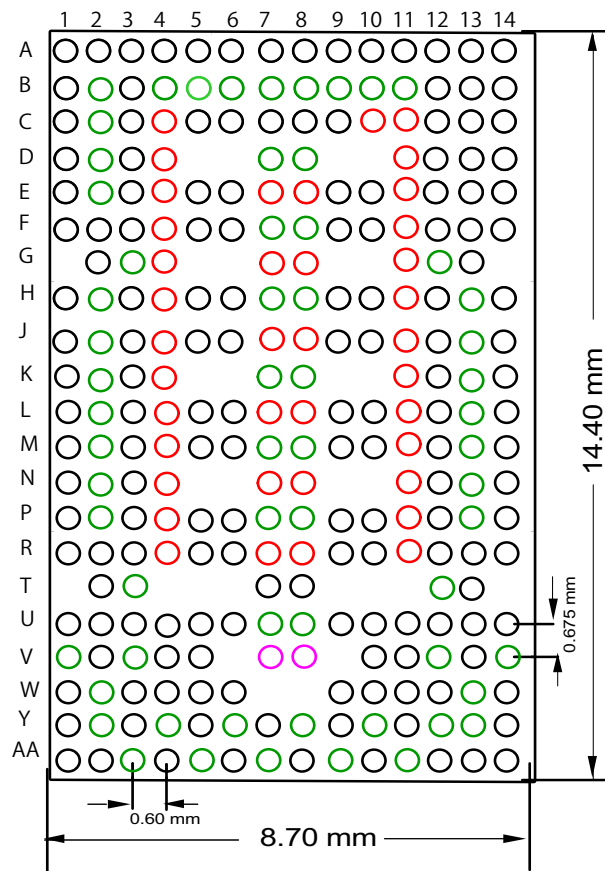


Figure 1 — Ball Configuration, Top View

Ball pitch: 0.60 mm x 0.675 mm. Size (ø 0.3 mm), SMD Pad SRO (ø 0.275 mm)
X-ray view from top side

NOTE 1 This variation defines a nominal package thickness of 0.90 mm with tolerance of +/- 0.1 mm.

2.1 Pinout

Table 1 specifies the pinout for the DDR5RCD05.

Table 1 — Ball Assignment -264 ball BGA, 14 x 21 Grid, TOP VIEW

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	
A	NU2	QB CA7_A	QB CA3_A	QB CA13_A	QB CA13_A	QB CA12_A	QB CA10_A	QB CA10_B	QB CA12_B	QB CA11_B	QB CA13_B	QB CA3_B	QB CA7_B	NU0	A
B	QB CA1_A	V _{SS}	QB CA9_A	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	QB CA9_B	V _{SS}	QB CA1_B	B
C	QB CA6_A	V _{SS}	QB CA8_A	V _{DD}	ZQ CAL	SCL	DERROR _IN_A_n	DERROR _IN_B_n	SDA	V _{DDIO}	V _{DD}	QB CA8_B	V _{SS}	QB CA6_B	C
D	QB CA5_A	V _{SS}	QB CA2_A	V _{DD}			V _{SS}	V _{SS}			V _{DD}	QB CA2_B	V _{SS}	QB CA5_B	D
E	QB CA0_A	V _{SS}	QB CA4_A	V _{DD}	QBCK _A_t	QDCK _A_c	V _{DD}	V _{DD}	QDCK _B_c	QBCK _B_t	V _{DD}	QB CA4_B	V _{SS}	QB CA0_B	E
F	QBCS0 _A_n	QBCS2 _A_n	QBCS1 _A_n	V _{DD}	QBCK _A_c	QDCK _A_t	V _{SS}	V _{SS}	QDCK _B_t	QBCK _B_c	V _{DD}	QBCS1 _B_n	QBCS02 _B_n	QBCS0 _B_n	F
G		QBCS3 _A_n	V _{SS}	V _{DD}			V _{DD}	V _{DD}			V _{DD}	V _{SS}	QBCS03 _B_n		G
H	QA CA11_A	V _{SS}	QA CA13_A	V _{DD}	QXCK _A_t	QZCK _A_c	V _{SS}	V _{SS}	QZCK _B_c	QXCK _B_t	V _{DD}	QA CA13_B	V _{SS}	QA CA11_B	H
J	QA CA9_A	V _{SS}	QA CA12_A	V _{DD}	QXCK _A_c	QZCK _A_t	V _{DD}	V _{DD}	QZCK _B_t	QXCK _B_c	V _{DD}	QA CA12_B	V _{SS}	QA CA9_B	J
K	QA CA10_A	V _{SS}	QA CA3_A	V _{DD}			V _{SS}	V _{SS}			V _{DD}	QA CA3_B	V _{SS}	QA CA10_B	K
L	QA CA6_A	V _{SS}	QA CA7_A	V _{DD}	QACK _A_t	QCCK _A_c	V _{DD}	V _{DD}	QCCK _B_c	QACK _B_t	V _{DD}	QA CA7_B	V _{SS}	QA CA6_B	L
M	QA CA2_A	V _{SS}	QA CA8_A	V _{DD}	QACK _A_c	QCCK _A_t	V _{SS}	V _{SS}	QCCK _B_t	QACK _B_c	V _{DD}	QA CA8_B	V _{SS}	QA CA2_B	M
N	QA CA1_A	V _{SS}	QA CA4_A	V _{DD}			V _{DD}	V _{DD}			V _{DD}	QA CA4_B	V _{SS}	QA CA1_B	N
P	QA CA5_A	V _{SS}	QA CA0A	V _{DD}	QWCK _A_t	QYCK _A_c	V _{SS}	V _{SS}	QYCK _B_c	QWCK _B_t	V _{DD}	QA CA0_B	V _{SS}	QA CA5_B	P
R	QACS0 _A_n	QACS2 _A_n	QACS1 _A_n	V _{DD}	QWCK _A_c	QYCK _A_t	V _{DD}	V _{DD}	QYCK _B_t	QWCK _B_c	V _{DD}	QACS1 _B_n	QACS2 _B_n	QACS0 _B_n	R
T		QACS3 _A_n	V _{SS}				QLBD	QLBS				V _{SS}	QACS3 _B_n		T
U	DNU	DNU	DNU	DNU	DNU	DNU	V _{SS}	V _{SS}	DNU	DNU	DNU	DNU	DNU	DNU	U
V	V _{SS}	DNU	V _{SS}	DCS1 _A_n	QRST _A_n		DCK_t	DCK_c		QRST _B_n	DCS0 _B_n	V _{SS}	DNU	V _{SS}	V
W	DCA0 _A	V _{SS}	DCS0 _A_n	DLBD_A	DLBS_A	ALERT _n			DRST_n	DLBS_B	DLBD_B	DCS1 _B_n	V _{SS}	DPAR _B	W
Y	DCA1 _A	V _{SS}	DCA3 _A	V _{SS}	DPAR _A	V _{SS}	DCA6 _A	V _{SS}	DCA1 _B	V _{SS}	DCA3 _B	V _{SS}	V _{SS}	DCA6 _B	Y
AA	NU3	DCA2 _A	V _{SS}	DCA4 _A	V _{SS}	DCA5 _A	V _{SS}	DCA0_B	V _{SS}	DCA2 _B	V _{SS}	DCA4 _B	DCA5 _B	NU1	AA
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	

2.2 Terminal Functions

Table 2 — Terminal Functions

Signal Group	Signal Name	Type	Description
Input Control bus	DCS[1:0]_[B:A]_n	POD V_{REF} based	Chip Select inputs to the RCD. Two inputs per DRAM channel.
Input Address and Command bus	DCA[6:0]_[B:A]	POD V_{REF} based	Command/Address bus inputs to the RCD. Separate sets per channel.
Parity input	DPAR_[B:A]	POD V_{REF} based	Command Address input parity is received on the DPAR pin and should maintain even parity across the CA inputs. DPAR is sampled at the rising and falling edges of the input clock.
Clock inputs	DCK_t/DCK_c	POD differential	Differential system clock input pair to the PLL. The clock is common to both RCD channels, CH_A and CH_B.
Loopback	DLBD_[B:A] DLBS_[B:A]	POD V_{REF} based	Loopback Inputs to RCD DLBD - loopback Data DLBS - loopback Strobe
Reset input	DRST_n	CMOS input	Active LOW asynchronous reset input. When LOW, it causes a reset of the internal latches and disables the outputs, thereby forcing the outputs to float.
Error input	DERROR_IN_[B:A]_n	Low voltage swing POD input	DRAM CRC and ABO ALERT_n output is connected to this input pin, which in turn is buffered and redriven to the ALERT_n output of the register. There is a separate signal per channel.
Output Control bus	Q[B:A]CS[3:0]_[B:A]_n	POD	Chip Select signals to the DRAMs. 4 copies of each signal.
Output Address and Command bus	Q[B:A]CA[13:0]_[B:A]	POD	Command/Address bus outputs to the DRAMs, valid after the specified clock count and immediately following a rising edge of the clock. Two copies of each signal. When Output Inversion is enabled in RW00[5] , Copy B output signals get inverted during all commands other than Deselect. Both copies drive High during idle cycles (i.e., Deselect).
Clock outputs	Q[D:A]CK_[B:A]_t Q[D:A]CK_[B:A]_c Q[W,X,Y,Z]CK_[B:A]_t Q[W,X,Y,Z]CK_[B:A]_c	POD differential	Clock outputs to the DRAMs. Eight copies per channel.
Loopback	QLBD QLBS	POD	Loopback outputs to Host QLBD - loopback Data QLBS - loopback Strobe
Reset output	QRST_[B:A]_n	CMOS	Re-driven or CMD based reset. This is an asynchronous output. It is the responsibility of the RCD QRST_n to reset the DDR5 SDRAM on all DIMM topologies. The QRST outputs are asserted at power up. RCD requires MRW to independently de-assert to allow staggering of sub-channels.
Error out	ALERT_n	POD	When LOW, this output indicates that a parity error was identified associated with the CA inputs when parity checking is enabled or that the DERROR_IN_n input was asserted, regardless of whether parity checking is enabled or not. One signal for the two channels.
SidebandBus pins ¹	SDA	Open drain or push-pull I/O ²	SidebandBus Data
	SCL	CMOS input ³	SidebandBus Clock
	V_{DDIO}	Power input	SidebandBus power input
Miscellaneous pins	V_{DD}	Power Input	Power supply voltage
	V_{SS}	Ground Input	Ground
	ZQCAL	Reference	Reference pin for driver calibration
	NU	Mechanical ball	Do not connect on PCB
	DNU	Mechanical ball	Do not use. Do not connect on PCB.

- NOTE 1 SA pins are not required for DDR5RCD05 as the address is hard-coded. Refer to Clause 6.5.1, “Target Address,” on page 89 for details.
- NOTE 2 SDA driver operation is dynamic. Depending on the SidebandBus mode of operation (I²C [RW25\[5\]](#) = ‘0’ or I3C Basic [RW25\[5\]](#) = ‘1’), and even on the specific step (byte or bit) of a SidebandBus transaction packet, the SDA output driver can operate either in open-drain mode or push-pull mode.
- NOTE 3 These inputs are 1.0-V inputs.

Naming Convention:

Input Example:

DCAy_N - where ‘y’ is the signal number and ‘N’ is the sub-channel.

Output Example:

QxCAy_N - where ‘y’ is the signal number, ‘x’ is the output copy (A or B) and ‘N’ is the sub-channel.

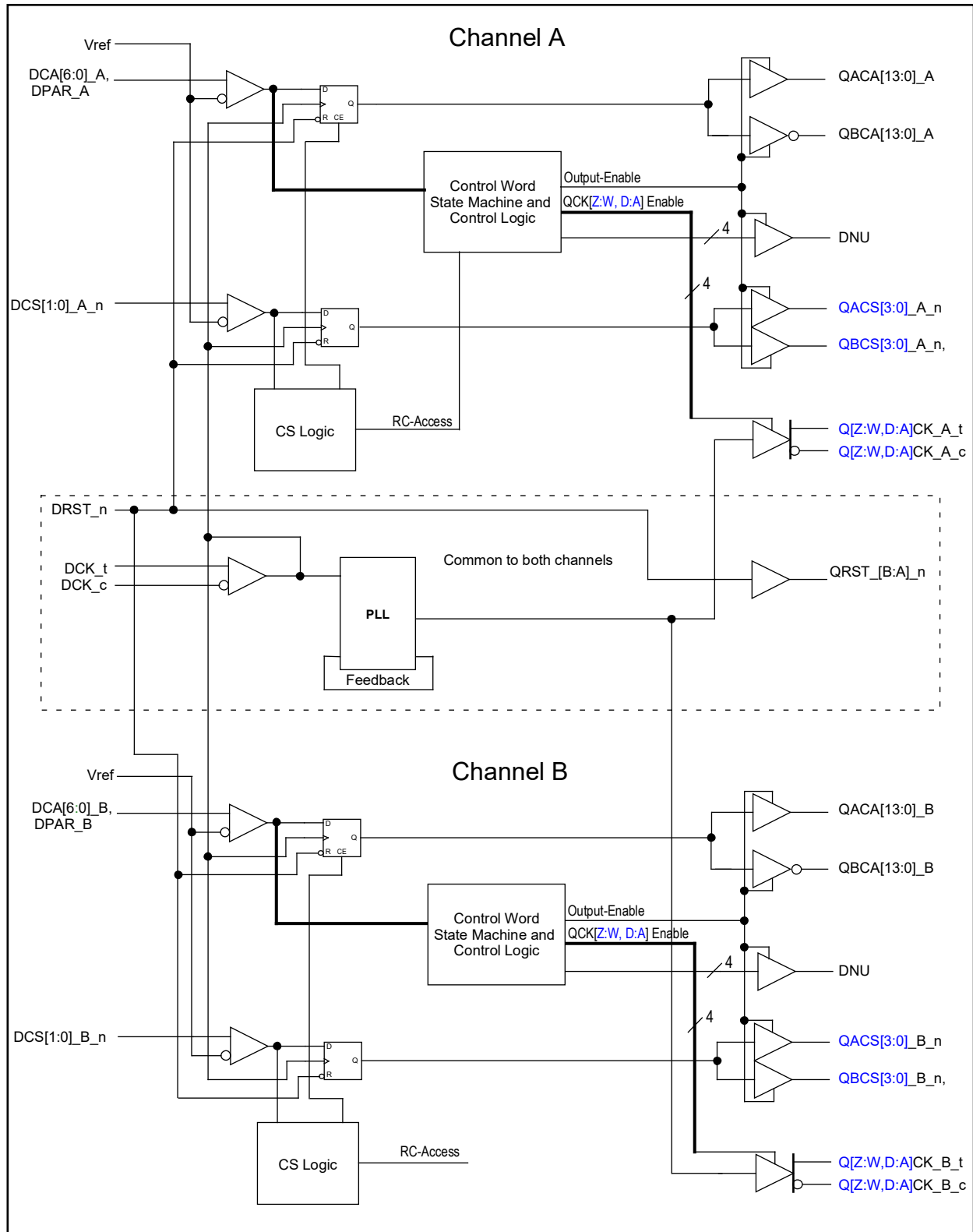
3 Device Standard

3.1 Description

The DDR5RCD05 is a registering clock driver used on DDR5 RDIMMs. Its primary function is to buffer the Command/Address (CA) bus, chip selects, and clock between the Host controller and the DRAMs.

It contains two separate channels which have some common logic such as clocking, but otherwise operate independently of each other. Each channel has a 7-bit double data rate CA bus input, a single parity input, two chip select inputs, and produces two copies of 14-bit single data rate CA bus outputs, and two copies of the chip select outputs. The RCD has a common clock input and PLL, but produces separate clock outputs to the DRAM channels.

3.2 Logic Diagram Positive Logic



3.3 Register Operation

3.3.1 Chip Select Operation

Per sub-channel, the component has two chip select inputs, DCS0_n and DCS1_n, and two copies of each chip select output, QACS0_n, QACS1_n, QBCS0_n and QBCS1_n. Commands are sent to a single rank or multiple ranks, as determined by the DCS[1:0]_n inputs. The number of input chip selects matches the number of output chip selects in each of the two sets (A-outputs and B-outputs).

Table 3 — DCS - QxCS Mapping

Input CS	Output CS
DCS0_N_n	QxCS0_N_n
DCS1_N_n	QxCS1_N_n

QxCS2_n and QxCS3_n outputs are disabled by default, and can be enabled in [PG\[70\]RW62](#). When enabled, they are the copies of QxCS0_n and QxCS1_n, respectively.

3.3.2 ODT Operation

DDR5 does not have a separate ODT (On Die Termination) signal going to the DIMM or the DRAMs. The ODT control is encoded into the chip selects. All commands that utilize the data bus require 2UI on the DCA bus in order to transfer the appropriate number of command and addressing bits. This requirement is used to signal ODT control by how the chip selects are asserted for the two UI.

Table 4 — ODT Encoding on the Chip Select

DCS_n on 1st UI	DCS_n on 2nd UI	QxCS[1:0]_n	DRAM DQ Terminations
Active	Inactive	Target of command	Read: none (device drives data) Write: RTT_WR.
Active	Active	Non-Target Termination should be applied.	Read: RTT_NOM_RD Write: RTT_NOM_WR
Inactive	Inactive	DRAM ignores commands and the Parked termination is maintained	RTT_PARK
Inactive	Active	Illegal	Illegal

The Host controller determines the termination at the time of the command, by activating the chip selects appropriately.

If the DCS_n signal is active during the 2nd UI of a command, it indicates a non-target termination for the DIMM. The command is targeting a different DIMM and the DRAMs should terminate with either RTT_NOM_WR for writes or RTT_NOM_RD for reads.

For a non-target operation, the DRAMs should remain in RTT_PARK. The RCD will not have received any DCS_n signals active in this case and will see Deselects.

3.3.3 QCA Bus Operation

Under normal operation, the RCD passes commands through from the D inputs to the Q outputs when a command is present on the bus, and drives HIGH on the QCA outputs when no command is being sent. The RCD passes the DCA bus through when either DCS input is active but there are exceptions to this:

3.3.3 QCA Bus Operation (cont'd)

- If the register detects a parity error and parity checking is enabled, the DCA bus is still passed through to DRAM and QCS is blocked.
- During the 2nd UI of a 2 UI command, the DCA bus must be passed through. There will only be a DCS signal active for the 2nd UI if a non-target termination is being signaled to a rank.
- When DRAM interface Block MR Mode is enabled $RW01[1] = 0$.
- When CA Pass-through mode is enabled $RW00[2] = 1$.

3.3.4 QCS Operation

Under normal operation the RCD passes the DCS signals through to the QCS outputs. There are several exceptions to this:

- If the register detects a parity error with parity checking enabled, on a one-cycle command or the 1st UI of two-cycle command, the DCS signal is not passed through, and the QCS outputs remain inactive.
- If the register detects a parity error with parity checking enabled, on the 2nd UI of a two-cycle command, the same QCS outputs that were active on the 1st UI will be active on the 2nd UI. This causes the command to be canceled in the DRAM. For read and write commands it causes the command to be converted to non-target termination.
- When DRAM interface Block MR Mode is enabled $RW01[1] = 0$.
- When CA Pass-through mode is enabled $RW00[2] = 1$.

3.3.5 Output Inversion and Mirroring

Output Inversion is enabled by default, after DRST_n is de-asserted, to reduce simultaneous output switching current.

- All QACA[13:0]_[B:A] outputs will follow the equivalent inputs. All QBCA[13:0]_[B:A] outputs will be inverted. In other words, when sending commands, the “B” copy will be the invert of the “A” copy.
- When no commands are being sent, both the “A” and “B” copies will drive HIGH.
- The DRAM devices connected to the “B” outputs will un-invert the signals internally before using them. This eliminates the need for the Host controller to send separate MRW commands for the two CA output sets, and allows every CA output to be inverted on the “B” set.

Address mirroring is also handled by the DRAM device, so there is no RCD requirements for mirroring.

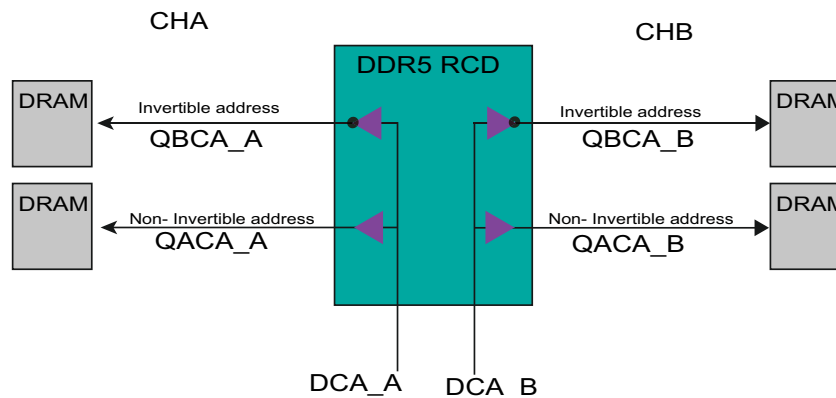


Figure 2 — RCD Output Inversion

3.3.6 ZQ Calibration

The RCD snoops the MPC command to initiate ZQ Calibration, which calibrates the output driver impedance across process, temperature, and voltage. ZQ Calibration occurs in the background of device operation.

There are two ZQ Calibration commands initiated with the MPC command: ZQCal Start, and ZQCal Latch. ZQCal Start initiates the RCD's calibration procedure, and ZQCal Latch captures the result and loads it into the RCD's drivers.

A ZQCal Start command may be issued anytime the DDR5 SDRAM is not in a power-down state. There are two timing parameters associated with ZQ Calibration. t_{ZQCAL} is the time from when the ZQCal Start MPC command is sent to when the Host can send the ZQCal Latch MPC command. t_{ZQLAT} is the time from when the ZQCal Latch MPC command is sent by the Host to when the CA bus (and subsequently the DQ bus) can be used for normal operation. A ZQCal Latch Command may be issued anytime outside of power-down after t_{ZQCAL} has expired and all CA bus operations have completed. The CA Bus must maintain a Deselect state during t_{ZQLAT} to allow CA ODT calibration settings to be updated.

ZQCal commands are issued independently on a sub-channel level. After a ZQCal Start and until t_{ZQCAL} finishes, neither another ZQCal Start nor a ZQCal Latch is allowed on this same sub-channel.

To use the ZQ calibration function, a $240\ \Omega \pm 1\%$ tolerance external resistor must be connected between the ZQ pin and VSS.

3.3.7 Latency Equalization Support

NOTE: Latency Equalization Support has been deprecated starting with spec revision 0.9. All RW11 bits will behave as RFU on devices that do not support Latency Equalization.

3D Stacked SDRAMs have a higher CAS latency than monolithic devices. For greater platform flexibility, it is highly desirable to mix DIMMs with both 3DS and mono SDRAMs on the same DDR5 channel. Since memory controllers typically can only handle devices with equal CAS latencies in the same channel, it is required that the DDR5 register has a mechanism to increase the CAS latency of mono SDRAMs to match the CAS latency of 3DS SDRAMs. To equalize different SDRAM latencies, the DDR5 register supports a programmable latency adder of 0 nCK, 1 nCK, 2 nCK, 3 nCK or 4 nCK for all DRAM commands—see conceptual diagram in Figure 3. The power-up default is 0 nCK latency adder.

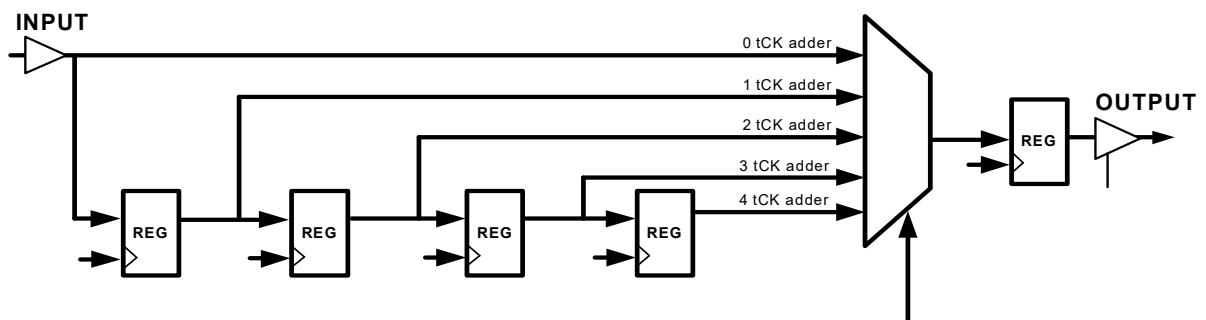


Figure 3 — Latency Equalizer Delays

With a latency adder enabled, the DDR5 register will delay assertion of the $QxCSy_N_n$ and $QxCAy_N$ outputs by the corresponding number of clock cycles. The output timing is determined by the Command Latency Adder control word [RW11](#) regardless of whether the device has parity checking enabled or disabled.

3.3.8 Per-group Output Delay Control

The RCD supports output delay control for output signal groups defined and located in [RW12](#) to [RW1C](#), [PG\[70\]RW\[7F:78\]](#). The output delay settings are incremental CK fractions of 1/64 tCK. Each signal group can be enabled or disabled independently through RCD Control Words. The Host must wait t_{ODU} after the Output Delay Control Word has been written to a signal group before the output becomes stable. The output delay feature controlled by [RW12](#) to [RW1C](#), [PG\[70\]RW\[7F:78\]](#) is not supported when the RCD is configured in Test Frequency mode (Band 2, [RW05\[7\] = 1](#)) or in PLL bypass mode ([RW05\[3:0\] = 1111](#)).

3.3.9 Per-bit QCA Output Delay Control

In DDR5RCD05, fine adjustment of the phase of individual QCA bit lanes relative to QCK is required. For this purpose, the Host controller can utilize the per-bit QCA output delay control words in [PG\[5\]RW\[7B:60\]](#) to control the phase of A-copy and B-copy QCA bits, respectively. Since all bits within a copy are generally aligned by routing, only a small range of [0, 40ps] is provided for fine-grained adjustment of individual bit lane delay differences. A positive delay in these control words means that the particular lane requires slightly more delay than the previously established QCA delay in [RW1B](#) and [RW1C](#) for the entire copy.

3.3.10 VHost Mode

The Virtual Host mode or “VHost mode” allows a sequence of commands to be sent on the DRAM interface without receiving commands via the Host interface. Commands to be sent on the DRAM interface are programmed by writing RCD control words. The intention is to operate this RCD feature via SidebandBus in a test environment. VHost mode is not intended for normal operation. The Host must configure [RW01\[1\] = ‘1’](#) for RCD to operate VHost mode; otherwise RCD will block VHost commands to the DRAM interface. A sequence of commands is programmed into the RCD, then executed by writing a START MRW bit.

Virtual Host mode has the following features:

- Up to 4 commands may be programmed.
- Each command may be a 1 or 2 UI command.
- Control words specify the complete CA[13:0] bus and the two chip selects for each UI of the commands.
- There is a programmable number of clocks between commands, programmed separately for the spacing between each command.
- Command spacing can be 2, 4, 8, 16, 64, 256, or 1024 clock.
- Following the last command, the sequence may then optionally repeat starting at command 0, 1, 2, or 3.
- Shorter sequences can be supported by programming Deselects (neither chip select active) for some of the commands.
- Non-target termination can be signaled by programming the chip select to be active for both UI of a command that supports non-target termination.

Each command is programmed using four 8-bit control words, to specify the state if CA[13:0], CS0_n and CS1_n for each of the 2 UI. For a 1UI command, the 2nd UI is programmed as a Deselect, with both chip selects inactive. Note that two back to back one UI commands can be programmed instead of a 2UI command, but these will always be back to back, with no programmable spacing.

There are four three-bit delay fields to specify the delay between commands 0 and 1, commands 1 and 2, commands 2 and 3, and command 3 to start of the repeat sequence.

Following the execution of command 3, the sequence will optionally repeat. The sequence can repeat starting at any command (0 through 3) and will continue again through command 3.

3.3.10 VHost Mode (cont'd)

16 control words specify the four commands (4 registers each). Two registers specify the gap between commands. One register specifies the command to repeat from and enables repeating. One register contains a start bit for each channel. Writing a 1 to a start bit begins the sequence on that channel. Writing a 0 stops the sequence. The sequencer is common to the two channels, so the sequence cannot be started on the two channels at different times. The commands operate in either 1N or 2N mode as specified by the existing 1N/2N mode bit. VHost is not supported during SRE/PDE/Initialization or when any training mode is enabled. The commands processed by the VHost logic are not interpreted by the RCD. For example, if the programmed commands include PDE or SRE, those commands will be sent to the DRAMs but they will not cause the RCD to power down. VHost settings cannot be modified while the VHost state machine is running. The RCD will auto stop after cmd3 executes if repeat is not enabled. RST, DCK signals must be applied on the Host interface during VHost mode.

3.3.10.1 VHost Lockout mode

When the RCD receives an In-band MRW to [RW01](#) the RCD will Lockout the VHost mode until the next DRST_n assertion. SidebandBus write to RW01 will not trigger the lockout mechanism.

Suppliers must guarantee a permanent lockout with a fuse option.

3.3.11 CA Validation Pass-Through Mode

To facilitate DRAM or RCD validation the RCD will be required to support a validation pass-through mode. In this mode, the DCA signals are passed through to QCA, regardless of DCS assertion. In this mode, the DCS0_n and DCS1_n signals are passed through to QCS0_n and QCS1_n, respectively, regardless of DCA signal state. Parity checking must be disabled prior to and during validation pass-through mode. Validation pass-through mode is entered when [RW07\[4\]](#)=1. When [RW07\[5\]](#)=1 in CA Validation Pass-through mode, all MRW which write to the RCD are blocked and further configuration is expected via the SidebandBus. This SidebandBus is not required to be driven by the controller. To avoid [RW07\[5:4\]](#) being cleared by the input DRST_n assertion, the users can enable the DRST_n masking feature in [RW2B\[0\]](#) to avoid this problem.

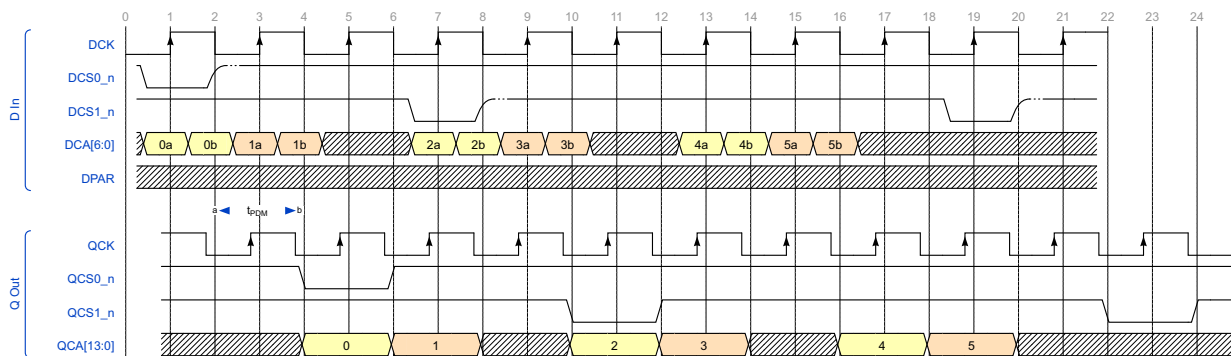


Figure 4 — Validation Pass-Through Mode - DDR

3.3.11 CA Validation Pass-Through Mode (cont'd)

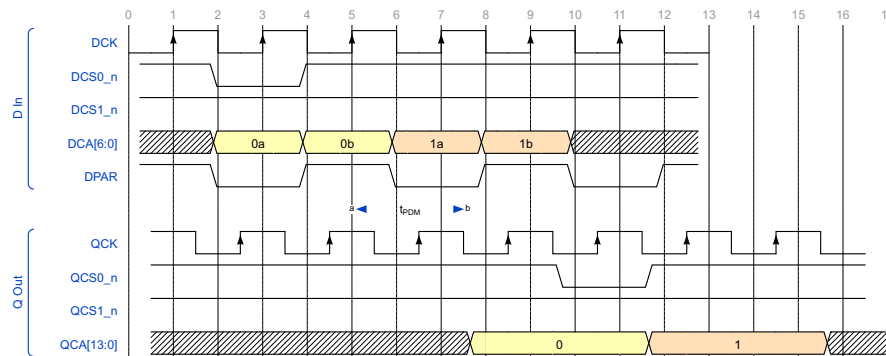


Figure 5 — Validation Pass-Through Mode - SDR1

Similar to CA Pass-Through Mode described in Clause 5.2.4, when Validation Pass-Through Mode is enabled in SDR Mode, the DPAR signal is used to indicate 1st UI QCA[6:0] (DPAR = LOW) and 2nd UI QCA[13:7] (DPAR = HIGH).

3.3.11.1 Clock Stop Support in Validation Pass-Through Mode

Clock stop procedure is supported in the Validation Pass-Through Mode. However, the Controller shall meet the following requirements:

- RW07[5] must be set to disable MRW process prior to the VPTM entry;
- Frequency change is not allowed during the clock stop procedure;
- The tSTAB increases from 3.5 μ s to 5 μ s any time the clock stops and restarts outside of self-refresh;

During the clock stop condition, the outputs of the RCD are don't care. The RCD will retain internal state (RCWs will not be altered), and remain in VPTM once the clock restarts. So there may be traffic that is not acquired (due to the longer tSTAB) once the clock restarts.

3.3.12 DRAM Interface Training Support

In order for the Host to train the DRAM interface, the RCD supports a Pass Through mode: CA Pass-Through mode, described in clause 5.2.4.

3.4 Command Address Bus

The DDR5RCD05 can support two data rates on the Host Command Address signals. The first setting is Double Data Rate (DDR) on the DCA with 1N timing on the QCA. The second is Single Data Rate (SDR) on DCA with 2N timing on the QCA to the DRAM interface. Chip Select is SDR for both settings on DCA and QCA.

Table 5 — Command Address Rates

RW00[1:0]	DCA	QCA
00	SDR1	2N timing (extra setup time)
01	DDR	1N timing
10	SDR2	2N timing (extra hold time)

3.4.1 Double Data Rate DCA

The DDR5 RCD supports DDR (Double Data Rate) on the Host-interface DCA signals. The Host-interface CA bus is 7 bits, plus parity. The DRAM-interface CA bus remains SDR (Single Data Rate) and is 14 bits and without parity. The RCD will expand the incoming Host-interface 7-bit DCA bus to 14 bits on the DRAM interface. Table 6 shows the mapping of the incoming DCA bits to the output QCA. The Chip Selects remain SDR on both the Host-interface and DRAM interface. The two channel DDR5RCD has six CA ports, two DCA input ports and four QCA output ports as shown in Figure 6.

Table 6 — DDR CA Mapping DCA to QCA

UI	DCA0	DCA1	DCA2	DCA3	DCA4	DCA5	DCA6
0	QCA0	QCA1	QCA2	QCA3	QCA4	QCA5	QCA6
1	QCA7	QCA8	QCA9	QCA10	QCA11	QCA12	QCA13

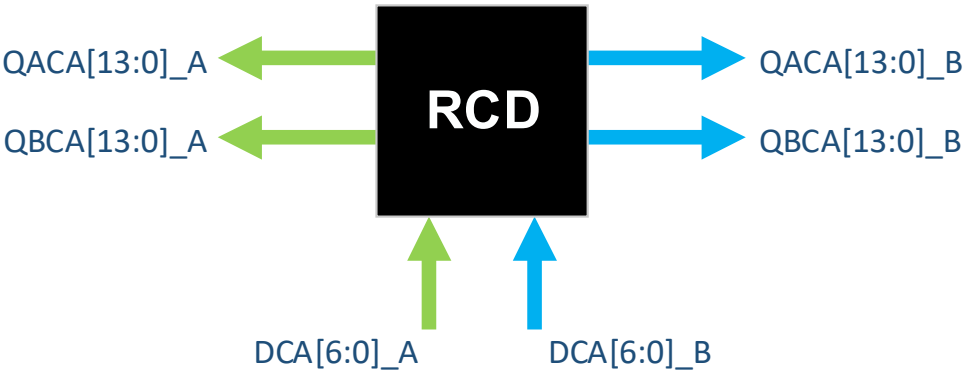
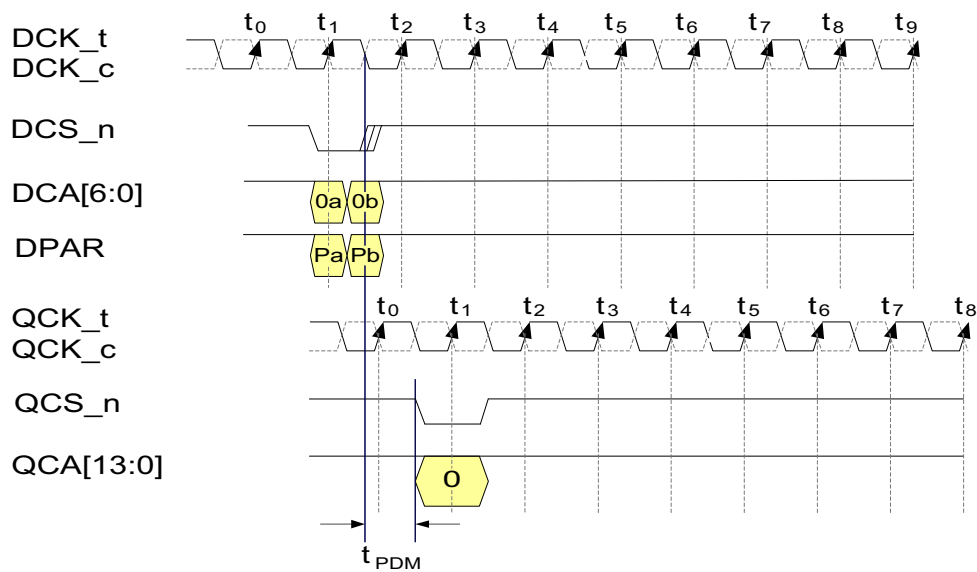


Figure 6 — RCD DCA and QCA Ports

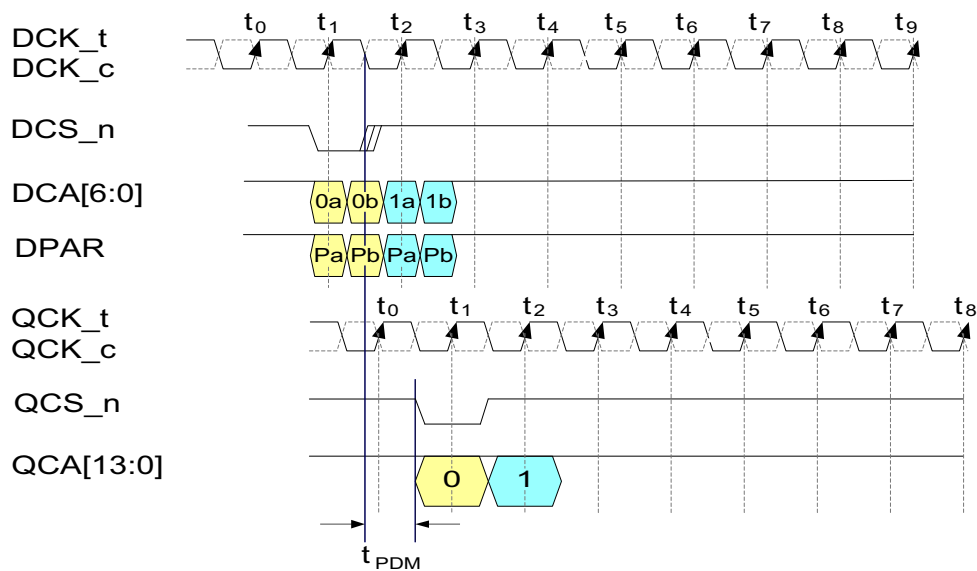
The following timing diagrams in Figures 7, 8, and 9 show the timing relationship from the Dn inputs to the Qn outputs for a 1UI command, a 2UI command, and multiple commands.

3.4.1 Double Data Rate DCA (cont'd)



NOTE: Timing Diagram for 0 nCK command latency adder.

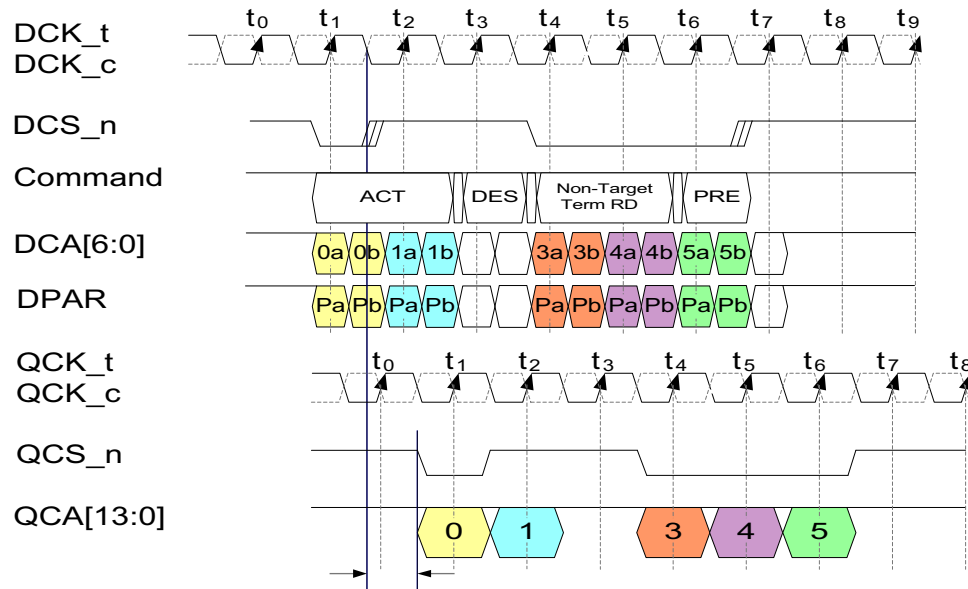
Figure 7 — One UI DRAM Command Timing Diagram



NOTE: Timing Diagram for 0 nCK command latency adder.

Figure 8 — Two UI DRAM Command Timing Diagram

3.4.1 Double Data Rate DCA (cont'd)



NOTE: Timing Diagram for 0 nCK command latency adder.

Figure 9 — DDR CA Multi-Command Timing Diagram Example

The DCS_n signal is SDR and is sampled by the RCD on the rising edge of DCK. See Clause 12.10 on page 280 for details on DCS input receiver electrical and timing parameters. The DDR5RCD must maintain output timings to the DRAM and comply with the output tolerance skew parameter t_{QSK} as shown in Figure 10.

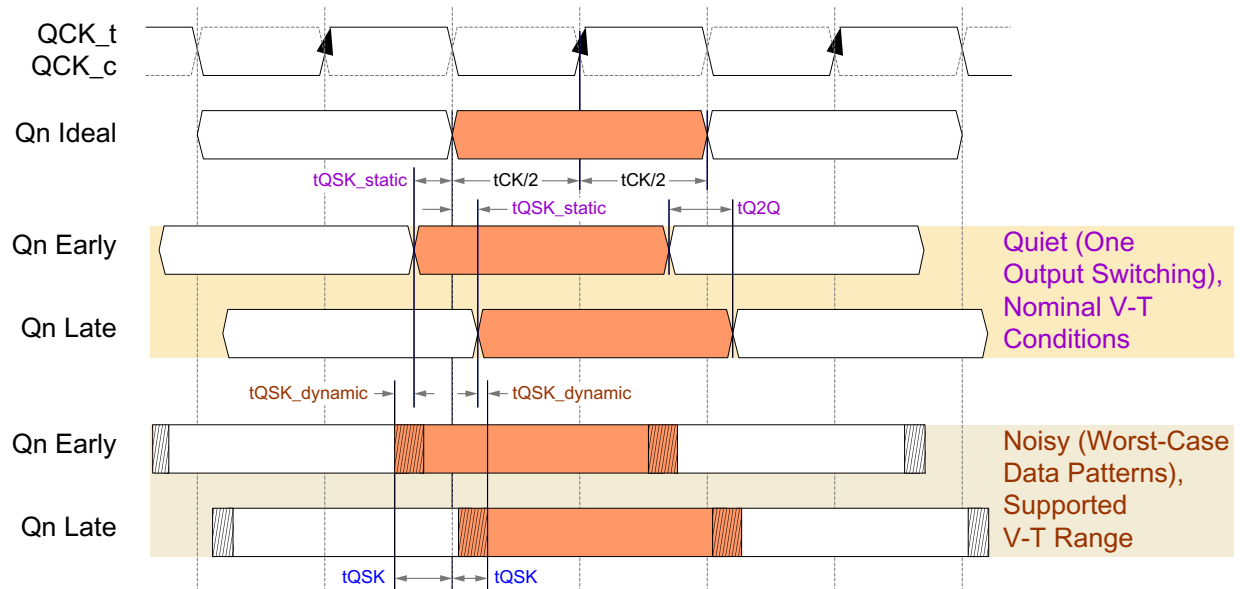


Figure 10 — Qn Output Skew

NOTE: For Figure 10 outputs as specified in Table 233, “Output Timing Requirements” Footnote 7.

3.4.2 Single Data Rate DCA

The DDR5RCD05 supports SDR (Single Data Rate) on the Host-interface DCA signals. In this case, the RCD will apply 2N timing to the DRAM interface signals. This allows more setup or more hold time on the QCA bus. This mode is enabled when **RW00[0] = 0**. DDR5 has defined two-cycle commands that require the RCD to capture the commands differently between DDR and SDR modes. In both modes, the first half of the command is sampled on the rising edge of clock when the chip select is active. In SDR mode, the second half of the command is sampled on the next rising clock edge. Non-target ODT signaling (through chip select inputs) is also delayed by a clock in SDR mode. For applications that require SDR on the Host interface but do not need extra setup time on the DRAM interface, QCS pulses can be pulled earlier by one clock cycle by setting **RW00[1] = 1**.

The QCA will follow the DRAM specification for 2N mode.

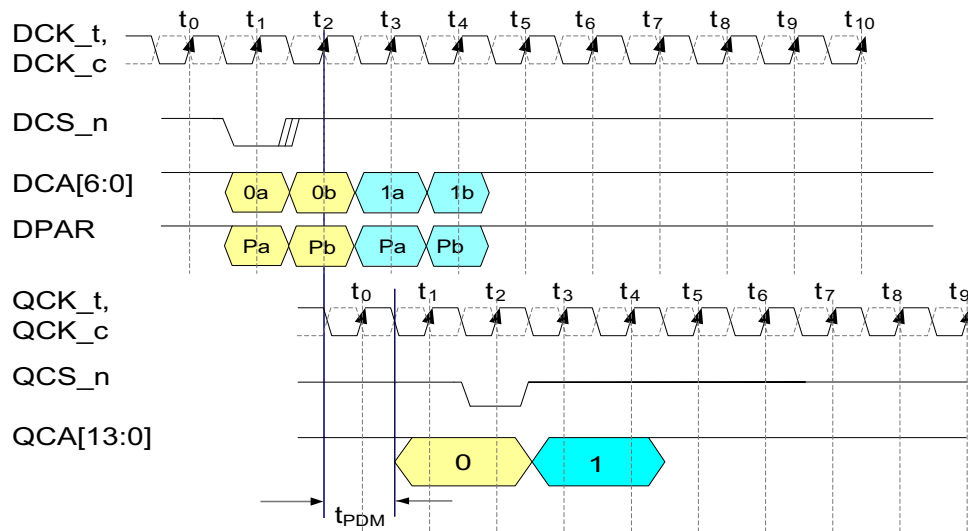


Figure 11 — SDR1 Mode Example of DRAM WR Command with **RW00[1] = 0**

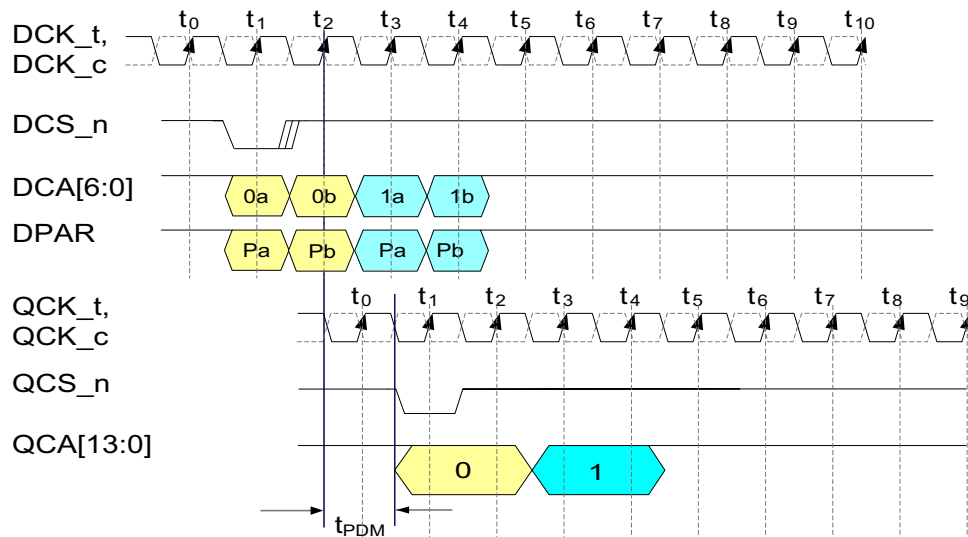


Figure 12 — SDR2 Mode Example of DRAM WR Command with **RW00[1] = 1**

3.4.3 SDR to DDR Transition

This mode is set through SidebandBus during initialization between t_{STAB01} and t_{STAB02} . There is no transition during normal operation. Transitions for SDR to DDR or SDR1 to SDR2 occur prior to Host Interface Training. The Host shall not switch between the SDR, DDR, SDR1 and SDR2 modes after initialization.

3.5 Scrambling on DCA

In SDR DCA mode, scrambling on DCA is not supported. In DDR DCA mode and after initialization and training, the DCA bus can be temporally scrambled using an LFSR that increments with every UI. Each bit of the DCA bus is XORed with a different bit of the LFSR according to Table 25. Each sub-channel has its own LFSR. This feature is disabled by default and enabled by setting PG[70]RW60[2]. It can be enabled at any time the RCD is not in a training mode. The scrambler is disabled by clearing PG[70]RW60[2], after which the Host must wait $t_{\text{MRD_L2}}$ before sending another command. Note that scrambling should be disabled by the Host during any training mode.

The initial seed of the LFSR is set in RW2D and RW2E, as illustrated in Table 25, “16-bit LFSR Seed Mapping”. This seed must be changed from the default value of 0000 in order for the data to be scrambled. The LFSR is synchronized between the Host and the RCD by enabling scrambling in a control word, then sending a NOP command on DCS0 to each sub-channel. The Host shall drive DCA High after the NOP. The NOPs need not be sent at the same time on the two sub-channels, allowing for the LFSRs to be offset from each other. The LFSR begins incrementing four clocks after the NOP command and continues to increment. On the 4th clock, the LFSR produces the +1 value from the seed. The scrambled DCA always starts on a four-cycle boundary relative to the NOP command, i.e., at the 4th clock cycle, the 8th clock cycle, the 12th clock cycle, etc. The first command with scrambling (DCS_n asserted) is permitted 12 clocks from the NOP. The MRW to enable scrambling may be sent either in-band or via the I3C bus.

When the scrambler function is enabled, the calculated DPAR, in addition to DCA[6:0], is scrambled. When {DCA[6:0],DPAR} is received, the RCD first unscrambles it by XORing it with the same LFSR value used by the Host to scramble it, according to Table 25. It then checks parity. Therefore, the parity checking logic can be used to detect loss of synchronization between the Host and RCD LFSRs.

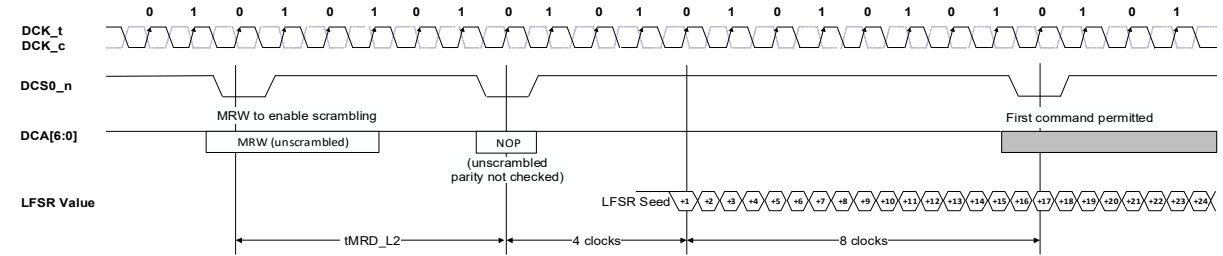
When DCA signals are selected for loopback, the scrambled data from the receivers is sent to the loopback output. For the error log, the unscrambled commands are captured.

The scrambler is reset in the following cases, after which the LFSR must be re-synced with the Host:

- Exit from Self Refresh with Clock Stop.
- If the Scrambler Reset feature (PG[70]RW60[6]) is enabled:
 - Exit from Self-Refresh without Clock Stop.
 - ALERT_n assertion due to internal error (i.e., DCA Parity Error)
- If the Scrambler Reset on DERROR_IN_n Assertion feature (PG[70]RW61[3]) is enabled:
 - DERROR_IN_[B:A]_n assertion due to external event.

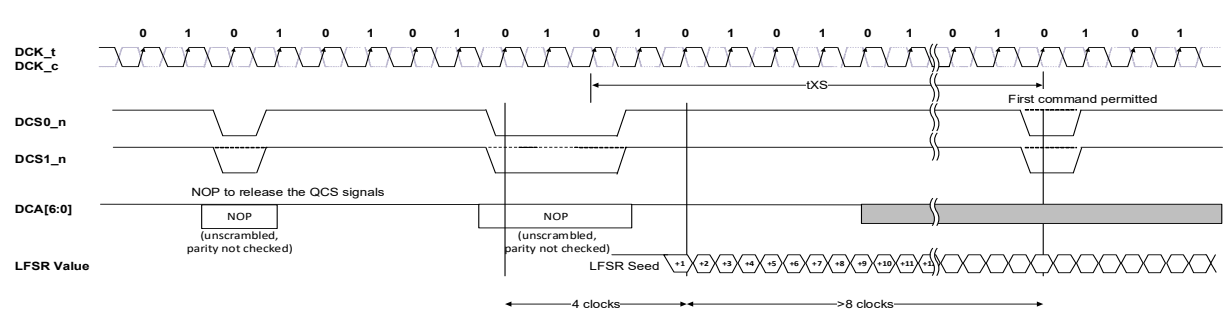
3.5 Scrambling on DCA (cont'd)

If DCA Scrambling is enabled prior to entering HIT-SR mode, see Step 3 in Clause 5.6 for details.



- NOTE 1 No other command may be sent between MRW and NOP.
- NOTE 2 When DCS1_n is set to enabled with RW09[2]=0, the DCS1_n should be driven to High during the synchronization sequence. When DCS1_n is set to disabled with RW09[2]=1, the DCS1_n can be H or L or Z.

Figure 13 — Scrambler Synchronization at Initialization



- NOTE 1 When DCS1_n is set to enabled with RW09[2]=0, the DCS1_n should toggle along with DCS0_n. When DCS1_n is set to disabled with RW09[2]=1, the DCS1_n can be H or L or Z.

Figure 14 — Scrambler Synchronization at Self Refresh Exit

3.5.1 Error Recovery with Scrambling

Table 7 — RCD Action on Error ALERT_n Assertion

Scrambler Enabled ¹ (PG70RW60[2] = 1)							
Scrambler Reset Enabled ² (PG70RW60[6] = 1)							
Error		Scrambler Disable on Error PG70 RW61[2]	Scrambler Reset on DERROR_ IN_n Assertion. PG70 RW61[3]	RCD Command Blocking	RCD Scrambler Disabled	Scrambler Re-sync	Exit Sequence
1	SRE Command with Parity Error with Alert Assertion	Disabled	X	Both Sub CH	No	Both Sub CH	NOP + NOP +3NOP
		Enabled	X	Both Sub CH	Yes	No	N/A (Re-enable Scrambler)
2	Command with Parity Error other than SRE	Disabled	X	Both Sub CH	No	Both Sub CH	NOP + NOP+NOP or NOP + NOP +3NOP
		Enabled	X	Both Sub CH	Yes	No	<u>N/A</u> (<u>Re-enable</u> <u>Scrambler</u>)
3	DERROR_IN_Pulse (DERROR_IN_n pin)	X	Disabled ³	None	No	No	None
		Disabled	Enabled	Both Sub CH	No	Both Sub CH	NOP + NOP+NOP or NOP + NOP +3NOP
		Enabled	Enabled	Both Sub CH	Yes	No	<u>N/A</u> (<u>Re-enable</u> <u>Scrambler</u>)

NOTE 1 If DCA Scrambler is Disabled (PG[70]RW60[2] = 0), then Errors in each sub-channel are handled independently as in RCD parity error, based on ALERT_n setting. Offending Sub-Channel will block commands.

NOTE 2 If DCA Scrambler is Enabled PG[70]RW60[2] = 1 and Scrambler Reset is Disabled PG70RW60[6] = 0, then Errors in each sub-channel are handled independently as in RCD parity error, based on ALERT_n setting. Offending Sub-Channel will block commands. DERROR_IN pulse are passed through with No RCD Command Blocking

NOTE 3 If this case happens at the same time as an error that requires blocking and re syncing, that other case takes precedence.

3.5.1.1 Mode Configuration

Static ALERT_n assertion is not allowed when DCA Scrambling feature is enabled.

If the scrambling feature is disabled (PG[70]RW60[2]=0) or if the Scrambler Reset feature is disabled (PG[70]RW60[6]=0), parity checking and recovery are handled independently per-sub-channel. Scrambler resets caused by errors require resetting the scramblers on both sub-channels because the Host will not know which sub-channel was the source of the ALERT_n pulse.

When the Scrambler Reset feature is enabled (PG[70]RW60[6]=1), and after an internal DCA parity error, the RCD will not execute or forward commands in both sub-channels during the ALERT_n low pulse.

When the Scrambler Reset on DERROR_IN_n Assertion feature is enabled (PG[70]RW61[3]=1) and the Scrambler Reset feature is enabled (PG[70]RW60[6]=1), the RCD will also block commands in both sub-channels after a DERROR_IN_n assertion. The length of time that commands will be blocked is the same length as the pulsed ALERT_n output for an internal error, regardless of the length of the DERROR_IN_n pulse.

When the Scrambler Disable on Error feature is enabled (PG[70]RW61[2]=1), the RCD will not automatically re-enable scrambling after command forwarding is re-enabled during the error recovery. The RCD will clear PG[70]RW60[2] in this case, after which the Host can re-enable it by setting that bit again. Note that the Scrambler Reset feature must also be enabled in this mode because scrambling will be disabled in both sub-channels and therefore commands must be blocked in both sub-channels.

3.5.1.2 Error Recovery Procedure

An ALERT_n assertion at the Host may be caused by a parity error in one of the RCD sub-channels or an Alert Back-Off (ABO) request from the DRAM. The ABO protocol allows the Host to continue to send commands to the DRAM during the ALERT_n pulse, and the DRAM will continue to process them. That is why the Scrambler Reset on DERROR_IN_n Assertion feature defaults to disabled and, as a result, does not require an RCD error recovery procedure. The Host uses the ALERT_n pulse width to differentiate between RCD parity errors and ABO pulses and, therefore, whether the RCD scrambler needs to be reset. An RCD parity error is detected when ALERT_n deasserts before the minimum ABO pulse width.

DRAM CRC is not compatible with Scrambling when the Reset on DERROR_IN_n Assertion feature is disabled (PG[70]RW61[3]=0). The ALERT_n error pulses generated by DRAM CRC errors can coalesce due to the loading of multiple DRAMs on the signal and therefore cannot be distinguished from RCD parity errors. This prevents the Host from being able to use pulse width to know when to resync the scrambler.

If a parity error is detected after an SRE command was sent, each RCD sub-channel may or may not be in a Self Refresh state, waiting for the DCS_n assertion that will indicate whether this will be a Self Refresh With Clock Stop or Without Clock Stop. One or more of the DRAMs may also be a Self Refresh state if the SRE was executed and forwarded by the RCD.

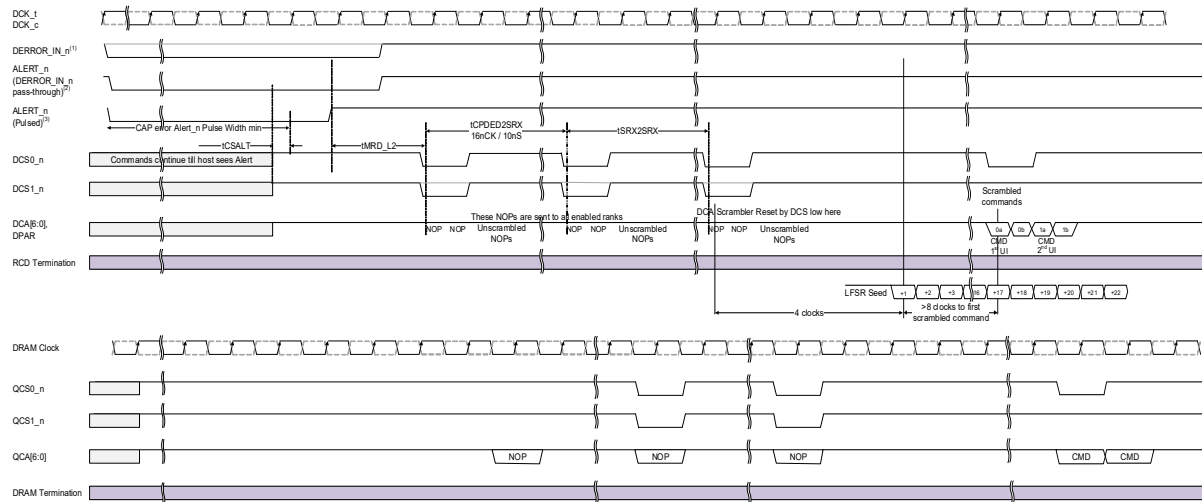
At least tMRD_L2 after the ALERT_n pulse is deasserted for a parity error, while holding the DCA signals High the Host sends a sequence of NOPs to all enabled ranks. If the error detected by the Host is after an SRE command, this sequence consists of two single-cycle NOPs followed by three back-to-back NOPs. Otherwise, the Host will send three single-cycle NOPs.

There are three cases to consider for when an ALERT_n assertion requires a Reset of the DCA scrambler. Cases 2 and 3 are identical from the point of view of the Host and only differ depending on whether a given sub-channel has executed an SRE command.

1. Non-SRE command causing a parity error in the RCD
2. SRE command not executed due to a DCA parity error
3. SRE command executed and forwarded before the ALERT_n assertion

3.5.2 Case #1 - Non-SRE

The non-SRE case is shown in Figure 15. The RCD uses the first NOP to enable command forwarding. DCS is not forwarded to QCS, but DCA is still forwarded to QCA. The second NOP is used for resetting the scrambler logic and it is executed and forwarded as a regular NOP command (without scrambling or parity checking applied). The third NOP in each sub-channel will synchronize that sub-channel's scrambler with the same timing as Initialization in Figure 13. Parity is not checked for the three NOPs. The RCD can either treat any DCS_n Low as a valid NOP, or use the DCS_n Low and DCA High as a valid command.

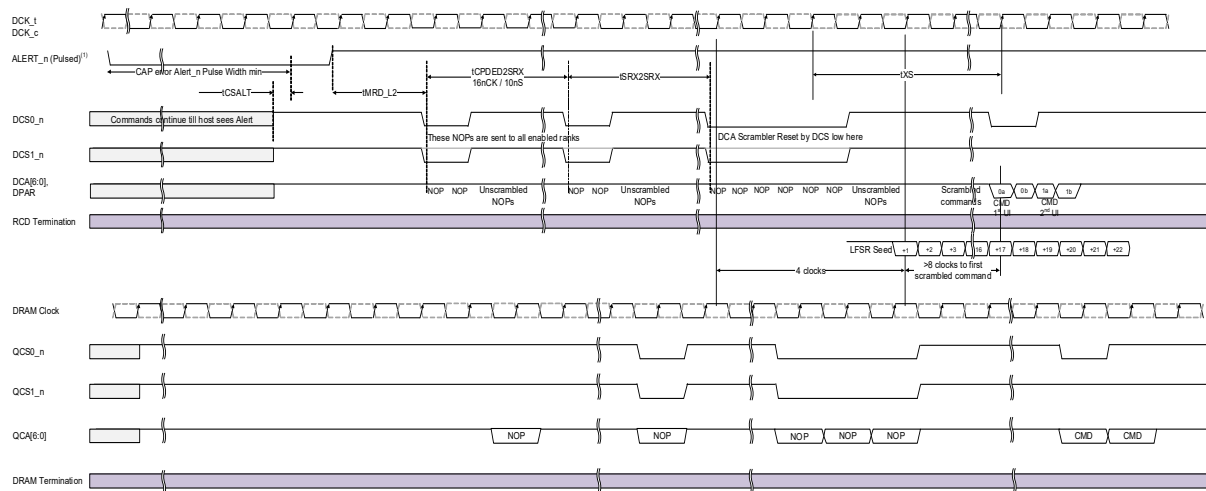


1. DERR0R_IN_n only results in command blocking and requires a scrambler reset if PG[7:0]/RW61[3]=1.
2. If DERR0R_IN_n is asserted by the DRAM, the ALERT_n output will be asserted for the same length of time.
3. This also represents the length of time that commands are blocked in all cases.
4. When DCS1_n is set to enabled with RW09[2]=0, the DCS1_n should toggle along with DCS0_n. When DCS1_n is set to disabled with RW09[2]=1, the DCS1_n can be H or L or Z.

Figure 15 — ALERT_n Scrambler Reset - Non-SRE

3.5.3 Case #2 - SRE - Not Executed Due to a CA Parity Error

In the case where an RCD sub-channel detects a parity error on an SRE command, that command is not executed or forwarded. Therefore, the first two NOPs are handled as in the non-SRE case. The three back-to-back NOPs in each sub-channel will synchronize that sub-channel's scrambler with the same timing as Self Refresh Exit in Figure 14. Parity is not checked for the NOPs. The RCD can either treat any DCS_n Low as a valid NOP, or use the DCS_n Low and DCA High as a valid command. The DRAMs will handle the NOPs as regular NOPs. This is shown in Figure 16.

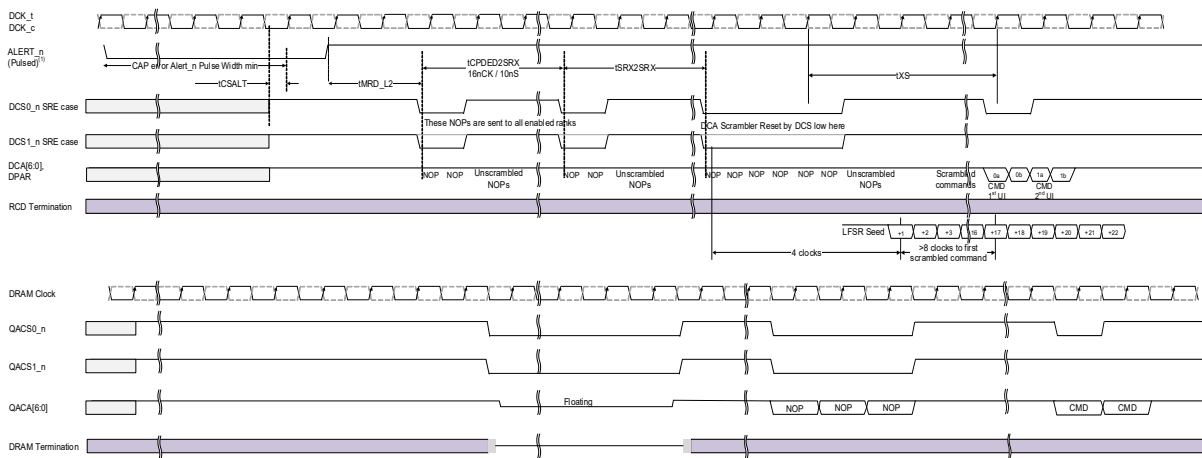


1. The pulsed **ALERT_n** will be asserted for the length of time specified in the '**ALERT_n Pulse Width for Parity Error**' table.
2. When **DCS1_n** is set to enabled with **RW09[2]=0**, the **DCS1_n** should toggle along with **DCS0_n**. When **DCS1_n** is set to disabled with **RW09[2]=1**, the **DCS1_n** can be H or L or Z.

Figure 16 — ALERT_n Scrambler Reset - SRE not Executed due to Parity Error

3.5.4 Case #3 - SRE Executed and Forwarded before ALERT_n Assertion

If a given sub-channel has successfully executed and forwarded an SRE command, that sub-channel will be in Self Refresh. This may be followed by a CA Parity Error on the opposite sub-channel. In that case, the Host will send the same NOP sequence to both sub-channels. The sub-channel in Self Refresh will interpret the NOPs as a Self Refresh Without Clock Stop sequence. The sub-channel not in Self Refresh will interpret the NOPs as regular NOPs. The first NOP by the Host controller will assert Q[B:A]CS[1:0]_n LOW. The 2nd NOP will deassert Q[B:A]CS[1:0]_n HIGH and reset the scrambler. The three back-to-back NOPs in each sub-channel will synchronize that sub-channel's scrambler with the same timing as Self Refresh Exit in Figure 14 and will also complete the Self Refresh Exit procedure in any DRAMs in Self Refresh. Parity will not be checked for the NOPs. The RCD can either treat any DCS_n Low as a valid NOP, or use the DCS_n Low and DCA High as a valid command. This is shown in Figure 17.



1. The ALERT_n output will be asserted for the length of time specified in the 'ALERT_n Pulse Width for Parity Error' table.
2. When DCS1_n is set to enabled with RW09[Z]=0, the DCS1_n should toggle along with DCS0_n. When DCS1_n is set to disabled with RW09[Z]=1, the DCS1_n can be H or L or Z.

Figure 17 — ALERT_n Scrambler Reset, Sub-Channel in Self Refresh

3.5.5 Galois LFSR

Figure 18 shows the LFSR topology to be used by the Memory Controller hardware for CA scrambling.

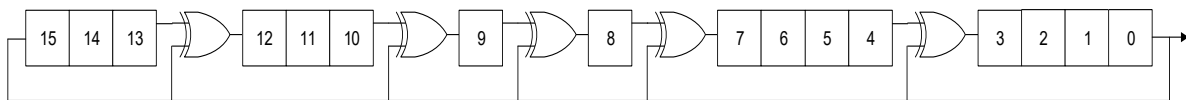


Figure 18 — Galois LFSR: $X^{16} + X^{13} + X^{10} + X^9 + X^8 + X^4 + 1$

Note that the diagram above is the ordering of the bits that is used in Table 8.

3.5.5 Galois LFSR (cont'd)**Table 8 — LFSR Seed Mapping**

LFSR it	DCA ¹	Seed Register Bit	Read Register bit
LFSR bit 0	DPAR_B	RW2D_0	RW35_0
LFSR bit 1	DCA6_B	RW2D_1	RW35_1
LFSR bit 2	DCA5_B	RW2D_2	RW35_2
LFSR bit 3	DCA4_B	RW2D_3	RW35_3
LFSR bit 4	DCA3_B	RW2D_4	RW35_4
LFSR bit 5	DCA2_B	RW2D_5	RW35_5
LFSR bit 6	DCA1_B	RW2D_6	RW35_6
LFSR bit 7	DCA0_B	RW2D_7	RW35_7
LFSR bit 8	DPAR_A	RW2E_0	RW2F_0
LFSR bit 9	DCA6_A	RW2E_1	RW2F_1
LFSR bit 10	DCA5_A	RW2E_2	RW2F_2
LFSR bit 11	DCA4_A	RW2E_3	RW2F_3
LFSR bit 12	DCA3_A	RW2E_4	RW2F_4
LFSR bit 13	DCA2_A	RW2E_5	RW2F_5
LFSR bit 14	DCA1_A	RW2E_6	RW2F_6
LFSR bit 15	DCA0_A	RW2E_7	RW2F_7

NOTE 1 There is a separate LFSR per sub-channel. The DCA/DPAR inputs from sub-channel A are XORED with bits [15:8] of that LFSR and the DCA/DPAR inputs from sub-channel B are XORED with bits [7:0] of that LFSR.

3.5.5 Galois LFSR (cont'd)

Table 9 provides the scrambler output for the first 32 iterations:

Table 9 — Example of Scrambler Output for the First 32 Iterations

DCA UI	Output Bit															
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Default	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
+1	1	1	1	0	1	1	0	0	0	1	1	1	0	1	1	1
+2	1	1	1	0	0	1	0	1	1	0	1	1	0	0	1	1
+3	1	1	1	0	0	0	0	1	0	1	0	1	0	0	0	1
+4	1	1	1	0	0	0	1	1	0	0	1	0	0	0	0	0
+5	0	1	1	1	0	0	0	1	1	0	0	1	0	0	0	0
+6	0	0	1	1	1	0	0	0	1	1	0	0	1	0	0	0
+7	0	0	0	1	1	1	0	0	0	1	1	0	0	1	0	0
+8	0	0	0	0	1	1	1	0	0	0	1	1	0	0	1	0
+9	0	0	0	0	0	1	1	1	0	0	0	1	1	0	0	1
+10	1	0	0	1	0	0	0	0	0	0	0	0	0	1	0	0
+11	0	1	0	0	1	0	0	0	0	0	0	0	0	0	1	0
+12	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0	1
+13	1	0	0	0	0	0	0	1	1	0	0	0	1	0	0	0
+14	0	1	0	0	0	0	0	0	1	1	0	0	0	1	0	0
+15	0	0	1	0	0	0	0	0	0	1	1	0	0	0	1	0
+16	0	0	0	1	0	0	0	0	0	0	1	1	0	0	0	1
+17	1	0	0	1	1	0	1	1	1	0	0	1	0	0	0	0
+18	0	1	0	0	1	1	0	1	1	1	0	0	1	0	0	0
+19	0	0	1	0	0	1	1	0	1	1	1	0	0	1	0	0
+20	0	0	0	1	0	0	1	1	0	1	1	1	0	0	1	0
+21	0	0	0	0	1	0	0	1	1	0	1	1	1	0	0	1
+22	1	0	0	1	0	1	1	1	0	1	0	1	0	1	0	0
+23	0	1	0	0	1	0	1	1	1	0	1	0	1	0	1	0
+24	0	0	1	0	0	1	0	1	1	1	0	1	0	1	0	1
+25	1	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0
+26	0	1	0	0	0	0	0	0	1	0	1	1	0	0	0	1
+27	1	0	1	1	0	0	1	1	1	1	0	1	0	0	0	0
+28	0	1	0	1	1	0	0	1	1	1	1	0	1	0	0	0
+29	0	0	1	0	1	1	0	0	1	1	1	1	0	1	0	0
+30	0	0	0	1	0	1	1	0	0	1	1	1	1	0	1	0
+31	0	0	0	0	1	0	1	1	0	0	1	1	1	1	0	1
+32	1	0	0	1	0	1	1	0	0	0	0	1	0	1	1	0

3.6 Parity

The Parity function in DDR5 differs from DDR4 in several ways

- The parity signal is received on the same cycle as the command/address bits rather than one cycle later.
- 2UI DRAM commands require a different protocol to block commands when the parity error is on the 2nd UI.
- No parity signal is sent on to the DRAMs.

The convention of parity is even parity across the DCA_N[6:0] and DPAR_N signals. The Parity is checked separately per UI on the DCA bus.

Parity is checked separately on the two sub channels. A parity error on one sub channel does not affect the operation of the other sub channel unless scrambling feature is enabled. See Clause 3.5 when scrambling is enabled.

When DDR Command Address Rate is selected, [RW00\[0\]](#) = 1, ALERT_n will be asserted three or four input clocks after rising edge of first UI of DCA in which the erroneous command is registered.

In SDR mode, [RW00\[0\]](#) = 0, ALERT_n will be asserted three or four input clocks after the rising edge corresponding to the second half of the erroneous command. This is the case regardless of the error being in the first, second or both halves.

If parity checking is disabled, the register forwards sampled commands to the outputs unconditionally, the command appears on the outputs regardless of whether a parity error occurred or not.

For single and 2 UI DRAM commands, if parity checking is enabled and there is no parity error, the register will forward the sampled commands to the outputs.

3.6.1 Single UI DRAM Commands with Parity Enabled

For single UI DRAM commands, if parity checking is enabled and a parity error is detected on either UI of the DCA bus, the register will forward the command on QCA bus but will not assert any chip select to output.

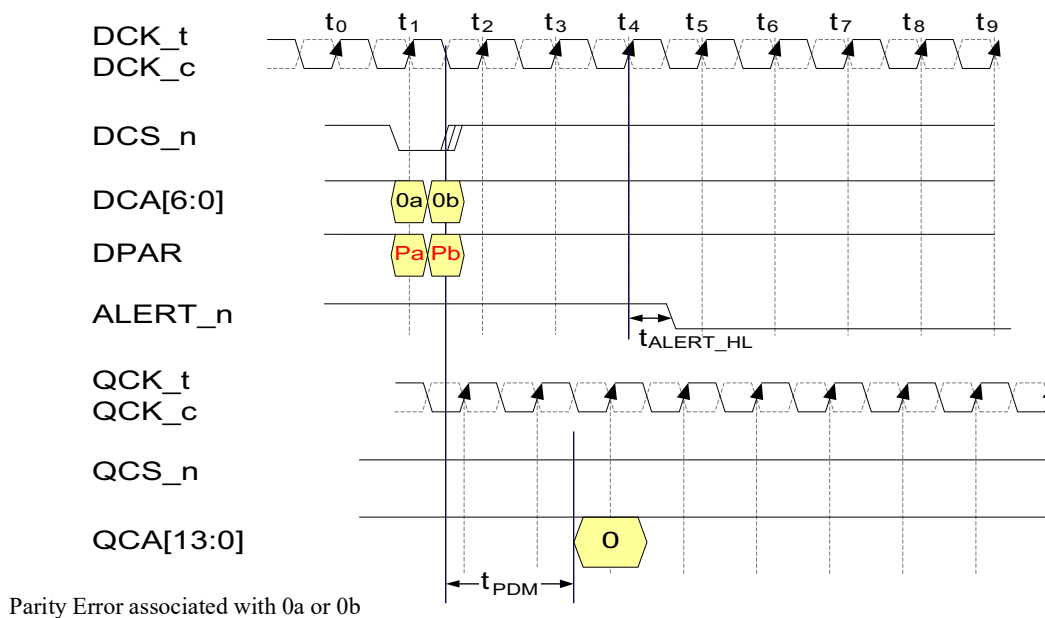


Figure 19 — 1 UI DRAM Command with Parity Checking Enabled and CLA = 0

3.6.1 Single UI DRAM Commands with Parity Enabled (cont'd)

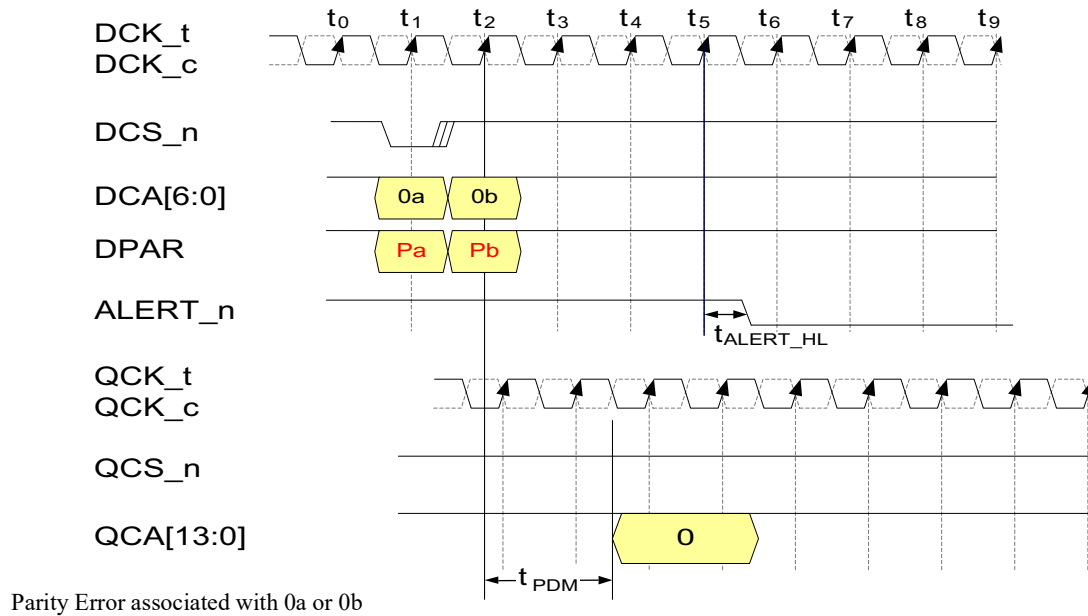


Figure 20 — SDR Mode 1 UI DRAM Command with Parity Checking Enabled and CLA = 0

3.6.2 2UI DRAM Commands with Parity Enabled

For 2UI DRAM commands, if parity checking is enabled and a parity error is detected on either UI of the DCA bus for the 1st UI of the DRAM command the register will forward the command on the QCA but will not assert any chip select output as shown in Figure 21.

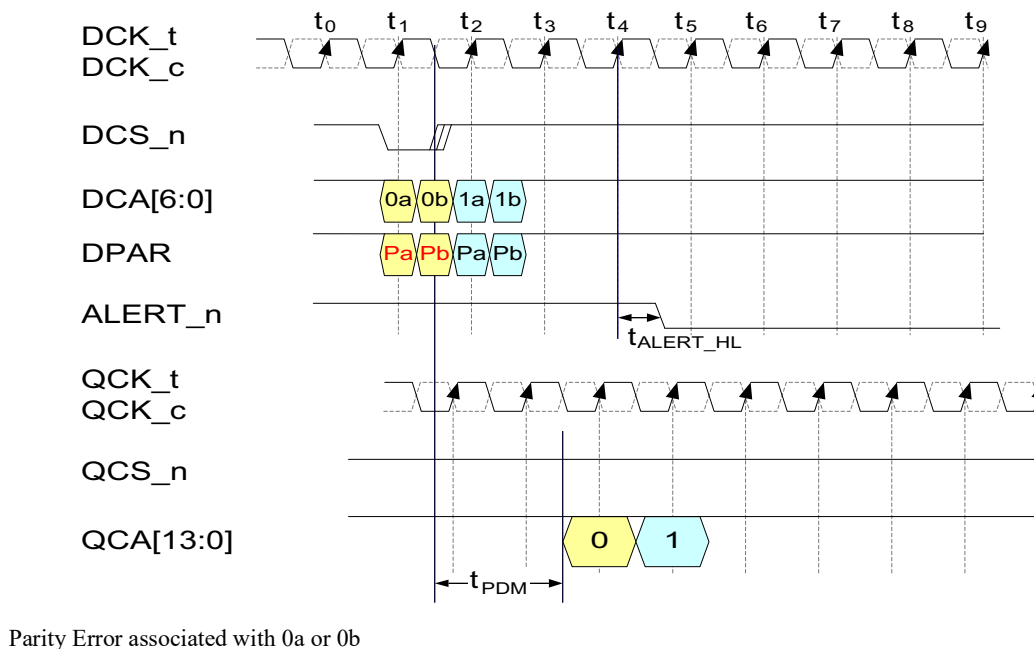
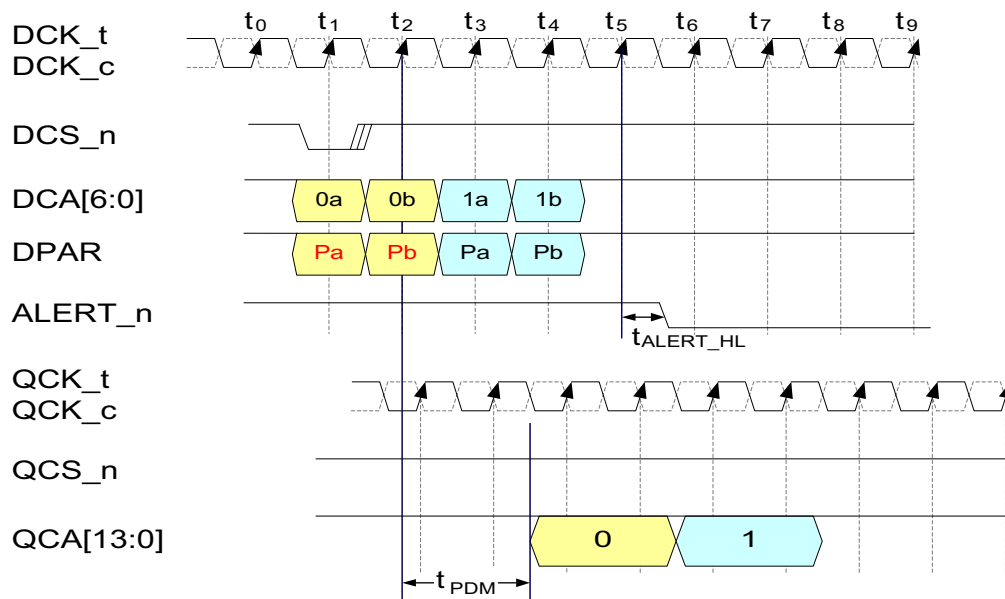


Figure 21 — Error in 1st UI of 2 UI DRAM Command with Parity Checking Enabled

3.6.2 2UI DRAM Commands with Parity Enabled (cont'd)



Parity Error associated with 0a or 0b

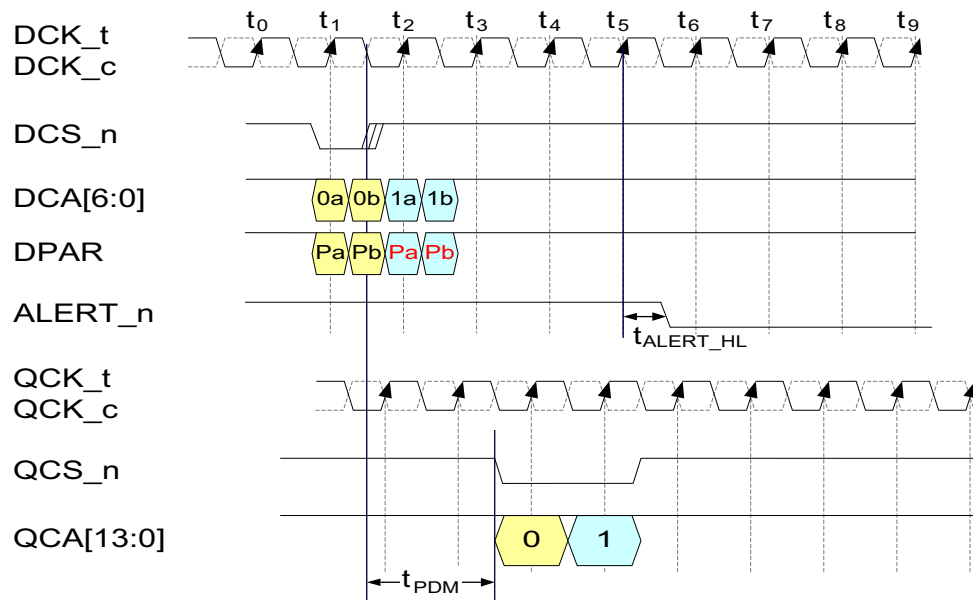
Figure 22 — SDR Mode Error in 1st UI of 2 UI DRAM Command with Parity Checking Enabled

For 2UI DRAM commands, if the parity error occurs in either UI of the DCA bus for the 2nd UI of the DRAM command and the 1st had correct parity, the command will have already been sent to the DRAMs. In this case the command itself will be known to be correct, but the additional address information contained in the 2nd UI will be incorrect. In order to prevent the command from being executed by the DRAM the RCD will assert the chip select in the 2nd UI also for all ranks which received a chip select in the 1st UI as shown in Figure 23.

For RD, WR, and MRR commands, this will convert the command to a non-target termination encoding. All ranks receiving the chip select will terminate for this command, but no rank will execute the command.

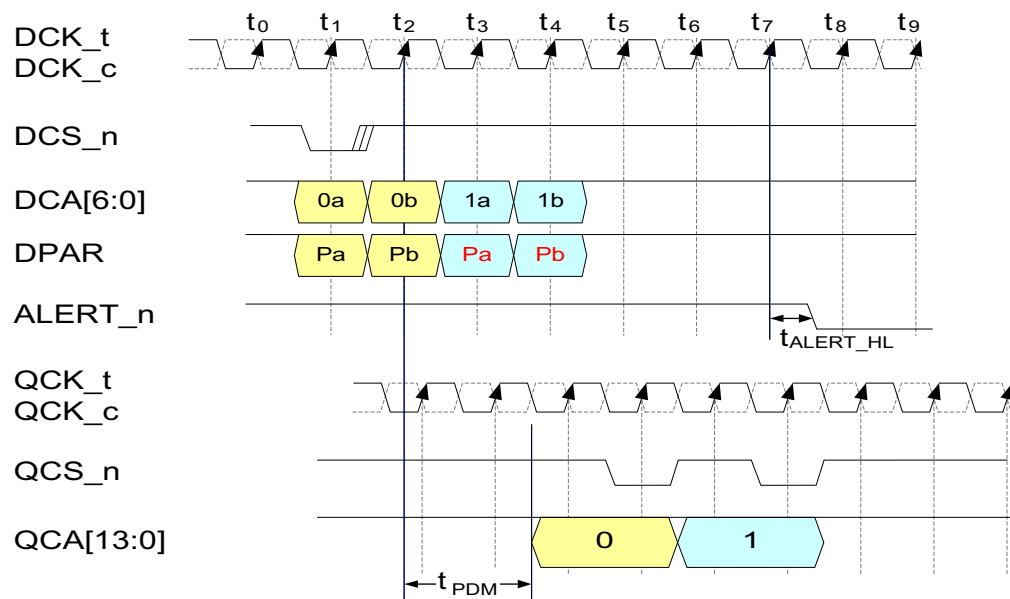
The only other 2 UI DRAM commands are the Activate, MRW, and Write Pattern commands. A DRAM seeing the chip select active for both UI of an Activate or Write Pattern command will ignore the command. Note that an MRW command will not use the data bus. The DRAM will not execute the MRW command if the chip select is asserted in both UI.

3.6.2 2UI DRAM Commands with Parity Enabled (cont'd)



Parity Error associated with 1a or 1b

Figure 23 — Error in 2nd UI of 2 UI DRAM Command with Parity Checking Enabled



Parity Error associated with 1a or 1b

Figure 24 — SDR1 Mode Error in 2nd UI of 2 UI DRAM Command with Parity Checking Enabled

If a parity error occurs on the 1st UI of a DRAM command, regardless of the command length, the command encoding itself may be corrupt. The register is required to block all future commands until command forwarding is re-enabled. When commands are re-enabled, the register must not enable commands until it sees a UI with all CS inactive in order to avoid re-enabling in the middle of a command.

3.6.2 2UI DRAM Commands with Parity Enabled (cont'd)

Table 10 — Blocking Commands on Parity Error

Parity Error on 1st DRAM UI	Parity Error on 2nd DRAM UI	Outputs
No	No	Command is forward to DRAM
No	Yes	First UI of command forward to DRAM. 2nd UI of command forward to DRAM, but with QCS asserted on ALL ranks which received a DCS on the 1st UI. Future commands not sent until parity checking is re-enabled.
Yes	Yes or No	First UI and Second UI of the command forward to DRAM but QCS is not asserted. Future commands not sent until parity checking is re-enabled.

3.6.3 ALERT_n Assertion

The behavior of ALERT_n with parity checking disabled is the same as when parity checking is enabled with the exception that ALERT_n is never asserted as result of a CA parity error. However, when parity checking is disabled, ALERT_n can still be asserted as a result of an assertion of the DERROR_IN_n input.

After the RCD receives DPAR_N from the memory controller, it compares it with the data received on the CA inputs and indicates on its open-drain ALERT_n pin (active LOW) whether a parity error has occurred. The computation only takes place for data which is qualified by at least one of the DCS[1:0]_n signals being Active, or the 2nd UI of a 2UI DRAM Command.

The convention of parity is even parity across the DCA and DPAR signals. Parity is checked independently for the two channels.

If a parity error occurs and parity checking is enabled in [RW01](#), the RCD sets the ‘CA Parity Error Status’ bit in [RW24](#) to ‘1’ and disables parity checking. ALERT_n is asserted three or four input clocks after the erroneous command is registered.

If the ‘CA Parity Error Status’ bit is ‘0’, the RCD logs the error by storing the erroneous command and address bits in the Error Log Register. ALERT_n stays asserted LOW until a ‘Clear CA Parity Error Status’ command is sent if the ‘ALERT_n Assertion’ bit in the Parity Control Word [RW01](#) is ‘0’. In this case the erroneous command and all subsequent commands are not forwarded (i.e., QxCsy_N_n are not asserted) to the DRAM until the memory controller issues a ‘Clear CA Parity Error’ command, which will also clear the ‘CA Parity Error Status’ bit in the Error Log Register.

If the ‘ALERT_n Assertion’ bit is ‘1’, the ALERT_n pulse width is as defined in Table 93 on page 141 with start of the ALERT_n pulse width counted from the third or fourth input clock edge after the 1st parity error. The erroneous command and all subsequent commands are not forwarded (i.e., QxCsy_N_n are not asserted) to the DRAM until the end of the ALERT_n pulse width. After the ALERT_n pulse, the device will automatically resume forwarding commands to the DRAM.

- If the ‘ALERT_n Re-enable’ bit is ‘0’, parity checking remains disabled until a ‘Clear CA Parity Error’ command is sent, which will also clear the ‘CA Parity Error Status’ bit in the Error Log Register.
- If the ‘ALERT_n Re-enable’ bit is ‘1’, the device will re-enable parity checking after the ALERT_n pulse. The ‘CA Parity Error Status’ bit will remain set. If a subsequent parity error is detected, the device will re-enter the parity error state and set the ‘> 1 Error’ bit. The other bits in the Error Log Register are not updated on this subsequent error. Both the ‘CA Parity Error Status’ bit as well as the ‘> 1 Error’ bit will be cleared by sending a ‘Clear CA Parity Error’ command.

3.7 DCA Decision Feedback Equalization

When the DCA is configured to Double Data Rate (i.e., [RW00\[0\]=1](#)), the RCD supports a 6 Tap DFE on the DCA Host-interface receivers. The 6-tap DFE subsystem consists of a gain amplifier, a DFE summer, 6 CA slicers (also called Taps) with outputs that loop back to the DFE summer, and a coefficient multiplier for each Tap. The gain control of the front end is used to ensure that the cursor or the current bit is in a congruent relationship with the ISI correction required for the channel. The taps C1, C2, C3, C4, C5, C6 coefficients provide the corrections needed to the current bit by adding or subtracting the effects of ISI of the previous bits. The Host can enable 1, 2, 3, 4, 5, or 6 taps in a consecutive order always starting with Tap 1 as shown in Table 11, “DCA DFE Tap Configurations”. DFE input gain adjustment and DFE Tap Coefficients 1 through 6 are set by control words located in PG[1:0]. These DFE control words allow programming of each parameter on a DCA I/O-specific basis, and they are intended to be trained by the Host. The DDR5RCD05 device does not support adaptive DFE.

When the DCA is configured to Single Data Rate (i.e., [RW00\[0\]=0](#)), the RCD supports a 4 Tap DFE on the DCA Host-interface receivers. The tap 5 and tap 6 will be disabled in [RW33\[7:6\]](#) by the Host.

3.7.1 DCA DFE Tap Configurations

Table 11 — DCA DFE Tap Configurations

RW31 OP4	RW31 OP5	RW31 OP6	RW31 OP7	RW33 OP6	RW33 OP7	Tap 1	Tap 2	Tap 3	Tap 4	Tap 5	Tap 6
0	x	x	x	x	x	Disabled	Disabled ¹	Disabled ¹	Disabled ¹	Disabled ¹	Disabled ¹
1	0	x	x	x	x	Enabled	Disabled	Disabled ²	Disabled ²	Disabled ²	Disabled ²
1	1	0	x	x	x	Enabled	Enabled	Disabled	Disabled ³	Disabled ³	Disabled ³
1	1	1	0	x	x	Enabled	Enabled	Enabled	Disabled	Disabled ⁴	Disabled ⁴
1	1	1	1	0	x	Enabled	Enabled	Enabled	Enabled	Disabled	Disabled ⁵
1	1	1	1	1	0	Enabled	Enabled	Enabled	Enabled	Enabled	Disabled
1	1	1	1	1	1	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled

NOTE 1 DDR5RCD05 hardware disabled when [RW31\[4\] = 0](#) and {[RW31\[7:5\]](#), [RW33\[7:6\]](#)} are don't care and ignored by the RCD.

NOTE 2 DDR5RCD05 hardware disabled when [RW31\[5\] = 0](#) and {[RW31\[7:6\]](#), [RW33\[7:6\]](#)} are don't care and ignored by the RCD.

NOTE 3 DDR5RCD05 Hardware disabled when [RW31\[6\] = 0](#), and {[RW31\[7\]](#), [RW33\[7:6\]](#)} are don't care and ignored by the RCD.

NOTE 4 DDR5RCD05 Hardware disabled when [RW31\[7\] = 0](#), and [RW33\[7:6\]](#) are don't care and ignored by the RCD.

NOTE 5 DDR5RCD05 Hardware disabled when [RW33\[6\] = 0](#), and [RW33\[7\]](#) is a don't care and ignored by the RCD.

3.7.2 DCA DFE Gain and Tap Range

Table 12 — DCA DFE Gain and Tap Total Control Word Range

DFE Parameter	Min	Max	Unit
Gain	-6	6	dB
Tap 1	- 150	150	mV
Tap 2	- 60	60	mV
Tap 3	- 45	45	mV
Tap 4	- 45	45	mV
Tap 5	- 45	45	mV
Tap 6	- 45	45	mV

3.7.2 DCA DFE Gain and Tap Range (cont'd)

Table 13 — DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin

DFE Parameter	DDR5-3200 - 8000			Unit
	Min	Typ	Max	
DFE Gain Bias Step Size ^{1,2}	1.7	2	2.3	dB
DFE Gain Bias Tolerance (INL) ^{1,2}	- 0.5	-	0.5	dB
DFE Gain Bias Step Size Tolerance (DNL) ^{1,2}	- 0.3	-	0.3	dB
DFE Gain Bias Step Time ¹	-	-	300	ns
DFE Tap Bias Step Size ^{1,2}	1	3	5	mV
DFE Tap Bias Tolerance (INL) (-150 mV to 0 mV) ^{1,2}	Min ($V_{ideal} \times 115\%$, $V_{ideal} - 3 * LSB$) ^{3,4}	-	Max ($V_{ideal} \times 85\%$, $V_{ideal} + 3 * LSB$) ^{3,4}	mV
DFE Tap Bias Tolerance (INL) (0 mV to 150 mV) ^{1,2}	Min ($V_{ideal} \times 85\%$, $V_{ideal} - 3 * LSB$) ^{3,4}	-	Max ($V_{ideal} \times 115\%$, $V_{ideal} + 3 * LSB$) ^{3,4}	mV
DFE Tap Bias Step Size Tolerance (DNL) ⁻²	- 66.67	-	66.67	% of Step Size
DFE Tap Bias Step Time	-	-	64	tCK

NOTE 1 Host Vref fixed at $0.75 \times V_{DD}$, typical Voltage-Temperature condition (i.e., $V_{DD} = 1.1$ V, 25 °C), and default gain setting.

NOTE 2 These parameters are neither subject to silicon validation nor production testing.

NOTE 3 V_{ideal} refers to the ideal DFE Tap value based on the setting.

NOTE 4 $LSB = 3$ mV.

3.7.3 DCA DFE Tap Measurement

When DFE taps are enabled, they add offset to the DFE summer, which affects the input to the slicer. The feedback to the taps may be positive or negative, based on the sign of the coefficient and the level of the input, resulting in four cases, all of which must be tested. Each tap is measured individually with other tap coefficients set to 0. Other combinations can be extrapolated from the results.

3.7.3.1 HIGH-to-LOW Transition Test Method

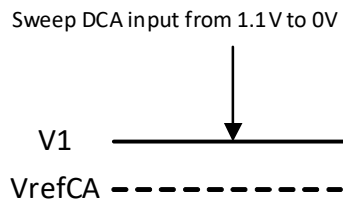
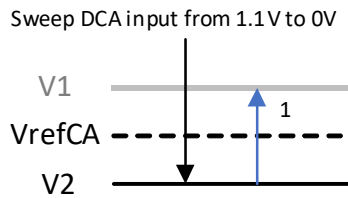


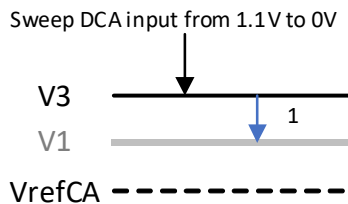
Figure 25 — HIGH-to-LOW Sweep: No DFE Applied

3.7.3.1 HIGH-to-LOW Transition Test Method (cont'd)



Note 1: Positive feedback results in an increase in voltage as seen by the slicer

Figure 26 — HIGH-to-LOW Sweep: DFE Positive Bias Applied



Note 1: Negative feedback results in a decrease in voltage as seen by the slicer

Figure 27 — HIGH-to-LOW Sweep: DFE Negative Bias Applied

1. Make sure VrefCA (RW[47:40]) is set to the default, DFE_Vref (PG[2]RW[62, 66, 6A, 6E, 72, 76, 7A, 7E]) is set to 0, power supply is 1.1 V, and DFE is disabled.
2. Sweep the input signal from 1.1V to 0V to find the lowest level that produces a stable HIGH output and record this input level as V1. No overshoot is allowed on the input. See [Figure 25](#).
3. Enable DFE (RW31[0]). Enable the tap under test and all previous taps in RW31[7:4]. Set the coefficients for the previous taps to 0. All configuration in this procedure is via Sideband-Bus access.
4. Configure the sign bit to 0 and the coefficient to n steps for the tap under test, where n is a loop variable.
5. Sweep the input signal from 1.1 V to 0 V to find the lowest level that produces a stable HIGH output and record this input level as V2. No overshoot is allowed on the input. See [Figure 26](#).
6. The DFE Tap Bias $V(+) = (V1 - V2)$ for positive feedback. Validate $V(+)$ is within spec.
7. Configure the sign bit to 1 and the coefficient to n steps for the tap under test, where n is a loop variable.
8. Sweep the input signal from 1.1 V to 0 V to find the lowest level that produces a stable HIGH output and record this input level as V3. No overshoot is allowed on the input. See [Figure 27](#).
9. The DFE Tap Bias $V(-) = (V1 - V3)$ for negative feedback. Validate $V(-)$ is within spec.
10. Repeat steps 4-9 until all the Tap steps for Taps 1-4 are measured.

3.7.3.2 LOW-to-HIGH Test Transition Method

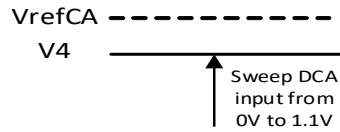
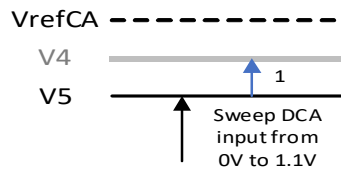
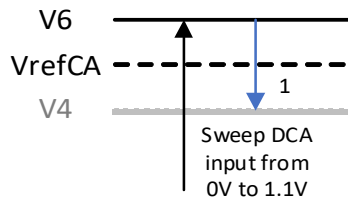


Figure 28 — LOW-to-HIGH Sweep: No DFE Applied



Note1: Positive feedback results in an increase in voltage as seen by the slicer

Figure 29 — LOW-to-HIGH Sweep: DFE Positive Bias Applied



Note 1: Negative feedback results in a decrease in voltage as seen by the slicer

Figure 30 — LOW-to-HIGH Sweep: DFE Negative Bias Applied

1. Make sure VrefCA (RW[47:40]) is set to the default, DFE_Vref (PG[2]RW[62, 66, 6A, 6E, 72, 76, 7A, 7E]) is set to 0, power supply is 1.1 V, and DFE is disabled.
2. Sweep the input signal from 0 V to 1.1 V to find the highest level that produces a stable LOW output and record this input level as V4. No overshoot is allowed on the input. See [Figure 28](#).
3. Enable DFE (RW31[0]). Enable the tap under test and all previous taps in RW31[7:4]. Set the coefficients for the previous taps to 0. All configuration in this procedure is via Sideband-Bus access.
4. Configure the sign bit to 1 and the coefficient to n steps for the tap under test, where n is a loop variable.
5. Sweep the input signal from 0 V to 1.1 V to find the highest level that produces a stable LOW output and record this input level as V5. No overshoot is allowed on the input. See [Figure 29](#).
6. The DFE Tap Bias $V(+)$ = $(V4 - V5)$ for positive feedback. Validate $V(+)$ is within spec.
7. Configure the sign bit to 0 and the coefficient to n steps for the tap under test, where n is a loop variable.
8. Sweep the input signal from 0 V to 1.1 V to find the highest level that produces a stable LOW output and record this input level as V6. No overshoot is allowed on the input. See [Figure 30](#).
9. The DFE Tap Bias $V(-)$ = $(V4 - V6)$ for negative feedback. Validate $V(-)$ is within spec.
10. Repeat steps 4-9 until all the Tap steps for Taps 1-4 are measured.

3.8 DCS Decision Feedback Equalization

The RCD supports a 4 Tap DFE on the DCS Host-interface receivers. The 4-tap DFE subsystem consists of a gain amplifier, a DFE summer, 4 CS slicers (also called Taps) with outputs that loop back to the DFE summer, and a coefficient multiplier for each Tap. The gain control of the front end is used to ensure that the cursor or the current bit is in a congruent relationship with the ISI correction required for the channel. The taps C1, C2, C3, C4 coefficients provide the corrections needed to the current bit by adding or subtracting the effects of ISI of the previous bits. The Host can enable 1, 2, 3 or 4 taps in a consecutive order always starting with Tap 1 as shown in Table 11, “DCA DFE Tap Configurations”. DFE input gain adjustment and DFE Tap Coefficients 1 through 4 are set by control words located in PG[6]. These DFE control words allow programming of each parameter on a DCS I/O-specific basis, and they are intended to be trained by the Host. The RCD device does not support adaptive DCS DFE.

3.8.1 DCS DFE Tap Configurations

Table 14 — DCS DFE Tap Configurations

PG[6] RW78 OP4	PG[6] RW78 OP5	PG[6] RW78 OP6	PG[6] RW78 OP7	Tap 1	Tap 2	Tap 3	Tap 4
0	x	x	x	Disabled	Disabled ¹	Disabled ¹	Disabled ¹
1	0	x	x	Enabled	Disabled	Disabled ²	Disabled ²
1	1	0	x	Enabled	Enabled	Disabled	Disabled ³
1	1	1	0	Enabled	Enabled	Enabled	Disabled
1	1	1	1	Enabled	Enabled	Enabled	Enabled

NOTE 1 DDR5RCD05 hardware disabled when PG[6]RW78[4] = 0 and {PG[6]RW78[7:5]} are don't care and ignored by the RCD.

NOTE 2 DDR5RCD05 hardware disabled when PG[6]RW78[5] = 0 and {PG[6]RW78[7:6]} are don't care and ignored by the RCD.

NOTE 3 DDR5RCD05 hardware disabled when PG[6]RW78[6] = 0, and {PG[6]RW78[7]} are don't care and ignored by the RCD.

3.8.2 DCS DFE Gain and Tap Range

Table 15 — DCS DFE Gain and Tap Total Control Word Range

DFE Parameter	Min	Max	Unit
Gain	-6	6	dB
Tap1	- 150	150	mV
Tap 2	- 60	60	mV
Tap 3	- 45	45	mV
Tap 4	- 45	45	mV

3.8.2 DCS DFE Gain and Tap Range (cont'd)**Table 16 — DCS DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin**

DFE Parameter	DDR5-3200 - 8000			Unit
	Min	Typ	Max	
DFE Gain Bias Step Size ^{1,2}	1.7	2	2.3	dB
DFE Gain Bias Tolerance (INL) ^{1,2}	- 0.5	-	0.5	dB
DFE Gain Bias Step Size Tolerance (DNL) ^{1,2}	- 0.3	-	0.3	dB
DFE Gain Bias Step Time ¹	-	-	300	ns
DFE Tap Bias Step Size ^{1,2}	1	3	5	mV
DFE Tap Bias Tolerance (INL) (-150 mV to 0 mV) ^{1,2}	Min ($V_{ideal} \times 115\%$, $V_{ideal} - 3 * LSB$) ^{3,4}	-	Max ($V_{ideal} \times 85\%$, $V_{ideal} + 3 * LSB$) ^{3,4}	mV
DFE Tap Bias Tolerance (INL) (0 mV to 150 mV) ^{1,2}	Min ($V_{ideal} \times 85\%$, $V_{ideal} - 3 * LSB$) ^{3,4}	-	Max ($V_{ideal} \times 115\%$, $V_{ideal} + 3 * LSB$) ^{3,4}	mV
DFE Tap Bias Step Size Tolerance (DNL) ²	- 66.67	-	66.67	% of Step Size
DFE Tap Bias Step Time	-	-	64	tCK

NOTE 1 Host Vref fixed at $0.75 \times V_{DD}$, typical Voltage-Temperature condition (i.e., $V_{DD} = 1.1 \text{ V}$, 25°C), and default gain setting.

NOTE 2 These parameters are neither subject to silicon validation nor production testing.

NOTE 3 V_{ideal} refers to the ideal DFE Tap value based on the setting.

NOTE 4 $LSB = 3 \text{ mV}$.

3.9 Continuous Time Linear Equalization (CTLE)

3.9.1 Background

Continuous time linear equalization can be an effective method to improve signal margins at input receivers of the DDR5RCD05 device.

3.9.2 CTLE Transfer Function

The equation below represents the CTLE transfer function implemented in the DDR5RCD05 device.

$$\frac{A_{dc} \left(1 + \frac{s}{Z} \right)}{\left(1 + \frac{s}{P_1} \right) \left(1 + \frac{s}{P_2} \right)}$$

Where

- A_{dc} is the gain of the CTLE at DC,
- Z is the location of the zero,
- P_1 is the location of the first pole, and
- P_2 is the location of the second pole.

The DDR5RCD05 receivers support 16 possible combinations of CTLE parameter values as shown in Table 17 below. The device revision can only support one of the CTLE Configuration Ranges, A, B, C, or D. The Host can read out the supported range from the CTLE Configuration Control Word, [RW50\[7:5\]](#). Each combination can be selected through 4-bit control word settings [RW52\[3:0\]](#) (CTLE Parameter Set A) and [RW53\[3:0\]](#) (CTLE Parameter Set B). There is a CTLE global feature enable control bit in [RW50\[0\]](#), and enable/disable controls per-pin in [RW51\[7:0\]](#). An 8-bit control word, [RW54\[7:0\]](#), provides per-pin control to determine whether a receiver uses CTLE Parameter Set A controlled by [RW52\[3:0\]](#), or Parameter Set B controlled by [RW53\[3:0\]](#).

3.9.2 CTLE Transfer Function (cont'd)**Table 17 — Supported CTLE Parameter Value Combinations¹**

Range	CW Bits OP[3:0] in RW52 or RW53	Gain (A_{dc}) ²	Zero (Z)	Pole 1 (P ₁)	Pole 2 (P ₂)
A	0000 _B	VS_A	VS_A	VS_A	VS_A
	0001 _B	VS_A	VS_A	VS_A	VS_A
	0010 _B	VS_A	VS_A	VS_A	VS_A
	0011 _B	VS_A	VS_A	VS_A	VS_A
	0100 _B	VS_A	VS_A	VS_A	VS_A
	0101 _B	VS_A	VS_A	VS_A	VS_A
	0110 _B	VS_A	VS_A	VS_A	VS_A
	0111 _B	VS_A	VS_A	VS_A	VS_A
	1000 _B	VS_A	VS_A	VS_A	VS_A
	1001 _B	VS_A	VS_A	VS_A	VS_A
	1010 _B	VS_A	VS_A	VS_A	VS_A
	1011 _B	VS_A	VS_A	VS_A	VS_A
	1100 _B	VS_A	VS_A	VS_A	VS_A
	1101 _B	VS_A	VS_A	VS_A	VS_A
	1110 _B	VS_A	VS_A	VS_A	VS_A
	1111 _B	VS_A	VS_A	VS_A	VS_A
B	0000 _B	VS_B	VS_B	VS_B	VS_B
	0001 _B	VS_B	VS_B	VS_B	VS_B
	0010 _B	VS_B	VS_B	VS_B	VS_B
	0011 _B	VS_B	VS_B	VS_B	VS_B
	0100 _B	VS_B	VS_B	VS_B	VS_B
	0101 _B	VS_B	VS_B	VS_B	VS_B
	0110 _B	VS_B	VS_B	VS_B	VS_B
	0111 _B	VS_B	VS_B	VS_B	VS_B
	1000 _B	VS_B	VS_B	VS_B	VS_B
	1001 _B	VS_B	VS_B	VS_B	VS_B
	1010 _B	VS_B	VS_B	VS_B	VS_B
	1011 _B	VS_B	VS_B	VS_B	VS_B
	1100 _B	VS_B	VS_B	VS_B	VS_B
	1101 _B	VS_B	VS_B	VS_B	VS_B
	1110 _B	VS_B	VS_B	VS_B	VS_B
	1111 _B	VS_B	VS_B	VS_B	VS_B

Table 17 — Supported CTLE Parameter Value Combinations¹ (cont'd)

C	0000 _B	VS _C	VS _C	VS _C	VS _C
	0001 _B	VS _C	VS _C	VS _C	VS _C
	0010 _B	VS _C	VS _C	VS _C	VS _C
	0011 _B	VS _C	VS _C	VS _C	VS _C
	0100 _B	VS _C	VS _C	VS _C	VS _C
	0101 _B	VS _C	VS _C	VS _C	VS _C
	0110 _B	VS _C	VS _C	VS _C	VS _C
	0111 _B	VS _C	VS _C	VS _C	VS _C
	1000 _B	VS _C	VS _C	VS _C	VS _C
	1001 _B	VS _C	VS _C	VS _C	VS _C
	1010 _B	VS _C	VS _C	VS _C	VS _C
	1011 _B	VS _C	VS _C	VS _C	VS _C
	1100 _B	VS _C	VS _C	VS _C	VS _C
	1101 _B	VS _C	VS _C	VS _C	VS _C
	1110 _B	VS _C	VS _C	VS _C	VS _C
	1111 _B	VS _C	VS _C	VS _C	VS _C
D	0000 _B	VS _D	VS _D	VS _D	VS _D
	0001 _B	VS _D	VS _D	VS _D	VS _D
	0010 _B	VS _D	VS _D	VS _D	VS _D
	0011 _B	VS _D	VS _D	VS _D	VS _D
	0100 _B	VS _D	VS _D	VS _D	VS _D
	0101 _B	VS _D	VS _D	VS _D	VS _D
	0110 _B	VS _D	VS _D	VS _D	VS _D
	0111 _B	VS _D	VS _D	VS _D	VS _D
	1000 _B	VS _D	VS _D	VS _D	VS _D
	1001 _B	VS _D	VS _D	VS _D	VS _D
	1010 _B	VS _D	VS _D	VS _D	VS _D
	1011 _B	VS _D	VS _D	VS _D	VS _D
	1100 _B	VS _D	VS _D	VS _D	VS _D
	1101 _B	VS _D	VS _D	VS _D	VS _D
	1110 _B	VS _D	VS _D	VS _D	VS _D
	1111 _B	VS _D	VS _D	VS _D	VS _D

NOTE 1 The Gain, Zero and Pole values are vendor specific. For the four ranges, these values are VS_A (Vendor Specific A), VS_B (Vendor Specific B), VS_C (Vendor Specific C), VS_D (Vendor Specific D).

NOTE 2 The A_{dc} gain parameter is implemented by overriding the DFE Gain coefficient settings in PG[1:0]RW[60, 68, 70, 78]. When CTLE is enabled in a given receiver through RW50[0] and RW51[7:0], the gain settings for that receiver are determined only by the values programmed in RW52[3:0], RW53[3:0], and RW54[7:0]; and the values in PG[1:0]RW[60, 68, 70, 78] are ignored for that receiver. This applies regardless of any one or more of the following features being enabled or disabled: DFE, DFE Training, or DFE Training Acceleration

3.10 Enhanced CTLE

In the legacy CTLE definition, CTLE Parameter Set A in [RW52\[3:0\]](#) and CTLE Parameter Set B in [RW53\[3:0\]](#) are defined to select two settings out of the total of sixteen CTLE combinations that the device offers. Each DCA bit chooses either Set A or Set B as the final CTLE setting in [RW54](#).

The legacy CTLE Set A and Set B structure may not be sufficient when different DCA bits require more than two CTLE settings. For example, the optimum setting for DCA0 is setting 0, the optimum setting for DCA1 is setting 1, while the optimum setting for DCA2 is setting 2. If there are only Set A and Set B, then they cannot offer the optimum settings for all the DCA bits.

To resolve the restriction of the legacy CTLE, the Enhanced CTLE is defined with independent four-bit control word defined in [PG\[7\]RW\[75:71\]](#) for each DCA or DCS bit to store its optimum setting.

3.11 RX Loopback

3.11.1 Loopback Mode

When the loopback circuit is enabled in [RW26](#), the DDR5RCD05 can feed a received signal or internal data back to the Host for debugging, testing, and/or training purposes. Loopback Mode and DFE Training Mode shall not be enabled simultaneously. Loopback Mode is not supported in Test Mode (Frequency Band 2). Loopback is necessary in order for the Host memory controller or test instrument to immediately read back data that was written to the RCD, DRAM without having to issue multiple DRAM WRITE/READ commands. There are also inherent limitations when characterizing the receiver using statistical analysis methods such as Bit Error Rate (BER) analysis.

For example, at $BER=10^{-16}$:

1. There is not enough memory depth in the DRAM to store all the 10^{16} data.
2. The amount of time to perform multiple WRITE/READ commands to and from the array is prohibitively long.
3. Since the amount of time involved performing these operations is much longer than the DRAM refresh rate interval, the Host or memory controller must also manage Refreshes during testing to ensure data retention.
4. Limited pattern depth means limited Inter symbol Interference (ISI). Loopback is a necessity for characterizing the receiver without the limitations and complexities of other traditional methods.

3.11.2 Loopback Ports

There are five RCD loopback ports, four input ports and one output port. The input ports consist of two internal and two external port as shown in Figure . Each port contains one data signal and one strobe signal. [RW26](#) selects the internal or external signals to loopback to the Host on the output port. Transitions in the incoming data signal are aligned to the rising edges of the incoming strobe. The RCD will sample incoming data with the falling edges of the incoming strobe and it will drive the strobe and data signals out to the Host controller. Internal RCD Loopback is only intended to send back the output of the functional path slicer. Internal RCD Loopback is independent from [RW32\[2:1\]](#) Training Source selection field.

3.11.2 Loopback Ports (cont'd)

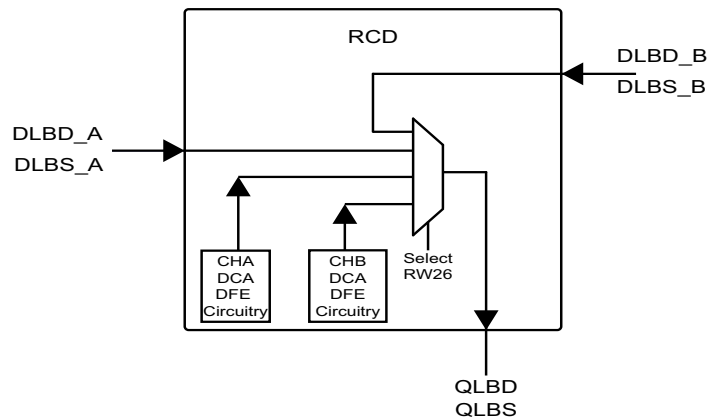


Figure 31 — RCD Loopback Ports Pin Assignment for Loopback, Timing Diagrams and Timing Parameters

Inputs (From DRAM)

DLBD_A

DLBS_A

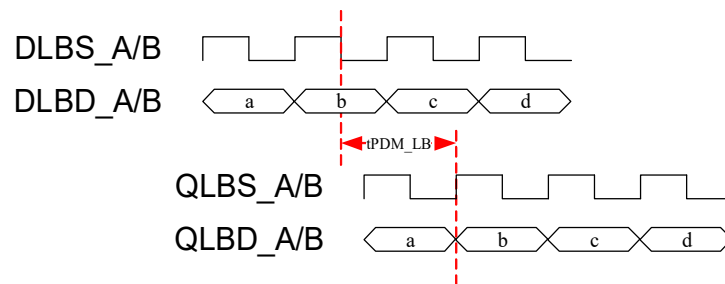
DLBD_B

DLBS_B

Outputs (To Host)

QLBD

QLBS



NOTE: A waiting time $t_{\text{Ext_LB_Entry}}$ applies when External Loopback is enabled in [RW26\[2:0\]](#).

Figure 32 — External Loopback Timing Diagram

3.11.2 Loopback Ports (cont'd)

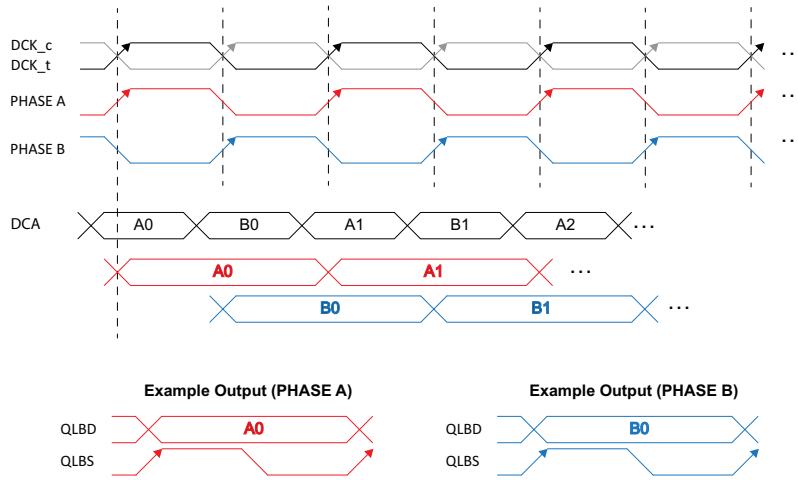


Figure 33 — Internal Loopback 2-Phase A and B Phase

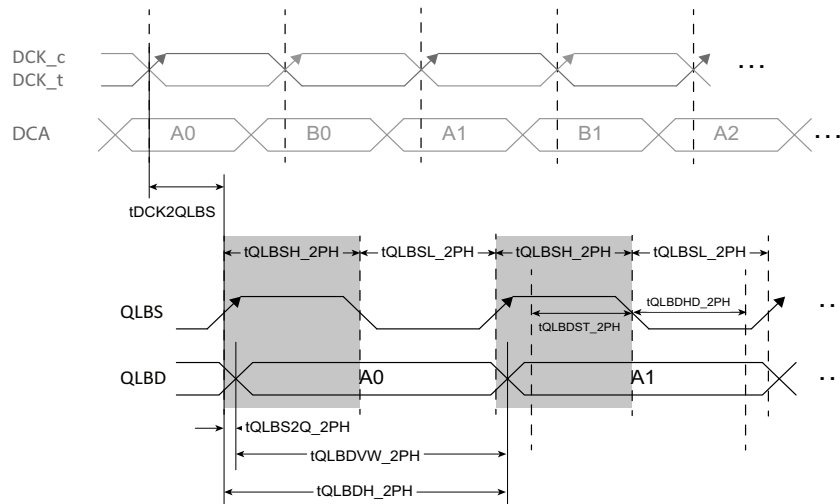


Figure 34 — Loopback Output 2-Phase Timing Parameters

3.11.2 Loopback Ports (cont'd)

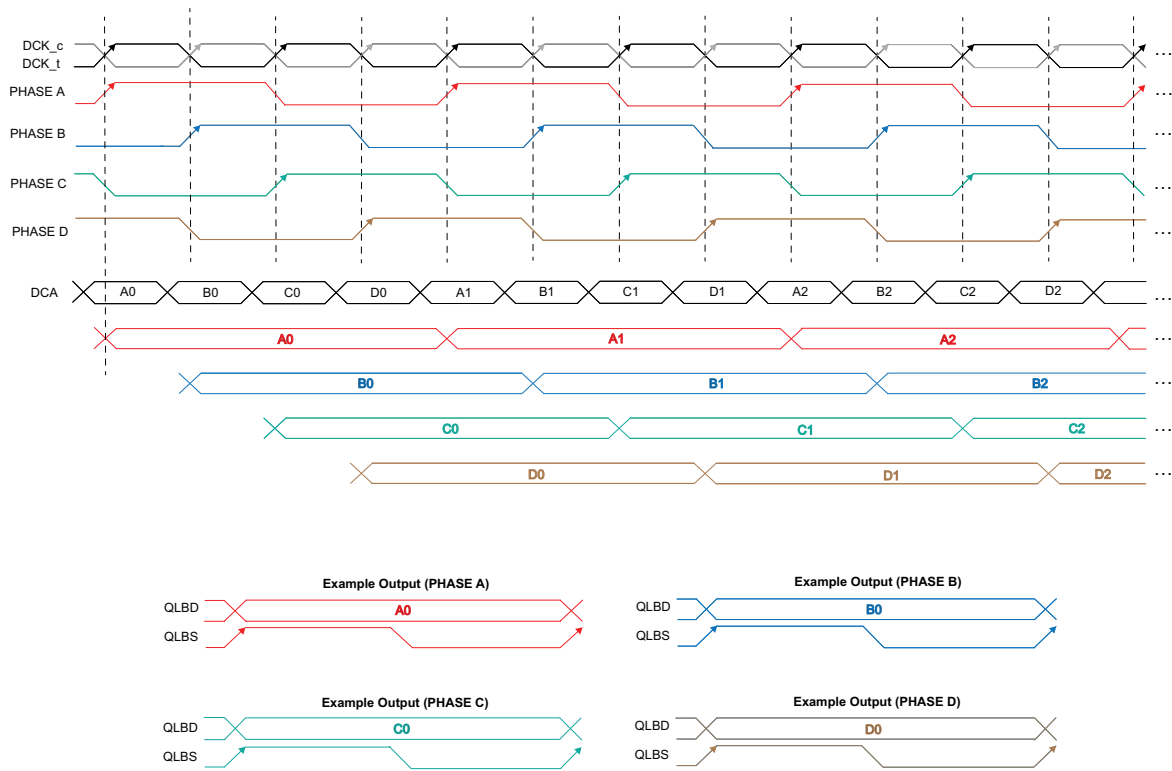


Figure 35 — Internal Loopback 4-Phase A, B, C, and D Phase

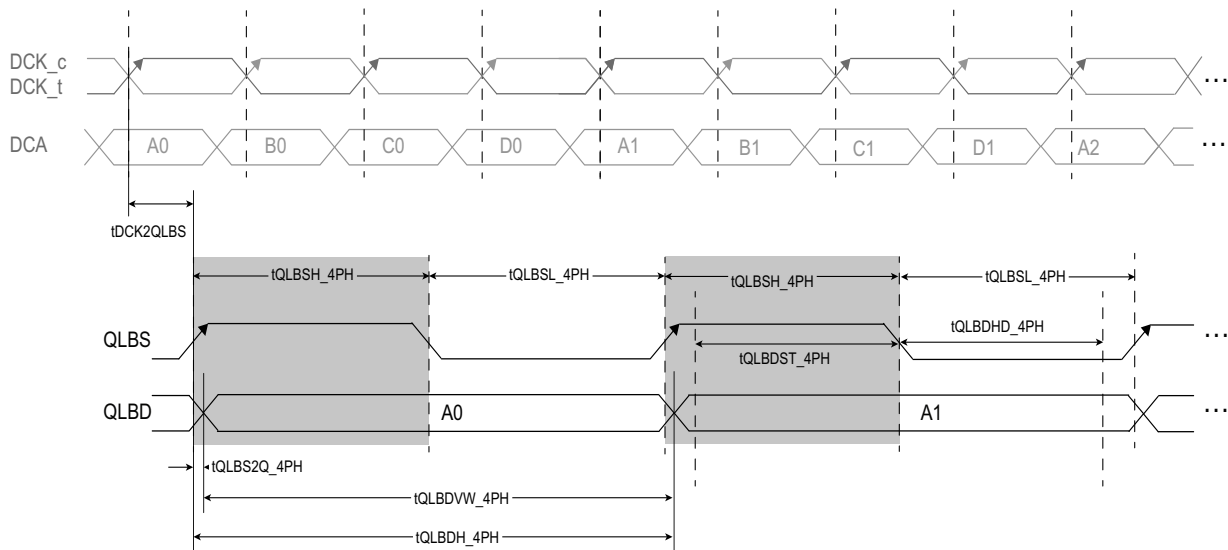


Figure 36 — Loopback Output 4-Phase Timing Parameters

3.11.3 Internal Loopback Mode Entry

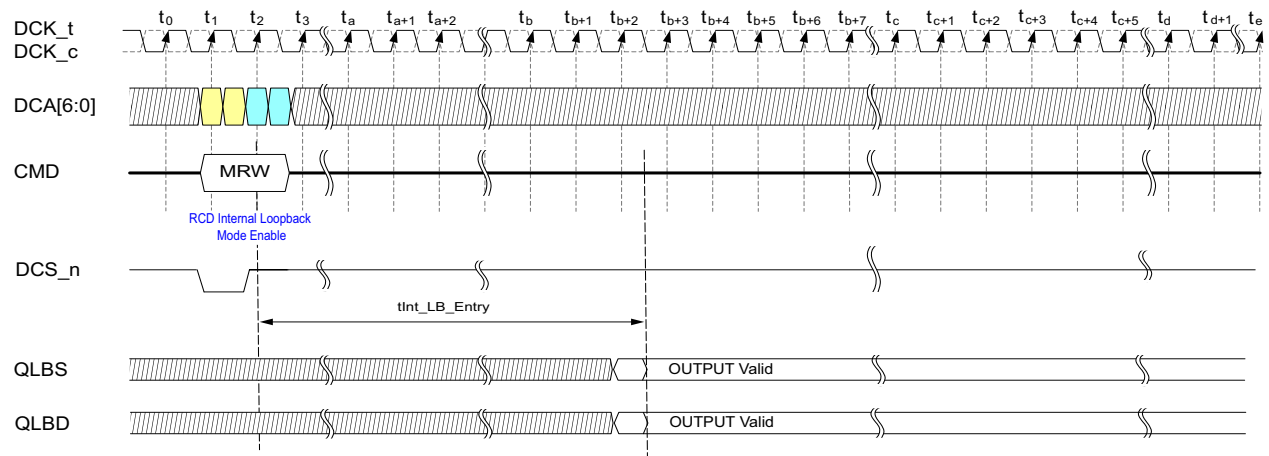


Figure 37 — Internal Loopback mode Entry

- Once the 2-Phase or 4-Phase Internal Loopback mode is registered through In-Band MRW to [RW26](#), the DCA sampled by the first DCK *rising* edge after $t_{Int_LB_Entry}$ will be the first Phase A output. The DCA sampled by the first DCK *falling* edge after $t_{Int_LB_Entry}$ will be the first Phase B output. Similarly, after $t_{Int_LB_Entry}$, the 2nd rising edge DCK sampled DCA is the first Phase C output and the 2nd falling edge DCK sampled DCA is the first Phase D output.
- If Internal Loopback is enabled through Sideband, the entry time will be much longer and asynchronous.
- While Internal Loopback is enabled, switching Phases (such as In-Band or SideBand MRW to [RW27\[7\]](#) = 0 or 1) is supported. Once the register write is received, the QLBS and QLBD output will move to the new Phase.
- Because the 4-phase Loopback phase is non-deterministic until the first UI has been captured after a clock discontinuity, testing each of the rising edge phases or each of the falling edge phases can be achieved by sending the same stimulus in consecutive bursts, offset by an odd number of clock cycles, and with no resets, clock stops, or MRWs between them.

3.12 DLBD and DLBS Fine Vref Control and Input Delay Control

In DDR5RCD05, fine-grained DLBD and DLBS Vref control is required. The Host controller can utilize the Loop-Back Vref control words, [RW4B](#), to control the Vref of DLBD and DLBS.

In DDR5RCD05, adjustment of the phase of the received DLBD and DLBS is required. The Host controller can utilize the Loop-Back input delay control words, [RW4C](#), to control the phase of the received DLBD and DLBS.

3.13 Device Initialization

To ensure defined outputs from the register before a stable clock has been supplied, the register must enter the reset state during power-up. After the voltage ramp, stable power is provided for a minimum of t_{RINIT1} μ s with DRST_n asserted. When the reset input DRST_n is LOW, all input receivers are disabled, and shall be left floating. In addition, when DRST_n is LOW, all non-sticky control registers are restored to their default states, which is all '0's unless explicitly stated otherwise. The outputs QRST_n must drive LOW. All other Qx outputs must float with the exception of the QCS[x]_n outputs, which are driven LOW. The RCD must float QLBD, QLBS and ALERT_n outputs. As long as the DRST_n input is pulled LOW, the register is in low-power state and input termination is not present.

The DDR5RCD05 device will not affect DRST_n signal voltage levels even when V_{DD} is not powered on. An RCD with V_{DD} powered off shall not prevent other devices connected to the same DRST_n net from receiving the correct High and Low logic voltage levels driven by the Host on that net. Also, the DDR5RCD05 device will not sustain permanent damage if DRST_n is driven HIGH (to V_{IH} levels) when V_{DD} is powered off, and it must be able to support all the specified features and functions once power is restored.

Before the DRST_n signal goes HIGH, all DCS_n inputs are driven LOW by the Host controller. This puts the signals in a similar state as self refresh allowing the initialization and self refresh protocol to be similar. After DRST_n goes HIGH, the DCS_n input signals will go HIGH. The Host may stagger (i.e., delay) this transition between sub-channels by up to $t_{DCSLHSK1}$, but DCS0_n and DCS1_n within each sub-channel can only be staggered by up to $t_{DCSLHSK2}$. This transition will enable the termination on the DCS_n, DCA, and DCK inputs. The Host will start the DCK clock early enough to meet t_{CKACT}^2 . After t_{STAB01} , the SidebandBus Interface is operational and the Host controller will write the coarse and fine grain frequency registers and put the RCD in the proper DCA input mode (DDR or SDR). The Host controller must then wait t_{STAB02} to allow the PLL to re-lock.

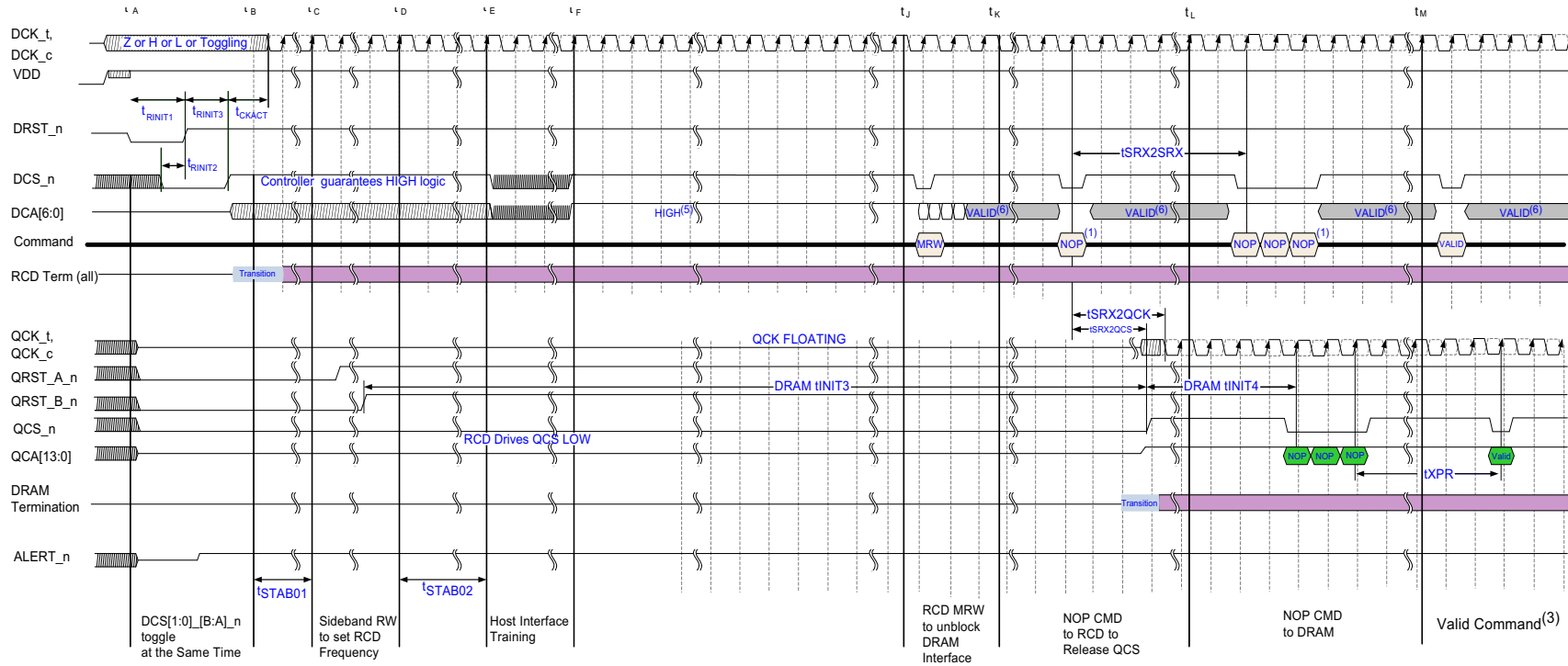
Training of the DCS and DCA signals now takes place. Commands to the DRAMs are blocked by default, and the DRAM QCS signals will remain LOW.

The QRST_n outputs will remain LOW after DRST_n goes HIGH. The QRST_n signals do not go HIGH until the Host writes the Command Control Word with the commands to do so. This may be done via the SidebandBus or in-band. The QRST_n signal for each sub channel is controlled separately to allow staggering of the signals for power supply inrush control.

As part of the power-on initialization, all control words are reset to their default state. After initialization, the Host must write to those control registers whose contents are required for frequency and DIMM configuration.

NOTE 2 Since DCS_n Low-to-High transitions can be staggered by up to $t_{DCSLHSK1}$ (for the entire chip) or $t_{DCSLHSK2}$ (within the same sub-channel), t_{CKACT} must be met with respect to the DCS_n signal with the earliest rising transition.

3.13 Device Initialization (cont'd)



1. The NOP (SRX) Commands that release QCS outputs, and the consecutive NOP Commands sent to the DRAM after that, are required to meet RCD parameters tDCSLHSK1 and tDCSLHSK2 as well as DRAM parameter tINIT4.
2. QRST outputs remain LOW until RCD receives RW04 command to de-assert reset.
3. Valid command shown in diagram, includes the MPC command, DRAM default 2N mode.
4. Sideband Interface becomes enabled for Private Write/Read access and DEVCTRL CCC with RegMode = 1 at time t_C .
5. HIGH signal levels, driven by the Host or pulled-up by the RCD termination, required to be held static for a minimum tDFE_PRD time prior to first assertion of DCS if DFE enabled.
6. Valid signal timing and levels required if DFE is enabled.

Figure 38 — Timing of Clock and Data During Initialization Sequence

3.13 Device Initialization (cont'd)

From a device perspective, the initialization sequence must be as shown in Table 18.

Table 18 — DDR5RCD05 Device Initialization Sequence at Power-on Ramping

Step	Power	Inputs: Signals provided by the Controller					RCD Input Termination	Outputs: Signals Provided by the Device				
		DRST_n	DCS[1:0]_n	DCA	DPAR	DCK_t, DCK_c		QCS[1:0]_n	QRST_n	QCA	ALERT_n	QCK_t, QCK_c
0	0V	X or Z	X or Z	X or Z	X or Z	X or Z	OFF	Z	Z	Z	Z	Z
1	0-->V _{DD}	X or Z	X or Z	X or Z	X or Z	X or Z	OFF	X or Z	X or Z	X or Z	X or Z	X or Z
2	V _{DD}	L	X or Z	X or Z	X or Z	X	OFF	L	L	Z	Z or H	Z
3	V _{DD}	L	L	X or Z	X or Z	X	OFF	L	L	Z	Z or H	Z
4	V _{DD}	H	L	X or Z	X or Z	X	OFF	L	L	Z	H	Z
5	V _{DD}	H	H	X	X	running	ON	L	Note 2	Z	H	Z

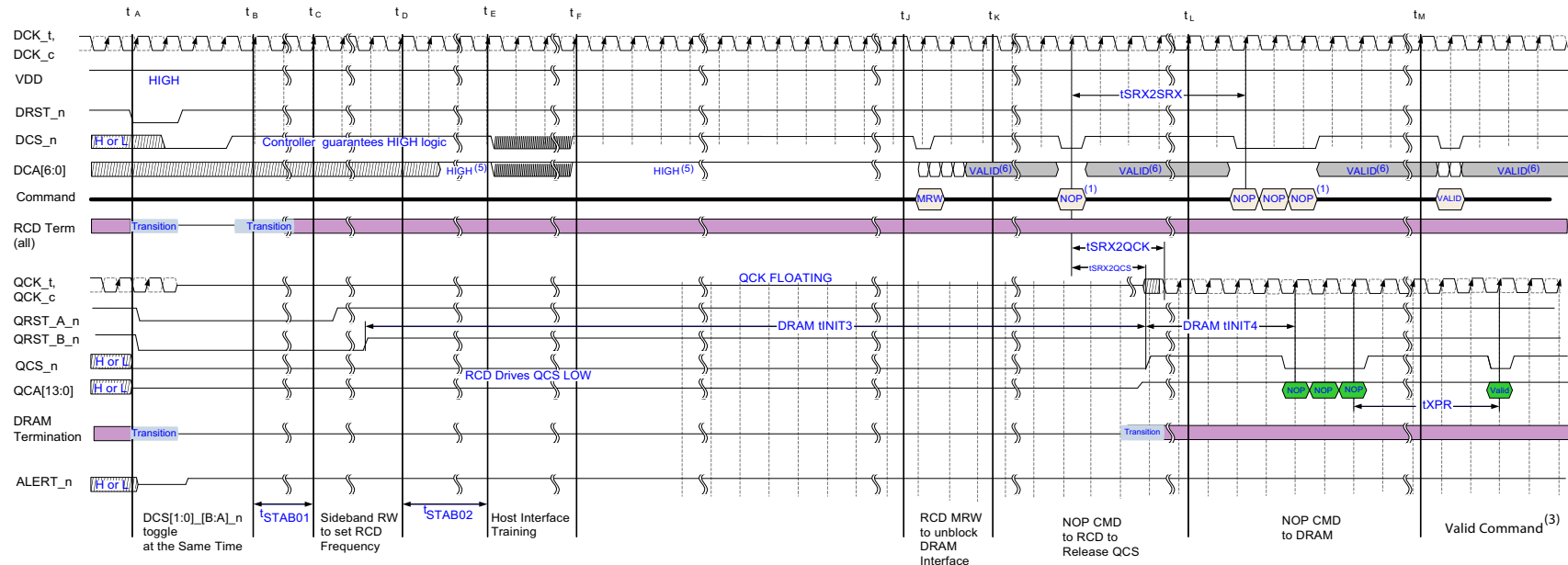
NOTE 1 X = Logic LOW or Logic HIGH. Z = Floating

NOTE 2 QRST_n goes HIGH with the proper Command Control Word write.

NOTE 3 ALERT_n is pulled HIGH externally after DRST_n is driven LOW and V_{DD} is nominal.

3.14 Reset Initialization with Stable Power

The timing diagram in Figure 39 depicts the initialization sequence with stable power and clock. This will apply to the situation when we have a soft reset in the system. DRST_n will be asserted for minimum 1 μ s. This DRST_n timing is based on DDR5 DRAM Reset Initialization with Stable Power requirement, and is a minimum requirement. Actual DRST_n timing can vary based on specific system requirement, but it cannot be less than 1 μ s. Some of the steps in Figure 39 could be skipped by taking advantage of control words with sticky attributes.



1. The NOP (SRX) Commands that release QCS outputs, and the consecutive NOP Commands sent to the DRAM after that, are required to meet RCD parameters tDCSLHSK1 and tDCSLHSK2 as well as DRAM parameter tINIT4.
2. ORST outputs remain LOW until RCD receives RW04 command to de-assert reset.
3. Valid command shown in diagram, includes the MPC command.
4. Sideband interface is not operational for Private Write/Read access and DEVCTRL CCC with RegMode = 1 between times tA to tC.
5. HIGH signal levels, driven by the Host or pulled-up by the RCD termination, required to be held static for a minimum tDFE_PRD time prior to first assertion of DCS if DFE enabled.
6. Valid signal timing and levels required if DFE is enabled.

Figure 39 — Reset Initialization With Stable Power

3.14 Reset Initialization with Stable Power (cont'd)

Table 19 — DDR5RCD05 Device Initialization Sequence when Power and Clock are Stable ¹

Step	Power	Inputs: Signals provided by the controller					RCD Input Termination	Outputs: Signals provided by the device				
		DRST_n	DCS[1:0]_n	DCA	DPAR	DCK_t, DCK_c		QCS[1:0]_n	QRST_n	QCA	ALERT_n	QCK_t, QCK_c
1	V _{DD}	H	X	X	X	running	ON	X	H	X	X	running
2	V _{DD}	L	X	X	X	X	Transitioning	L	L	Z	Z or H ³	Z
3	V _{DD}	L	L	X	X	X	OFF	L	L	Z	Z or H ³	Z
4	V _{DD}	H	L	X	X	X	OFF	L	L	Z	H	Z
5	V _{DD}	H	H	X	X	running	ON	L	Note 2	Z	H	Z

NOTE 1 X = Logic LOW or Logic HIGH. Z = Floating

NOTE 2 QRST_n goes HIGH with the proper Command Control Word write.

NOTE 3 ALERT_n is pulled HIGH externally after DRST_n is driven LOW and V_{DD} is nominal.

4 Power Down Operation

DDR5 does not have a separate CKE signal going to the DIMM or the DRAMs. Power Down Entry, including self refresh, is signaled via a single UI command.

4.1 Power Savings Modes

The DDR5RCD05 device supports the following power saving mechanisms:

- Self Refresh Modes. With and without Clock Stop.

The DRST_n input has priority over all other power saving mechanisms. When DRST_n is driven LOW, the RCD will force the Qn outputs to float (except QCS_n, QRST_n, which are driven LOW), float the ALERT_n output or drive it to High, and disable Input Bus Termination (IBT).

4.2 Self Refresh Modes

Following the sending of SRE command, the Host will EITHER assert the DCS[x]_n signals for a single clock pulse (indicating Self Refresh WITHOUT clock stop), or for the t_{CSSR} minimum (indicating Self Refresh WITH clock stop). No pulse width in between is permitted. All DCS[x]_n signals must be asserted in the same manner.

4.2.1 Self Refresh Mode with Clock Stop Entry

Self Refresh Mode is a very low power state in which the input clocks will stop, and both the RCD and DRAM inputs terminations are disabled.

Self-refresh entry is signaled when the Host sends SRE commands to both ranks within a sub-channel at the same time.

After all ranks on both sub-channels have been put into self refresh with no parity error detected, the Host controller will pulse the DCS[1:0]_[B:A]_n inputs for t_{CSSR} to maintain self refresh. No parity checking is done on this operation, as the DCA bus is not used.

Unlike the DDR4 RCD, there is no detection done on the clock inputs, instead the RCD will detect the last DCS_n transitions to LOW of the CS pulse to disable DCK, DCA and DCS_n terminations. The DCS transition to LOW is required to apply valid DCS input timings with respect to DCK. The Host controller will stop the clock. DCK_t and DCK_c can be driven LOW or can be floating. The PLL is disabled and DCS[1:0]_[B:A]_n inputs are kept LOW to maintain self refresh.

The RCD outputs will be disabled with the exception of the QRST_n and QCS[x]_n signals to keep the DRAMs in self refresh. ALERT_n output is floating or could be driven High by the RCD. QCS_n signals are driven LOW. If a parity error is detected on any of the self refresh entry commands the Host will take any DIMMs or sub-channels already in self refresh out of self refresh and retry the entry operation.

4.2.2 Exit from Self Refresh Mode with Clock Stop

Exiting Self Refresh Mode is accomplished when the first DCS_n input transitions HIGH. The Host may stagger (i.e., delay) this transition between sub-channels by up to $t_{DCSLHSK1}$, but DCS_{0_n} and DCS_{1_n} within each sub-channel can only be staggered by up to $t_{DCSLHSK2}$. This transition will re-enable the termination on the DCK, DCS, and DCA inputs and enable the PLL. The Host will start the DCK clock early enough to meet t_{CKACT}^3 , and wait for the PLL(s) to lock. After t_{STAB01} , the SidebandBus Interface is operational. Note that the DCS_{[x]_n} inputs going HIGH does NOT pass through to the DRAMs at this point.

Once the PLL is locked, using the SidebandBus Interface, the Host is allowed to use DCS, DCA, and DFE Training Modes, including DFE Sweep Accelerator, through SidebandBus to train the DCS and DCA signals if needed due to a modification of the DCK frequency. The Host controller will send NOP (SRX) commands to each rank, which will take the QCS_{[x]_n} outputs HIGH. This will enable the termination on the DRAMs. The RCD starts the QCLK outputs at this time and begins passing commands through to the DRAMs. The Host controller will then send three or more back-to-back NOP commands to each rank, which completes the exit of self refresh in the DRAMs.

DCA and parity errors are ignored for the NOP (SRX) which will take the QCS_{[x]_n} outputs HIGH and the back-to-back NOP commands to each rank. Any LOW on DCS_{[x]_n} will be recognized as a valid NOP command. For the back-to-back NOP commands, the RCD will drive valid NOP states on the QCA and QCS outputs to the associated rank. The RCD will begin processing in-band commands on DCA within t_{XS} after the back-to-back NOP commands. This process happens independently, per sub channel, to support the allowed $t_{DCSLHSK1}$ skew. Training modes during the self-refresh exit procedure will be handled normally as defined in Clause 5.

4.2.3 Self Refresh Mode without Clock Stop Entry

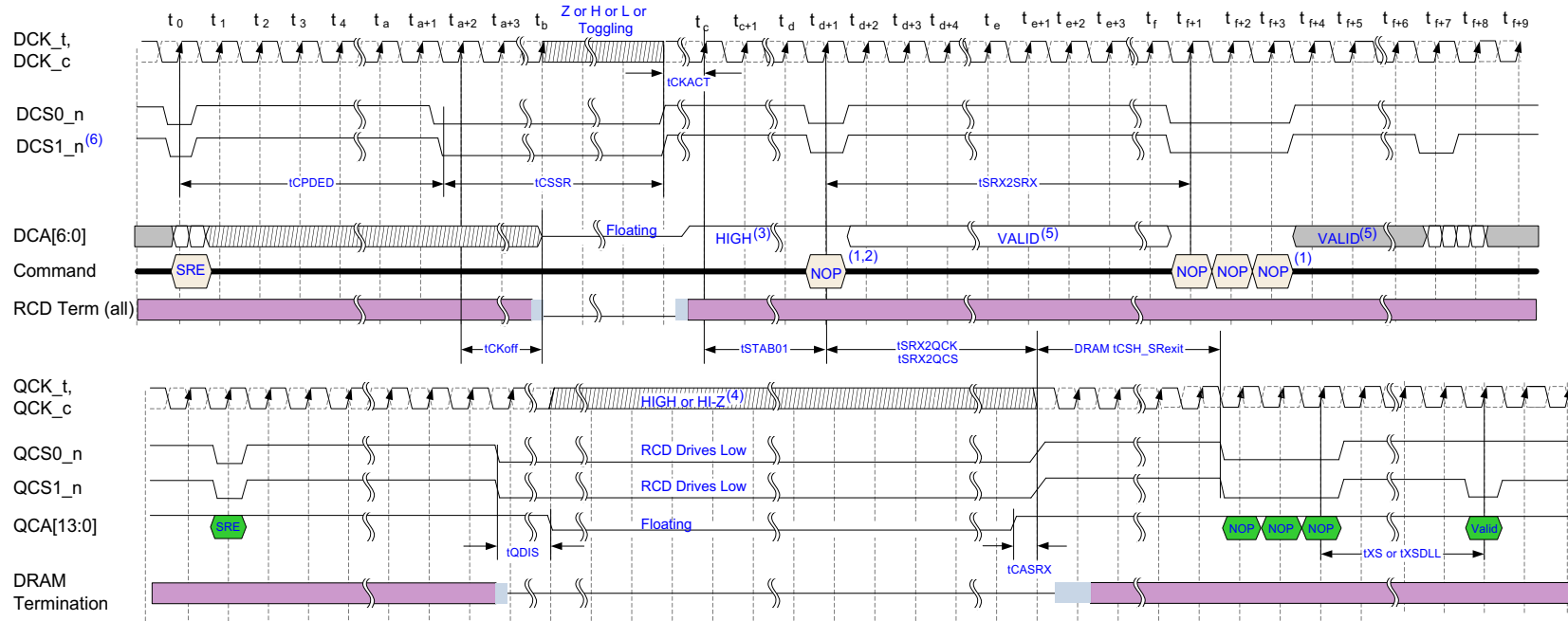
Self Refresh without Clock Stop is similar to Self Refresh with Clock Stop mode except that the Host controller will not stop the DCK input. After both sub-channels have received the SRE command, the Host signals the RCD to enter this mode by sending a one clock wide pulse on DCS_{[1:0]_n} instead of holding it LOW for multiple cycles at t_7 in Figure 44. No parity checking is done on this operation, as the DCA bus is not used. The RCD will not disable any of its terminations and will not disable the PLL during Self Refresh without clock stop. The RCD will also not stop the QCK clock outputs in this mode.

4.2.4 Self Refresh Mode without Clock Stop Exit

Exiting this mode is similar to Self Refresh with Clock Stop, except that the Host will not wait t_{STAB} upon exit, as the PLL is already locked. Since the DCS_{[x]_n} signals are already HIGH, the first indication of the exit is the NOPs that release the QCS_{[x]_n} signals.

NOTE 3 Since DCS_n Low-to-High transitions can be staggered by up to $t_{DCSLHSK1}$ (for the entire chip) or $t_{DCSLHSK2}$ (within the same sub-channel), t_{CKACT} must be met with respect to the DCS_n signal with the earliest rising transition.

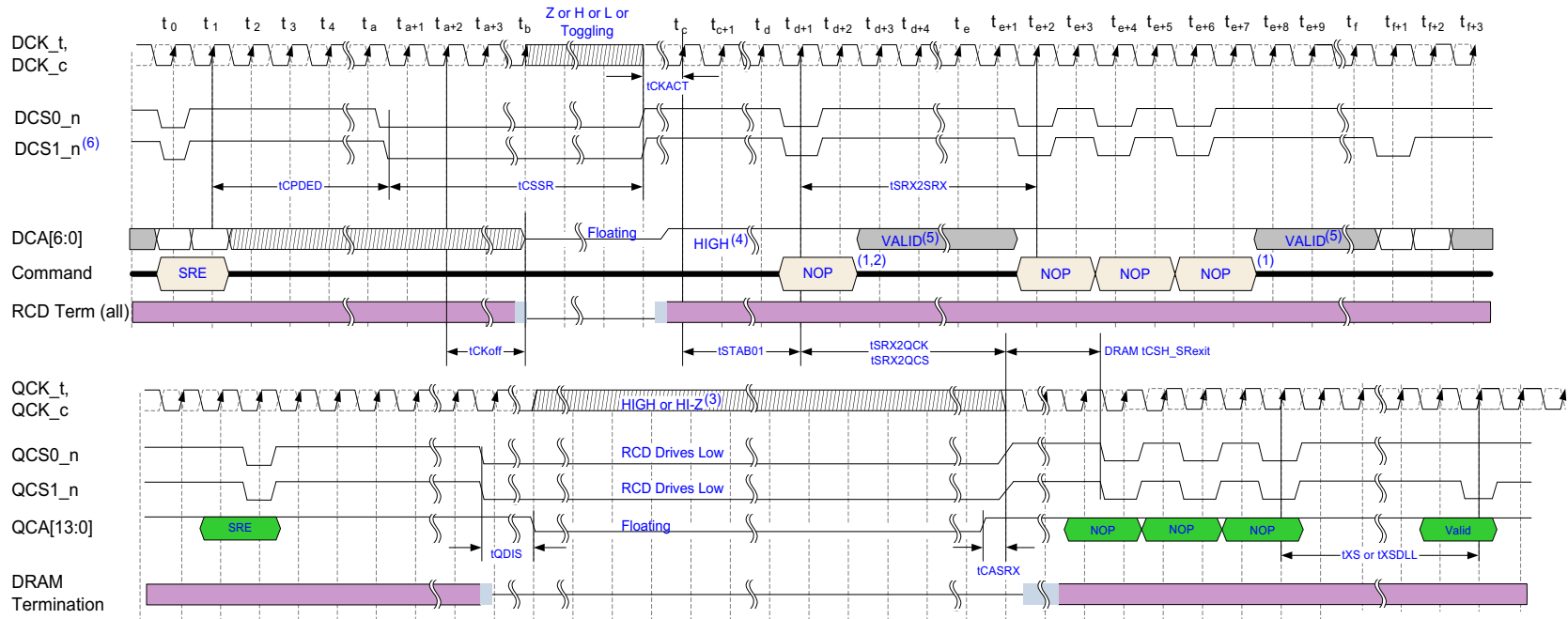
4.2.4 Self Refresh Mode without Clock Stop Exit (cont'd)



1. The NOP (SRX) Commands that release QCS outputs, and the consecutive NOP Commands sent to the DRAM after that, are required to meet RCD parameters tDCSLHSK1 and tDCSLHSK2 as well as DRAM parameter tCSH_SRExit.
2. NOP (SRX) Command to DRAM Rank 0 & 1 to take the DRAM out of Self Refresh.
3. HIGH signal levels, driven by the Host or pulled-up by the RCD termination, required to be held static for a minimum tDFE_PRD time prior to first assertion of DCS if DFE enabled.
4. The RCD is allowed to drive HIGH or HI-Z.
5. Valid signal timing and levels required if DFE enabled.
6. When DCS1_n and QCS1_n are set to disabled with RW09[2]=1, the DCS1_n can be H or L or Z, and QCS1_n output will be disabled by RCD.

Figure 40 — Self Refresh Entry Exit with Clock Stop with DCK Frequency Change

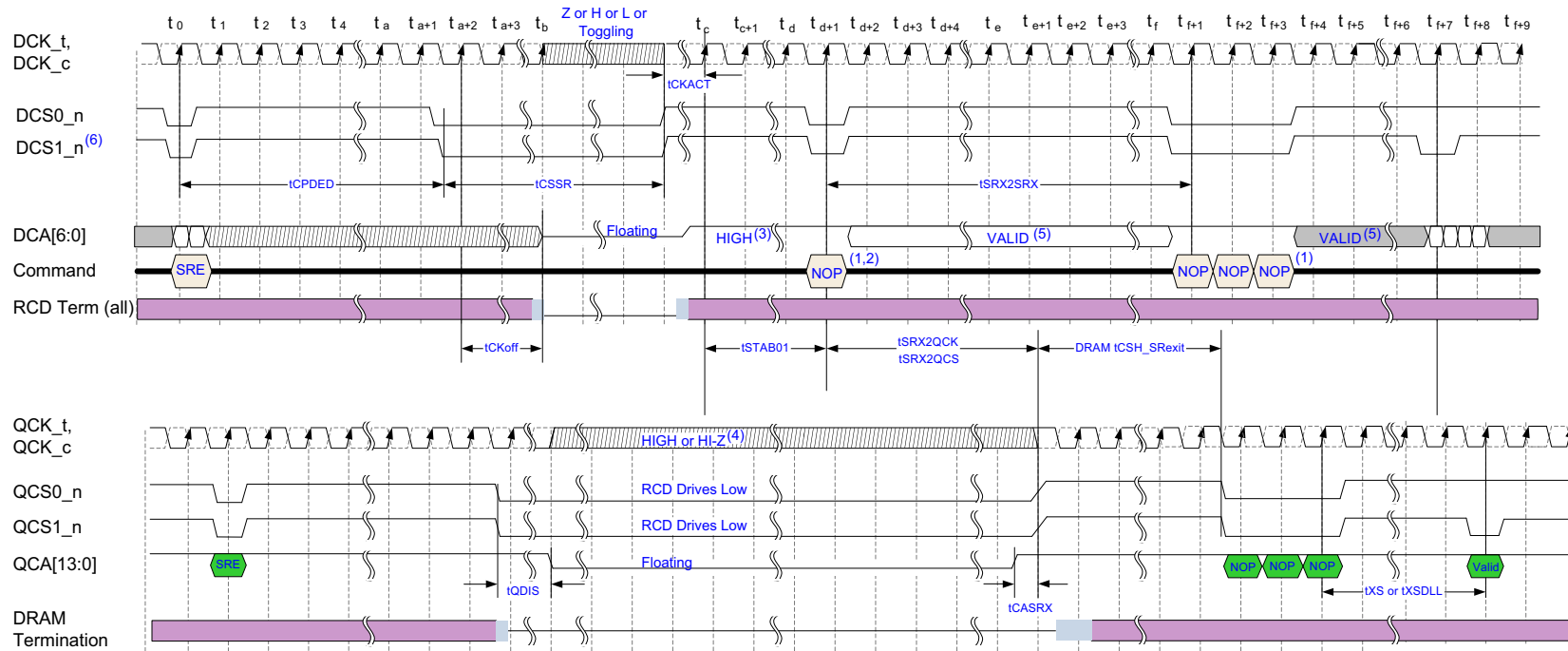
4.2.4 Self Refresh Mode without Clock Stop Exit (cont'd)



1. The NOP (SRX) Commands that release QCS outputs, and the consecutive NOP Commands sent to the DRAM after that, are required to meet RCD parameters $t_{DCSLHSK1}$ and $t_{DCSLHSK2}$ as well as DRAM parameter t_{CSH_SRExit} .
2. NOP (SRX) Command to DRAM Rank 0 & 1 to take the DRAM out of Self Refresh.
3. The RCD is allowed to drive HIGH or HI-Z.
4. HIGH signal levels, driven by the Host or pulled-up by the RCD termination, required to be held static for a minimum t_{DFE_PRD} time prior to first assertion of DCS if DFE enabled.
5. Valid signal timing and levels required if DFE enabled.
6. When $DCS1_n$ and $QCS1_n$ are set to disabled with $RW09[2]=1$, the $DCS1_n$ can be H or L or Z, and $QCS1_n$ output will be disabled by RCD.

Figure 41 — Self Refresh Entry Exit with Clock Stop in SDR1 Mode with DCK Frequency Change

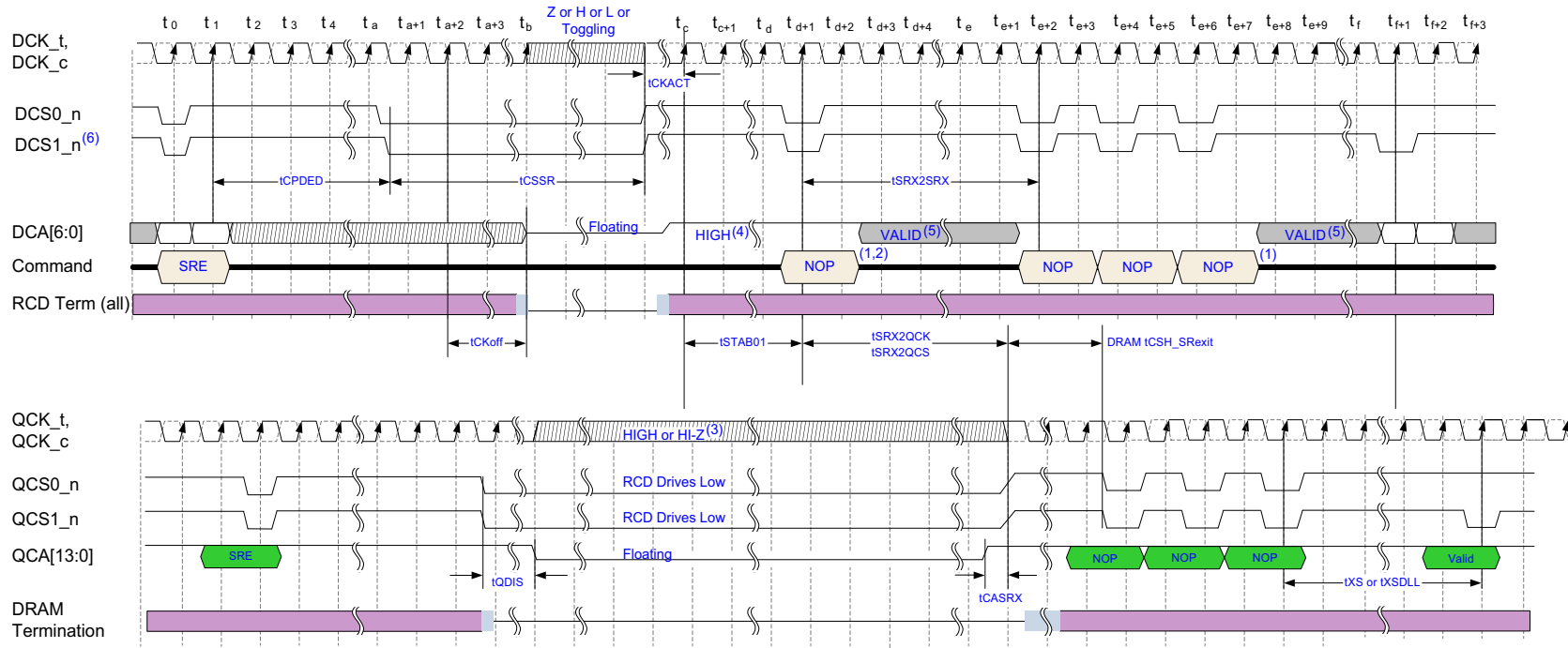
4.2.4 Self Refresh Mode without Clock Stop Exit (cont'd)



1. The NOP (SRX) Commands that release QCS outputs, and the consecutive NOP Commands sent to the DRAM after that, are required to meet RCD parameters tDCSLHSK1 and tDCSLHSK2 as well as DRAM parameter tCSH_SReXit.
2. NOP (SRX) Command to DRAM Rank 0 & 1 to take the DRAM out of Self Refresh.
3. HIGH signal levels, driven by the Host or pulled-up by the RCD termination, required to be held static for a minimum tDFE_PRD time prior to first assertion of DCS if DFE enabled.
4. The RCD is allowed to drive HIGH or HI-Z.
5. Valid signal timing and levels required if DFE enabled.
6. When DCS1_n and QCS1_n are set to disabled with RW09[2]=1, the DCS1_n can be H or L or Z, and QCS1_n output will be disabled by RCD.

Figure 42 — Self Refresh Entry Exit with Clock Stop without DCK Frequency Change

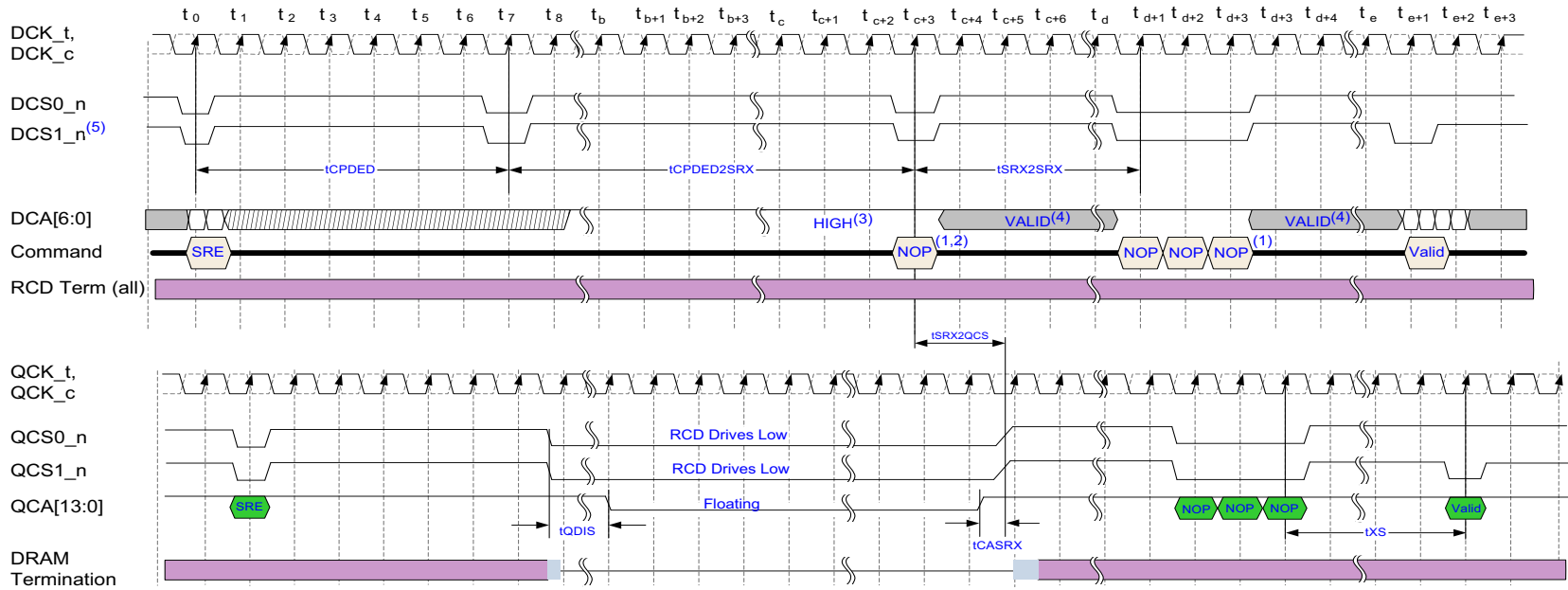
4.2.4 Self Refresh Mode without Clock Stop Exit (cont'd)



1. The NOP (SRX) Commands that release QCS outputs, and the consecutive NOP Commands sent to the DRAM after that, are required to meet RCD parameters tDCSLHSK1 and tDCSLHSK2 as well as DRAM parameter tCSH_SRExit.
2. NOP (SRX) Command to DRAM Rank 0 & 1 to take the DRAM out of Self Refresh.
3. The RCD is allowed to drive HIGH or HI-Z.
4. HIGH signal levels, driven by the Host or pulled-up by the RCD termination, required to be held static for a minimum tDFE_PRD time prior to first assertion of DCS if DFE enabled.
5. Valid signal timing and levels required if DFE enabled.
6. When DCS1_n and QCS1_n are set to disabled with RW09[2]=1, the DCS1_n can be H or L or Z, and QCS1_n output will be disabled by RCD.

Figure 43 — Self Refresh Entry Exit with Clock Stop in SDR1 Mode without DCK Frequency Change

4.2.4 Self Refresh Mode without Clock Stop Exit (cont'd)



1. The NOP (SRX) Commands that release QCS outputs, and the consecutive NOP Commands sent to the DRAM after that, are required to meet RCD parameters tDCSLHSK1 and tDCSLHSK2 as well as DRAM parameter tCSH_SRExit.
2. NOP (SRX) Command to DRAM Rank 0 & 1 to take the DRAMs out of Self Refresh.
3. HIGH signal levels required to be held static for a minimum tDFE_PRD time prior to first assertion of DCS if DFE enabled.
4. Valid signal timing and levels required if DFE enabled.
5. When DCS1_n and QCS1_n are set to disabled with RW09[2]=1, the DCS1_n can be H or L or Z, and QCS1_n output will be disabled by RCD.

Figure 44 — Self Refresh Entry and Exit without Clock Stop

5 Training Modes

5.1 CS Training Modes

5.1.1 DCS Training Mode (DCSTM) - Host Interface

The DCS Training Mode is a method to facilitate the loopback of a sampled sequence of the DCS_n signal. In this mode, the DCK is running, and the DCA and DPAR signals are ignored by the RCD. Once this mode is enabled, the RCD is selected to actively sample and drive feedback. The RCD will sample the DCS_n signal on the rising edge of DCK. Every set of four DCK rising edge samples will be included in a logical computation to determine the DCSTM Output result that is sent back to the Host on ALERT_n or QLBx configured in [RW01\[5\]](#). Once sampling begins, the RCD must maintain the consecutive grouping of the samples every 4 tCK. When the DCS_n Sample[0] and Sample[2] results in a logic 0 and the DCS_n Sample[1] and Sample[3] results in a logic 1, the RCD will drive a 0 on ALERT_n or QLBx. The output signal can transition as often as every 4 tCK. All commands to DRAM are blocked by the RCD when DCS Training mode is enabled.

5.1.1.1 Entry and Exit for DCS Training Mode

The DCS Training Mode is enabled by a SidebandBus write or an in-band write with Enhanced RWUPD feature to [RW02\[3:0\]](#). The signal used to provide the feedback is configured by [RW01\[5\]](#). RCD can be configured to use ALERT_n (which requires training each sub-channel independently and one after the other), or use both QLBD and QLBS (which allows training both sub-channels in parallel). For the remainder of this section, we assume ALERT_n is selected for feedback. Once the RCD has DCS Training Mode enabled, the RCD begins sampling on every rising CK edge, with the 4-sample groups looping consecutively. Depending on the value of the samples, ALERT_n is driven HIGH or LOW. RCD hardware will block the signals coming from the DERROR_IN_n receivers if ALERT_n has been selected for feedback in [RW01\[5\]](#). Prior to entering DCS Training Mode, the ALERT_n or QLBx shall remain High. The DCS Training Mode is disabled by a SidebandBus write or an in-band write with Enhanced RWUPD feature to [RW02\[3:0\]](#). In the example sequences illustrated in Figure 45 and Figure 46, either SidebandBus commands or in-band commands can be used to enter or exit the mode for proper operation.

5.1.1.2 DCS Training Mode Operation

In DCS Training Mode, the DCS_n values are sampled on all DCK rising edges. Each group of 4 consecutive samples is evaluated in pairs, and then the two pairs are combined with a logical OR prior to sending on ALERT_n. The samples evaluation to determine the output is as follows:

Table 20 — Sample Evaluation for Intermediate Output[0]

Output[0]	DCS_n Sample[0]	DCS_n Sample[1]
1	0	0
0	0	1
1	1	0
1	1	1

5.1.1.2 DCS Training Mode Operation (cont'd)

Table 21 — Sample Evaluation for Intermediate Output[1]

Output[1]	DCS_n Sample [2]	DCS_n Sample[3]
1	0	0
0	0	1
1	1	0
1	1	1

Table 22 — Sample Evaluation for Final DCSTM Output

DCSTM Output ^{1,2}	Output[0]	Output[1]
0	0	0
1	0	1
1	1	0
1	1	1

NOTE 1 When there is no change on the DCSTM Output from previous evaluation, ALERT_n shall continue to drive same value continuously with no switching on the bus.

NOTE 2 These values are driven asynchronously, but may switch as often as every 4 tCK.

As shown in Table 20 through Table 22, DCSTM Output will only be 0 when DCS_n Sample[0] = Sample[2] = 0 and Sample[1] = Sample[3] = 1. The DCSTM output will be 1 in all other cases.

During DCS Training Mode the DCS ODT is enabled as for functional operation. The VrefCS is set in [RW\[49:48\]](#). The delay from when the DCS signals are sampled during the fourth DCK rising edge (Sample[3]) to when the output of the sample evaluation is driven to a stable value on ALERT_n is specified as tDCSTM_Valid, as shown in the following figure. The details of the tDCSTM_Entry, tDCSTM_Exit, and tDCSTM_ALERT_Window are also illustrated.

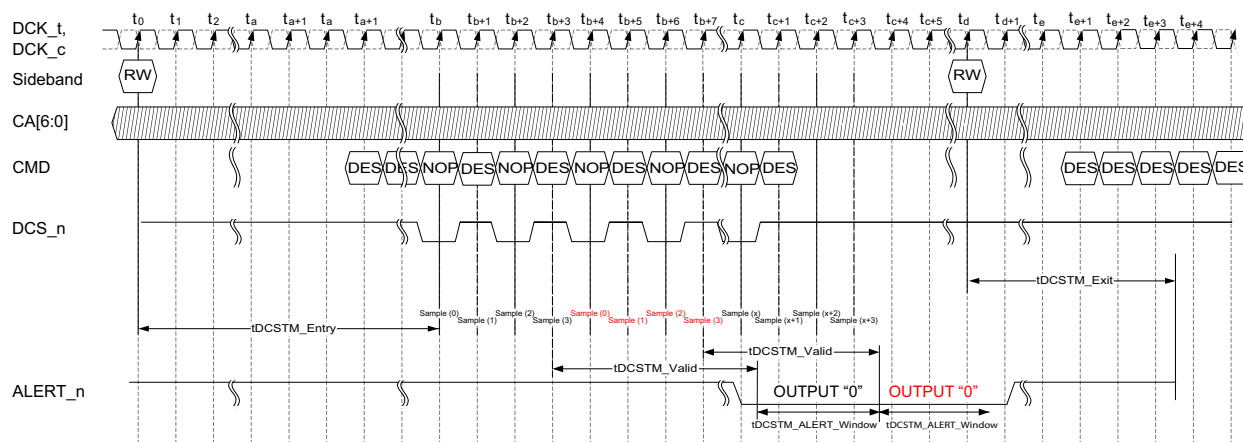


Figure 45 — Timing Diagram for DCS Training Mode with Consecutive Output Samples = 0

5.1.1.2 DCS Training Mode Operation (cont'd)

Figure 46 illustrates an example where the ALERT_n Output switches from a logic 0 to a logic 1 value, demonstrating the minimum tDCSTM_ALERT_Window:

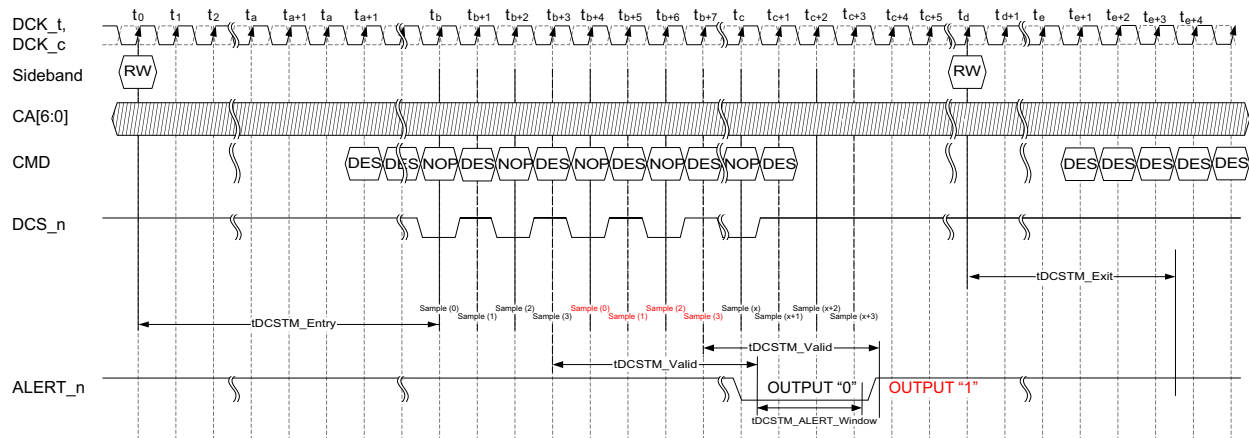


Figure 46 — Timing Diagram for DCS Training Mode with Output Sample Toggle

5.1.2 QCS Training Mode (QCSTM) - DRAM Interface

The DDR5RCD05 must support the DRAM CS training mode. Since the MPC command must be sent to the DRAM prior to completing training of the QCS and QCA signals, the RCD shall support the forwarding of DRAM MPC and VrefCA commands with extended setup and hold CA timings by using the RCD CA Pass-through mode set in the Global Features Control word.

During QCSTM the RCD must be able to support the DDR5 DRAM CS training Mode with the following features:

- QCS_n pattern generation. When the QCS_n signal is selected in RW03 the RCD will generate a continuous clock pattern to the DRAM, while sending a NOP encoding with proper inversion applied according to RW00 on the associated QCA signals
- The Host does not need to set the DRAM Interface blocking explicitly. The QCSTM mode will automatically block commands to the DRAM Interface.
- The RCD must adjust the QCS_n output delay when the Host sends an MRW to RW[1A:17].

5.1.2 QCS Training Mode (QCSTM) - DRAM Interface (cont'd)

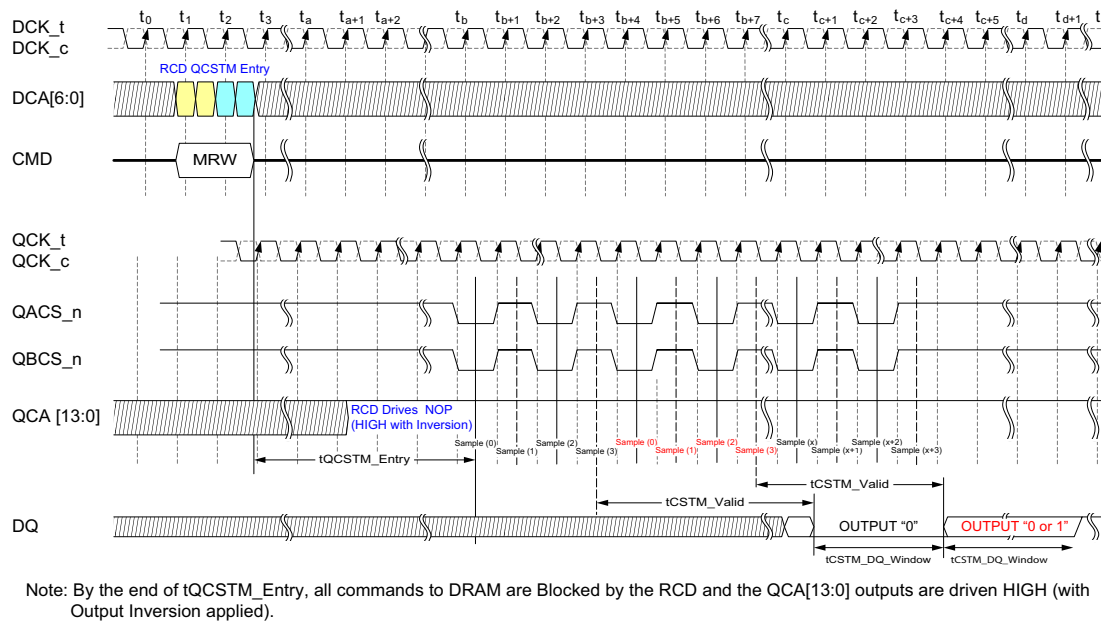


Figure 47 — Timing Diagram for QCSTM with Output Sample Toggle

5.2 CA Training Modes

5.2.1 DCA Training Mode (DCATM) - Host Interface

The DCA Training Mode is a method to facilitate the loopback of a logical combination of the sampled DCA[6:0] and DPAR signals. This mode can only be entered after DCS training has been performed. In DCATM, the DCK is running, and the DCS0_n qualifies when the DCK samples the DCA signals. A loopback equation that includes all the DCA and DPAR signals results in an output value that is sent asynchronously on the ALERT_n or QLBx signal back to the Host memory controller. The Host timings between DCS_n, DCK, DCA[6:0] and DPAR signals can then be optimized for proper alignment. DCK must stay valid with constant phase and frequency. When the RCD is in this mode, no functional commands are executed. The functional command interface is restored only after exiting this mode. All commands to DRAM are blocked by the RCD during DCA Training mode. The Host must ensure Parity Checking is disabled in RCD prior to and during DCA training.

5.2.1.1 Entry and Exit for DCA Training Mode

The DCA Training Mode is enabled through an SidebandBus write, or an in-band write with Enhanced RWUPD feature to [RW02\[3:0\]](#), or a normal in-band MRW after initial training is complete. The signal used to provide the feedback is configured by [RW01\[5\]](#). RCD can be configured to use ALERT_n (which requires training each sub-channel independently and one after the other), or use both QLBD and QLBS (which allows training both sub-channels in parallel). For the remainder of this section, we assume ALERT_n was selected for feedback. Once this SidebandBus or in-band command has executed, no other commands will be interpreted by the RCD in the sub-channel that enters DCA Training Mode. The sub-channel that is not in Training Mode will interpret commands as in normal mode of operation. The Host is responsible for avoiding undesirable signal events or commands on the RCD sub-channel that is not in Training Mode. That includes avoiding commands that may interfere with the resources needed to support DCA Training Mode such as, for example, MRW to enable the Parity Checking. For the sub-channel that is in Training Mode, only the sampling of the DCA signals, evaluation of the XOR result, and loop back to the ALERT_n will occur. While in DCA Training Mode, the DCS0_n signal will only assert for a single tCK at a time.

5.2.1.1 Entry and Exit for DCA Training Mode (cont'd)

The maximum sampling rate on the DCA signals will be every 4tCK. RCD hardware will block the signals coming from the DERROR_IN_n receivers if ALERT_n has been selected for feedback in [RW01\[5\]](#).

The DCA Training Mode is disabled by SidebandBus write or an in-band write with Enhanced RWUPD feature to [RW02\[3:0\]](#) or by asserting DCS0_n for 2 or more cycles in a row, while sending a NOP command on the DCA bus.

In the example sequences illustrated in Figure 48 and Figure 49, either SidebandBus commands or in-band commands can be used to enter or exit the mode for proper operation.

5.2.1.2 DCA Training Mode (DCATM) Operation

In DCA Training Mode, the DCA and DPAR values are only sampled when DCS0_n is asserted. The sample is captured by the rising, falling or both DCK edges. The DCA XOR sampling edge is selected in [RW02\[5:4\]](#). Unlike functional operation, there is no concept of multiple cycle commands in DCA Training Mode. Once the DCA and DPAR signals are sampled, the values are Xored to produce an output value. This output value is driven on the ALERT_n signal, as a static value. This output value will be held until the next sample is captured on the DCA bus, according to the DCS0_n assertion.

During DCA Training Mode the DCA ODT is enabled as for functional operation. The VrefCA is set according to [RW\[47:40\]](#). The timing requirements for the Host Interface signals are the same as for functional operation.

The delay from when the DCA and DPAR signals are sampled during the DCS0_n assertion and when the output of the XOR computation is driven on the ALERT_n signal is specified as $t_{\text{DCATM_Valid}}$, as shown in the following figure. DCS_n may be asserted every 4tCK, and thus the DCA XOR output may transition every 4tCK. The following figure demonstrates an example where two DCS0_n assertions occur within 4tCK. The RCD will exit DCA Training Mode by SidebandBus write or an in-band write with Enhanced RWUPD feature to [RW02\[3:0\]](#) or when the DCS0_n is asserted for 2 or more consecutive cycles but limited to 8 cycles.

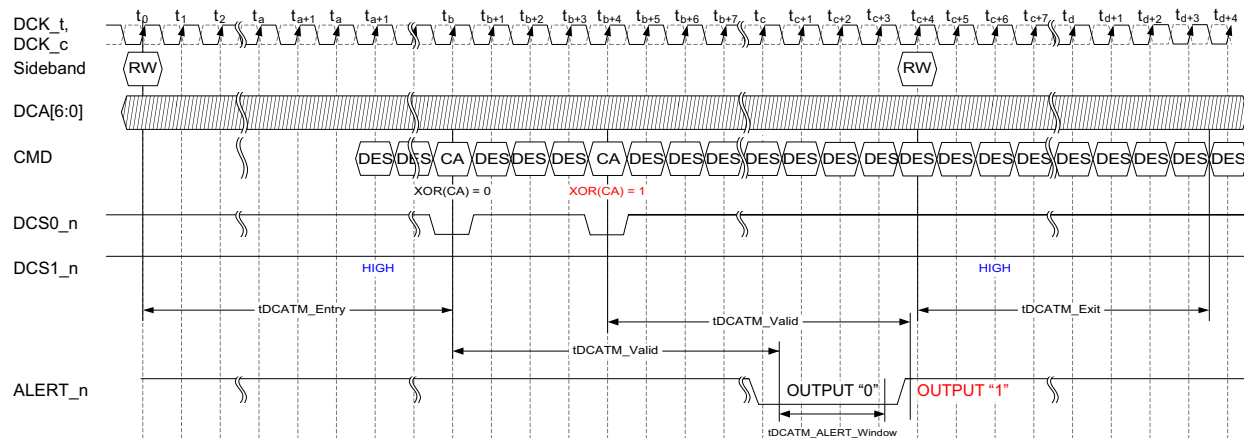


Figure 48 — Timing Diagram for DCA Training Mode SidebandBus Exit

5.2.1.2 DCA Training Mode (DCATM) Operation (cont'd)

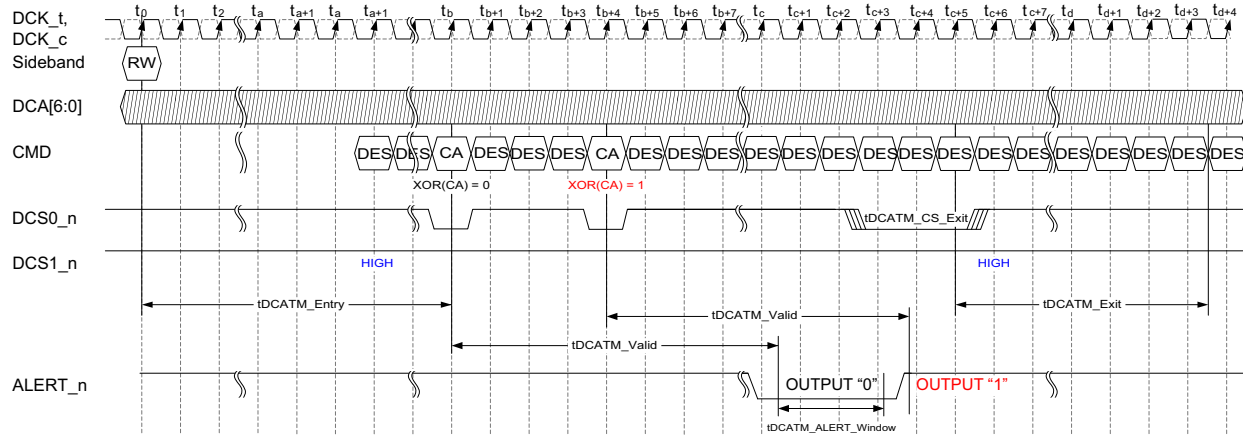


Figure 49 — Timing Diagram for DCA Training Mode Double CS Exit

5.2.1.3 DCA Training Mode Loopback Equation

The DCATM Output is computed based on the DCS_n assertion and the values of the DCA and DPAR inputs. Table 23 clarifies the output computation.

Table 23 — DCA Training Mode Output

DCS _n	DCATM Output
0	XOR (DPAR, DCA[6:0]) ^{1,2,3,4}
1	Hold Previous value

- NOTE 1 For any DCA or DPAR signals not supported (i.e., disabled) in the RCD, the logical value of these signals shall be considered 0 for the XOR computation
- NOTE 2 Clock sampling edge for XOR computation can be DCK rising, DCK falling or both DCK rising and falling edges and is selected in RW02[5:4].
- NOTE 3 The DCK rising edge that captures DCS_n LOW must be used in cases with rising edges enabled in RW02[5:4]. The DCK falling edge immediately following the rising edge that captures DCS_n LOW must be used in cases with falling edges enabled in RW02[5:4].
- NOTE 4 When both rising and falling DCK edges are enabled, 'XOR (rising edge DPAR, rising edge CA[6:0], falling edge DPAR, falling edge CA[6:0]).

5.2.2 Enhanced DCATM

DDR5RCD05 supports the enhanced functionality of the DCA Training Mode, by enabling the user to select the signals that are part of the XOR function used in DCATM. Besides DCA, the DCS0 and DCS1 can be included in the loopback function XOR calculation. When DCS0 is included in the XOR function as part of this enhanced DCATM, DCS1 is used as the control (or qualifier) signal. When DCS1 is included in the XOR function as part of this enhanced DCATM, DCS0 is used as the control (or qualifier) signal. The selection of inclusion of DCS0/DCS1 as well as the selection of the control (or qualifier) signal is programmable through the related control words.

This enhancement allows the fine tuning of DCS training with the toggling of the DCA signals at a later stage (during or after DCA training).

5.2.3 QCA Training - DRAM Interface

There is no RCD QCA Training Mode. In order for the RCD to align the QCA signals to QCK, the RCD must be able to support the DDR5 DRAM CA training Mode. During RCD QCA Training the Host will enable CA Pass-Through mode in [RW00\[2\]](#). The RCD will need to process MRW commands and block DRAM MRW commands while in CA Pass-Through mode. The RCD must be capable of QCA output delay adjustment when the Host sends an MRW to [RW\[1C:1B\]](#) and [PG\[5\]RW\[7B:60\]](#). CA Parity Checking must be disabled in RCD prior to QCA Training, however the DPAR receivers will remain enabled to support SDR CA Pass-Through mode. CA Pass-Through mode can only be enabled when the RCD is forwarding DRAM commands, [RW01\[1\] = 1](#).

5.2.4 CA Pass-through Mode

In order to train the DRAM interface, the RCD will be required to support a pass-through mode. In this mode the DCA signals are passed through to QCA regardless of DCS assertion. This allows the Host to send multiple cycles of QCA setup/hold and multiple cycles of QCS assertion, while also controlling the duration and timing relationship of these signals at a clock cycle granularity. The Host Interface DCA must be stable before the RCD can be placed into CA Pass-through mode. Parity checking must be disabled prior to and during Pass-Through mode. CA Pass-Through is performed on a per Rank basis and entered via MRW [RW00](#). The Host is only allowed to enable one Rank at a time for CA Pass-through mode, to ensure the ability to still send MRWs on the other Rank. The RCD executes DCS_n/DCA commands on the rank that is not selected for Pass-Through mode, but it is illegal for the Host to send commands other than MRW targeting the RCD. MRW to DRAM MR63 (for RCD Control Word read sequence) is not supported in CA pass-through mode. When Pass-Through mode is enabled for Rank 0 or Rank 1 all DCA signals will pass through to QCA. When [RW00\[3\] = 0](#), Rank 0 is selected then only DCS0 will get passed through to QCS0 and the RCD will process RW commands on Rank 1 and not process any commands for Rank 0. When [RW00\[3\]=1](#), Rank 1 is selected then only DCS1 will get passed through to QCS1 and the RCD will process RW commands on Rank 0 and not process any commands for Rank 1. The RCD keeps QCS_n static High for the rank that is not selected for Pass-Through mode. If the DRAM Interface Block all CMDs feature is enabled ([RW01\[1\] = 0](#)), the DCS_n input will not be passed through to QCS_n because all QCS_n outputs will be held statically HIGH by the RCD. CA Pass-through mode is exited by disabling CA Pass-Through mode via [RW00](#).

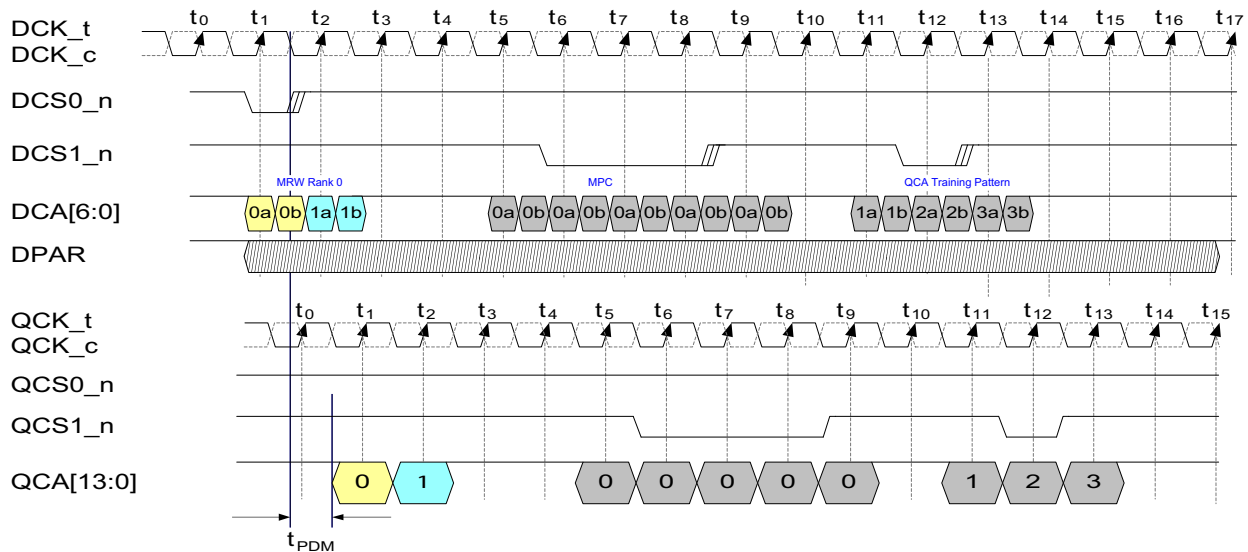


Figure 50 — MRW Example of MRW on DCS0 and CA Pass-Through on DCS1

5.2.4 CA Pass-through Mode (cont'd)

In SDR Mode when Pass-Through mode is enabled, DPAR will be used to indicate 1st UI QCA[6:0] (DPAR = LOW) and 2nd UI QCA[13:7] (DPAR = HIGH) as shown in Figure 51. When the DPAR signal starts toggling, it may take up to two clock cycles (1 DPAR cycle) for the correct bit sequence to get established at the QCA[13:0] outputs of the RCD. In Addition, the DDR5RCD05 device cannot guarantee the logic values of QCA[13:0] outputs unless the DPAR input is toggling continuously (i.e., once per DCK clock cycle) as shown in Figure 51. Therefore, the Host shall keep the DCA[6:0] input signals static HIGH and not assert DCS during the first two clock cycles of toggling parity (1 DPAR cycle) and the Host shall keep the DCA[6:0] input signals static HIGH and not assert DCS during the last two clock cycles of toggling parity (1 DPAR cycle, low to high transition).

Prior to entering or exiting CA Pass-Through or modifying the rank selection bit (RW00[3]), the Host shall keep the DCA[6:0] input signals static HIGH and not assert DCS for a minimum of two clock cycles.

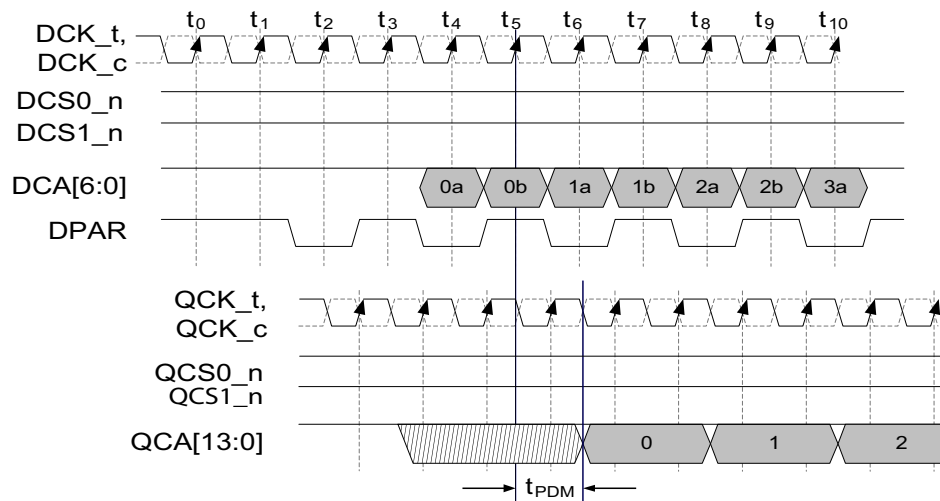


Figure 51 — SDR CA Pass-Through Mode

5.3 DFE Training Mode (DFETM)

The DDR5RCD05 supports a DCA and DCS DFE training mode. This Training Mode enables the use of pattern comparison and feedback features within the RCD during training. Figure 52 shows some of the DFE Training Circuitry associated with each individual DCA receiver. The DCS training circuitry is similar, with the exception of only having 4 DFE taps. These features include a margin monitor, an XOR to compare the functional receive path to the monitor output, an LFSR pattern generator and XOR to compare the monitor output to a known expected pattern, an error counter, and a path to the ALERT_n signal, QLBD signal, and QLBS signal to provide feedback to the Host controller. The Host must ensure Parity Checking is disabled in RCD prior to and during DFETM.

5.3 DFE Training Mode (DFETM) (cont'd)

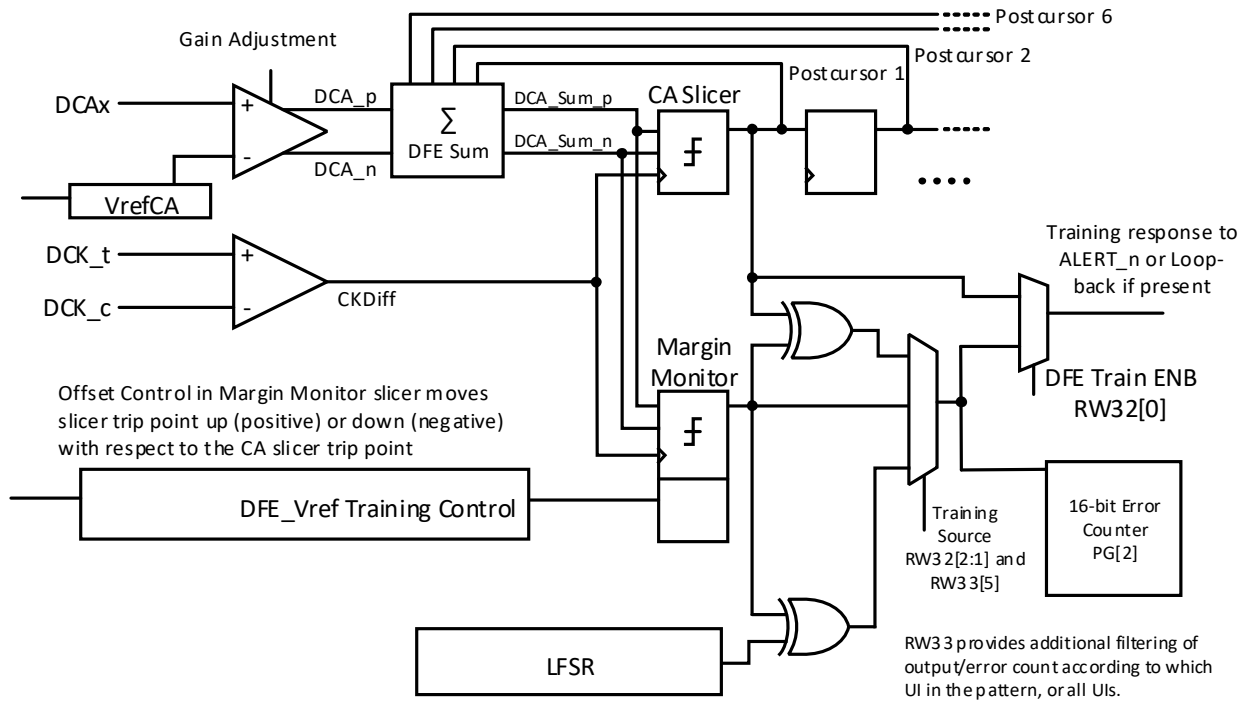


Figure 52 — DFE Training Circuitry

In addition to this fundamental set of DFE training features, the RCD supports an accelerator to sweep combinations of DFE Tap settings, Vref settings, and UI filters to enable more efficient DCA and DCS DFE Training.

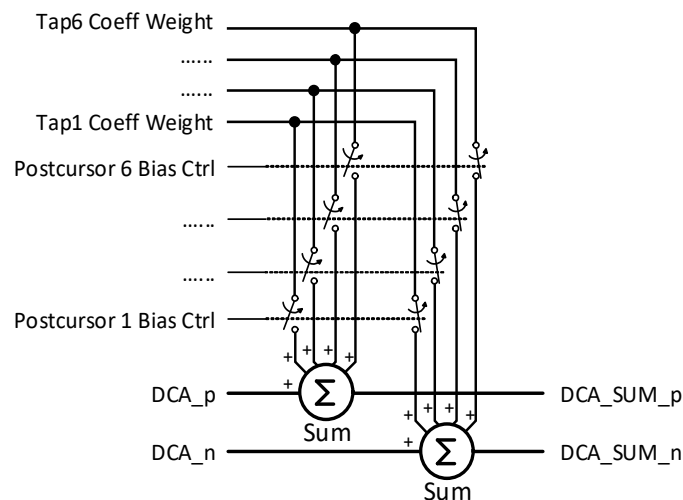


Figure 53 — DFE Summer

5.3 DFE Training Mode (DFETM) (cont'd)

Table 24 — Post-cursor Bias Ctrl Definition

Tap k Sign Bit	Post-cursor k	Switch to DCA_p Sum	Switch to DCA_n Sum
0	0	Open	Closed
	1	Closed	Open
1	0	Closed	Open
	1	Open	Closed

5.3.1 Galois LFSR

Two kinds of Galois LFSR (Linear Feedback Shift Register) are implemented to provide known pattern generation for DFE training: legacy per-pin 8-bit LFSRs and a global 16-bit LFSR. The LFSR Seed Value sets the initial state of the LFSR, and all UI's of the DCA or DCS pattern are compared to the output of the LFSR. A new seed setting is only applied when the LFSR Seed value is written. This seed is never restored as the LFSR state during training unless the Host writes the value to the seed register again.

The LFSR is reset to its default state under the following conditions:

- Power-up initialization
- DRST_n assertion

The RCD does not reset LFSR when Self Refresh Entry is registered. This is because during DFE training, the SRE command is not decoded.

5.3.1.1 8-bit LFSR

The legacy 8-bit LFSR is used by default for DCA and DCS DFE training. There are 10 in total, one for each DCA, DPAR and DCS. The ten seed registers are located in [PG\[2\]RW\[63, 67, 6B, 6F, 73, 77, 7B, 7F\]](#) and [PG\[6\]RW\[73, 77\]](#). The polynomial for the 8-bit Galois LFSR is $x^8 + x^6 + x^5 + x^4 + 1$. The current state of the LFSR associated with the DCA or DCS pin selected by [RW32\[5:3\]](#) can be read from [RW35](#).

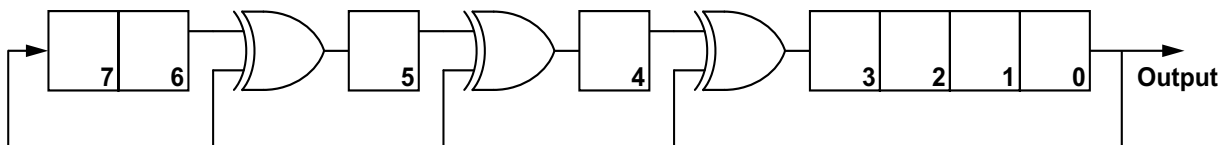


Figure 54 — 8-bit Galois LFSR of Polynomial $x^8 + x^6 + x^5 + x^4 + 1$

5.3.1.2 16-bit LFSR

The 16-bit LFSR can be optionally selected for use by DCA and DCS DFE training by setting [RW34\[1\]](#). There is one LFSR used for all pins, with the seed set in [RW2E, RW2D](#). The polynomial for the 16-bit Galois LFSR is $x^{16} + x^{13} + x^{10} + x^9 + x^8 + x^4 + 1$. The current state can be read from [RW2F](#) for the upper byte and [RW35](#) for the lower byte.

5.3.1.2 16-bit LFSR (cont'd)

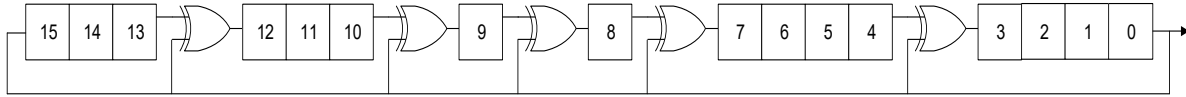


Figure 55 — 16-bit Galois LFSR of Polynomial $x^{16} + x^{13} + x^{10} + x^9 + x^8 + x^4 + 1$

Note that the diagram in Figure 55 is the ordering of the bits that is used in Table 25.

Table 25 — 16-bit LFSR Seed Mapping

LFSR Bit	Seed Register Bit	Read Register Bit
LFSR bit 0	RW2D_0	RW35_0
LFSR bit 1	RW2D_1	RW35_1
LFSR bit 2	RW2D_2	RW35_2
LFSR bit 3	RW2D_3	RW35_3
LFSR bit 4	RW2D_4	RW35_4
LFSR bit 5	RW2D_5	RW35_5
LFSR bit 6	RW2D_6	RW35_6
LFSR bit 7	RW2D_7	RW35_7
LFSR bit 8	RW2E_0	RW2F_0
LFSR bit 9	RW2E_1	RW2F_1
LFSR bit 10	RW2E_2	RW2F_2
LFSR bit 11	RW2E_3	RW2F_3
LFSR bit 12	RW2E_4	RW2F_4
LFSR bit 13	RW2E_5	RW2F_5
LFSR bit 14	RW2E_6	RW2F_6
LFSR bit 15	RW2E_7	RW2F_7

5.3.1.2 16-bit LFSR (cont'd)

Table 26 provides the 16-bit LFSR output for the first 32 iterations with a starting seed of 16'hFFFF:

Table 26 — Example of LFSR Output for the First 32 Iterations

UI or Cycle	Output Bit															
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Default	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
+1	1	1	1	0	1	1	0	0	0	1	1	1	0	1	1	1
+2	1	1	1	0	0	1	0	1	1	0	1	1	0	0	1	1
+3	1	1	1	0	0	0	0	1	0	1	0	1	0	0	0	1
+4	1	1	1	0	0	0	1	1	0	0	1	0	0	0	0	0
+5	0	1	1	1	0	0	0	1	1	0	0	1	0	0	0	0
+6	0	0	1	1	1	0	0	0	1	1	0	0	1	0	0	0
+7	0	0	0	1	1	1	0	0	0	1	1	0	0	1	0	0
+8	0	0	0	0	1	1	1	0	0	0	1	1	0	0	1	0
+9	0	0	0	0	0	1	1	1	0	0	0	1	1	0	0	1
+10	1	0	0	1	0	0	0	0	0	0	0	0	0	1	0	0
+11	0	1	0	0	1	0	0	0	0	0	0	0	0	0	1	0
+12	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0	1
+13	1	0	0	0	0	0	0	1	1	0	0	0	1	0	0	0
+14	0	1	0	0	0	0	0	0	1	1	0	0	0	1	0	0
+15	0	0	1	0	0	0	0	0	0	1	1	0	0	0	1	0
+16	0	0	0	1	0	0	0	0	0	0	1	1	0	0	0	1
+17	1	0	0	1	1	0	1	1	1	0	0	1	0	0	0	0
+18	0	1	0	0	1	1	0	1	1	1	0	0	1	0	0	0
+19	0	0	1	0	0	1	1	0	1	1	1	0	0	1	0	0
+20	0	0	0	1	0	0	1	1	0	1	1	1	0	0	1	0
+21	0	0	0	0	1	0	0	1	1	0	1	1	1	0	0	1
+22	1	0	0	1	0	1	1	1	0	1	0	1	0	1	0	0
+23	0	1	0	0	1	0	1	1	1	0	1	0	1	0	1	0
+24	0	0	1	0	0	1	0	1	1	1	0	1	0	1	0	1
+25	1	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0
+26	0	1	0	0	0	0	0	0	1	0	1	1	0	0	0	1
+27	1	0	1	1	0	0	1	1	1	1	0	1	0	0	0	0
+28	0	1	0	1	1	0	0	1	1	1	1	0	1	0	0	0
+29	0	0	1	0	1	1	0	0	1	1	1	1	0	1	0	0
+30	0	0	0	1	0	1	1	0	0	1	1	1	1	0	1	0
+31	0	0	0	0	1	0	1	1	0	0	1	1	1	1	0	1
+32	1	0	0	1	0	1	1	0	0	0	0	1	0	1	1	0

5.3.2 DFE Training Pattern Comparison and Feedback Features

The DFE Training Pattern Comparison features include many different configuration options to compare the output of the receiver to an expected pattern, and the ability to change the monitor DFE_Vref setting, for margining. The RCD also supports the ability to filter the comparison based on UI location in the pattern sequence. Some of these configuration settings are included in [RW32](#) DFE Training Mode Control Word. The UI Filtering configuration are included in [RW33](#) Additional Filtering for DFE Training Mode Control Word. When training DCA DFE, the LFSR state advances once per UI in the DFE pattern, only when DCS0_n is asserted.

When training DCS DFE, the LFSR state advances once per tCK in the DFE pattern, only when the DCS not under test is asserted. For example, when [RW33\[5\]=1](#) and [RW32\[5:3\]=0](#) (to test DCS0_n), the LFSR will increment when DCS1_n is asserted.

5.3.2 DFE Training Pattern Comparison and Feedback Features (cont'd)

When UI Filtering is enabled, only the XOR comparisons or the monitor output (based on Training Source setting) corresponding to the UI Filter Setting is fed back to the ALERT_n (or QLBD or QLBS) signal. This is also the only UI (or group of UI's for the even/odd configuration) that triggers any events in the error counter. When UI Filtering is enabled and set to UI[n] as the UI Filter Setting, only the nth UI of the DCA pattern will be compared/recorded/looped back. When Per-UI Filtering is enabled, only patterns that are 8 UI in length can be sent to the RCD by the Host. For all other patterns, the pattern length must be a multiple of 8 UI. When either the Even UI Filtering is enabled or the Odd UI Filtering is enabled, the pattern length must also be a multiple of 8 UI. The even UI's are all rising edge samples. The odd UI's are all falling edge samples for DDR DCA mode, or all rising edge samples for DCS or SDR DCA mode.

The following timing diagram shows an example of the LFSR pattern sent by the Host to the RCD. Within each tDFETM_Interval time period (which is 4tCK for DDR DCA mode, and 8tCK for DCS and SDR DCA mode), if any mismatches occur, the RCD will pull the ALERT_n (or QLBD or QLBS) signal LOW after tDFETM_Valid. If no mismatches occur during the tDFETM_Interval time period, the ALERT_n (or QLBD or QLBS) signal will remain HIGH.

Configuration of the output signal for the DFETM output is set in the RW01 Parity and Alert Global Control Word.

NOTE 1: For DDR DCA DFE, one UI is ½ tCK. For DCS and SDR DCA DFE, one UI is 1tCK.

NOTE 2: For DDR DCA, tDFETM_Interval time period is 4tCK. For DCS and SDR DCA, it is 8tCK.

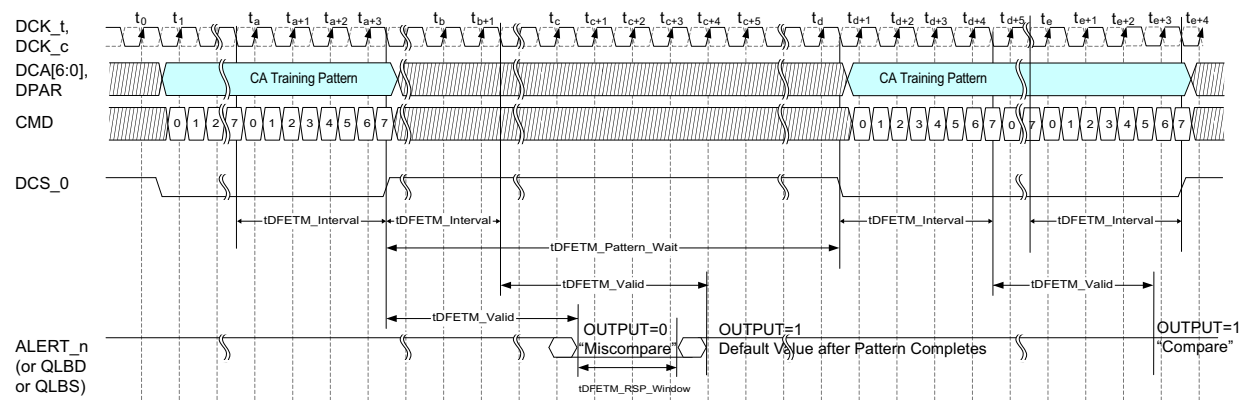


Figure 56 — LFSR CA DFE Training Pattern for DDR DCA

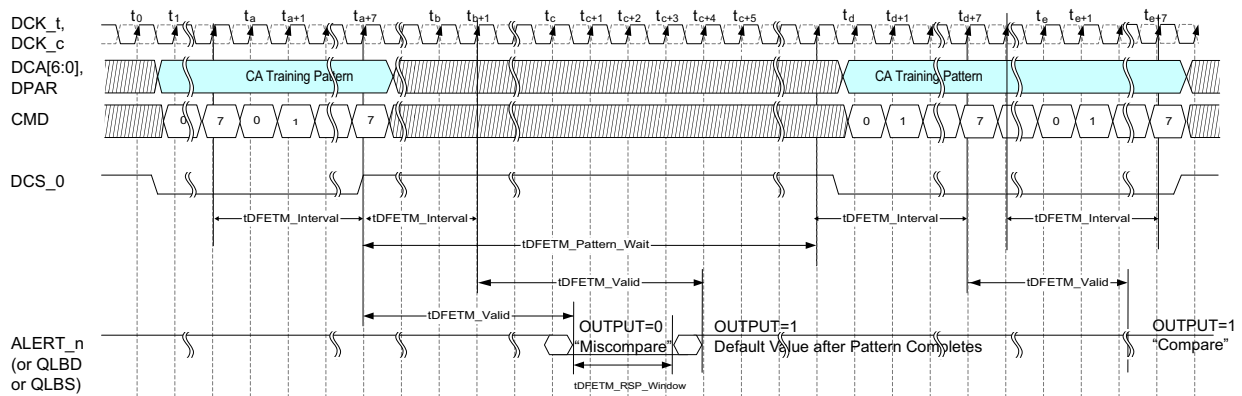


Figure 57 — LFSR CA DFE Training Pattern for SDR DCA

5.3.2 DFE Training Pattern Comparison and Feedback Features (cont'd)

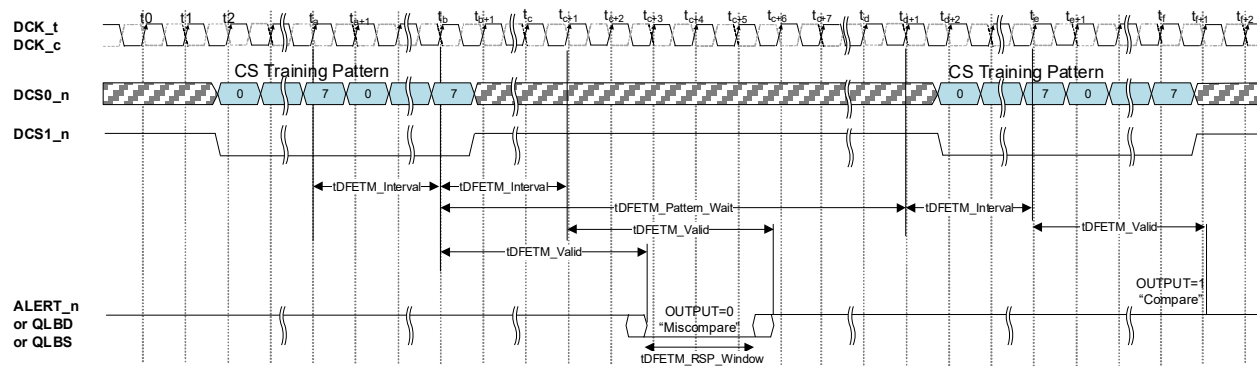


Figure 58 — LFSR DCS DFE Training Pattern⁴

The first tDFETM_Interval begins on the first UI of the pattern. Once the first tDFETM_Interval has elapsed the first Output is generated on the ALERT_n (or QLBD or QLBS) pin, following the tDFETM_Valid time. Every tDFETM_Interval after will also generate a new Output value. For the different training configuration options, the following feedback will apply:

LFSR XOR Monitor - If any XOR result in the tDFETM_Interval = 1, the ALERT_n (or QLBD or QLBS) output will be 0.

Monitor XOR Slicer - If any XOR result in the tDFETM_Interval = 1, the ALERT_n (or QLBD or QLBS) output will be 0.

Monitor - If any Monitor sample in the tDFETM_Interval = 1, the ALERT_n (or QLBD or QLBS) output will be 0.

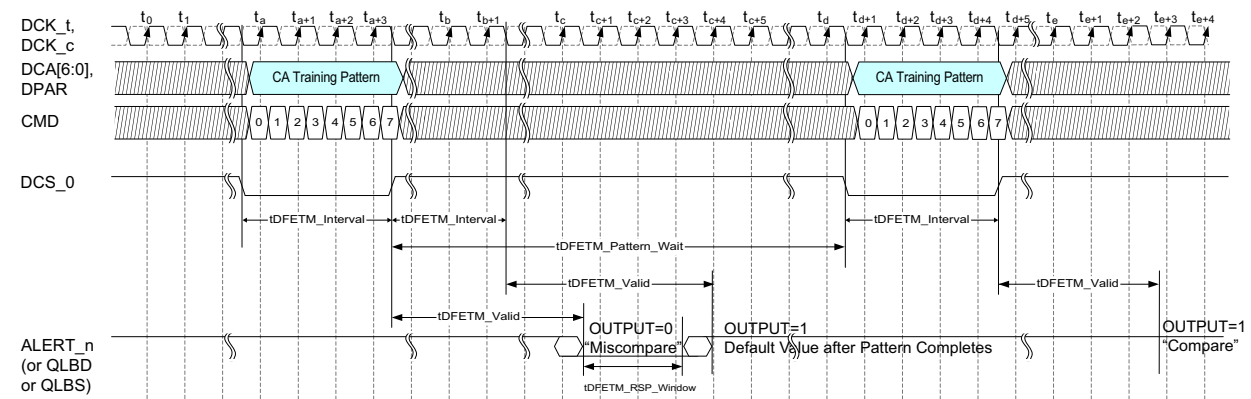


Figure 59 — CA DFE UI Filter Pattern for DDR DCA

NOTE 4 In this example, RW33[5]=1 and RW32[5:3]=0 (to test DCS0_n)

5.3.2 DFE Training Pattern Comparison and Feedback Features (cont'd)

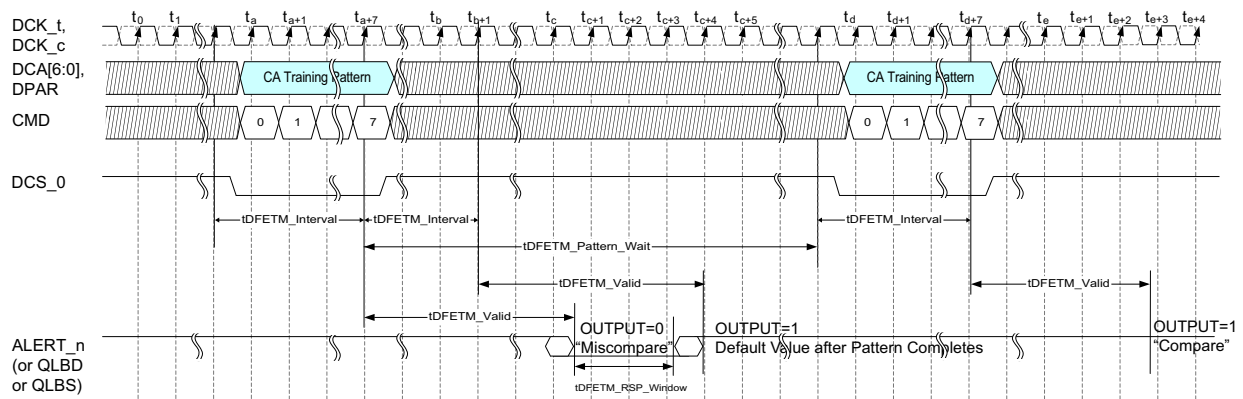


Figure 60 — CA DFE UI Filter Pattern for SDR DCA

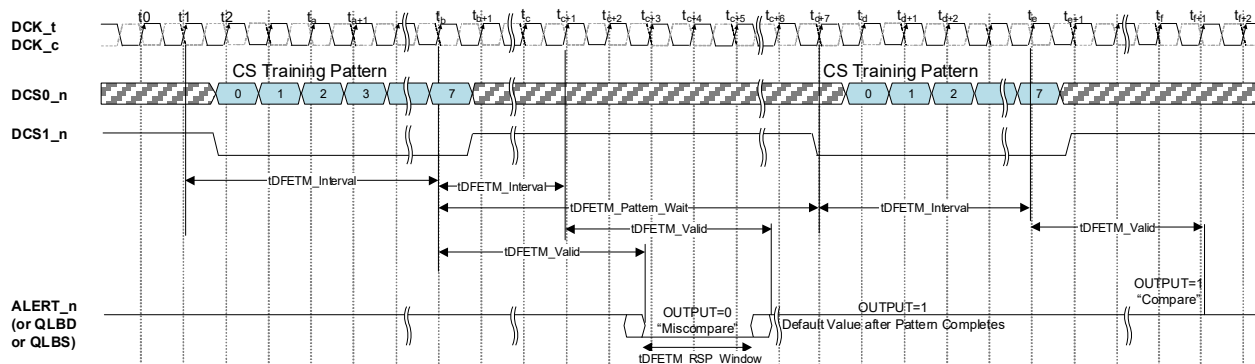


Figure 61 — LFSR DCS DFE UI Filter Pattern⁵

When UI filtering is enabled, only the XOR result or the Monitor sample associated with the selected UI is fed back on the ALERT_n (or QLBD or QLBS) signal. As described above, the XOR or Monitor sample result is inverted on the ALERT_n (or QLBD or QLBS) signal.

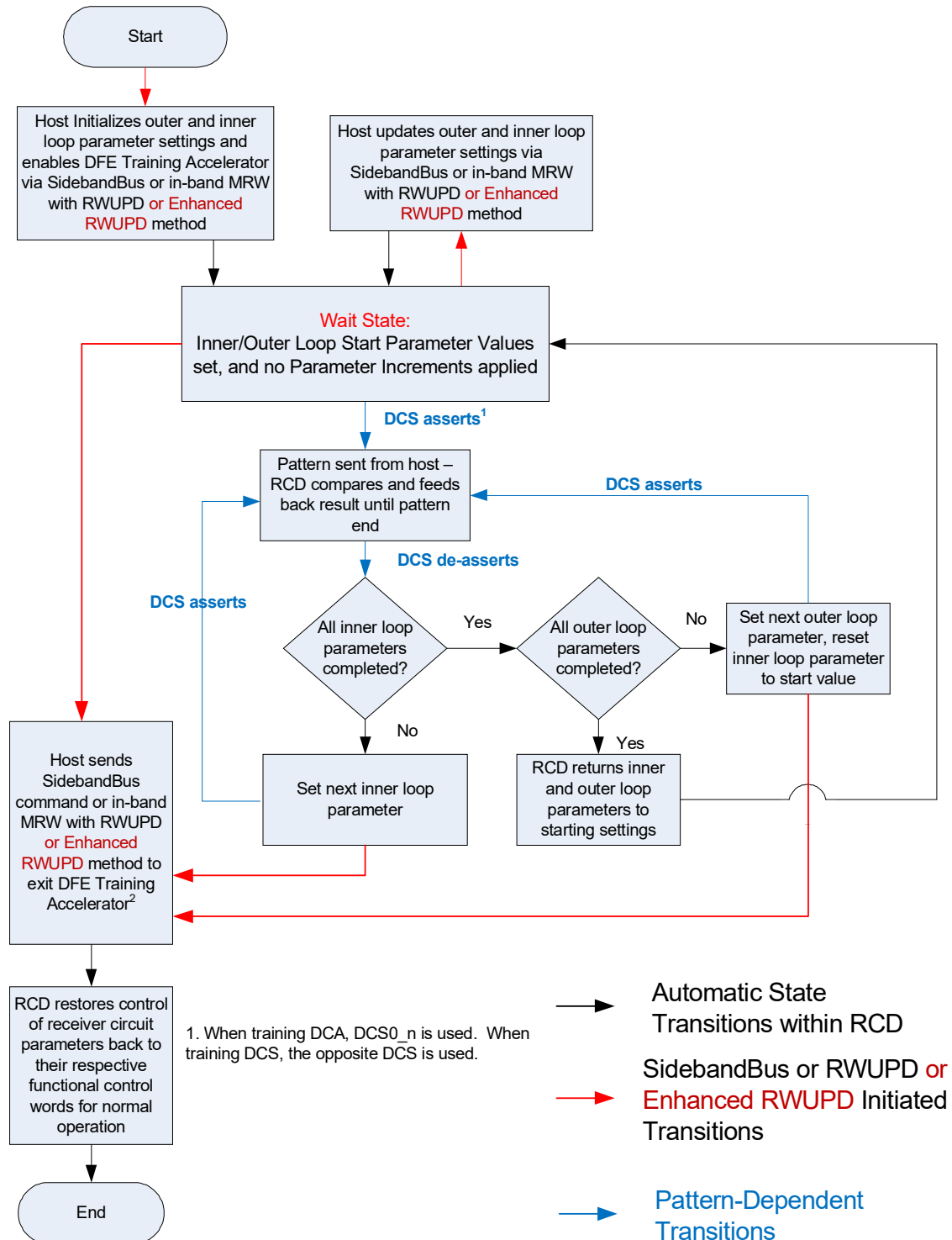
There will not be a glitch on ALERT_n if the evaluation stays the same within a burst.

5.3.3 DFE Parameter Sweep Acceleration

In addition to the features used to compare patterns and record or feedback the results of those comparisons, the RCD shall support the ability to accelerate the training sweeps of the critical DFE training parameters.

NOTE 5 In this example, RW33[5]=1 and RW32[5:3]=0 (to test DCS0_n)

5.3.3 DFE Parameter Sweep Acceleration (cont'd)



NOTE: To read Loop Parameter Current Values when DFE Parameter Sweep Acceleration is enabled in the RCD, the Host must use the sideband management interface and it must keep DCS HIGH to stop training patterns. If these conditions are satisfied, the RCD shall provide the Loop Parameter Values intended for the next training pattern.

Figure 62 — RCD Operation during DFE Parameter Sweep Acceleration

5.3.3 DFE Parameter Sweep Acceleration (cont'd)

The parameters that are included as options for the outer loop sweep are:

- UI - (RW33[4:2])
- Tap1 - (PG[1:0]RW[61,69,71,79] or PG[6]RW[61,69], depending on the DCA, DPAR, or DCS signal selected for training in the RW32[5:3] register)
- Tap2 - (PG[1:0]RW[62,6A,72,7A] or PG[6]RW[62,6A], depending on DCA, DPAR, or DCS signal selected for training in the RW32[5:3] register)
- Tap3 - (PG[1:0]RW[63,6B,73,7B] or PG[6]RW[63,6B], depending on DCA, DPAR, or DCS signal selected for training in the RW32[5:3] register)
- Tap4 - (PG[1:0]RW[64,6C,74,7C] or PG[6]RW[64,6C], depending on DCA, DPAR, or DCS signal selected for training in the RW32[5:3] register)
- Tap5 - (PG[1:0]RW[65,6D,75,7D], depending on DCA or DPAR signal selected for training in the RW32[5:3] register)
- Tap6 - (PG[1:0]RW[66,6E,76,7E], depending on DCA or DPAR signal selected for training in the RW32[5:3] register)
- Null

The parameters that are included as options for the inner loop sweep are:

- VrefCA - (RW[47:40])
- DFE_Vref - (PG[2]RW[62,66,6A,6E,72,76,7A,7E] or PG[6]RW[72,76], depending on DCA, DPAR, or DCS signal selected for training in the RW32[5:3] register)
- Null

The tDFETM_Pattern_Wait time is the amount of time the Host must wait between de-assertion of the qualifying DCS for one pattern to the qualifying DCS assertion of the next pattern. The tDFETM_Pattern_Wait_Accel restriction only applies when the DFE Training Accelerator is operating, and is defined to allow for enough time in the RCD to change settings for the inner and outer loop parameters. The actual register values associated with the inner and outer loop parameters may or may not change during the execution of the DFE training accelerator. The settings may be applied directly from the accelerator logic output, bypassing the functional operation registers.

The outer loop tap parameters are defined as signed magnitude fields. For the Outer Loop Start Value in RW37, the format is two's complement. This simplifies the logic for incrementing from negative to positive values. The RCD shall convert the final parameter value per increment to the signed magnitude values required by the actual Tap settings.

The Host is responsible for avoiding incorrect combinations of the loop parameter control word settings.

When the DFE accelerator exits, the inner and outer loop parameters are returned to the values prior to enabling the accelerator within t_{DFETA_Exit_Wait_Loop_Value} time.

5.3.4 RWUPD

The RW In-Band Update (RWUPD) feature is enabled in RW32[6]. The feature allows Host to update configuration registers when the RCD is only under DCA DFE training and using DFE Training Accelerator. This feature is not applicable for any other trainings such as DCATM, DCSTM, or DCS DFE training.

The RCD supports RWUPD feature during DCA DFE training only when DFE Training Accelerator is enabled (i.e., RW32[0] = 1, RW34[0] = '1'). The RCD does not support RWUPD feature during manual DCA DFE training (i.e., RW32[0] = 1, RW34[0] = '0').

The Host enables the RWUPD feature and Global DFE Training Mode feature at the same time (RW32[6,0] = '11'). Next Host programs DFE configuration registers and sets accelerator loop parameters via inband or SideBandBus. Then Host enables the DFE Training Accelerator (RW34[0] = '1') via inband or SideBandBus.

The Host shall not enable RWUPD in RW32[6] and Enhanced RWUPD in PG[7]RW7F[0] at the same time. These two features are mutually exclusive.

When DDR5RCD05 is in the wait state of the DCA DFE Parameter Sweep Accelerator (DFETA) and if DCS1_[B:A]_n is asserted then the RCD shall enter a mode where it allows multi cycle RW writes as specified below. The mode is referred to as RWUPD mode. The wait state of the DFE training mode is defined as any state in which no iteration is active and the RCD can accept changes to the DFE training accelerator parameters.

During the entire RWUPD duration (RWUPD entry, Operation and Exit) the host is not allowed to assert DCS0_[B:A]_n.

Figure 63 shows a state machine implementing the RWUPD mode and Figure 64 shows a timing diagram demonstrating operation. Table 232 has the relevant timing parameters.

5.3.4.1 RWUPD Entry

When DDR5RCD05 is in DCA DFETA wait state (outside of inner and outer loop iterations), if DCS1_[B:A]_n is asserted, the RCD enters in RWUPD mode. Figure 63 and Figure 64 show how RCD enters RWUPD mode. The RCD requires two DCS1_[B:A]_n assertions to receive first RW address.

- On entry, the RCD shall apply DCA VrefCA values that are currently present in RW[47:40] to the corresponding input pins and only DCA DFE shall be disabled.

5.3.4.2 RWUPD Operation

After entry in RWUPD mode, the DDR5RCD05 expects pairs of DCS1_[B:A]_n assertions.

- On the first assertion the RCD samples the target RW address on {DCA[6:0]_[B:A], DPAR_[B:A]}.
- On the second assertion, the RCD samples the value to write to the target RW address.

5.3.4.3 RWUPD Exit

In RWUPD mode, if RW32[7] is written to '1' then device shall exit the RWUPD mode and return to the DFETA wait state.

The RCD also allows to exit the RWUPD mode via SideBandBus.

- On exit, the RCD applies DCA VrefCA value as presented by the training accelerator if inner loop is selected for VrefCA; otherwise RCD applies DCA VrefCA value that is currently present in RW[47:40] to all input pins.

The host is responsible for exiting the RWUPD mode before exiting the DFE training mode (i.e., RW32[0] = '0').

5.3.4.3 RWUPD Exit (cont'd)

The input signals {DCA[6:0]_[B:A], DPAR_[B:A]} must remain static High during $t_{RWUPD\ Exit}$ to ensure deterministic initialization of DFE circuits as they get re-enabled.

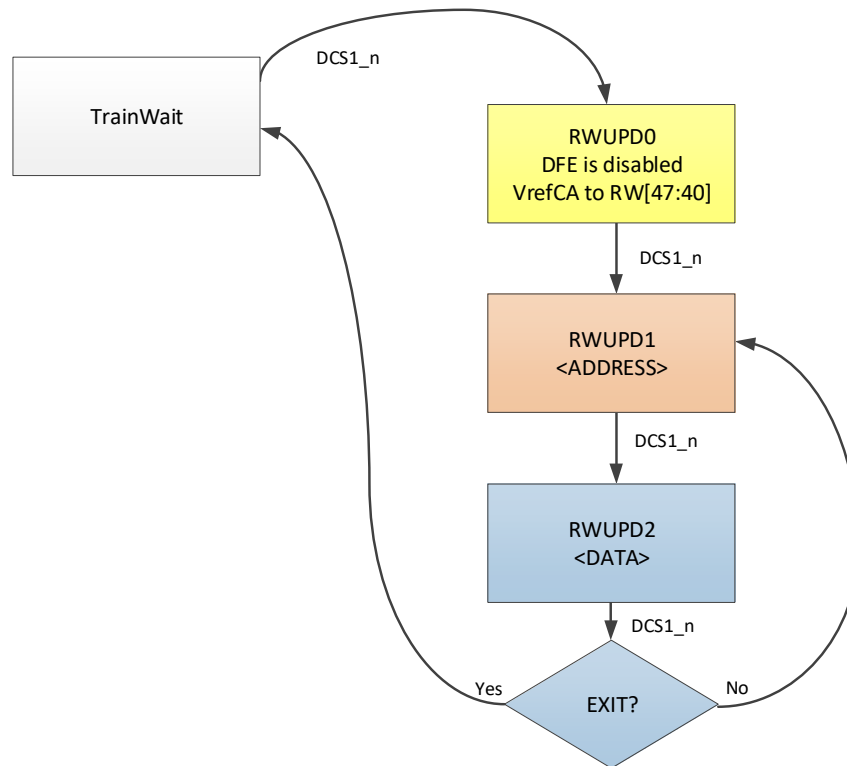


Figure 63 — RWUPD State Machine

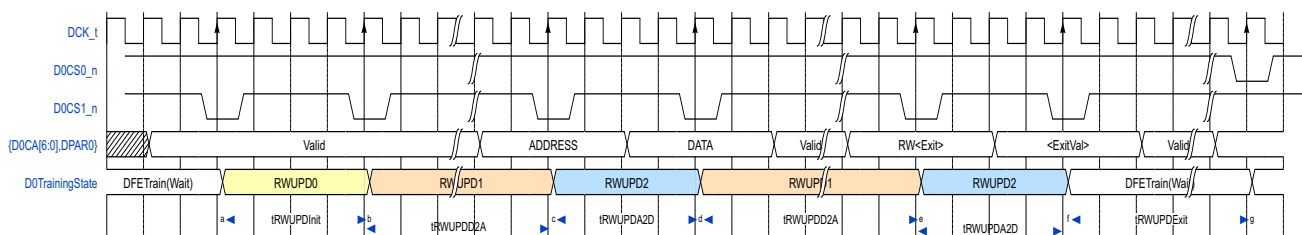


Figure 64 — RWUPD Timing Diagram for Channel A

5.4 Enhanced RWUPD

Unlike RWUPD feature, the Enhanced RWUPD feature expands the Host's ability to update any configuration registers when the RCD is under DCSTM or DCATM or DCADFE training.

The Host sets PG[7]RW7F[0] = '1' via Sideband Bus to enable the Enhanced RWUPD feature, selects the proper DCS qualifier in PG[7]RW7F[1], (and for DFETA, Global DFE Training Mode feature (RW32[0] = '1') and the DFE Training Accelerator (RW34[0] = '1')) prior to entering a specific training mode. The host may now perform one of the DCS/DCA training modes using Enhanced RWUPD to update the RCD control words. Once the Host interface training is complete, the Enhanced RWUPD feature is allowed to be enabled in-band.

The Host shall not enable RWUPD in RW32[6] and Enhanced RWUPD in PG[7]RW7F[0] at the same time. These two features are mutually exclusive.

Table 27 shows the allowed usage of Enhanced RWUPD for Host Interface DCS/DCA training and which DCS_n qualifier is required to use. For DCS DFETA training, both DCS0_n and DCS1_n are used (one for training pattern and other as qualifier) and hence Enhanced RWUPD feature is not supported during DCS DFETA.

Host is responsible for disabling CA Scrambling and parity checking prior to enabling Enhanced RWUPD feature. The RCD blocks all commands to the DRAM interface and it does not decode all the DRAM commands including MRW command. The RCD utilizes the Enhanced RWUPD sequence to update any configurations registers including configurations registers to enter/exit training mode or to update the configurations registers during the training.

When DDR5RCD05 is in an idle state and if selected DCS_n qualifier is asserted twice, spaced by tRWUPDInit_ENH, then the RCD shall enter a mode where it allows multi cycle RW writes as specified below. The mode is referred to as Enhanced RWUPD mode. The wait state is defined as any state in which no iteration is active.

During the entire Enhanced RWUPD duration (Enhanced RWUPD entry, Operation and Exit) the host is not allowed to assert the non-qualifier DCS_n.

Figure 65 shows a state machine implementing the Enhanced RWUPD mode and Figure 66 shows a timing diagram demonstrating operation. Table 232 has the relevant timing parameters.

Table 27 — Enhanced RWUPD Usage

Host Interface Training mode	PG[7]RW7F[1] DCS Qualifier	PG[7]RW7F[0] Enhanced RWUPD enable	Target	Qualifier ¹
DCSTM	1	1	DCS0	DCS1
DCSTM	0	1	DCS1	DCS0
DCATM	1	1	DCS0	DCS1 ²
DCA DFETA ³	1	1	DCS0	DCS1
DCS DFETA ⁴	Not Supported during this mode ⁵			

NOTE 1 The Qualifying DCS assertion pulse width must meet tRWUPD_DCSPW_ENH.

NOTE 2 DCS Qualifier will not take part in Enhanced DCATM XOR

NOTE 3 DCA DFETA or DCA DFETM

NOTE 4 DCS DFETA or DCS DFETM

NOTE 5 Enhanced RWUPD can be used prior to DCS DFETA

5.4.1 Enhanced RWUPD Entry

When DDR5RCD05 is in an idle state and if selected DCS_n qualifier is asserted twice, spaced by $t_{RWUPDInit_ENH}$, the RCD enters in Enhanced RWUPD mode. Figure 65 and Figure 66 show how RCD enters Enhanced RWUPD mode. The RCD requires two qualifier DCS_n assertions to be ready to receive first RW address.

- On entry, the RCD applies default value for DCA VrefCA to all input pins and only DCA DFE shall be disabled.

5.4.2 Enhanced RWUPD Operation

After entry in Enhanced RWUPD mode, the DDR5RCD05 expects pairs of DCS1_[B:A]_n assertions.

- On the first assertion the RCD samples the target RW address on {DCA[6:0]_[B:A], DPAR_[B:A]}.
- On the second assertion, the RCD samples the value to write to the target RW address.

5.4.3 Enhanced RWUPD Exit

In Enhanced RWUPD mode, if PG[7]RW7F[7] is written to '1' then RCD shall exit the Enhanced RWUPD mode.

The RCD also allows to exit the Enhanced RWUPD mode via SideBandBus.

Upon Enhanced RWUPD exit:

- For manual training mode for DCA DFE training, the DCSTM and DCATM training, the RCD applies DCA VrefCA value that is currently present in RW[47:40] to all input pins.
- For training accelerator mode for DCA DFE training, the RCD applies DCA VrefCA value as presented by the training accelerator if inner loop is selected for VrefCA.

The input signals {DCA[6:0]_[B:A], DPAR_[B:A]} must remain static High during $t_{RWUPDExit_ENH}$ to ensure deterministic initialization of DFE circuits as they get re-enabled.

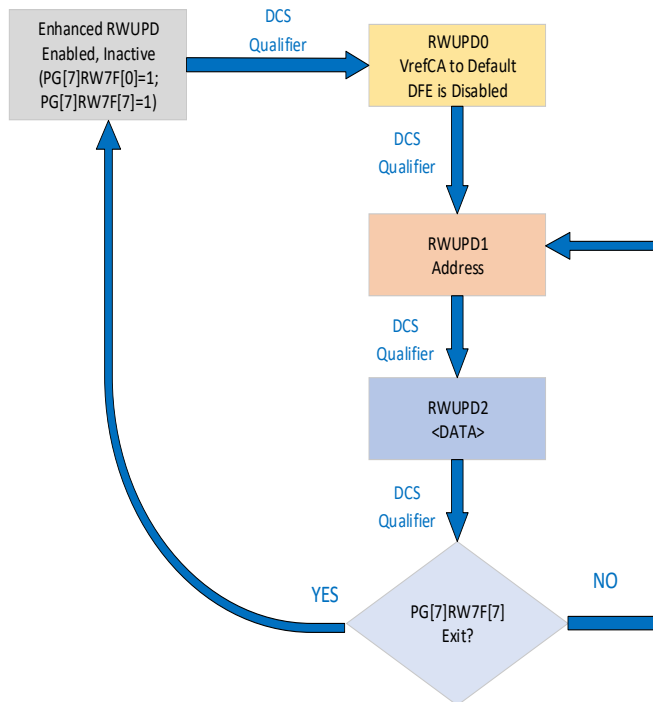


Figure 65 — Enhanced RWUPD State Machine

5.4.3 Enhanced RWUPD Exit (cont'd)

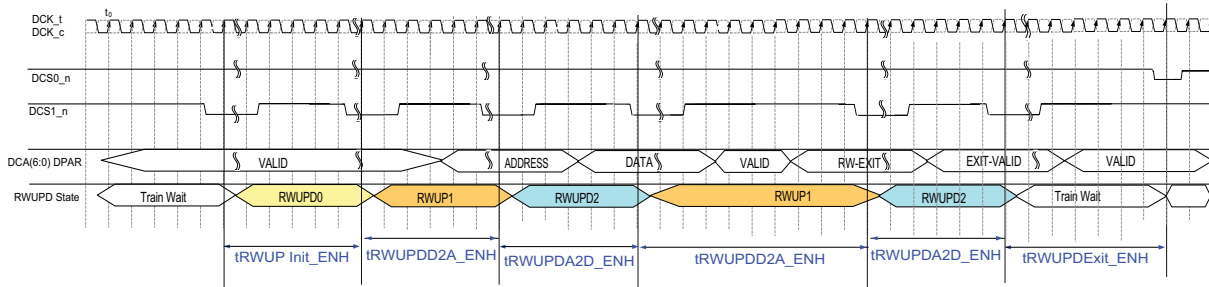


Figure 66 — Enhanced RWUPD with DCS1_n as Qualifier Example

Note: Since the exit bit is in a paged register, the exit requires two writes (four DCS pulses) - one to [RW5F](#) and the other to [PG\[7\]RW7F](#).

5.5 Device Equalization Self-Train (DESTM) for DFE and Enhanced CTLE Training

To improve the training time of DFE and CTLE on the DCS and DCA signals, an alternative training method is defined to calibrate the DFE tap coefficients and CTLE settings on DCS and DCA Host-interface input receivers.

The Host must configure the DESTM LFSR pattern length, select the DCS and DCA signals which will be trained. The Host must also enable DFE Taps [RW31\[7:4\]](#), [RW33\[7:6\]](#), and DFE ENB/Vref [RW31\[1:0\]](#) prior to enabling the DESTM. If the DESTM training is to include CTLE coefficients then the Host must enable Enhanced CTLE [PG\[7\]RW70\[0\]](#) and CTLE [RW50\[0\]](#) as part of the configuration process.

Once the configuration is done, and prior to Start Training, the Host will start sending the LFSR pattern to the selected DCS and DCA signals. The Host must continue driving the LFSR until the DESTM training is completed, as shown in Figure 67. During DESTM only one LFSR training pattern, either 8-bit or 16-bit, is issued by the controller to each DCA/DCS lane.

The DESTM training sequence is started when the Host enables the Training Start bit in [PG\[7\]RW60\[1\]](#) through SidebandBus. The RCD drives ALERT_n or QLBD/QLBS LOW during the DESTM operation. The input receivers will train their internal DFE Tap coefficients for all enabled Taps and CTLE settings automatically. Once the optimum settings are found, the device will clear [PG\[7\]RW60\[1\]](#) and signal the Host by driving ALERT_n or QLBD/QLBS back to HIGH prior to t_{DESTM} if [PG\[7\]RW60\[7\]=1](#).

After RCD de-asserts the ALERT_n, the Host can either restart the training or exit the DESTM mode through SidebandBus, as shown in Figure 68. The Host may stop the training at any time through a SidebandBus write to [PG\[7\]RW60\[1:0\] = '01'](#) or [PG\[7\]RW60\[1:0\] = '00'](#). It is illegal to write [PG\[7\]RW60\[1:0\] = '10'](#).

The Fail Status registers are read-only and indicate an error has occurred. The fail status register bits are updated when DESTM training stops, either by the Host or RCD self-clear of [PG\[7\]RW60\[1\]='0'](#)

If the RCD did not execute the training correctly by t_{DESTM} , the RCD will not de-assert ALERT_n, at this point the Host will stop the training through SidebandBus by writing [PG\[7\]RW60\[1\] = 0](#) and the RCD will update Fail Status Registers [PG\[7\]RW63\[7:6\]](#) and [PG\[7\]RW65\[7:0\]](#).

5.5 Device Equalization Self-Train (DESTM) for DFE and Enhanced CTLE Training (cont'd)

When the continuous training mode is enabled, the device will repeatedly run the internal training state machine on one selected signal until the Host stops the training by writing `PG[7]RW60[1]="0"`. Prior to the continuous training mode being enabled, the Host must disable the ALERT_n or QLBD/QLBS Low Assertion feature by setting `PG[7]RW60[7]="0"`. The Host must repeat the entire flow for the next selected signal to be trained in continuous mode.

At the end of the training procedure, the selected DFE Tap coefficients and CTLE settings registers on the selected DCS and DCA bits will be updated by the RCD device with the trained results.

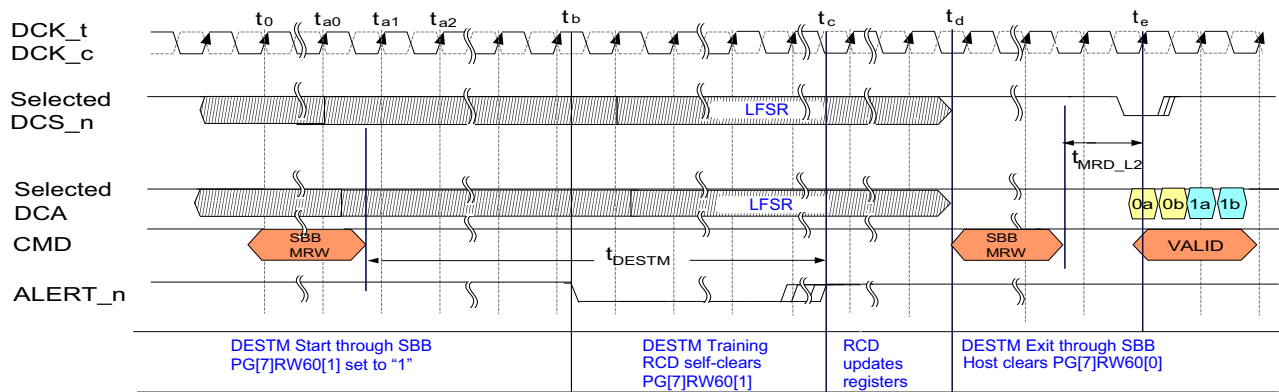


Figure 67 — Typical DESTM Start and Stop Training Timing Diagram

5.5 Device Equalization Self-Train (DESTM) for DFE and Enhanced CTLE Training (cont'd)

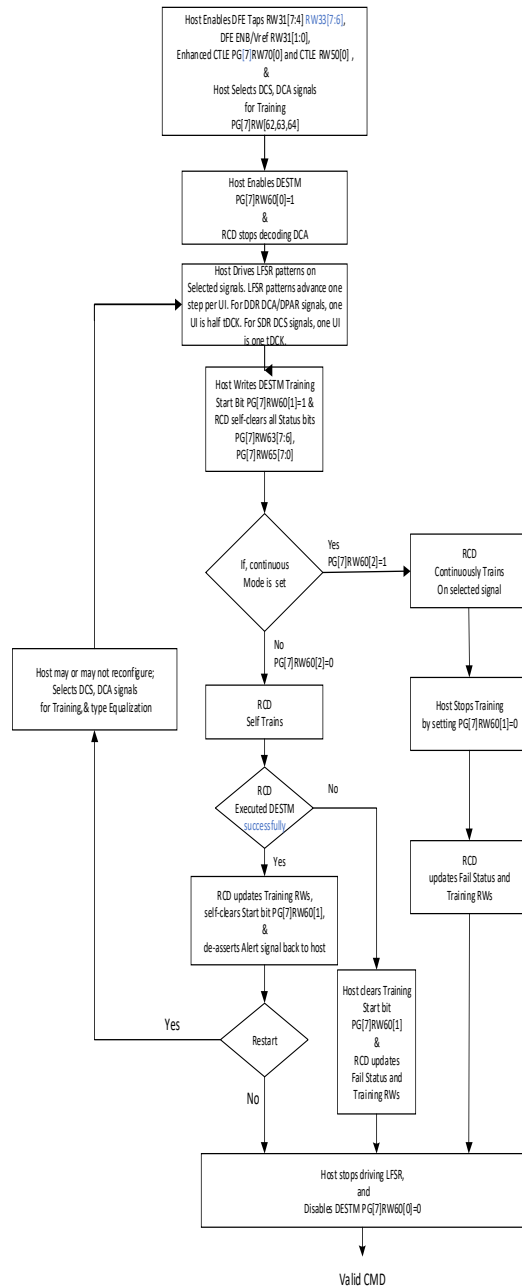


Figure 68 — Example Flow after DESTM Configuration

5.6 Host Interface Training during Self-Refresh Mode (HIT-SR)

HIT-SR is supported during Self-Refresh without Clock Stop only. Host interface training support during self-refresh mode will allow the Host controller to put DRAMs into self-refresh without clock stop, and enable any of the Host interface training modes including DCSTM, DCATM, DCSDFETM, DCADFETM, and CTLE Training. The ALERT_n signal remains functional for DCA/DCS training.

When the Host interface training support during self-refresh without clock stop mode is enabled the DCK will toggle and RCD inputs termination will be enabled during the entire procedure. The following is the operation sequence:

1. To enable the Host interface training support during self-refresh without clock stop mode, the Host controller will configure PG[7]RW68[0] to “1” t_{MRD_L2} time ahead of issuing the SRE command. This control word is global, and both sub-channels must enable or disable the support together.
2. The Host controller issues the SRE command to all Ranks of both sub-channels. The device will forward the SRE commands to the DRAM interface.
3. An ALERT_n pulse during HIT-SR entry can result in a loss of synchronization between the Host and RCD. To prevent DRAM errors during this time, the Host must ensure that all DRAM pages are closed prior to issuing the MRW to enter HIT-SR. To handle parity errors in the RCD, the RCD must automatically disable HIT-SR by clearing PG[7]RW68[0] when ALERT_n asserts for any reason and the RCD is not yet in HIT-SR mode (the time from MRW to RCD to enable HIT-SR to end of t_{HIT_SU} time). This allows the Host Controller to always use the normal error recovery procedure as defined in Clause 3.5, “Scrambling on DCA” and Clause 3.6, “Parity”, after which it must return to step 1. The Host Controller must ensure that all ranks on both sub-channels have received the SRE command with no parity error detected before proceeding to step 4.
4. The Host controller will issue a single-cycle NOP command at least t_{CPDED} time after the SRE command. Parity is not checked for this NOP. Any LOW on DCSx_n will be recognized as a valid NOP command. The device will block this NOP command, drive QCS to LOW, stop driving QCA, and disable scrambling on DCA. After this NOP command, after t_{HIT_SU} time, the RCD enters HIT-SR mode and gets ready for the Host interface training. Scrambling will be re-enabled and re-synced as usual during the SRX that closes out the HIT-SR process. The Scrambler Reset feature PG[70]RW60[6] must be enabled during HIT-SR so that the scrambler is re-enabled after the HIT-SR.
5. If a parity error happens while in HIT-SR, after scrambling has been automatically disabled, PG[7]RW68[0] will not be automatically cleared by the RCD. In this case, errors are handled independently in each sub-channel as if scrambling was disabled in PG[70]RW60[2]. Only the offending sub-channel will stop executing commands during the ALERT_n pulse. Note that parity checking is only applicable in the context of when Host sets/configures the RCD device for any specific training. The Host is still responsible to follow normal training rule where it must disable parity checking prior to actually starting the training. Once training is complete, the Host is required to re-enable the parity checking when it exits the HIT-SR.
6. After t_{HIT_SU} the device is ready for the Host interface training and keeps the termination enabled on DCK, DCS and DCA. Each sub-channel can be trained independently or simultaneously with the other sub-channel. During the Host interface training, the DCK continues to toggle. To use in-band MRW for RCD Host Interface training modes other than DCSTM, both DCS0 and DCS1 inputs need be enabled in RW09[2] during the training for single Rank DIMMs.
7. After the Host interface training is finished, the Host controller will configure PG[7]RW68[0] to “0” to disable HIT-SR. After t_{MRD_L2} time, the device will be back to normal self-refresh without clock stop mode, keep the termination enabled on DCK, DCS and DCA, and wait for the one-cycle NOP and three-cycle NOP commands to exit the self-refresh mode properly. Parity is not checked for these NOPs.

5.6 Host Interface Training during Self-Refresh Mode (HIT-SR) (cont'd)

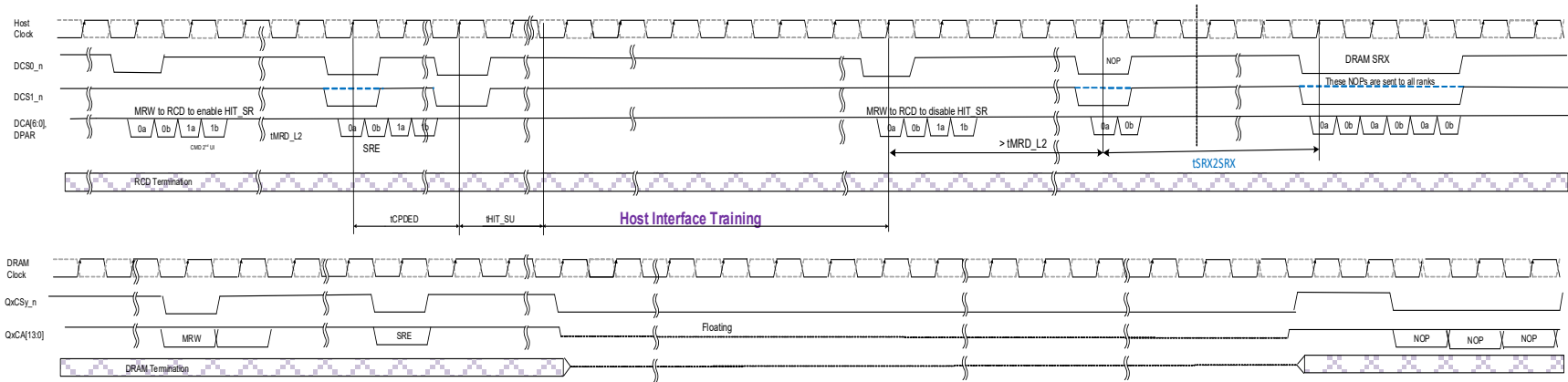


Figure 69 — Host Interface Training during Self Refresh without Clock Stop Example

5.7 Dual Frequency Support

The DDR5 register supports operation at a second, i.e., lower than nominal, frequency as a means to save buffer and DRAM power when the memory bandwidth demand allows.

To enable fast frequency switching without the need for retraining every time the frequency is changed, the DDR5 register can be trained at two, or more, different frequencies at boot up time. When only two frequencies need to be supported, the DDR5RCD05 can retain register settings associated with each of the two frequencies. The two sets of RCD registers are listed in Table 28. The RCD hardware will take care of updating any other frequency-dependent internal settings in each frequency context as needed. In cases where more than two frequencies of operation are necessary, RCD training information will need to be stored in memory space available to the Host controller for this purpose since the DDR5RCD05 device only contains two sets of frequency context registers.

Table 28 — Control Words Duplicated for Frequency Context Support

Register Address	Description
RW0A	QCK Signals Driver Characteristics Control Word
RW0C	QxCA and QxCS_n Signals Driver Characteristics Control Word
RW10	IBT Control Word
RW11[3:0]	Command Latency Adder Configuration Control Word (Latency Equalization Support has been deprecated. All RW11 bits will behave as RFU.)
RW[12:15]	Q[A:D]CK Output Delay Control Word
RW17 .. RW1A	QxCS_n Output Delay Control Word
RW1B, RW1C	QxCA Output Delay Control Word
RW31[7:4, 0]	DFE Configuration Control Word
RW33[7:6]	DFE Tap 5 and Tap 6 Configuration Control Word
RW40 .. RW47	Internal VrefCA Control Word
RW48, RW49	Internal VrefCS Control Word
RW50[0], RW51, RW52[3:0], RW53[3:0], RW54	CTLE Control Words
PG[00, 01]	DCA DFE Gain and Tap 1, Tap 2, Tap 3, Tap 4, Tap 5, Tap 6 Coefficients per Input Receiver
PG[5]RW[7B:60]	Per-bit QCA Output Delay Control Words
PG[6]RW[60:64, 68:6C, 78]	DCS DFE Gain and Tap 1, Tap 2, Tap 3, Tap4 Coefficients.
PG[7]RW70[0], PG[7]RW[75:71]	Enhanced CTLE Control Words
PG[70]RW6A	Q[Z:W]CK Driver Characteristics
PG[70]RW[7B:78]	Q[Z:W]CK Output Delay Control
PG[70]RW[7F:7C]	QxCS[3:2]_n Output Delay Control

Switching between the two frequency contexts is achieved by writing to control word RW05. RW05[6] = 0 selects the default Frequency Context 1 while RW05[6] = 1 selects Frequency Context 2. Changing the setting in RW05[6] by itself only affects which copy of frequency dependent registers responds to MRW writes, MRR reads and SidebandBus transactions. However, when RW05[6] is different from the value it had in the previous Exit from Clock Stop event, the new settings any updates in RW05[3:0], RW06, and the dual-context registers listed in Table 28 will not be applied internally in the RCD until after the RCD and DRAMs have entered and exited Self Refresh with Clock Stop mode. The RCD will use the value of RW05[6] at the time of Exit from Self Refresh with Clock Stop to determine which context to switch to. A context switch only occurs when the value of RW05[6] is different from the value it had in the previous Exit from Self Refresh with Clock Stop event.

5.7.1 Initial Frequency Setting

Since [RW05\[6\]](#) is a sticky control bit, that is, only cleared by power cycle, the internal current-context state maintained by the RCD must also be sticky. After DRST_n event with stable power, the internal current-context state and [RW05\[6\]](#) will retain the same values they had prior to the DRST_n event.

After Power-on Reset, the internal current-context state will match the Context-1 setting [RW05\[6\]](#) = '0'. Therefore, in this case, any updates in [RW05\[3:0\]](#), [RW06](#), and the dual-context registers listed in Table 28 will be applied immediately to internal circuits and logic without waiting for Exit from Self Refresh with Clock Stop.

5.7.2 Input Clock Frequency Change

Once the DDR5RCD05 is initialized, the DDR5RCD05 requires the clock to be stable during almost all states of normal operation. This means that, once the clock frequency has been set and is to be in a stable state, the clock period is not allowed to deviate except for what is allowed for by the clock jitter and SSC (spread spectrum clocking) specifications.

The input clock frequency can be changed from one stable clock rate to another stable clock rate only by going through Self Refresh with Clock Stop mode. The sequence must allow the Host controller to update the frequency dependent registers in the background during normal operation. The sequence of steps for an input frequency change to an RDIMM is outlined below.

1. Set [RW05\[6\]](#) to choose a frequency context different from the current one. At the same time, update the Frequency Information settings for the next operating speed in [RW05\[3:0\]](#). These updates will only be applied internally after the RCD exits from Self Refresh with Clock Stop.⁶
2. Write Fine Granularity Frequency information for the next operating speed in [RW06](#). The new setting will only be applied internally after the RCD exits from Self Refresh with Clock Stop.⁶
3. Set new values for the frequency specific registers listed in Table 28 in the background as needed during normal operation. These changes will only be applied internally after the RCD exits from Self Refresh with Clock Stop mode.
4. Go through Entry and Exit from Self Refresh with Clock Stop. The RCD will apply the new settings upon Exit from Self Refresh with Clock Stop.

With the exception of Self Refresh Entry, normal DRAM traffic and operations are supported intermingled with Steps 2 and 3 of the transition sequence defined above.

NOTE 6 Due to postponed application of [RW05/RW06](#), a t_{STAB01} waiting time is always sufficient after exit from Self Refresh with Clock Stop (i.e., t_{STAB02} is not required). See timing diagrams in Figure 40 on page 54 and Figure 41 on page 55.

6 SidebandBus Interface

For all configuration registers, the DDR5RCD05 supports register access mechanisms through a SidebandBus in addition to In-band Channel commands. The registers may be read by software from the SidebandBus Host at any time the RCD is powered on and receiving valid input clock, except in the Self Refresh with Clock Stop or when the device DRST_n pin is asserted.

The SidebandBus interface of the DDR5RCD05 device is compliant to the JEDEC Module Sideband Bus (SidebandBus) standard, JESD403-1. See JESD403-1 for details. SidebandBus is a two-wire interface based on SDA and SCL. This section describes the minimum subset of the I3C Basic Specification that must be supported to meet the requirements and usage modes of the SidebandBus in the DDR5 DIMM application space.

The DDR5RCD05 SidebandBus Interface must co-exist with other devices using the same bus on an RDIMM, including Temperature Sensor, SPD, and PMIC devices, and shall not inhibit the operation of the SidebandBus when the module V_{DD} or V_{DDQ} supply rails are disabled (but V_{DDIO} is available) or when the RCD goes through Self Refresh Entry or Exit with Clock Stop.

DRST_n does not reset the SidebandBus Interface of the DDR5RCD05 device. When it is under Clock Stop condition or when DRST_n is asserted (LOW), the DDR5RCD05 device is required to support the following operations from normal operation:

- Timeout Reset (see Clause 6.6 on page 110).
- I2C/I3C Basic Common Command Code (CCC) packets (excluding DEVCTRL with RegMod = 1).

I2C and I3C Basic Write/Read packets are not supported in Clock Stop condition or when DRST_n is asserted and they may result in undefined responses.

6.1 SidebandBus Requirements During Initialization of RCD

- DDR5RCD05 is responsible for staying off the bus when V_{DD} is not powered on but V_{DDIO} is enabled. When V_{DD} is not powered on, the RCD does not respond to any commands or events.
- The Host is responsible for keeping the SidebandBus idle (i.e., no traffic) during the time V_{DD} is ramping up (e.g., following a PMIC VR Enable command).
- DDR5RCD05 is required to respond to CCC (excepting DEVCTRL with RegMode = 1) and also to Timeout Reset when V_{DD} is valid and stable (as well as V_{DDIO}) even when DRST_n is still LOW during power-up initialization.
- The RCD is required to support register Write/Read access and DEVCTRL CCC with RegMode = 1 only after t_{STAB01} following stable DCK clock (which happens after DCS_n LOW-to-HIGH transition).

6.2 Feature Summary

- I²C Fast-mode Plus (FM+) and I3C Basic supported.
- In-band interrupt supported in I3C Basic mode.
- The DDR5RCD05 SidebandBus Interface shall not initiate clock stretching.
- Multi-controller capability not supported.
- Hot join capability not supported.

The DDR5RCD05 is required to support Read and Write Transactions without requiring clock stretching in order to simplify Host controller requirements. For similar reasons, the RCD shall not control SidebandBus transactions in normal operation.

6.3 Operating Ranges

- Speed: support 1 MHz (I²C FM+) in I²C Mode and up to 12.5 MHz in I3C Basic mode.
- Voltage: V_{DDIO} Supply from 1.0 V - 0.05 V to 1.0 V + 0.05 V for SDA/SCL I/O levels.

6.4 External Pins

The RCD Sideband Interface uses the following two external device pins.

6.4.1 Serial Clock (SCL)

This input signal is used to strobe data in and out of the device. This signal driven by the bus controller using a push-pull driver. In I²C mode only, it is also possible to use an open-drain driver in the bus controller, provided that the board has a pull-up resistor connected between SCL and V_{DDIO}, for example.

6.4.2 Serial Data (SDA)

This bi-directional signal is used to transfer data in or out of the device. It is an output capable of operating in open-drain mode or push-pull mode. A pull up resistor may be connected from Serial Data (SDA) to V_{DDIO}, for example. If the pull-up resistor is not present in the board, the bus controller must provide on-chip termination.

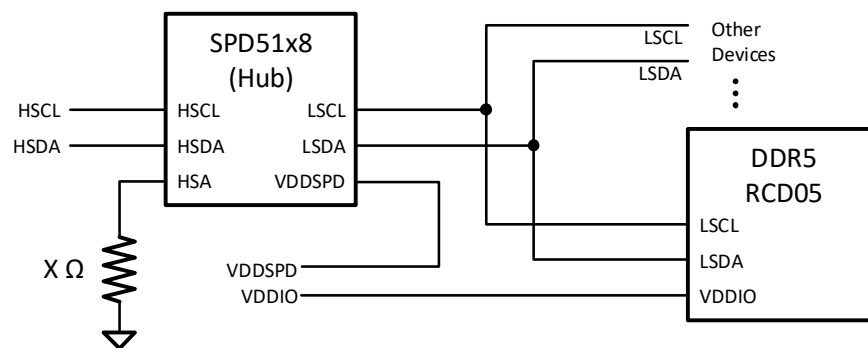


Figure 70 — SidebandBus Wiring Diagram

6.5 System Management Access

System Management software in the platform can initiate system management access to the configuration registers. This can be done through SidebandBus accesses.

DDR5RCD05 components contain a SidebandBus target port and allow access to the configuration registers.

SidebandBus operations are made up of two major steps:

1. Writing information to registers within each component.
2. Reading configuration registers from each component.

The following clauses will describe the protocol for a SidebandBus controller to access an RCD component's internal configuration registers.

6.5.1 Target Address

The 7-bit target address used for each primitive SidebandBus transaction is determined by the 4-bit Local Device address (LID) and the 3-bit Host Device address (HID). The HID bits of the RCD device have a default value of ‘111’ but the value of LID is fixed.

- DDR5RCD05 I²C Bus and I3C Basic Bus address:
 - Target Address[6:3] = 4'b1011 (LID)
 - Target Address[2:0] = HID code configured by SETHID command

6.5.2 Supported SidebandBus Commands

The DDR5RCD05 Sideband target port supports register reads and writes built out of the following Management Bus primitive commands:

- I²C Mode:
 - **Block Write** — **Byte Write**
 - **Block Read** — **Byte Read**
- I3C Basic Mode:
 - **Block Write**
 - **Block Read**

The DDR5RCD05 device is not required to support block accesses larger than a double word.

Each SidebandBus transaction has an 8-bit command driven by the controller. The format for this command is defined in Table 29, “SidebandBus Command Format in I²C Mode” and Table 30, “SidebandBus Command Format in I3C Basic Mode”.

Table 29 — SidebandBus Command Format in I²C Mode

Bit 7	Bit 6	Bit 5	Bit 4	Bits [3:2]	Bits [1:0]
Begin	End	Rsvd	PEC_en ¹	Internal Command: 00 - Read DWord 01 - Write Byte 10 - Write Word 11 - Write DWord	SidebandBus Command: 00 - Byte Mode ² 01 - Reserved 10 - Block Mode 11 - Reserved

NOTE 1 See Table 30. The PEC_en bit only applies in I²C mode. In I3C Basic mode, Bit 4 of the SidebandBus Command is ignored and PEC is controlled by PEC Enable bit received via DEVCTRL CCC (see Table 75 on page 123). In I²C mode, the value of PEC Enable bit received via DEVCTRL CCC is ignored and PEC is controlled by Bit 4 of the SidebandBus Command.

NOTE 2 See Table 30. Byte mode transactions are only supported in I²C mode. When not in I²C mode, Bits [1:0] of the SidebandBus Command are ignored and all transactions are all conducted in block mode.

Table 30 — SidebandBus Command Format in I3C Basic Mode

Bit 7	Bit 6	Bit 5	Bit 4	Bits [3:2]	Bits [1:0]
Begin	End	Rsvd	Rsvd ¹	Internal Command: 00 - Read DWord 01 - Write Byte 10 - Write Word 11 - Write DWord	Rsvd ²

NOTE 1 In I3C Basic mode, Bit 4 of the SidebandBus Command is ignored and PEC is controlled by PEC Enable bit received via DEVCTRL CCC (see Table 75 on page 123).

NOTE 2 In I3C Basic mode, Bits [1:0] of the SidebandBus Command are ignored and all transactions are all conducted in block mode.

6.5.2 Supported SidebandBus Commands (cont'd)

The *Begin* bit indicates the first transaction of a read or write sequence.

The *End* bit indicates the last transaction of a read or write sequence.

The *PEC_en* bit enables the 8-bit PEC generation and checking logic when the interface is running in I²C mode.⁷

The *Internal Command* field specifies the internal command to be issued by the SidebandBus target logic. Note that the Internal Command must remain consistent (i.e., not change) during a sequence that accesses a configuration register. Operation cannot be guaranteed if it is not consistent when the command setup sequence is done.

The *SidebandBus Command* field specifies the I²C/I3C Basic command to be issued on the bus. This field is used as an indication of the length of transfer so the target knows when to expect the PEC packet (if enabled).

Reserved bits should be written to zero to preserve future compatibility.

Hosts are required to form commands that are internally self consistent. The length indicated by the internal command should be consistent with the byte count and the DDR5RCD05 behavior will be undefined when the internal command is inconsistent with the byte count.

6.5.3 Register Access Protocols

Sequences of these basic commands will initiate internal accesses to the component's configuration registers.

Each Configuration Read or Write consists of an I²C/I3C Basic Write sequence which initializes the register's address. The term sequence is used since these variables may be written with a single Block Write (in I²C or I3C Basic modes) or multiple Byte Writes (in I²C mode). Once these parameters are initialized, the SidebandBus controller can initiate a Read sequence (which performs a Configuration Read) or a Write sequence (which performs a Configuration Write).

Table 31 — SidebandBus Protocol Addressing Fields

Address Field Name	Bits	Description
Reserved	7:0	Reserved - Device may alias all these bits to 00h
Dev	3:0	Reserved - Device may alias all these bits to 0h
Channel_Num	3:0	Channel Number 0000 = Channel A 0001 = Channel B All others Vendor Specific
Page_Num[15:8]	7:0	Page number when Reg_Num is within 60h-7Fh address range. Ignored if Reg_Num is within 00h-5Fh address range.
Reg_Num[7:0]	7:0	Register Address. Addresses within 60h-7Fh range use the page number above.

NOTE 7 To keep backwards-compatibility with the DDR4 RCD device, PEC support in I²C mode is required in the DDR5RCD05 device even though this feature is not described in the JESD403-1 standard.

6.5.3.1 Access Mechanism

For all Configuration and Status registers, the DDR5RCD05 supports register access mechanisms through the SidebandBus Interface as well as through In-band Channel commands. The registers may be read by software from the SidebandBus Host at any time the DDR5RCD05 is powered on, except in the Self Refresh with Clock Stop or when the device DRST_n pin is asserted.

Table 32 shows the mapping between DDR5RCD05 control words and I²C/I3C Basic register numbers. The entire register space of the DDR5RCD05 is accessible with the Channel_Num, Page_Num, and Reg_Num SidebandBus address fields.

Table 32 — SidebandBus Address Map

RW Type	Page_Num [15:8]	Reg_Num [7:0]	RW Page	RW
Direct Control Words	x	00	NA	RW00
	x	01	NA	RW01

	x	5Fh	NA	RW5F
Paged Control Words	00	60h	PG[00]	RW60
	00	61h	PG[00]	RW61

	00	7Fh	PG[00]	RW7F
	01	60h	PG[01]	RW60

	FFh	7Fh	PG[FF]	RW7F

Each byte of the DDR5RCD05 register space has its own unique address. For CSR Writes, the RCD registers can be accessed in Byte (8-bit), Word (16-bit) or Double Word (32-bit) quantities. For CSR Reads, the device registers can only be accessed in Double Word (32-bit) quantities.

All multi-byte numeric fields use “little-endian” ordering (i.e., lower addresses contain the least significant parts of the field). As an example Table 33 defines the byte order for double word accesses to the DDR5RCD05 control words.

In this chapter, CSRs are defined as 8-bit registers. Since a byte is the smallest access granularity for CSRs, a single 8-bit CSR contains one RCD Control Word.

Table 33 — Double Word Byte Order for SidebandBus Control Word Access

Description	Data[31:24]	Data[23:16]	Data[15:8]	Data[7:0]
RW03 RW00	RW03	RW02	RW01	RW00
RW07 - RW04	RW07	RW06	RW05	RW04
...
RW7F - RW7C	RW7F	RW7E	RW7D	RW7C

6.5.4 Sequence for Switching from I²C Mode to I3C Basic

The DDR5RCD05 device will start with the Sideband Interface enabled to support I²C protocol by default. When I²C protocol is selected in [RW25\[5\]](#) (SidebandBus Mode status bit controlled by SETAASA and RSTDAA commands), the following limitations apply.

1. Operation speed is limited to 1 MHz compatible with FM+ mode I²C.
2. In-band interrupts are not supported.
3. CCC support limited to DEVCTRL, SETHID, and SETAASA common command codes.
4. In I²C mode, Start or Repeat Start operation followed by 7'h7E with W = 0 is only allowed for the purpose of issuing CCCs that are supported in I²C mode.

In I3C Basic mode, full functionality including 12.5 MHz operation and IBIs are enabled.

The Host puts the DDR5RCD05 device in I3C Basic mode by issuing SETAASA CCC. The Host must issue DEVCTRL and SETHID Commands first (if needed) followed by SETAASA. When SETAASA CCC is registered by the device, the DDR5RCD05 updates [RW25\[5\]](#) to '1'.

The Host puts the DDR5RCD05 device in I²C mode by issuing RSTDAA CCC. When RSTDAA CCC is registered by the device, the DDR5RCD05 updates [RW25\[5\]](#) to '0'. Moreover, the RCD is allowed to disable IBI, disable PEC, and enable I3C Basic Parity Checking functions. The Host is expected to send DISEC and DEVCTRL commands to disable IBI, disable PEC, and enable Parity Checking prior to issuing the RSTDAA CCC.

6.5.5 Parity Error Checking

By default, when device is put in I3C Basic mode, parity function is automatically enabled. The Host can disable the function after it is enabled. Host can also disable the parity function with DEVCTRL CCC. When parity function is disabled, the device simply ignores the "T" bit information from the Host. The Host may actually choose to compute the parity and send that information during "T" bit or simply drive static LOW or HIGH in "T" bit.

The device implements ODD parity. If an odd number of bits in the byte are '1', the parity bit value is '0'. If even number of bits in the byte are '1', the parity bit value is '1'. The Host computes the parity for each byte except for the device select code byte and sends it during "T" bit.

6.5.6 PEC Support

DDR5RCD05 devices operate on a standard I3C Basic serial interface. Transactions where the DDR5RCD05 device is the targeted Target device begin with the I3C Basic Host issuing a START condition followed by a 7-bit DDR5RCD05 device type identifier then a Read or Write bit, RW. All I3C Basic data are transmitted with the most significant bit MSB first. During select code transmission, the DDR5RCD05 device typically replies with an ACK unless there are exceptional conditions when it may passively assert a NACK.

The optional appended PEC on the data stream covers the information transmission between the Host and the DDR5RCD05 device.

If the optional IBI header (7'h7E and W = 0) byte is present, the DDR5RCD05 device will exclude it in its PEC calculation. Other than that, the RCD target device will include all bytes, including the address byte, in its local PEC checking logic.

All DDR5RCD05 devices implement an 8-bit Packet Error Code (PEC) which is appended at the end of all I3C Basic transactions if PECs are enabled through DEVCTRL CCC. The RCD also supports PEC in I2C mode, if enabled in Bit 4 of the Bus Command. The PEC is a CRC-8 value calculated on all the message bytes excluding START, Repeat START, STOP, T-bits, ACK, NACK, and IBI header (7'h7E followed by W = 0) bits. The algorithm for all CRC-8 calculations is:

6.5.6 PEC Support (cont'd)

$$C(x) = x^8 + x^2 + x^1 + 1$$

The seed value for PEC function is all zero.

PECs are disabled by default on power up or RESET. The Host may optionally enable PEC function. If enabled, the Host must complete the burst length (or byte count) as indicated. In other words, the Host must not interrupt the burst length (or byte count) prematurely for Write or Read operation. It is considered an illegal operation.

6.5.7 Sideband Control Word Read Protocol

Configuration Reads are accomplished through an I²C/I3C Basic Write(s) and later followed by an I²C/I3C Basic Read. The Write sequence is used to initialize the Device, Channel, Page, and Register Numbers for the configuration access. The writing of this information can be accomplished through any combination of the supported I²C/I3C Basic write commands (Block command in I²C and I3C Basic modes or Byte command in I²C mode). The *Internal Command* field for each write should specify Read DWord.

All I²C/I3C Basic Configuration Reads should be DWord aligned. The DDR5RCD05 register will ignore the lowest two bits of the Register Address and return the four bytes within a DWord in the byte order shown in the following examples, i.e., Most Significant Byte (Data[31:24]) first and Least Significant Byte (Data[7:0]) last.

After all the information is set up, the last Write (*End* bit is set) initiates an Internal Configuration Read. If an error occurs during the internal access, the last Write Command will receive a NACK. A status field indicates abnormal termination and contains status information such as target abort. The status field encoding is defined in Table 34.

Table 34 — Status Field Encoding for SidebandBus Reads

Bit	Description
7	Reserved
6	Reserved
5	Reserved
4	Internal Target Abort ¹
3:1	Reserved
0	Successful

NOTE 1 A value of 1 indicates access to invalid internal register address. Access to Reserved locations of the RCD is not considered invalid.

6.5.7.1 I²C Read Packet Format Definitions

Examples of Configuration Reads are illustrated below. For I²C Bus read transactions, the last byte of data (or the PEC byte if enabled) is NACKed by the controller to indicate the end of the transaction.

6.5.7.1 I²C Read Packet Format Definitions (cont'd)

Table 35 — I²C Read Command Packet Example (Block Mode, PEC Disabled, Legacy Format)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11000010								A	
	Byte Count = 4								A	
	Reserved								A	
	Dev/Channel_Num								A	
	Page_Num [7:0]								A	
	Reg_Num [7:0]								A	
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11000010								A	
Sr	1	0	1	1	HID			R=1	A	
	Byte Count = 5								A	
	Status								A	
	Rd Data[31:24]								A	
	Rd Data[23:16]								A	
	Rd Data[15:8]								A	
	Rd Data[7:0]								N	P

The above packet format must be supported in I²C Legacy mode for backwards compatibility with older controllers.

Table 36 — I²C Read Command Packet Example (Block Mode, PEC Enabled, Legacy Format)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11010010								A	
	Byte Count = 4								A	
	Reserved								A	
	Dev/Channel_Num								A	
	Page_Num [7:0]								A	
	Reg_Num [7:0]								A	
	PEC(8)								A	

S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11010010								A	
Sr	1	0	1	1	HID			R=1	A	
	Byte Count = 5								A	
	Status								A	
	Rd Data[31:24]								A	
	Rd Data[23:16]								A	
	Rd Data[15:8]								A	
	Rd Data[7:0]								A	
	PEC(8)								N	P

The above packet format must be supported in I²C mode for backwards compatibility with older controllers. The table coloring identifies the portion of the packet covered by each PEC byte.

6.5.7.1 I²C Read Packet Format Definitions (cont'd)

Table 37 — I²C Read Command Packet Example (Block Mode, PEC Disabled, Optimized Format)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11000010								A	
	Byte Count = 4								A	
	Reserved								A	
	Dev/Channel_Num								A	
	Page_Num [7:0]								A	
	Reg_Num [7:0]								A	
Sr	1	0	1	1	HID			R=1	A	
	Byte Count = 5								A	
	Status								A	
	Rd Data[31:24]								A	
	Rd Data[23:16]								A	
	Rd Data[15:8]								A	
	Rd Data[7:0]								N	P

The optimized I²C Read packet format is only supported in Block Mode with PEC disabled. This optimized case without redundant bytes must be supported in I²C mode for better protocol efficiency.

6.5.7.1 I²C Read Packet Format Definitions (cont'd)

Table 38 — I²C Read Command Packet Example (Byte Mode, PEC Disabled, Legacy Format)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 10000000							A		
	Reserved							A	P	
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 00000000							A		
	Dev/Channel_Num							A	P	
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 00000000							A		
	Page_Num [7:0]							A	P	
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 01000000							A		
	Reg_Num [7:0]							A	P	
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 10000000							A		
Sr	1	0	1	1	HID			R=1	A	
	Status							N		
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 00000000							A		
Sr	1	0	1	1	HID			R=1	A	
	Rd Data[31:24]							N		
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 00000000							A		
Sr	1	0	1	1	HID			R=1	A	
	Rd Data[23:16]							N		
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 00000000							A		
Sr	1	0	1	1	HID			R=1	A	
	Rd Data[15:8]							N		
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 00000000							A		
Sr	1	0	1	1	HID			R=1	A	
	Rd Data[7:0]							N		

The package format shown above must be supported in I²C mode for backwards compatibility with older controllers.

6.5.7.1 I²C Read Packet Format Definitions (cont'd)

Table 39 — I²C Read Command Packet Example (Byte Mode, PEC Enabled, Legacy Format)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop								
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 10010000								A		
								Reserved								A		
								PEC(8)								A		
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 00010000								A		
								Dev/Channel_Num								A		
								PEC(8)								A		
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 00010000								A		
								Page_Num [7:0]								A		
								PEC(8)								A		
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 01010000								A		
								Reg_Num [7:0]								A		
								PEC(8)								A		
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 10010000								A		
								Sr	1		0	1	1	HID			R=1	A
																	Status	
PEC(8)										N								
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 00010000								A		
								Sr	1		0	1	1	HID			R=1	A
																	Rd Data[31:24]	
PEC(8)										N								
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 00010000								A		
								Sr	1		0	1	1	HID			R=1	A
																	Rd Data[23:16]	
PEC(8)										N								
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 00010000								A		
								Sr	1		0	1	1	HID			R=1	A
																	Rd Data[15:8]	
PEC(8)										N								
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 00010000								A		
								Sr	1		0	1	1	HID			R=1	A
																	Rd Data[7:0]	
PEC(8)										N								
S	1	0	1	1	HID			W=0	A	P								
								SidebandBus Command = 01010000								A		
								Sr	1		0	1	1	HID			R=1	A
																	Rd Data[7:0]	
PEC(8)										N								

The packet format shown above must be supported in I²C mode for backwards compatibility with older controllers. The table coloring identifies the portion of the packet covered by PEC.

The case for Optimized Packet format is not supported in Byte Mode I²C Read transactions in byte mode with optimization does not need to be supported due to the inherent inefficiency of Byte Mode.

6.5.7.2 I3C Basic Mode Read Packet Format Definitions

Prior to the Repeated START in the Read command data packet, the “T” bit carries Parity information from the Host for Address Offset bytes. See Clause 6.5.5.

After the Host sends the Repeated START, the “T” bit carries information from the device to the Host (“T” bit semantics are compliant with the I3C Basic Specification). The device sends Continue (‘1’) or Stop (‘0’) information to the Host to inform whether it is transmitting the last byte or not. The number of bytes transmitted is predetermined by the contents of the SidebandBus Command (see Table 29 on page 89).

Table 40 — I3C Basic Read Command Packet Example (PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	0	1	1	HID			W=0	A ^{1,2,3}	
	SidebandBus Command = 11000000								T	
	Byte Count = 4								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
Sr	1	0	1	1	HID			R=1	A/N ^{4,5}	
	Byte Count = 5								T=1	
	Status								T=1	
	Rd Data[31:24]								T=1	
	Rd Data[23:16]								T=1	
	Rd Data[15:8]								T=1	
	Rd Data[7:0]								T=0 ⁶	
										Sr ⁷ or P

NOTE 1 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 2 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 The DDR5RCD05 device does not check for parity error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 4 Figure 134 shows the transition from Host Push-Pull Operation to Target Open Drain (ACK).

NOTE 5 If target device NACKs during Repeat START for any reason, the Host may re-try Repeat START again. The Host may do the Repeat START as many times as it may desire. If the target device NACKs due to parity error in previous bytes from the Host, it will always NACK regardless of how many times the Host tries Repeat START. If there were no Parity errors, the RCD may eventually ACK (e.g., if delay in access of register caused the first NACK).

NOTE 6 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

NOTE 7 Repeat Start or Repeat Start with 7'h7E.

Table 41 shows the I3C Basic Read Command Packet format for the case PEC is enabled. This packet includes two PEC bytes. The first PEC byte is generated by the Host and it covers from the START bit to the first PEC Byte. The RCD checks the data it receives from the Host with respect to the first PEC byte. The second PEC byte is generated by the RCD and it covers from the Repeated START bit to the second PEC byte. The Host checks the data it receives from the RCD with respect to the second PEC byte.

6.5.7.2 I3C Basic Mode Read Packet Format Definitions (cont'd)

Table 41 — I3C Basic Read Command Packet Example (Block Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	0	1	1	HID			W=0	A ^{1,2,3}	
	SidebandBus Command = 11000000								T	
	Byte Count = 4								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
	PEC(8)								T	
Sr	1	0	1	1	HID			R=1	A/N ^{4,5}	
	Byte Count = 5								T=1	
	Status								T=1	
	Rd Data[31:24]								T=1	
	Rd Data[23:16]								T=1	
	Rd Data[15:8]								T=1	
	Rd Data[7:0]								T=1	
	PEC(8)								T=0 ⁶	Sr ⁷ or P

NOTE 1 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 2 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 The DDR5RCD05 device does not check for parity or PEC error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 4 Figure 134 shows the transition from Host Push-Pull Operation to Target Open Drain (ACK).

NOTE 5 If target device NACKs during Repeat START for any reason, the Host may re-try Repeat START again. The Host may do the Repeat START as many times as it may desire. If the target device NACKs due to parity error or PEC error in previous bytes from the Host, it will always NACK regardless of how many times the Host tries Repeat START. If there were no Parity or PEC errors, the RCD may eventually ACK (e.g., if delay in access of register caused the first NACK). The PEC calculation by the target device only includes device select code of the ACK response of the Repeat start operation.

NOTE 6 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

NOTE 7 Repeat Start or Repeat Start with 7'h7E.

The table coloring identifies the portion of the packet covered by each PEC byte. In I3C Basic mode, only the block mode optimized format without redundant bytes is supported.

In I3C Basic mode, Bits [4] and [1:0] of the SidebandBus Command are ignored (see Table 29).

The Host may optionally allow the DDR5RCD05 device to request IBI. For this case, the transactions to the DDR5RCD05 device begin with the I3C Basic Host issuing a START condition followed by 7'h7E and W = 0. If the RCD or any other connected device has a pending IBI, it transmits its 7-bit device select code followed by R = 1. If the RCD has no pending IBI, there is no action taken by the RCD. Table 42 shows the I3C Basic Read Command Packet format from Table 41 with the optional IBI header. As shown in color coding, the IBI header is not included in the calculations to generate PEC.

6.5.7.2 I3C Basic Mode Read Packet Format Definitions (cont'd)

Table 42 — I3C Basic Read Command Packet Example with IBI Header and No Pending Interrupt (Block Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S	1	1	1	1	1	1	0	W = 0	A ¹	
Sr	1	0	1	1	HID			W = 0	A ^{1,2,3}	
	SidebandBus Command = 11000000								T	
	Byte Count = 4								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
	PEC(8)								T	
Sr	1	0	1	1	HID			R=1	A/N ^{4,5}	
	Byte Count = 5								T=1	
	Status								T=1	
	Rd Data[31:24]								T=1	
	Rd Data[23:16]								T=1	
	Rd Data[15:8]								T=1	
	Rd Data[7:0]								T=1	
	PEC(8)								T=0 ⁶	Sr ⁷ or P

NOTE 1 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 3 The DDR5RCD05 device does not check for parity or PEC error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 4 Figure 134 shows the transition from Host Push-Pull Operation to Target Open Drain (ACK).

NOTE 5 If target device NACKs during Repeat START for any reason, the Host may re-try Repeat START again. The Host may do the Repeat START as many times as it may desire. If the target device NACKs due to parity error or PEC error in previous bytes from the Host, it will always NACK regardless of how many times the Host tries Repeat START. If there were no Parity or PEC errors, the RCD may eventually ACK (e.g., if delay in access of register caused the first NACK). The PEC calculation by the target device only includes device select code of the ACK response of the Repeat start operation.

NOTE 6 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

NOTE 7 Repeat Start or Repeat Start with 7'h7E.

6.5.8 Sideband Control Word Write Protocol

Configuration Writes are accomplished through a series of I²C/I3C Basic Writes. As with Configuration Reads, a Write Sequence is first used to initialize the Device, Channel, Page, and Register Numbers for the configuration access. The writing of this information can be accomplished through any combination of the supported I²C/I3C Basic write commands (Block command in I²C and I3C Basic modes or Byte command in I²C mode).

On SidebandBus, there is no concept of Byte Enables. Therefore, the Register Number written to the target is assumed to be aligned to the length of the Internal Command. In other words, for a Write Byte Internal Command, the Register Number specifies the Byte Address. For a Write DWord Internal Command, the two least-significant bits of the Register Number are ignored. This is different from PCI, where Byte Enables are used to indicate the byte of interest.

After all the information is set up, the SidebandBus Controller initiates one or more Writes which sets up the data to be written. The final Write (*End* bit is set) initiates an Internal Configuration Write. If an error occurred, the SidebandBus interface NACKs the last write operation just before the stop bit.

6.5.8.1 I²C Write Packet Format Definitions

Examples of Configuration Writes are shown below.

Table 43 — I²C Write Command Packet Example (Write DWord, Block Mode, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11001110								A	
	Byte Count = 8								A	
	Reserved								A	
	Dev/Channel_Num								A	
	Page_Num [7:0]								A	
	Reg_Num [7:0]								A	
	Wr Data[31:24]								A	
	Wr Data[23:16]								A	
	Wr Data[15:8]								A	
	Wr Data[7:0]								A	

The above packet format must be supported in I²C mode for backwards compatibility with older controllers.

Table 44 — I²C Write Command Packet Example (Write DWord, Block Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11011110								A	
	Byte Count = 8								A	
	Reserved								A	
	Dev/Channel_Num								A	
	Page_Num [7:0]								A	
	Reg_Num [7:0]								A	
	Wr Data[31:24]								A	
	Wr Data[23:16]								A	
	Wr Data[15:8]								A	
	Wr Data[7:0]								A	
	PEC(8)								A	

The above packet format must be supported in I²C mode for backwards compatibility with older controllers. The table coloring identifies the portion of the packet covered by PEC.

Table 45 — I²C Write Command Packet Example (Write Byte, Block Mode, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11000110								A	
	Byte Count = 5								A	
	Reserved								A	
	Dev/Channel_Num								A	
	Page_Num [7:0]								A	
	Reg_Num [7:0]								A	
	Wr Data[7:0]								A	

The above packet format must be supported in I²C mode for backwards compatibility with older controllers.

6.5.8.1 I²C Write Packet Format Definitions (cont'd)

Table 46 — I²C Write Command Packet Example (Write Word, Block Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop
S	1	0	1	1	HID			W=0	A	
	SidebandBus Command = 11011010								A	
	Byte Count = 6								A	
	Reserved								A	
	Dev/Channel_Num								A	
	Page_Num [7:0]								A	
	Reg_Num [7:0]								A	
	Wr Data[15:8]								A	
	Wr Data[7:0]								A	
	PEC(8)								A	

The above packet format must be supported in I²C mode for backwards compatibility with older controllers. The table coloring identifies the portion of the packet covered by PEC.

Table 47 — I²C Write Command Packet Example (Write DWord, Byte Mode, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop	
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 10001100		A
									Reserved		A
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 00001100		A
									Dev/Channel_Num		A
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 00001100		A
									Page_Num [7:0]		A
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 00001100		A
									Reg_Num [7:0]		A
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 00001100		A
									Wr Data[31:24]		A
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 00001100		A
									Wr Data[23:16]		A
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 00001100		A
									Wr Data[15:8]		A
S	1	0	1	1	HID			W=0	A		
									SidebandBus Command = 00001100		A
									Wr Data[7:0]		A

The above packet format must be supported in I²C mode for backwards compatibility with older controllers.

6.5.8.1 I²C Write Packet Format Definitions (cont'd)

Table 48 — I²C Write Command Packet Example (Write Word, Byte Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N	Stop							
S	1	0	1	1	HID			W=0	A	P							
									SidebandBus Command = 10011000								
									Reserved								
									PEC(8)								
S	1	0	1	1	HID			W=0	A	P							
									SidebandBus Command = 00011000								
									Dev/Channel_Num								
									PEC(8)								
S	1	0	1	1	HID			W=0	A	P							
									SidebandBus Command = 00011000								
									Page_Num [7:0]								
									PEC(8)								
S	1	0	1	1	HID			W=0	A	P							
									SidebandBus Command = 00011000								
									Reg_Num [7:0]								
									PEC(8)								
S	1	0	1	1	HID			W=0	A	P							
									SidebandBus Command = 00011000								
									Wr Data[15:8]								
									PEC(8)								
S	1	0	1	1	HID			W=0	A	P							
									SidebandBus Command = 01011000								
									Wr Data[7:0]								
									PEC(8)								

The above packet format must be supported in I²C mode for backwards compatibility with older controllers. The table coloring identifies the portion of the packet covered by PEC.

6.5.8.2 I³C Basic Write Packet Format Definitions

During Write command data packet, the “T” bit carries Parity information from the Host. See Clause 6.5.5.

The number of bytes transmitted is predetermined by the contents of the SidebandBus Command (see Table 29 on page 89).

6.5.8.1 I²C Write Packet Format Definitions (cont'd)

Table 49 — I3C Basic Write Command Packet Example (Write DWord, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	0	1	1	HID			W=0	A ^{1,2,3}	
	SidebandBus Command = 110011xx								T	
	Byte Count = 8								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
	Wr Data[31:24]								T	
	Wr Data[23:16]								T	
	Wr Data[15:8]								T	
	Wr Data[7:0]								T	
										Sr ⁴ or P

NOTE 1 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 2 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 The DDR5RCD05 device does not check for parity error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

In I3C Basic mode, Bits [4] and [1:0] of the SidebandBus Command are ignored (see Table 29).

Table 50 — I3C Basic Write Command Packet Example (Write DWord, Block Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	0	1	1	HID			W=0	A ^{1,2,3}	
	SidebandBus Command = 110111xx								T	
	Byte Count = 8								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
	Wr Data[31:24]								T	
	Wr Data[23:16]								T	
	Wr Data[15:8]								T	
	Wr Data[7:0]								T	
	PEC(8)								T	

NOTE 1 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 2 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 The DDR5RCD05 device does not check for parity or PEC error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

The table coloring identifies the portion of the packet covered by the PEC byte. In I3C Basic mode, Bits [4] and [1:0] of the SidebandBus Command are ignored (see Table 29).

6.5.8.1 I²C Write Packet Format Definitions (cont'd)

Table 51 — I3C Basic Write Command Packet Example (Write Byte, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	0	1	1	HID			W=0	A ^{1,2,3}	
	SidebandBus Command = 110001xx								T	
	Byte Count = 5								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
	Wr Data[7:0]								T	

NOTE 1 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 2 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 The DDR5RCD05 device does not check for parity error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

In I3C Basic mode, Bits [4] and [1:0] of the SidebandBus Command are ignored (see Table 29).

Table 52 — I3C Basic Write Command Packet Example (Write Word, Block Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	0	1	1	HID			W=0	A ^{1,2,3}	
	SidebandBus Command = 110111xx								T	
	Byte Count = 6								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
	Wr Data[31:24]								T	
	Wr Data[7:0]								T	
	PEC(8)								T	
										Sr ⁴ or P

NOTE 1 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 2 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 The DDR5RCD05 device does not check for parity or PEC error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

The table coloring identifies the portion of the packet covered by the PEC byte. In I3C Basic mode, Bits [4] and [1:0] of the SidebandBus Command are ignored (see Table 29).

The Host may optionally allow the DDR5RCD05 device to request IBI. For this case, the transactions to the DDR5RCD05 device begin with the I3C Basic Host issuing a START condition followed by 7'h7E and W = 0. If the RCD or any other connected device has a pending IBI, it transmits its 7-bit device select code followed by R = 1. If the RCD has no pending IBI, there is no action taken by the RCD. Table 53 shows the same I3C Basic Write Command Packet format from Table 52 with the optional byte to allow target devices to issue an IBI request. As shown in color coding, the IBI byte is not included in the calculations to generate PEC.

6.5.8.1 I²C Write Packet Format Definitions (cont'd)

Table 53 — I3C Basic Write Command Packet Example with IBI Header and No Pending Interrupt (Write Word, Block Mode, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S	1	1	1	1	1	1	0	W = 0	A ^{1,2}	
Sr	1	0	1	1	HID			W = 0	A ^{2,3,4}	
	SidebandBus Command = 110111xx								T	
	Byte Count = 6								T	
	Reserved								T	
	Dev/Channel_Num								T	
	Page_Num [7:0]								T	
	Reg_Num [7:0]								T	
	Wr Data[31:24]								T	
	Wr Data[7:0]								T	
	PEC(8)								T	Sr ⁵ or P

NOTE 1 Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (Repeat Start).

NOTE 2 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 Figure 134 shows the transition from Host Push-Pull Operation to Target Open Drain (ACK) and Figure 130 depicts the transition from Target Open Drain (ACK) to Host Push-Pull Operation (1st bit, SidebandBus Command).

NOTE 4 The DDR5RCD05 device does not check for parity or PEC error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 5 Repeat Start or Repeat Start with 7'h7E.

6.5.9 In-Band Interrupts

In-Band interrupts may be generated by the RCD device if IBI is enabled by receiving a broadcast or directed ENEC CCC. In I²C mode, in-band interrupt function is not supported. Only I3C Basic mode supports the in-band interrupt function.

6.5.9.1 Enabling/Disabling In-Band Event Interrupts

By default, all interrupt sources are disabled (i.e., set to '0'). The Host may enable interrupts in the DDR5RCD05 device. Once enabled, the RCD device sends an IBI when that event occurs.

- When any of the bits in [RW28\[1:0\]](#) (Parity Error or PEC Error Status Bits) get set to '1', the RCD device sets [RW28\[7\]](#) (In-band Interrupt Status) to 1 and updates Pending Interrupt Bits [3:0] = '0001' for GETSTATUS CCC.
 - If IBI is enabled by ENEC CCC, the RCD device sends the IBI at next available opportunity.
 - If IBI is disabled by DISEC CCC, the device does not send the IBI regardless of the register bit status in [RW28](#).

6.5.9.2 Mechanics of Interrupt Generation

Event interrupts may be generated by the local device if IBI is enabled by receiving a broadcast or directed ENEC CCC. When there is a pending Event In-Band Interrupt (i.e., [RW28\[7\]](#) = '1') and IBI is enabled, the DDR5RCD05 will request an interrupt after detecting a START bit by transmitting its 7-bit binary address (LID bits '1011' followed by HID bits) followed by R/W bit = '1' on the SDA bus serially (synchronized by SCL falling transitions).

If the RCD detects no START bits, but the Host has been inactive (no edges seen) for t_{AVAL} period, the RCD may assert SDA Low by $t_{\text{IBI_ISSUE}}$ time to request an interrupt. The Host will respond by toggling SCL. The RCD device transmits its 7-bit binary address (LID bits '1011' followed by HID bits) followed by R/W bit = '1'. This is shown in Figure 71.

6.5.9.2 Mechanics of Interrupt Generation (cont'd)

When the RCD requests an interrupt, the Host may take one of the two actions described below.

- **Option 1:** The Controller sends ACK on 9th bit to accept the interrupt request. At this point, if the DDR5RCD05 confirms that it has won the arbitration (i.e., the address driven in SDA matches its own Device address) the RCD transmits the IBI payload as shown in Table 54 and Table 55 for PEC disabled and PEC enabled configurations, respectively. Figure 71 depicts this case, but it only shows the first two data bits of the MDB byte (0x00) to illustrate the timing. The Host then issues a STOP command. The Controller accepts the IBI payload if it sends an ACK on the 9th bit to accept the interrupt request. The Controller can terminate the IBI payload at T bit as shown in Table 54 or Table 55. If Controller stops the IBI payload after a T bit in the middle of the payload, the RCD will retain the IBI flag internally and will wait for the next opportunity to request an interrupt. If the DDR5RCD05 device successfully transmits the entire IBI payload, it then clears IBI status flag and Pending Interrupt Bits [3:0] = '0000' on its own and does not request for an IBI again unless there is another different event occurs; for another same event, the device does not request for an IBI.
- **Option 2:** The Controller sends NACK on the 9th bit as shown in Figure 72 followed by a STOP command. In this case, DDR5RCD05 does not transmit the IBI payload and waits for the next opportunity to request an interrupt. At this point, even though the Controller sent a NACK, it does have knowledge of which device sent the IBI request.

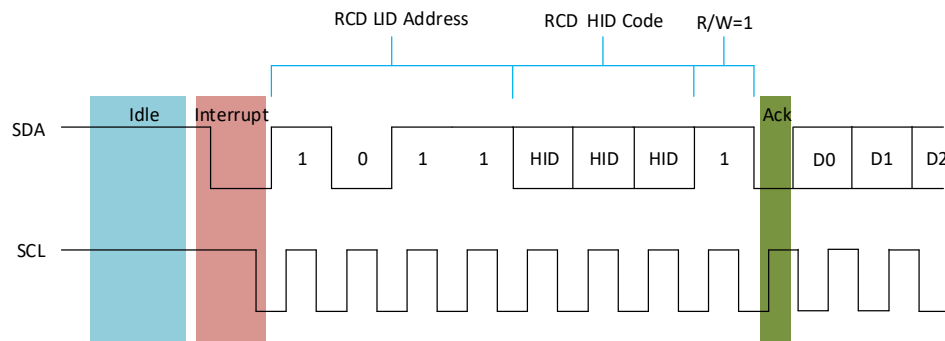


Figure 71 — RCD Interrupt Request - Controller ACK followed by RCD IBI Payload

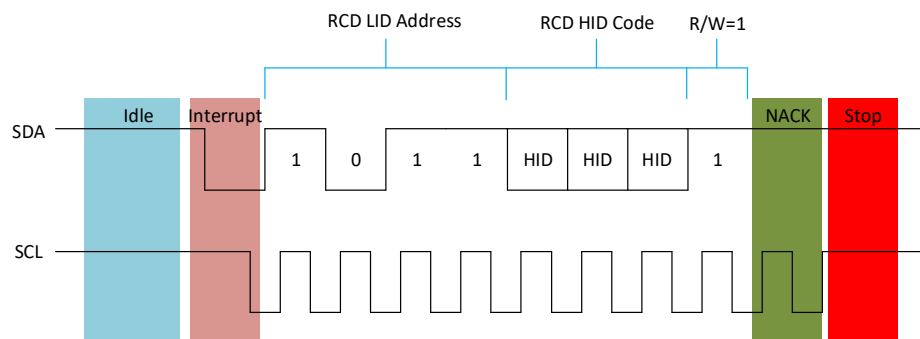


Figure 72 — RCD Interrupt Request - Controller NACK followed by STOP

6.5.9.2 Mechanics of Interrupt Generation (cont'd)

Table 54 — Interrupt Response (PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S	Device Select Code (7)							RW(1)	Host ACK ¹	
	MDB = 0x00								T = 1	
	RW28[7:0] (last error code byte) (8)								T = 0 ²	
										P

NOTE 1 Figure 131 illustrates the transition from Controller Open Drain (ACK) to Target Push Pull Operation (1st bit of MDB Byte).

NOTE 2 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

Table 55 — Interrupt Response (PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S	Device Select Code (7)							RW(1)	Host ACK ¹	
	MDB = 0x00								T = 1	
	RW28[7:0] (last error code byte) (8)								T = 1	
	PEC(8)								T = 0 ²	P

NOTE 1 Figure 131 illustrates the transition from Controller Open Drain (ACK) to Target Push Pull Operation (1st bit of MDB Byte).

NOTE 2 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

6.5.9.3 Interrupt Arbitration

As there are multiple devices in the I3C Basic bus, more than one device may request an interrupt when the Host I3C Basic bus is inactive for t_{AVAL} period. This makes an arbitration process necessary.

There could be up to 13 different devices, including the RCD, in the I3C Basic bus of a DDR5 DIMM application environment.

On a typical DDR5 DIMM application environment, all devices behind the SPD5 Hub device have the same 3-bit HID code. Hence, the arbitration is always won by the lowest 4-bit LID code. For example, if one local target device has LID code of '0010' and other device (RCD) has a LID code of '1011', through the arbitration process, the LID code of '0010' wins. If a higher priority device than the RCD device is serviced, the RCD must release the bus and wait for the next opportunity to request an interrupt.

It is possible for the controller to start a command transaction at the same time as the RCD requests an interrupt. When this happens, the controller participates in the arbitration process along with the other devices in the bus. During the arbitration phase, there will always be only one winning device and it could be one of the target devices (e.g., RCD) or the controller. If the controller wins during the arbitration phase, it continues with normal operation. The losing devices (e.g., RCD) must wait for next opportunity to send an interrupt. If the controller loses the arbitration, it must let go of the bus. When the controller loses during the arbitration, it must allow the winning device (e.g., RCD) to finish sending its 4-bit LID code followed by the 3-bit HID code followed by R/W = '1'. At this point, during the 9th bit, the controller has the following two options:

- Option 1. The controller sends ACK to accept the interrupt and hence accepts the IBI payload from the winning device (e.g., RCD). After the IBI payload, the controller issues a STOP operation.
- Option 2. Host sends NACK followed by STOP operation.

In the cases when the controller is starting a command transaction to an RCD that is requesting an interrupt at the same time, neither the controller nor the RCD know if they are a winner until the 8th bit, and controller always wins. This is because the RCD sends R/W=1 (8th bit) during the interrupt. The controller sets R/W=0 (8th bit) during the operation. As a result, the controller wins and the RCD must let go of the bus and wait for the next opportunity to send an interrupt.

6.5.9.4 Clearing Status Registers

The DDR5RCD05 device provides the device status in Table 123, “RW28: I2C and I3C Basic Error Status Global Word”. When the RCD device generates an IBI condition in RW28[1:0], it sets RW28[7] to ‘1’. The RCD clears RW28[7] to ‘0’ automatically when it sends a complete IBI (including payload and without interruption) the operation gets an ACK from the Host. The status information in Table 123 RW28[1:0] are latched and remains valid even after target device sends payload or if the condition that triggered to generate the status is no longer present. The Host must explicitly clear the status register through Clear command by writing ‘1’ to register bits in Table 124, “RW29: I2C and I3C Basic Clear Error Status Global Word”, respectively. After the Host Clear command, if the condition is still present, the device will again set the status information in Table 123, “RW28: I2C and I3C Basic Error Status Global Word” registers appropriately and will again generate interrupt at next available opportunity. When RW28[1:0] are cleared to ‘00’ as a result of a Clear command in RW29, the IBI Status Register RW28[7] will also get cleared to ‘0’ by the RCD hardware. IBI will get disabled when the RCD receives DISEC CCC. IBI may also get disabled when the RCD receives RSTDAA CCC since the Host is expected to disable Error Interrupts by issuing DISEC CCC prior to sending the RSTDAA CCC.

6.5.10 I/O Operation

The DDR5RCD05 device supports configurable IO operation scheme of either Open Drain or Push-Pull on its Host interface (SCL and SDA).

At power on, by default, DDR5RCD05 comes up in I²C mode of operation with Open Drain I/O for SidebandBus interface. The device shall operate in this mode until put into I3C Basic mode via SETAASA CCC.

After power on, the Host may put the SidebandBus interface of the RCD device in I3C Basic mode of operation by issuing a SETAASA command.

In I3C Basic mode, the Host may drive the SCL clock input of the RCD device using either Push-Pull output driver or using open-drain output driver.

To support in band interrupt, the RCD device supports dynamic switching between Open Drain mode and Push Pull mode on its SDA I/O for various events. Table 56 describes the different mode of operation by the RCD device for each cycle in I3C Basic mode.

Table 56 — RCD Device Dynamic I/O Operation Mode Switching; I3C Basic Mode

Operation	Open Drain Mode	Push-Pull Mode
START + Device Select Codes	Yes	No
START + 7'h7E IBI Header Byte	Yes	No
REPEAT START + Device Select Codes	No	Yes
REPEAT START + 7h'7E Header Byte	No	Yes
CCC Byte (i.e., after 7'h7E + W = 0 + ACK)	No	Yes
STOP	No	Yes
ACK/NACK Responses	Yes	No
Command, Address Operation	No	Yes
Interrupt Request by Target	Yes	No
IBI Payload	No	Yes
Write Data, T-Bit Sequence	No	Yes
Read Data, T-Bit Sequence	No	Yes
PEC, T-Bit Sequence	No	Yes

6.6 I²C and I3C Basic Reset

To prevent a malfunctioning device from locking up the I3C Basic bus, a bus protocol reset mechanism is defined. It uses a timeout mechanism on SCL as shown in Figure 73. All devices (including SPD5 Hub and all target devices behind the hub) on an I²C or I3C Basic bus are RESET simultaneously. Bus reset operation works same way regardless of whether device is operating in I2C or I3C Basic mode.

To guarantee the device resets I²C bus or I3C Basic bus, the SCL clock input LOW time has to be greater than or equal to $t_{\text{TIMEOUT(Max)}}$.

The device does not reset I²C bus or I3C Basic bus if the SCL clock input LOW time is less than $t_{\text{TIMEOUT(Min)}}$.

If the SCL clock input LOW time is between $t_{\text{TIMEOUT(Min)}}$ and $t_{\text{TIMEOUT(Max)}}$, the device does not guarantee and it may or may not reset the I2C bus or I3C Basic bus.

When a SidebandBus Reset is detected, DDR5RCD05 devices:

1. Interface and any pending command or transaction cleared.
2. All internal register values are preserved unless noted otherwise in Item 3 below.
3. Device mode returns to power-on default conditions as follows: I3C Basic error interrupt disabled, I²C mode enabled (RW25[5] cleared to '0'), I3C Basic parity checking enabled, I3C Basic PEC checking disabled, Parity and PEC Error Status bits (RW28[1:0]) cleared '00', and Device HID code set to '111'.
4. Device floats the SDA pin such that it gets pulled High by the external pull-up.
5. Device treats Bus Reset as STOP operation.

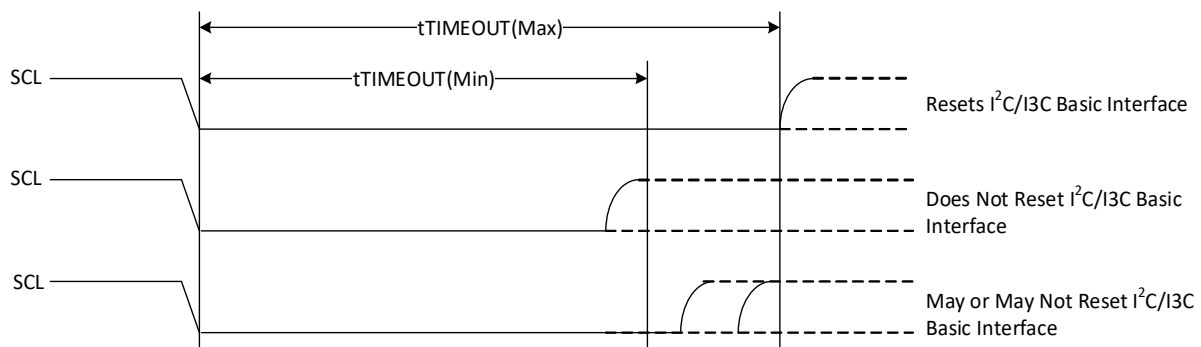


Figure 73 — I²C or I3C Basic Reset

6.6.1 Sideband Interface and DRST_n RCD Reset Events

To maintain consistent configuration state with other devices in the DDR5 module, configuration settings and status registers pertaining to the Sideband Interface in the DDR5RCD05 device will not be affected by DRST_n Reset events. In particular:

1. I²C or I3C Basic protocol selected before DRST_n event will continue in operation after DRST_n Reset event. RW25[5] shall be sticky.
2. I3C Basic error interrupt remains unchanged. IBI remains enabled or disabled after DRST_n Reset event.
3. I3C Basic parity checking and I3C Basic PEC checking remain unchanged after DRST_n Reset event.
4. Parity and PEC Error Status information retained after DRST_n Reset event. RW28 shall be sticky.

6.6.1 Sideband Interface and DRST_n RCD Reset Events (cont'd)

5. Device HID code configured before DRST_n event will remain unchanged after DRST_n Reset event.
6. When DRST_n is asserted, the DDR5RCD05 device is required to detect Timeout Reset and to execute I2C/I3C Basic Common Command Code (CCC) packets (excluding DEVCTRL with RegMod = 1).

6.7 I²C Bus Clear

The DDR5RCD05 device supports the following described Bus Clear feature in I²C mode only. Any attempt by Host to perform I²C Bus clear on a target device in I3C mode may result in an active drive bus contention on the SDA data line.

There may be abnormal circumstances when the Host abruptly stops clocking SCL while the target device is in the middle of outputting data for read operation. For these types of events, the SDA data line may appear as stuck LOW as the device is expecting to receive more clock pulses from the Host. Eventually when the Host has control of the SCL clock, the Host may optionally clear the device that is stuck LOW on the SDA data line by sending continuous 18 clock pulses without driving the SDA data line followed by STOP operation. The device floats the SDA line within 18 clock pulses and returns to the Idle state. The device is ready for normal new transaction with Start condition.

6.8 I²C Bus Error Handling

The I²C Bus target interface handles two types of errors: internal and PEC. These errors manifest as a Not-Acknowledge (NACK) for the read command (End bit is set). If an internal error occurs during a configuration write, the final write command receives a NACK just before the stop bit. If the controller receives a NACK, the entire configuration transaction should be reattempted.

If the controller supports packet error checking (PEC) and the PEC_en bit in the command is set, then the PEC byte is checked in the target interface. If the check indicates a failure, then the target will NACK the PEC packet.

6.9 Error Handling in I3C Basic

There are two types of error checking done by the DDR5RCD05 device. I3C Basic Parity error checking and Packet Error checking. By default, the parity error checking is always enabled (in I3C Basic mode) and packet error checking is disabled. The Host may enable the packet error checking at any time. The parity error is calculated for each byte. The packet error is computed for the entire packet. The Host sends parity error information in "T" bit.

I3C Basic defines TE0, TE1, TE2, TE3, TE4, TE5, TE6 and CE0, CE1, CE2 errors. Only TE1 and TE2 errors are supported by the DDR5RCD05 device. All other errors are not supported and not applicable. The DDR5RCD05 device will NACK unsupported CCCs.

6.9.1 Write Command Data Packet Error Handling - PEC Is Disabled

When I3C Basic mode is enabled, the DDR5RCD05 device checks for the parity error for each byte that it receives from the Host in the Write Command Data Packet as shown in Table 49 through Table 51. The following description applies to I3C Basic mode only.

If no parity error detected in Write command:

- The DDR5RCD05 device executes the command.

If parity error in Write command:

- The DDR5RCD05 device discards the byte that had parity error.

6.9.1 Write Command Data Packet Error Handling - PEC Is Disabled (cont'd)

- The DDR5RCD05 device discards all subsequent bytes in that packet until STOP operation. The DDR5RCD05 device may or may not check the parity for all subsequent bytes in that packet.
- Note that if the Host write command was for two-byte write operation and if the parity error occurred in second byte of data, the RCD may or may not execute the first byte write operation but the second byte write operation is discarded.
- The DDR5RCD05 device sets registers [RW28\[0\]](#) and [RW28\[7\]](#) to '1'; sets P_Err to '1' and Pending Interrupt Bits [3:0] to '0001' in GETSTATUS CCC response; and waits for the next opportunity to send in band interrupt (if IBI is enabled by ENEC CCC).

6.9.2 Read Command Data Packet Error Handling - PEC Is Disabled

For Read Command Data Packet as shown in Table 40, the device checks for the parity error for each byte in a packet except for the device select code byte that it receives from the Host.

The DDR5RCD05 device does not compute the parity when it sends the data to the Host. The Host does not check for parity error for the data bytes sent by the RCD. The device sends Continue ('1') or Stop ('0') information during T bit when device is sending the read data.

If no parity error detected in Read command:

- The DDR5RCD05 sends ACK back to the Host when Host perform Repeat START operation.
- The DDR5RCD05 device executes the command and sends the data back to the Host as shown in Table 40.

If parity error in Read command:

- The DDR5RCD05 device discards the byte that had parity error.
- The DDR5RCD05 device discards all subsequent bytes in that packet until STOP operation. The DDR5RCD05 device may or may not check the parity for all subsequent bytes in that packet.
- The DDR5RCD05 sends NACK back to the Host when the Host applies a Repeat START. This is shown in the **RED colored** cell in Table 40. The NACK represents either a parity error in one of the six bytes or that DDR5RCD05 is not able to start the read operation. The Host may re-try Repeat START again. The Host may do the Repeat START as many times as it may desire. If the RCD NACKs due to parity error in previous bytes from the Host, it will always NACK regardless of how many times Host tries Repeat START.
- The DDR5RCD05 does not send Read data back to the Host.
- The DDR5RCD05 device sets registers [RW28\[0\]](#) and [RW28\[7\]](#) to '1'; sets P_Err to '1' and Pending Interrupt Bits [3:0] to '0001' in GETSTATUS CCC response; and waits for the next opportunity to send in band interrupt (if IBI is enabled by ENEC CCC).

6.9.3 Write Command Data Packet Error Handling - PEC Is Enabled

When I3C Basic mode is enabled, the DDR5RCD05 device checks for the parity error for each byte and each packet that it receives from the Host in the Write Command Data Packet as shown in Table 52. The following description applies to I3C Basic mode only.

If no parity error in Write command:

- The DDR5RCD05 device waits for the entire packet. If no error in packet, the DDR5RCD05 device executes the command. If there is an error in the packet, the DDR5RCD05 device discards the entire packet and does not execute that packet and waits for STOP, sets registers [RW28\[1\]](#) and [RW28\[7\]](#) to '1'; sets PEC_Err to '1' and Pending Interrupt Bits [3:0] to '0001' in GETSTATUS CCC response; and waits for the next opportunity to send in band interrupt (if IBI is enabled by ENEC CCC).

6.9.3 Write Command Data Packet Error Handling - PEC Is Enabled (cont'd)

If parity error in Write command:

- The DDR5RCD05 device discards that byte and the entire packet until STOP operation.
- The DDR5RCD05 device sets registers [RW28\[0\]](#) and [RW28\[7\]](#) to '1'; sets P_Err to '1' and Pending Interrupt Bits [3:0] to '0001' in GETSTATUS CCC response; and waits for the next opportunity to send in band interrupt (if IBI is enabled by ENEC CCC).
- The DDR5RCD05 may or may not check the error for the packet. If the device checks for the packet error, it will likely detect an error in the packet and the device may also set the [RW28\[1\]](#) register and PEC_Err in GETSTATUS CCC response to '1' as well.

6.9.4 Read Command Data Packet Error Handling - PEC Is Enabled

For Read Command Data Packet as shown in Table 41, the DDR5RCD05 device checks for the parity error for each byte in a packet except for the device select code byte that it receives from the Host (prior to Repeat Start).

The RCD does not compute the parity when it sends the data to the Host. The Host does not check for parity error for the bytes shown in Table 41. The device sends Continue ('1') or Stop ('0') information during "T" bit when the device is sending the Read data.

The RCD device checks for the PEC error for in a packet that it receives from the Host from START condition to Repeat START condition (From first Device Select code followed by the Address Offset).

The device computes the packet error code for the entire packet starting with Repeat START (Device Select code and the data that device transmits back to the Host).

If no parity error and no PEC error in Read command:

- The DDR5RCD05 device sends ACK back to the Host in response to Repeat START event.
- The DDR5RCD05 device executes the command and sends the Read data back to the Host as shown in Table 41.
- The RCD computes PEC from Repeat START condition until STOP condition (Device Select code followed by the Data) the bytes shown in Table 41.

If parity error or PEC error in Read command:

- The DDR5RCD05 device discards the byte that had a parity error.
- The DDR5RCD05 device discards second byte in that packet if a parity error occurred in first byte. The DDR5RCD05 device may or may not check parity for the second byte in that packet.
- The DDR5RCD05 device sends NACK back to the Host in response to Repeat START event. This is shown in the **RED colored** cell in Table 41. The NACK represents either parity error in one of the seven bytes or that DDR5RCD05 is not able to start the read operation. The Host may re-try Repeat START again. The Host may do the Repeat START as many times as it may desire. If the RCD NACKs due to parity error or PEC error in previous bytes from the Host, it will always NACK regardless of how many times Host tries Repeat START.
- The device does not send Read data back to the Host and instead expects the Host to perform STOP operation.
- The DDR5RCD05 device sets [RW28\[0\]](#) register and P_Err bit in GETSTATUS CCC response to '1' for parity error and [RW28\[1\]](#) register and PEC_Err bit in GETSTATUS CCC response to '1' for PEC error. Further, the RCD sets [RW28\[7\]](#) register to '1' and Pending Interrupt Bits [3:0] to '0001' in GETSTATUS CCC response and waits for the next opportunity to send in band interrupt (if IBI is enabled by ENEC CCC).

6.9.5 CCC Packet Error Handling

Parity error and PEC error detected in a CCC packet are handled the same way as described for normal Read/Write operations.

6.10 Supported I3C Basic Common Command Codes (CCCs)

Table 57 lists all the I3C Basic Common Command Codes that must be supported by the DDR5RCD05 device. The RCD will NACK unsupported CCCs.

The DDR5RCD05 device requires STOP operation in between when switching from CCC operation to private device specific Write or Read operation and vice versa. In other words, any CCC operation must be followed by STOP operation before continuing to any device specific Write or Read. Similarly, any device specific Write or Read operation must be followed by STOP operation before continuing to any CCC operation. The DDR5RCD05 device also requires STOP operation from any Direct CCC to Broadcast CCC.

The DDR5RCD05 device does allow Repeat Start operation between any Direct CCC to any other Direct CCC or between any Broadcast CCC to any other Broadcast CCC or between any private Write or Read operation to any other private Write or Read operation.

Table 57 — Supported I3C Basic Common Command Codes (CCCs)

Command	Mode	Code	Description	Note
ENEC	Broadcast	0x00	Enable Events Command	
	Direct	0x80		
DISEC	Broadcast	0x01	Disable Events Command	
	Direct	0x81		
RSTDAA	Broadcast	0x06	Put the Device in I ² C Mode (a.k.a. Reset Dynamic Address Assignment Command)	1
SETAASA	Broadcast	0x29	Put the Device in I3C Basic Mode (a.k.a. Set All Addresses to Static Address Command)	
GETSTATUS	Direct	0x90	Get Device Status Command	
DEVCAP	Direct	0xE0	Get Device Capability Command	2
SETHID	Broadcast	0x61	Update HID Code	2
DEVCTRL	Broadcast	0x62	Configure SPD Hub and All Devices Behind Hub	2
NOTE 1 It is illegal for the Host to send Direct RSTDAA CCC Code 0x86.				
NOTE 2 JEDEC specific CCC.				

6.10.1 Enable/Disable Events Command (ENEC/DISEC) Operation

Refer to the I3C Basic Version 1.0 Specification document for details on the encoding and usage of the ENEC/DISEC Command. This command is only supported by the RCD when it is operating in I3C Basic mode. In I²C mode, it is illegal for Host to issue this CCC. If Host issues this CCC while the RCD is in I²C mode, the response is undefined.

The only event types support by the DDR5RCD05 for ENEC/DISEC Command are **Target Interrupt Requests**. All other event types are not supported and ignored.

When ENEC/DISEC Command is received, it takes effect at the next START operation (i.e., after STOP condition). If PEC function is enabled, the PEC calculation starts with Start or Repeat Start operation but does not include 7'h7E with W=0 byte in PEC calculation.

6.10.1 Enable/Disable Events Command (ENEC/DISEC) Operation (cont'd)

Table 58 — ENEC/DISEC CCC (I3C Basic, Broadcast, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0x00 (Broadcast ENEC) or 0x01 (Broadcast DISEC)								T	
	0	0	0	0	0 ²	0	0 ²	ENINT/ DISINT	T	Sr ³ or P

NOTE 1 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 DDR5RCD05 ignores HJ (Hot Join) and CR (Control Request) bits.

NOTE 3 Repeat Start or Repeat Start with 7'h7E.

Table 59 — ENEC/DISEC CCC (I3C Basic, Broadcast, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0x00 (Broadcast ENEC) or 0x01 (Broadcast DISEC)								T	
	0	0	0	0	0 ²	0	0 ²	ENINT/ DISINT	T	
	PEC(8)								T	Sr ³ or P

NOTE 1 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 DDR5RCD05 ignores HJ (Hot Join) and CR (Control Request) bits.

NOTE 3 Repeat Start or Repeat Start with 7'h7E.

Table 60 — ENEC/DISEC CCC (I3C Basic, Direct, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0x80 (Direct ENEC) or 0x81 (Direct DISEC)								T	
Sr	1	0	1	1	HID			W = 0	A ^{1,2}	
	0	0	0	0	0 ³	0	0 ³	ENINT/ DISINT	T	Sr ⁴ or P

NOTE 1 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 The DDR5RCD05 device does not check for parity error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 3 DDR5RCD05 ignores HJ (Hot Join) and CR (Control Request) bits.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

Table 61 — ENEC/DISEC CCC (I3C Basic, Direct, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0x80 (Direct ENEC) or 0x81 (Direct DISEC)								T	
	PEC(8)								T	
Sr	1	0	1	1	HID			W = 0	A ^{1,2}	
	0	0	0	0	0 ³	0	0 ³	ENINT/ DISINT	T	
	PEC(8)								T	Sr ⁴ or P

NOTE 1 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 The DDR5RCD05 device does not check for parity or PEC error in subsequent bytes when it determines the 7-bit device select code issued by the Host does not match with its own device code. The RCD device ignores the entire packet until STOP or next Repeat Start operation.

NOTE 3 DDR5RCD05 ignores HJ (Hot Join) and CR (Control Request) bits.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S	1	1	1	1	1	1	0	W = 0	A	
	0x29 (Broadcast SETAASA)								T	P

6.10.4 Get Device Status Command (GETSTATUS) Operation

Refer to the I3C Basic Version 1.0 Specification document for details on the encoding and usage of the GETSTATUS Command. This command is only supported by the RCD when it is operating in I3C Basic mode. In I²C mode, this CCC is ignored (i.e., the GETSTATUS command is not executed internally and GETSTATUS Direct CCC are not acknowledged and Host must do STOP operation).

Table 65 shows the format of the MSb and LSb sent by the DDR5RCD05 device in response to a GETSTATUS command. When the DDR5RCD05 device completes a GETSTATUS CCC operation, it does not modify any of the status bits in Table 123, “RW28: I2C and I3C Basic Error Status Global Word”.

If PEC function is enabled, the PEC calculation starts with Start or Repeat Start operation but does not include 7'h7E with W=0 byte in PEC calculation.

Table 65 — GETSTATUS MSb-LSb Format

Bits	Field	Description
15	PEC Error	DDR5RCD05 returns the value of RW28[1]. This bit is cleared when Host issues Clear Command to RW29[1]. 0 = No Error 1 = PEC Error Occurred
14:8	Vendor Reserved	Hard coded to all-zeros in DDR5RCD05.
7:6	Activity Mode	Hard coded to all-zeros in DDR5RCD05.
5	Protocol Error	DDR5RCD05 returns the value of RW28[0]. This bit is cleared when Host issues Clear Command to RW29[0]. 0 = No Error 1 = Protocol Error; Parity Error Occurred
4	Reserved	Hard coded to zero in DDR5RCD05.
3:0	Pending Interrupt	DDR5RCD05 returns the value of RW28[7] in Bit 0. Bit 0 is cleared when Host issues a Clear Command that causes the IBI Status register RW28[7] to get cleared. 0000 = No Pending Interrupt 0001 = Pending Interrupt All other encodings are reserved

Table 66 — GETSTATUS CCC (I3C Basic, Direct, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0x90 (Direct GETSTATUS)								T	
Sr	1	0	1	1	HID			R = 1	A ¹	
	PEC_Err	0	0	0	0	0	0	0	T = 1	
	0	0	Prot_Err	0	Pending Interrupt				T = 0 ²	Sr ³ or P

NOTE 1 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

NOTE 3 Repeat Start or Repeat Start with 7'h7E.

6.10.4 Get Device Status Command (GETSTATUS) Operation (cont'd)

Table 67 — GETSTATUS CCC (I3C Basic, Direct, PEC Enabled)¹

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ²	
	0x90 (Direct GETSTATUS)								T	
	PEC(8)								T	
Sr	1	0	1	1	HID			R = 1	A ²	
	PEC_Err	0	0	0	0	0	0	0	T = 1	
	0	0	Prot_Err	0	Pending Interrupt				T = 1	
	PEC(8)								T = 0 ³	

NOTE 1 GETSTATUS CCC with PEC check is only supported in I3C Basic mode.

NOTE 2 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

When the device responds to GETSTATUS CCC, after it completes the response, the PEC_Err, Prot_Err, and Pending Interrupt Bits [3:0] do not automatically get cleared. The Host must explicitly clear the appropriate status register through Clear command by writing '1' to corresponding register or by issuing Global Clear command. Once the DDR5RCD05 device clears the appropriate status register, only then PEC_Err, Prot_Err, and Pending Interrupt Bits [3:0] get cleared.

After the Host issues a Clear command, if the condition is still present, the device will again set the appropriate status register, sets the IBI status register to '1' and Pending Interrupt Bits [3:0] to '0001'.

6.10.5 Get Device Capability Command (DEVCAP) Operation

Refer to JESD403-1 for details on the encoding and usage of the DEVCAP Command. This command is only supported by the RCD when it is operating in I3C Basic mode. In I²C mode, it is illegal for Host to issue this CCC. If Host issues this CCC while the RCD is in I²C mode, the response is undefined.

If PEC function is enabled, the PEC calculation starts with Start or Repeat Start operation but does not include 7'h7E with W=0 byte in PEC calculation.

Table 68 and Table 69 show the format of the DEVCAP CCC Packet.

Table 68 — DEVCAP CCC (I3C Basic, Direct, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0xE0 (Direct DEVCAP)								T	
Sr	1	0	1	1	HID			R = 1	A ¹	
	MSB (each bit defines capability); 1 = support; 0 = no support								T = 1	
	LSB (each bit defines capability); 1 = support; 0 = no support								T = 0 ²	

NOTE 1 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

NOTE 3 Repeat Start or Repeat Start with 7'h7E.

6.10.5 Get Device Capability Command (DEVCAP) Operation (cont'd)

Table 69 — DEVCAP CCC (I3C Basic, Direct, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0xE0 (Direct DEVCAP)								T	
	PEC(8)								T	
Sr	1	0	1	1	HID			R = 1	A ¹	Sr ³ or P
	MSB (each bit defines capability); 1 = support; 0 = no support								T = 1	
	LSB (each bit defines capability); 1 = support; 0 = no support								T = 1	
	PEC(8)								T = 0 ²	

NOTE 1 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 Figure 132 shows how the RCD ends the operation followed by the Controller STOP bit.

NOTE 3 Repeat Start or Repeat Start with 7'h7E.

Table 70 shows the format of the MSb and LSb sent by the DDR5RCD05 device in response to a DEVCAP command.

Table 70 — DEVCAP MSb-LSb Format

Bits	Field	Description
MSB[7]	Reserved	Hard coded to zero in DDR5RCD05.
MSB[6]	Reserved	Hard coded to zero in DDR5RCD05.
MSB[5]	Reserved	Hard coded to zero in DDR5RCD05.
MSB[4]	Reserved	Hard coded to zero in DDR5RCD05.
MSB[3]	Reserved	Hard coded to zero in DDR5RCD05.
MSB[2]	Timer Based Reset	Hard coded to one (yes support) in DDR5RCD05.
MSB[1:0]	Reserved	Hard coded to zero in DDR5RCD05.
LSB[7:0]	Reserved	Hard coded to zero in DDR5RCD05.

6.10.6 Set HID Command (SETHID) Operation

Refer to JESD403-1 for details on the encoding and usage of the SETHID Command. This command is supported by the RCD only when it is operating in I²C mode. In I²C mode, when Host issues this CCC, to guarantee that this CCC is registered by the device without any error and to avoid subsequent undesired effects, the Host shall limit the maximum speed of operation for this CCC to 1 MHz. In I3C Basic mode, it is illegal for Host to issue this CCC. If Host issues this CCC while the RCD is in I3C Basic mode, the response is undefined.

Upon receiving SETHID Command, the DDR5RCD05 device will update the HID code with the HID[2:0] bits it received in the SETHID command packet, and it takes effect at the next START operation (i.e., after STOP condition).

As the device is in I2C mode when SETHID CCC is issued, SETHID CCC does not support PEC function.

Table 71 — SETHID CCC (I²C, Broadcast)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S	1	1	1	1	1	1	0	W = 0	A	
	0x61 (Broadcast SETHID)								T	
	0	0	0	0	HID[2:0]			0	T	P

6.10.7 Configure SPD Hub and All Devices Behind Hub Command (DEVCTRL) Operation

Refer to JESD403-1 for details on the encoding and usage of the DEVCTRL Command. This command is supported by the DDR5RCD05 device in both I²C and in I3C Basic modes. In I²C mode, when Host issues this CCC, to guarantee that this CCC is registered by the device without any error and to avoid subsequent undesired effects, the Host shall limit the maximum speed of operation for this CCC to 1 MHz.

On a typical I²C or I3C Basic bus there can be up to 120 devices. For certain operation such as selecting the I3C Basic mode of operation or to enable or disable functions that are common to all devices such as Packet Error Check, the Host must go through one device at a time which takes significant amount of time at initial power up. Further, it requires additional complexity on the Host because it must speak different protocol depending on how it may access the device until all devices are configured identically.

To help expedite this configuration operation and to simplify the Host complexity, the device supports the DEVCTRL CCC. The DEVCTRL CCC is supported either in I²C mode or I3C Basic mode of operation. In I²C mode, when Host issues this CCC, to guarantee that this CCC is registered by the device without any error and to avoid subsequent undesired implication, the Host shall limit the maximum speed of operation for this CCC to 1 MHz. Table 72 to Table 73 show examples of DEVCTRL CCC command packets.

If PEC function is enabled, the PEC calculation starts with Start or Repeat Start operation but does not include 7'h7E with W = 0 byte in PEC calculation.

The Host must pay attention to DEVCTRL CCC. If DEVCTRL CCC is used to access device specific registers (i.e., RegMod = '1'), the Host must still follow any device specific register restriction. For instance, if any device specific register requires STOP operation for device to take in the effect of the setting, the Host must also use STOP operation when using DEVCTRL CCC to access device specific register.

Table 72 — DEVCTRL Command Operation (I²C or I3C Basic, Broadcast, PEC Disabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A ¹	
	0	1	1	0	0	0	1	0	T	
	AddrMask[2:0]			StartOffset[1:0]		0	0	RegMod	T	
	DevID[6:0]							0	T ²	
	Byte 0 Data Payload								T	
	Byte 1 Data Payload								T	
	Byte 2 Data Payload								T	
	Byte 3 Data Payload								T	

NOTE 1 The DDR5RCD05 NACKs if there was a parity error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 2 As an exception, the DDR5RCD05 device will check parity in this byte even when the 7-bit Device ID code issued by the Host does not match with its own device code. If the Device ID code is unmatched, the RCD will not check for Parity errors in subsequent bytes and it will ignore the entire packet until STOP or Repeat START operation.

NOTE 3 Repeat Start or Repeat Start with 7'h7E.

6.10.7 Configure SPD Hub and All Devices Behind Hub Command (DEVCTRL) Operation (cont'd)

Table 73 — DEVCTRL Command Operation (I3C Basic. Broadcast, PEC Enabled)¹

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop	
S or Sr	1	1	1	1	1	1	0	W = 0	A ²		
	0	1	1	0	0	0	1	0	T		
	AddrMask[2:0]			StartOffset[1:0]		PEC_BL		RegMod	T		
	DevID[6:0]							0	T ³		
	Byte 0 Data Payload								T		
	Byte 1 Data Payload								T		
	Byte 2 Data Payload								T		
	Byte 3 Data Payload								T		
	PEC(8)								T		Sr ⁴ or P

NOTE 1 DEVCTRL CCC with PEC check is only supported in I3C Basic mode.

NOTE 2 The DDR5RCD05 NACKs if there was a parity or PEC error in a previous transaction when Host performs consecutive transactions with Repeat Start.

NOTE 3 As an exception, the DDR5RCD05 device will check parity in this byte even when the 7-bit Device ID code issued by the Host does not match with its own device code. If the Device ID code is unmatched, the RCD will not check for Parity or PEC errors in subsequent bytes and it will ignore the entire packet until STOP or Repeat START operation.

NOTE 4 Repeat Start or Repeat Start with 7'h7E.

6.10.7 Configure SPD Hub and All Devices Behind Hub Command (DEVCTRL) Operation (cont'd)

Table 74 — DEVCTRL Command Definition

Parameter	Definition
AddrMask[2:0]	<p>Broadcast, Unicast or Multicast Command Selection</p> <p>000 = Unicast Command; Target device responds if DevID[6:0] field matches with target device's own 7-bit address (4-bit LID + 3-bit HID)</p> <p>011 = Multicast Command; Target and possible other device responds if DevID[6:3] field matches with target's own 4-bit LID address</p> <p>111 = Broadcast Command; All devices responds to this command All other encodings are reserved</p>
StartOffset[1:0]	<p>Only applicable if RegMod = '0'</p> <p>Identifies the starting Byte. (Byte 0 or Byte 1 or Byte 2 or Byte 3) in DEVCTRL command data packet. Host can start any Byte and can have continuous access to next byte until STOP operation. If Byte 3 is reached, the Host is responsible for applying STOP operation.</p> <p>00 = Byte 0 01 = Byte 1 10 = Byte 2 11 = Byte 3</p>
PEC_BL[1:0]	<p>Only applicable if RegMod = '0'</p> <p>Identifies the burst length just for the DEVCTRL command data packet. The device uses the setting in this field to know when the PEC byte is expected after the data bytes.</p> <p>00 = 1 Byte 01 = 2 Byte 10 = 3 Byte 11 = 4 Byte</p>
RegMod	<p>Identifies if DEVCTRL command is going to be used for device specific offset register or general registers as identified in Byte 0 to Byte 3.</p> <p>0 = Access to General Registers in Byte 0 to Byte 3 (i.e., StartOffset[1:0] = Valid)</p> <p>1 = Device Specific Offset Address (i.e., StartOffset[1:0] & PECBL[1:0] is a don't care and does not apply). The Host shall not use RegMod = '1' with Broadcast Command for DDR5 DIMM because there are different types of devices on the I3C Basic bus. The DDR5RCD05 device is not required to support the RegMod = '1' option when the interface is running in I²C mode.¹</p>
DevID[6:0]	<p>Identifies 7-bit device address. Device responds to DEVCTRL command data packet depending on AddrMask[2:0].</p> <p>If AddrMask[2:0] = '111', DevID[6:0] is a don't care and device always responds.</p> <p>If AddrMask[2:0] = '000', DevID[6:0] must match for device to respond</p> <p>If AddrMask[2:0] = '011', DevID[6:3] must match for device to respond. DevID[2:0] is don't care.</p> <p>For any other codes for AddrMask[2:0], the device always NACKs.</p>

NOTE 1 This is a deviation from the JESD403-1 Standard for JEDEC Module SidebandBus.

6.10.7 Configure SPD Hub and All Devices Behind Hub Command (DEVCTRL) Operation (cont'd)

Table 75 — DEVCTRL Command Definition

Byte	Bit	Function	Definition	Comment
Byte 0	[7]	PEC Enable	0 = Disable 1 = Enable ¹	
	[6]	Parity Disable	0 = Enable 1 = Disable	
	[5]	RFU	RFU	
	[4:2]	RFU	RFU	
	[1]	RSVD - Reserved	X (0 or 1) = No action	This bit is used by other devices and must be ignored by the RCD.
	[0]	RFU	RFU	
Byte 1	[7:5]	RFU	RFU	
	[4]	RFU	RFU	
	[3]	Global and IBI Clear	0 = No action 1 = Clear All Event and pending IBI ^{1,2}	RW28[1:0] are updated
	[2]	RFU	RFU	RFU
	[1:0]	RFU	RFU	
Byte2	[7:0]	RFU	RFU	
Byte 3	[7:4]	RFU	RFU	
	[3:1]	RFU	RFU	
	[0]	RFU	RFU	

NOTE 1 Global Clear and PEC Enable are only applicable after device is configured in I3C Basic mode.

NOTE 2 After DDR5RCD05 clears all events, the RCD can still have certain registers set to '1' if the event is still present, in which case, the RCD will generate an IBI again at the next opportunity.

6.10.7.1 DEVCTRL Command Examples

The following DEVCTRL Command configures frequency information to 4560 MT/s (RW05 = 04h and RW06 = 0Ch) in all RCD devices simultaneously.

Table 76 — DEVCTRL Command Example (I3C Basic, Broadcast, PEC Enabled)

Start	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	A/N/T	Stop
S or Sr	1	1	1	1	1	1	0	W = 0	A	
	0	1	1	0	0	0	1	0	T	
	AddrMask[2:0] = '011' (Mcast)			StartOffset = xx		PEC_BL = xx		RegMod=1	T	
	DevID[6:0] = 1011_xxx (Match LID code for RCD Device)							0	T	
	SidebandBus Command = 11xx_11xx (Double Word Write) ¹								T	
	Byte Count = 08h								T	
	Reserved								T	
	Dev/Channel_Num = 00h (Channel A)								T	
	Page_Num [7:0] = 00h (Ignored for RW05 & RW06)								T	
	Reg_Num [7:0] = 04h (points at RW04)								T	
	Wr Data[31:24] = 00h (RW07 default)								T	
	Wr Data[23:16] = 0Ch (fbin - 240 MT/s)								T	
	Wr Data[15:8] = 04 h (4400 MT/s to 4800 MT/s)								T	
	Wr Data[7:0] = 00h (Command Space CMD 0 - NOP)								T	
	PEC(8)								T	P

NOTE 1 In DEVCTRL, Bits [3:2] of SidebandBus Command can be set to 01 (Write Byte), 10 (Write Word), or 11 (Write DWord). In other words, all Write Internal Commands are supported in the DEVCTRL CCC packet.

7 Control Words

The DDR5RCD05 device features a set of 8-bit control words, which allow the optimization of the device properties for different raw card designs. DDR5RCD05 control word writes appear as MRW commands but with the CW bit HIGH. DRAMs will ignore MRW commands with the CW bit set HIGH. Each Register Word (RW) write generates an MRW command to the DRAMs behind the register, unless there is a parity error when parity checking is enabled or the DRAM interface Forward All Commands feature is disabled in [RW01\[1\]](#). The different control words and settings are described below. Any change to these control words require some time for the device to settle. For changes to the control word setting, except for [RW05](#) and [RW06](#), the controller needs to wait t_{MRD} after the last control word access before further access to the DRAM can take place. For any changes to the clock timing ([RW05](#) and [RW06](#)) this settling may take up to t_{STAB02} time. All chip select inputs for the accessed channel, DCS[1:0]_n, must be kept HIGH during that time.

The control words are independent between the two channels. Each channel has a separate control word space that is accessible via the input chip selects for that channel. Some control words are only accessible through Channel A. These are control words that pertain to the clock frequency, etc., that are global in nature. Control word writes may occur independently on the two channels, so it is possible that both channels will be processing control word accesses at the same time, possibly offset by any number of DCKs from each other. The DDR5RCD05 must support control word access for any of the DDR5RCD05 specified frequency ranges.

RCD Control Word attributes can be:

- Reserved⁸
- Read Only
- Write Only
- RD/WR
- One Time Programmable
- Sticky - Cleared by power cycle not Reset

The control word space is divided as follows:

Table 77 — Control Word Addressing

CW bit	MRA7	Description
0	x	DRAM MR space.
1	0	RCD CW space. 128 registers decoded via MRA[6:0]
1	1	Reserved

Within the RCD control word space, 96 registers are accessed directly, while 32 registers are addressed through an 8-bit paging system, providing 8192 registers. [RW5F](#) is the page register while addresses 60-7F are used to access the registers within each page. Pages 00-7F are for JEDEC use while pages 80-FF are vendor specific.

NOTE 8 Reserved control bits may not be physically implemented and they shall be written to zero to ensure forward compatibility.

7 Control Words (cont'd)

Table 78 — RCD Control Word Spaces

MRA[7:0]	Location	Page Pointer RW ¹	Page Pointer Value	Definition	Size (Bytes)	Description
00h to 5Fh	RCD	RW5F	X	JEDEC	96	96 directly addressed registers
60h to 7Fh	RCD	RW5F	00h-7Fh	JEDEC	4096	32 paged registers
60h to 7Fh	RCD	RW5F	80h-FFh	Vendor	4096	32 paged registers
80h to DFh	Reserved	RWDF	X	JEDEC	96	96 directly addressed registers
E0h to FFh	Reserved	RWDF	00h-7Fh	JEDEC	4096	32 paged registers
E0h to FFh	Reserved	RWDF	80h-FFh	Vendor	4096	32 paged registers

NOTE 1 RW5F is the Page Pointer located in the DDR5 Register

All registers are 8-bit. Control Word Naming Convention:

PG[x]RWyy[z:z]
x = Page
yy = RW Number
z = OP

7.1 Reading Control Words

Control words are read by passing the data onto the DRAM devices, where they are read by the Host controller by doing an MRR (Mode Register Read). The sequence is as follows:

Table 79 — Control Word Read Sequence

Function	Cmd	CW bit	Address (hex)	Description
Select which control word to read	MRW	1	5Eh	MRW command to RCD control word RW5E which points to which RCD control word will be read ¹ .
Transfer the RCD control word content to the DRAMs	MRW	0	3Fh	MRW command to the DRAM MR63 (3Fh). When the RCD detects address MR63 in an MRW command in the 1st UI, it will substitute the data from the control word pointed to by RW5E onto CA[7:0] of the 2nd UI (replacing the data from the Host) ² . This data is written into the scratch pad register MR63 of the DRAM.
Read the data into the Host controller	MRR	0	3Fh	MRR command to the DRAM MR63 to read the data from the DRAM.

NOTE 1 If the RCD Control Word to be read is in the paged space, then the Host must set the page register properly before issuing the MRW write to the DRAM scratch-pad register.

NOTE 2 When the MR63 command is issued, only CA[7:0] gets replaced by the control word data and all other bits are forwarded to the DRAM.

NOTE: It is required that the DRAM has an 8-bit scratch-pad register at location MR63. MR63 is read and written in the same manner as all other mode registers. The RCD will check MRA[7:0] when determining whether to replace the Host data with the selected RW register content.

7.2 Control Word Decoding

The control words are programmed by the Host controller using the MRW command function. The DDR5RCD05 forwards the MRW command to the DRAM. The DRAM is required to ignore the MRW Command when CW = '1'.

Table 80 — DDR MRW Command to RCD¹

MRW	DCS_n	CA Pins						
		CA0	CA1	CA2	CA3	CA4	CA5	CA6
UI1	L	H	L	H	L	L	MRA0	MRA1
UI2	H	MRA2	MRA3	MRA4	MRA5	MRA6	MRA7	V
UI3	H	OP0	OP1	OP2	OP3	OP4	OP5	OP6
UI4	H	OP7	V	V	CW	V	V	V

NOTE 1 V means H or L (a defined logic level).

The power-on reset default state of all control words is '0' unless specified otherwise. Every time the device is reset, its default state is restored with the exception of sticky RWs. Cycling the device in and out of low-power mode will not alter the control word settings.

7.3 Control Word Decoding

Table 81 — Control Word Decoding

Register Control Word	MRA [7:0] HEX ¹	Meaning	Global Only (Requires Channel A Access) ²
RW00	0x00	Global Features	Yes
RW01	0x01	Parity, CMD Blocking, and Alert	Yes
RW02	0x02	Host Interface Training Mode	Yes
RW03	0x03	DRAM Interface Training Mode	Yes
RW04	0x04	Command Space	Yes
RW05	0x05	DIMM Operating Speed	Yes
RW06	0x06	Fine Granularity DIMM Operating Speed	Yes
RW07	0x07	Validation Pass-Through and Lockout Protection	Yes
RW08	0x08	Clock Driver Enable	No
RW09	0x09	Output Address and Control Enable	No
RW0A	0x0A	QCK Signals Driver Characteristics	No
RW0B	0x0B	Reserved	No
RW0C	0x0C	QCA and QxCS_n Signals Characteristics	No
RW0D	0x0D	Reserved	No
RW0E	0x0E	QCK, QCA and QCS Output Slew Rate	No
RW0F	0x0F	Reserved	No
RW10	0x10	IBT	Yes
RW11	0x11	Command Latency Adder (Latency Equalization Support has been deprecated. All RW11 bits will behave as RFU.)	No
RW12	0x12	QACK Output Delay	No
RW13	0x13	QBCK Output Delay	No
RW14	0x14	QCK Output Delay Control	No
RW15	0x15	QDCK Output Delay Control	No
RW16	0x16	Reserved	No
RW17	0x17	QACS0 Output Delay	No
RW18	0x18	QACS1 Output Delay	No
RW19	0x19	QBCS0 Output Delay	No
RW1A	0x1A	QBCS1 Output Delay	No
RW1B	0x1B	QACA Output Delay	No
RW1C	0x1C	QBCA Output Delay	No
RW1D	0x1D	Reserved	No
RW1E	0x1E	Reserved	No
RW1F	0x1F	Reserved	No
RW20	0x20	Error Log Register	No
RW21	0x21	Error Log Register	No
RW22	0x22	Error Log Register	No
RW23	0x23	Error Log Register	No
RW24	0x24	Error Log Register	No
RW25	0x25	SidebandBus	Yes
RW26	0x26	Loopback	Yes
RW27	0x27	Loop-back I/O	Yes
RW28	0x28	I ² C & I3C Basic Error Status	Yes
RW29	0x29	I ² C & I3C Basic Clear Error Status	Yes
RW2A	0x2A	Vendor Specific	Yes
RW2B	0x2B	DRST_n Masking	Yes
RW2C	0x2C	Reserved	No

Table 81 — Control Word Decoding

Register Control Word	MRA [7:0] HEX ¹	Meaning	Global Only (Requires Channel A Access) ²
RW2D	0x2D	16-bit LFSR Seed - Lower Byte	No
RW2E	0x2E	16-bit LFSR Seed - Upper Byte	No
RW2F	0x2F	LFSR State for DFE Training Mode - Upper Byte for 16-bit LFSR	No
RW30	0x30	DFE_Vref Range Limit	Yes
RW31	0x31	DFE Configuration	No
RW32	0x32	DPAR and DCA[6:0] DFE Training Mode	No
RW33	0x33	Additional Filtering for DFE Training Mode	No
RW34	0x34	LFSR DFE Training Mode	No
RW35	0x35	LFSR State for DFE Training Mode	No
RW36	0x36	DFETM Inner Loop Start Value	No
RW37	0x37	DFETM Outer Loop Start Value	No
RW38	0x38	DFETM Inner Loop Current Value	No
RW39	0x39	DFETM Outer Loop Current Value	No
RW3A	0x3A	DFETM Inner and Outer Loop Step Size	No
RW3B	0x3B	DFETM Inner Loop Number of Increments	No
RW3C	0x3C	DFETM Outer Loop Number of Increments	No
RW3D	0x3D	DFETM Inner Loop Current Increment	No
RW3E	0x3E	DFETM Outer Loop Current Increment	No
RW3F	0x3F	DFE Vref Range Selection	No
RW40	0x40	DCA0 Internal Vref	No
RW41	0x41	DCA1 Internal Vref	No
RW42	0x42	DCA2 Internal Vref	No
RW43	0x43	DCA3 Internal Vref	No
RW44	0x44	DCA4 Internal Vref	No
RW45	0x45	DCA5 Internal Vref	No
RW46	0x46	DCA6 Internal Vref	No
RW47	0x47	DPAR Internal Vref	No
RW48	0x48	DCS0 Internal Vref	No
RW49	0x49	DCS1 Internal Vref	No
RW4A	0x4A	DERROR_IN_n Vref	No
RW4B	0x4B	Loop-Back Vref	No
RW4C	0x4C	Loop-Back Input Delay	No
RW4D	0x4D	DCA selection in the Enhanced DCATM	No
RW4E	0x4E	DCS selection in the Enhanced DCATM	No
RW4F	0x4F	Reserved	No
RW50	0x50	CTLE Configuration Global Control Word	Yes
RW51	0x51	CTLE per-pin Disable	No
RW52	0x52	CTLE Parameter Set A	No
RW53	0x53	CTLE Parameter Set B	No
RW54	0x54	CTLE Parameter Set Selection	No
RW55~RW5D	0x55~0x5D	Reserved	No
RW5E	0x5E	CW Read Pointer	No
RW5F	0x5F	CW Page	No

NOTE 1 MRA7 must be 0 for RCD Control Word accesses.

NOTE 2 This column indicates global Register Control Words that apply to both channels but are written and read from Channel A only. Any attempts to write to CH_B will do nothing.

7.4 Paged Control Word Decoding

7.4.1 Page 0 DFE Paged Control Word Decoding

Table 82 — Page 0 DFE Control Word Decoding

Page	Register Control Word	MR [7:0] HEX ¹	Meaning
0x00	RW60	0x60	DCA0 Rx DFE Gain Coefficients
	RW61	0x61	DCA0 Rx DFE Tap 1 Coefficients
	RW62	0x62	DCA0 Rx DFE Tap 2 Coefficients
	RW63	0x63	DCA0 Rx DFE Tap 3 Coefficients
	RW64	0x64	DCA0 Rx DFE Tap 4 Coefficients
	RW65	0x65	DCA0 Rx DFE Tap 5 Coefficients
	RW66	0x66	DCA0 Rx DFE Tap 6 Coefficients
	RW67	0x67	RFU
	RW68	0x68	DCA1 Rx DFE Gain Coefficients
	RW69	0x69	DCA1 Rx DFE Tap 1 Coefficients
	RW6A	0x6A	DCA1 Rx DFE Tap 2 Coefficients
	RW6B	0x6B	DCA1 Rx DFE Tap 3 Coefficients
	RW6C	0x6C	DCA1 Rx DFE Tap 4 Coefficients
	RW6D	0x6D	DCA1 Rx DFE Tap 5 Coefficients
	RW6E	0x6E	DCA1 Rx DFE Tap 6 Coefficients
	RW6F	0x6F	RFU
	RW70	0x70	DCA2 Rx DFE Gain Coefficients
	RW71	0x71	DCA2 Rx DFE Tap 1 Coefficients
	RW72	0x72	DCA2 Rx DFE Tap 2 Coefficients
	RW73	0x73	DCA2 Rx DFE Tap 3 Coefficients
	RW74	0x74	DCA2 Rx DFE Tap 4 Coefficients
	RW75	0x75	DCA2 Rx DFE Tap 5 Coefficients
	RW76	0x76	DCA2 Rx DFE Tap 6 Coefficients
	RW77	0x77	RFU
	RW78	0x78	DCA3 Rx DFE Gain Coefficients
	RW79	0x79	DCA3 Rx DFE Tap 1 Coefficients
	RW7A	0x7A	DCA3 Rx DFE Tap 2 Coefficients
	RW7B	0x7B	DCA3 Rx DFE Tap 3 Coefficients
	RW7C	0x7C	DCA3 Rx DFE Tap 4 Coefficients
	RW7D	0x7D	DCA3 Rx DFE Tap 5 Coefficients
	RW7E	0x7E	DCA3 Rx DFE Tap 6 Coefficients
	RW7F	0x7F	RFU

NOTE 1 MRA7 must be 0 for RCD accesses.

7.4.2 Page 1 DFE Paged Control Word Decoding

Table 83 — Page 1 DFE Control Word Decoding

Page	Register Control Word	MR [7:0] HEX ¹	Meaning
0x01	RW60	0x60	DCA4 Rx DFE Gain Coefficients
	RW61	0x61	DCA4 Rx DFE Tap 1 Coefficients
	RW62	0x62	DCA4 Rx DFE Tap 2 Coefficients
	RW63	0x63	DCA4 Rx DFE Tap 3 Coefficients
	RW64	0x64	DCA4Rx DFE Tap 4 Coefficients
	RW65	0x65	DCA4 Rx DFE Tap 5 Coefficients
	RW66	0x66	DCA4 Rx DFE Tap 6 Coefficients
	RW67	0x67	RFU
	RW68	0x68	DCA5 Rx DFE Gain Coefficients
	RW69	0x69	DCA5 Rx DFE Tap 1 Coefficients
	RW6A	0x6A	DCA5 Rx DFE Tap 2 Coefficients
	RW6B	0x6B	DCA5 Rx DFE Tap 3 Coefficients
	RW6C	0x6C	DCA5 Rx DFE Tap 4 Coefficients
	RW6D	0x6D	DCA5 Rx DFE Tap 5 Coefficients
	RW6E	0x6E	DCA5 Rx DFE Tap 6 Coefficients
	RW6F	0x6F	RFU
	RW70	0x70	DCA6 Rx DFE Gain Coefficients
	RW71	0x71	DCA6 Rx DFE Tap 1 Coefficients
	RW72	0x72	DCA6 Rx DFE Tap 2 Coefficients
	RW73	0x73	DCA6 Rx DFE Tap 3 Coefficients
	RW74	0x74	DCA6 Rx DFE Tap 4 Coefficients
	RW75	0x75	DCA6 Rx DFE Tap 5 Coefficients
	RW76	0x76	DCA6 Rx DFE Tap 6 Coefficients
	RW77	0x77	RFU
	RW78	0x78	DPAR Rx DFE Gain Coefficients
	RW79	0x79	DPAR Rx DFE Tap 1 Coefficients
	RW7A	0x7A	DPAR Rx DFE Tap 2 Coefficients
	RW7B	0x7B	DPAR Rx DFE Tap 3 Coefficients
	RW7C	0x7C	DPAR Rx DFE Tap 4 Coefficients
	RW7D	0x7D	DPAR Rx DFE Tap 5 Coefficients
	RW7E	0x7E	DPAR Rx DFE Tap 6 Coefficients
	RW7F	0x7F	RFU

NOTE 1 MRA7 must be 0 for RCD accesses.

7.4.3 Page 2 DFE Paged Control Word Decoding

Table 84 — Page 2 DFE Control Word Decoding

Page	Register Control Word	MR [7:0] HEX ¹	Meaning
0x02	RW60	0x60	DCA0 Rx DFE Error Counter Lower 8 Bits
	RW61	0x61	DCA0 Rx DFE Error Counter Upper 8 Bits
	RW62	0x62	DCA0 DFE_Vref
	RW63	0x63	DCA0 LFSR Seed
	RW64	0x64	DCA1 Rx DFE Error Counter Lower 8 Bits
	RW65	0x65	DCA1 Rx DFE Error Counter Upper 8 Bits
	RW66	0x66	DCA1 DFE_Vref
	RW67	0x67	DCA1 LFSR Seed
	RW68	0x68	DCA2 Rx DFE Error Counter Lower 8 Bits
	RW69	0x69	DCA2 Rx DFE Error Counter Upper 8 Bits
	RW6A	0x6A	DCA2 DFE_Vref
	RW6B	0x6B	DCA2 LFSR Seed
	RW6C	0x6C	DCA3 Rx DFE Error Counter Lower 8 Bits
	RW6D	0x6D	DCA3 Rx DFE Error Counter Upper 8 Bits
	RW6E	0x6E	DCA3 DFE_Vref
	RW6F	0x6F	DCA3 LFSR Seed
	RW70	0x70	DCA4 Rx DFE Error Counter Lower 8 Bits
	RW71	0x71	DCA4 Rx DFE Error Counter Upper 8 Bits
	RW72	0x72	DCA4 DFE_Vref
	RW73	0x73	DCA4 LFSR Seed
	RW74	0x74	DCA5 Rx DFE Error Counter Lower 8 Bits
	RW75	0x75	DCA5 Rx DFE Error Counter Upper 8 Bits
	RW76	0x76	DCA5 DFE_Vref
	RW77	0x77	DCA5 LFSR Seed
	RW78	0x78	DCA6 Rx DFE Error Counter Lower 8 Bits
	RW79	0x79	DCA6 Rx DFE Error Counter Upper 8 Bits
	RW7A	0x7A	DCA6 DFE_Vref
	RW7B	0x7B	DCA6 LFSR Seed
	RW7C	0x7C	DPAR Rx DFE Error Counter Lower 8 Bits
	RW7D	0x7D	DPAR Rx DFE Error Counter Upper 8 Bits
	RW7E	0x7E	DPAR DFE_Vref
	RW7F	0x7F	DPAR LFSR Seed

NOTE 1 MRA7 must be 0 for RCD accesses.

7.4.4 Page 3 Manufacturing ID Control Word Decoding

Page 3 RW60 ~ RW6E control words in the DDR5RCD05 contain detailed RCD manufacturing information provided by RCD vendor. This information is programmed in OTP. The purpose is for improved manufacturing logistics management and not meant to be used by Host platform to control normal operation. These registers must be accessible during run time.

Table 85 — Page 3 Manufacturing ID Control Word Decoding

Page	Register Control Word	MR [7:0] HEX ¹	Meaning
0x03	RW60	0x60	Date Code Byte 0
	RW61	0x61	Date Code Byte 1
	RW62	0x62	Date Code Byte 2
	RW63	0x63	Vendor Specific Unique Unit Code Byte 0
	RW64	0x64	Vendor Specific Unique Unit Code Byte 1
	RW65	0x65	Vendor Specific Unique Unit Code Byte 2
	RW66	0x66	Vendor Specific Unique Unit Code Byte 3
	RW67	0x67	Vendor Specific Unique Unit Code Byte 4
	RW68	0x68	Vendor Specific Unique Unit Code Byte 5
	RW69	0x69	Vendor Specific Unique Unit Code Byte 6
	RW6A	0x6A	Vendor ID Byte 0
	RW6B	0x6B	Vendor ID Byte 1
	RW6C	0x6C	Device ID Byte 0
	RW6D	0x6D	Device ID Byte 1
	RW6E	0x6E	Vendor Revision ID
	RW6F	0x6F	Reserved
	RW70	0x70	Reserved
	RW71	0x71	Reserved
	RW72	0x72	Reserved
	RW73	0x73	Reserved
	RW74	0x74	Reserved
	RW75	0x75	Reserved
	RW76	0x76	Reserved
	RW77	0x77	Reserved
	RW78	0x78	Reserved
	RW79	0x79	Reserved
	RW7A	0x7A	Reserved
	RW7B	0x7B	Reserved
	RW7C	0x7C	Reserved
	RW7D	0x7D	Reserved
	RW7E	0x7E	Reserved
	RW7F	0x7F	Reserved

NOTE 1 MRA7 must be 0 for RCD accesses.

Table 86 — Page4 VHost Control Word Decoding

[illegible]

7.4.6 Page 5 Per-bit QCA Output Delay Control Word Decoding

Table 87 — Page 5 per-bit QCA Output Delay Control Word Decoding¹

Page	Register Control Word	MR[7:0] HEX	Meaning
0x05	RW60	0x60	QACA0 Output Delay
	RW61	0x61	QACA1 Output Delay
	RW62	0x62	QACA2 Output Delay
	RW63	0x63	QACA3 Output Delay
	RW64	0x64	QACA4 Output Delay
	RW65	0x65	QACA5 Output Delay
	RW66	0x66	QACA6 Output Delay
	RW67	0x67	QACA7 Output Delay
	RW68	0x68	QACA8 Output Delay
	RW69	0x69	QACA9 Output Delay
	RW6A	0x6A	QACA10 Output Delay
	RW6B	0x6B	QACA11 Output Delay
	RW6C	0x6C	QACA12 Output Delay
	RW6D	0x6D	QACA13 Output Delay
	RW6E	0x6E	QBCA0 Output Delay
	RW6F	0x6F	QBCA1 Output Delay
	RW70	0x70	QBCA2 Output Delay
	RW71	0x71	QBCA3 Output Delay
	RW72	0x72	QBCA4 Output Delay
	RW73	0x73	QBCA5 Output Delay
	RW74	0x74	QBCA6 Output Delay
	RW75	0x75	QBCA7 Output Delay
	RW76	0x76	QBCA8 Output Delay
	RW77	0x77	QBCA9 Output Delay
	RW78	0x78	QBCA10 Output Delay
	RW79	0x79	QBCA11 Output Delay
	RW7A	0x7A	QBCA12 Output Delay
	RW7B	0x7B	QBCA13 Output Delay
	RW7C	0x7C	Reserved
	RW7D	0x7D	Reserved
	RW7E	0x7E	Reserved
	RW7F	0x7F	Reserved

NOTE 1 The corresponding group fractional delay feature must also be enabled to enable per-pin physical delay for a given output. For example, in order to change the QACA0 per-pin physical delay, the control bit [RW1B\[7\]](#) must be set to 1 in addition to the per-pin enable bit [PG\[5\]RW60\[7\]](#).

7.4.7 Page 6 DCS DFE Paged Control Word Decoding

Table 88 — Page 6 DCS DFE Control Word Decoding¹

Page	Register Control Word	MR [7:0] HEX ²	Meaning	Sticky
0x06	RW60	0x60	DCS0_n Rx DFE Gain Coefficients	Yes
	RW61	0x61	DCS0_n Rx DFE Tap 1 Coefficients	Yes
	RW62	0x62	DCS0_n Rx DFE Tap 2 Coefficients	Yes
	RW63	0x63	DCS0_n Rx DFE Tap 3 Coefficients	Yes
	RW64	0x64	DCS0_n Rx DFE Tap 4 Coefficients	Yes
	RW65	0x65	RFU	
	RW66	0x66	RFU	
	RW67	0x67	RFU	
	RW68	0x68	DCS1_n Rx DFE Gain Coefficients	Yes
	RW69	0x69	DCS1_n Rx DFE Tap 1 Coefficients	Yes
	RW6A	0x6A	DCS1_n Rx DFE Tap 2 Coefficients	Yes
	RW6B	0x6B	DCS1_n Rx DFE Tap 3 Coefficients	Yes
	RW6C	0x6C	DCS1_n Rx DFE Tap 4 Coefficients	Yes
	RW6D	0x6D	RFU	
	RW6E	0x6E	RFU	
	RW6F	0x6F	RFU	
	RW70	0x70	DCS0_n DFE Error Counter Lower 8 Bits	No
	RW71	0x71	DCS0_n DFE Error Counter Upper 8 Bits	No
	RW72	0x72	DCS0_n DFE_Vref	No
	RW73	0x73	DCS0_n LFSR Seed	No
	RW74	0x74	DCS1_n DFE Error Counter Lower 8 Bits	No
	RW75	0x75	DCS1_n DFE Error Counter Upper 8 Bits	No
	RW76	0x76	DCS1_n DFE_Vref	No
	RW77	0x77	DCS1_n LFSR Seed	No
	RW78	0x78	DCS DFE Training Register	Yes
	RW79	0x79	DCS DFE_Vref Range Selection	No
	RW7A	0x7A	RFU	
	RW7B	0x7B	RFU	
	RW7C	0x7C	RFU	
	RW7D	0x7D	RFU	
	RW7E	0x7E	RFU	
	RW7F	0x7F	RFU	

NOTE 1 PG[6]RW[60:64, 68:6C, 78] are duplicated to support dual-frequency application.

NOTE 2 MRA7 must be 0 for RCD accesses.

7.4.8 Page 7 Enhanced Training Paged Control Word Decoding**Table 89 — Page 7 Enhanced Training Paged Control Word Decoding**

Page	Register Control Word	MR [7:0] HEX ¹	Meaning	Sticky
0x07	RW60	0x60	Device Equalization Self-Train Mode Global Control	No
	RW61	0x61	RFU	
	RW62	0x62	DESTM CTLE Select	No
	RW63	0x63	DESTM DCS Select and Status	No
	RW64	0x64	DESTM DCA Select	No
	RW65	0x65	DESTM DCA Status	No
	RW66	0x66	RFU	
	RW67	0x67	RFU	
	RW68	0x68	HIT-SR Global Control	No
	RW69	0x69	RFU	
	RW6A	0x6A	RFU	
	RW6B	0x6B	RFU	
	RW6C	0x6C	RFU	
	RW6D	0x6D	RFU	
	RW6E	0x6E	RFU	
	RW6F	0x6F	RFU	
	RW70	0x70	Enhanced CTLE Global Control	Yes
	RW71	0x71	Enhanced CTLE DCS Select	Yes
	RW72	0x72	Enhanced CTLE DCA[1:0] Select	Yes
	RW73	0x73	Enhanced CTLE DCA[3:2] Select	Yes
	RW74	0x74	Enhanced CTLE DCA[5:4] Select	Yes
	RW75	0x75	Enhanced CTLE DPAR, DCA[6] Select	Yes
	RW76	0x76	RFU	
	RW77	0x77	RFU	
	RW78	0x78	RFU	
	RW79	0x79	RFU	
	RW7A	0x7A	RFU	
	RW7B	0x7B	RFU	
	RW7C	0x7C	RFU	
	RW7D	0x7D	RFU	
	RW7E	0x7E	RFU	
	RW7F	0x7F	Enhanced RWUPD	No

NOTE 1 MRA7 must be 0 for RCD accesses.

7.4.9 Page 70 Scrambling DCA Paged Control Word Decoding

Table 90 — Page 70 Scrambling DCA Paged Control Word Decoding

Page	Register Control Word	MR [7:0] HEX ¹	Meaning	Sticky
0x70	RW60	0x60	Scrambling DCA Control	Yes
	RW61	0x61	Scrambling DCA Error Handling Control	Yes
	RW62	0x62	Upper QCS Control	Yes
	RW63	0x63	Upper QCK Control	Yes
	RW64	0x64	RFU	
	RW65	0x65	RFU	
	RW66	0x66	RFU	
	RW67	0x67	RFU	
	RW68	0x68	RFU	
	RW69	0x69	RFU	
	RW6A	0x6A	Upper QCK Driver Characteristics	Yes
	RW6B	0x6B	RFU	
	RW6C	0x6C	RFU	
	RW6D	0x6D	RFU	
	RW6E	0x6E	RFU	
	RW6F	0x6F	RFU	
	RW70	0x70	RFU	
	RW71	0x71	RFU	
	RW72	0x72	RFU	
	RW73	0x73	RFU	
	RW74	0x74	RFU	
	RW75	0x75	RFU	
	RW76	0x76	RFU	
	RW77	0x77	RFU	
	RW78	0x78	QWCK Output Delay Control	Yes
	RW79	0x79	QXCK Output Delay Control	Yes
	RW7A	0x7A	QYCK Output Delay Control	Yes
	RW7B	0x7B	QZCK Output Delay Control	Yes
	RW7C	0x7C	QACS2_n Output Delay Control	Yes
	RW7D	0x7D	QBCS2_n Output Delay Control	Yes
	RW7E	0x7E	QACS3_n Output Delay Control	Yes
	RW7F	0x7F	QBCS3_n Output Delay Control	Yes

NOTE 1 MRA7 must be 0 for RCD accesses.

7.5 Sticky Bits

7.5.1 Direct

1. [RW00\[1:0\]](#): Command Address Rate and SDR Modes
2. [RW05\[3:0\]](#): Operating Speed
3. [RW05\[6:5\]](#): V_{DD} Operating Voltage & Frequency Context
4. [RW06](#): Fine Granularity DIMM Operating Speed
5. [RW08](#): Clock Driver Enable
6. [RW09](#): Output Address and Control Enable
7. [RW0A](#): QCK Signal Driver Characteristics
8. [RW0C](#): QxCA and QxCS Signal Driver Characteristics
9. [RW0E](#): QCK, QCA and QCS Output Slew Rate
10. [RW10](#): IBT
11. [RW11](#): Command Latency Adder (Latency Equalization Support has been deprecated. All RW11 bits will behave as RFU.)
12. [RW\[12:15\]](#): Q[A:D]CK Output Delay
13. [RW\[17:1A\]](#): Q[A:B]CS[0:1]_n Output Delay
14. [RW\[1B:1C\]](#): Q[A:B]CA Output Delay
15. [RW25\[5\]](#): SidebandBus Mode
16. [RW28](#): I²C & I3C Basic Error Status
17. [RW2B\[0\]](#): DRST_n masking
18. [RW31](#): DFE Configuration
19. [RW33\[7:6\]](#): DCA DFE Tap 5 and Tap 6 Configuration
20. [RW\[47:40\]](#): Internal VrefCA
21. [RW\[49:48\]](#): Internal VrefCS
22. [RW50\[0\]](#), [RW51](#), [RW52\[3:0\]](#), [RW53\[3:0\]](#), [RW54](#): CTLE Control Words

7.5.2 Paged

1. [PG\[1:0\]RW\[61, 69, 71, 79\]](#): DPAR and DCA[6:0] Receiver DFE Tap 1 Coefficients
2. [PG\[1:0\]RW\[62, 6A, 72, 7A\]](#): DPAR and DCA[6:0] Receiver DFE Tap 2 Coefficients
3. [PG\[1:0\]RW\[63, 6B, 73, 7B\]](#): DPAR and DCA[6:0] Receiver DFE Tap 3 Coefficients
4. [PG\[1:0\]RW\[64, 6C, 74, 7C\]](#): DPAR and DCA[6:0] Receiver DFE Tap 4 Coefficients
5. [PG\[1:0\]RW\[65, 6D, 75, 7D\]](#): DPAR and DCA[6:0] Receiver DFE Tap 5 Coefficients
6. [PG\[1:0\]RW\[66, 6E, 76, 7E\]](#): DPAR and DCA[6:0] Receiver DFE Tap 6 Coefficients
7. [PG\[1:0\]RW\[60, 68, 70, 78\]](#): DPAR and DCA[6:0] Receiver DFE Gain Offset Adjustment
8. [PG\[5\]RW\[7B:60\]](#): Per-bit QCA Output Delay Control Words
9. [PG\[6\]RW\[60:64, 68:6C, 78\]](#): DCS DFE Gain, Tap 1, Tap 2, Tap 3, Tap 4 Coefficients
10. [PG\[7\]RW70\[0\]](#), [PG\[7\]RW\[75:71\]](#): Enhanced CTLE Control Words
11. [PG\[70\]RW60\[6\]](#), [PG\[70\]RW61\[3:2\]](#): Scrambling DCA Control Words
12. [PG\[70\]RW62\[4:1\]](#): Q[B:A]CS[3:2] Enables
13. [PG\[70\]RW63\[3:0\]](#): Q[Z:W]CK Enables
14. [PG\[70\]RW6A](#): Q[Z:W]CK Driver Characteristics
15. [PG\[70\]RW\[7F:78\]](#): Q[Z:W]CK and Q[B:A]CS[3:2] Output Delay Control

7.6 Mode and Command Control Words

7.6.1 RW00 - Global Features Control Word

Table 91 — RW00 - Global Features Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Command Address Rate ¹	Single Data Rate (SDR)
x	x	x	x	x	x	x	1		Double Data Rate (DDR)
x	x	x	x	x	x	0	x	SDR Modes ^{1,2}	SDR1 (additional setup time)
x	x	x	x	x	x	1	x		SDR2
x	x	x	x	x	0	x	x	CA Pass Through mode Enable	Normal operation
x	x	x	x	x	1	x	x		Enabled - Rank selected in OP[3] ³
x	x	x	x	0	x	x	x	CA Pass Through mode Rank Selection	CA Pass Through Rank 0 ⁴
x	x	x	x	1	x	x	x		CA Pass Through Rank 1 ⁵
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Output Inversion ^{6,7}	Enabled
x	x	1	x	x	x	x	x		Disabled
x	0	x	x	x	x	x	x	DNU	DNU
x	1	x	x	x	x	x	x		DNU
0	x	x	x	x	x	x	x	Reserved (Do not use)	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 RW00[1:0] will be sticky, cleared by power cycle not reset.

NOTE 2 This bit does not apply for DDR CA when RW00[0] = 1.

NOTE 3 If DRAM commands are blocked by RW01[1] = 0, DCSy_n pulses are not forwarded to QCSy_n outputs for any rank even if CA Pass Through Mode is enabled in RW00[2].

NOTE 4 When Pass through mode is enable on Rank 0 the RCD will process MRW commands on Rank 1.

NOTE 5 When Pass through mode is enable on Rank 1 the RCD will process MRW commands on Rank 0.

NOTE 6 For normal operation, output inversion is always enabled. For DIMM vendor test purpose, output inversion can be disabled. When disabled, register tPDM is not guaranteed to be met.

NOTE 7 Both output copies must be driven HIGH between CMD, regardless of the setting in RW00[5].

7.6.2 RW01 - Parity, CMD Blocking, and Alert Control Word Global Control Word

Table 92 — RW01 - Parity, CMD Blocking, and Alert Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Parity Checking	Parity checking disabled ¹
x	x	x	x	x	x	x	1		Parity checking enabled
x	x	x	x	x	x	0	x	DRAM Interface Forward All CMDs	Block
x	x	x	x	x	x	1	x		Do not block
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Host Interface Training Feedback ²	Both Sub channels feedback on ALERT_n
x	x	1	x	x	x	x	x		Sub CH_A feedback on QLBD; Sub CH_B feedback on QLBS
x	0	x	x	x	x	x	x	ALERT_n Assertion ^{3,4}	Static ALERT_n Assertion Mode ⁵
x	1	x	x	x	x	x	x		Pulsed ALERT_n Assertion Mode ⁶
0	x	x	x	x	x	x	x	ALERT_n Re-enable ⁷	Parity checking remains disabled after ALERT_n pulse
1	x	x	x	x	x	x	x		Parity checking is re-enabled after ALERT_n pulse

NOTE 1 Register does not check for parity including control word programming.

NOTE 2 Includes DCS, DCA, DFE Training Mode, and DESTM

NOTE 3 This bit only affects ALERT_n assertion that is a result of a CA parity error. In case of a LOW level on the DERROR_IN_n input, ALERT_n stays asserted as long as DERROR_IN_n remains LOW unless DRST_n is LOW or the device is in clock stopped power down mode.

NOTE 4 For details on ALERT_n output driver strength settings, see Table 262, “Output Driver DC Electrical Characteristics, Entire Operating Temperature Range”.

NOTE 5 ALERT_n stays asserted until ‘Clear CA Parity Error’ command is sent.

NOTE 6 ALERT_n pulse width according to Table 93.

NOTE 7 CA Parity Error Status bit in Error Log Register remains set until cleared by sending a Clear CA Parity Error command.

Figure 74, “DxCSx_n Assertion during ALERT_n Pulse Width” shows DxCSx_n assertion are not permitted t_{CSALT} prior and after of ALERT_n de-assertion when **RW01[0] = 1**.

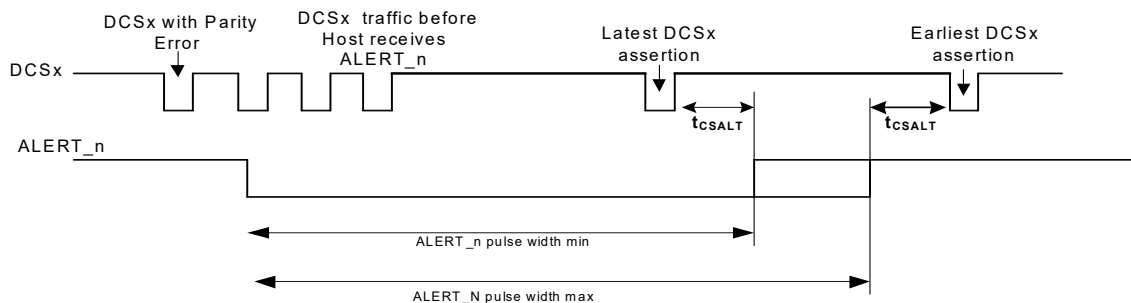


Figure 74 — DxCSx_n Assertion during ALERT_n Pulse Width

7.6.2 RW01 - Parity, CMD Blocking, and Alert Control Word Global Control Word (cont'd)

Table 93 — ALERT_n Pulse Width for Parity Error (DDR5-3200 ~ 5600)

ALERT_n Pulse Width ¹														
DDR5-3200		DDR5-3600		DDR5-4000		DDR5-4400		DDR5-4800		DDR5-5200		DDR5-5600		Units
Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
96	192	108	216	120	240	132	264	144	288	156	312	168	336	nCK

NOTE 1 The values in this table correspond to parity error in one of the channels. If parity errors occur in both CA channels, the resulting pulse width could be wider than the Maximum values shown in this table due to overlapping of the error pulse signals generated from each channel.

Table 94 — ALERT_n Pulse Width for Parity Error (DDR5-6000 ~ 8000)

ALERT_n Pulse Width ¹														
DDR5-6000		DDR5-6400		DDR5-6800		DDR5-7200		DDR5-7600		DDR5-8000		DDR5-8400		Units
Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
180	360	192	384	204	408	216	432	228	456	240	480	252	504	nCK

NOTE 1 The values in this table correspond to parity error in one of the channels. If parity errors occur in both CA channels, the resulting pulse width could be wider than the Maximum values shown in this table due to overlapping of the error pulse signals generated from each channel.

7.6.3 RW02 - Host Interface Training Mode Global Control Word

Table 95 — RW02: Host Interface Training Mode Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	Host Interface Training Mode selection CH_A	Normal operating mode
x	x	x	x	x	x	0	1		Clock-to-DCAy_A training mode
x	x	x	x	x	x	1	0		DCS0_A_n training mode
x	x	x	x	x	x	1	1		DCS1_A_n training mode
x	x	x	x	0	0	x	x	Host Interface Training Mode selection CH_B	Normal operating mode
x	x	x	x	0	1	x	x		Clock-to-DCAy_B training mode
x	x	x	x	1	0	x	x		DCS0_B_n training mode
x	x	x	x	1	1	x	x		DCS1_B_n training mode
x	x	0	0	x	x	x	x	DCA Training XOR sampling edge ^{1,2}	Both Rising and Falling Edges
x	x	0	1	x	x	x	x		Rising Edge
x	x	1	0	x	x	x	x		Falling Edge
x	x	1	1	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	VrefCA Broadcast ³	Disabled
x	1	x	x	x	x	x	x		Enabled ⁴
0	x	x	x	x	x	x	x	Enhanced DCATM Enable ^{5,6}	(default) Disabled
1	x	x	x	x	x	x	x		Enabled

NOTE 1 The DCA sampling edge bits only applies when Clock-to-DCAy_A or Clock-to-DCAy_B training modes are selected in [RW02\[3:2\]](#) or [RW02\[1:0\]](#).

NOTE 2 When SDR mode is enabled (i.e., [RW00\[0\]](#) = 0), only code 01 ‘Rising Edge’ is legal for this field.

NOTE 3 The VrefCA Broadcast Enable mode bit is global and is enabled on both sub-channels by setting [RW02\[6\]](#) = 1 on channel A only. The actual broadcasting of the VrefCA control word writes is independent per sub-channel.

NOTE 4 When VrefCA Broadcast mode is enabled, writes to [RW\[47:41\]](#) will be ignored by the RCD on both sub-channels. Vref DCA[6:0]_A and Vref DPAR_A are configured by writing to [RW\[40\]](#) on channel A. Vref DCA[6:0]_B and Vref DPAR_B are configured by writing to [RW40](#) on channel B.

NOTE 5 This setting is valid only when Clock-to-DCAy_A or Clock-to-DCAy_B training modes are selected in [RW02\[3:2\]](#) or [RW02\[1:0\]](#). In the Clock-to-DCAy_A or Clock-to-DCAy_B training modes, the Enhanced DCATM Enable setting is allowed to switch between “Disabled” and “Enabled”.

NOTE 6 When using back-to-back DCS assertion to exit the Enhanced DCATM, [RW02\[7\]](#) is not self cleared, but [RW02\[3:0\]](#) should be self cleared just like when the back-to-back DCS assertion to exit the normal DCATM.

7.6.4 RW03 - DRAM Interface Training Modes Global Control Word

Table 96 — RW03: DRAM Interface Training Modes Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	QCS Training Mode Enable	Disabled
x	x	x	x	x	x	x	1		Enabled - Rank selected in OP[1]
x	x	x	x	x	x	0	x	QCS Training Rank Selection	[Rank 0] QACS0 and QBCS0 Training mode
x	x	x	x	x	x	1	x		[Rank 1] QACS1 and QBCS1 Training mode
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	0	x	x	x	x	x		Reserved
x	x	1	x	x	x	x	x	Reserved	Reserved
x	0	x	x	x	x	x	x		Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x		Reserved
1	x	x	x	x	x	x	x	Reserved	Reserved

7.6.5 RW04 - Command Space Global Control Word

After issuing a register command via writes to **RW04**, tMRC is the minimum waiting time required by the RCD before the next DRAM command or MRW write can be issued. Some of the commands in **RW04** may require additional waiting times (longer than tMRC) to meet timing parameters specified for the DRAM.

Table 97 — RW04: Command Space Global Control Word definition

Command								Command No	Command Name	Result
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0			
0	0	0	0	0	0	0	0	CMD 0	NOP	NOP ¹
0	0	0	0	0	0	0	1	CMD 1	Reserved	Reserved
0	0	0	0	0	0	1	0	CMD 2	Reserved	Reserved
0	0	0	0	0	0	1	1	CMD 3	Reserved	Reserved
0	0	0	0	0	1	0	0	CMD 4	Reserved	Reserved
0	0	0	0	0	1	0	1	CMD 5	CH_A DRAM Reset	Switches QRST_A_n & QCSx_A_n to active which is LOW
0	0	0	0	0	1	1	0	CMD 6	Clear CH_A DRAM Reset	Switches QRST_A_n to inactive which is HIGH
0	0	0	0	0	1	1	1	CMD 7	CH_B DRAM Reset	Switches QRST_B_n & QCSx_B_n to active which is LOW
0	0	0	0	1	0	0	0	CMD 8	Clear CH_B DRAM Reset	Switches QRST_B_n to inactive which is HIGH
0	0	0	0	1	0	0	1	CMD 9	CH_A Clear parity Error	Clear 'CA Parity Error Status' bit and '> 1 Error' bit and re-enable parity checking (if not already enabled)
0	0	0	0	1	0	1	0	CMD 10	CH_B Clear parity Error	Clear 'CA Parity Error Status' bit and '> 1 Error' bit and re-enable parity checking (if not already enabled)
0	0	0	0	1	0	1	1	CMD 11	CH_A DFE ERROR Counter Reset	Resets All of CH_A DFE ERROR Counters to zero
0	0	0	0	1	1	0	0	CMD 12	CH_B DFE ERROR Counter Reset	Resets All of CH_B DFE ERROR Counters to zero
0	0	0	0	1	1	0	1	CMD 13	ALERT_n Toggle	Sends one 6 to 10-cycle LOW pulse on ALERT_n
0	0	0	0	1	1	1	0	CMD 14	CH_A QCS HIGH ²	QCSx_A_n Released
0	0	0	0	1	1	1	1	CMD 15	CH_B QCS HIGH ³	QCSx_B_n Released
1	1	1	1	0	0	0	0	Reserved	Reserved	Reserved
1	1	1	1	0	0	0	1	Reserved	Reserved	Reserved
1	1	1	1	0	0	1	0	Reserved	Reserved	Reserved
1	1	1	1	0	0	1	1	Reserved	Reserved	Reserved
1	1	1	1	0	1	0	0	Reserved	Reserved	Reserved
1	1	1	1	0	1	0	1	Reserved	Reserved	Reserved
1	1	1	1	0	1	1	0	Reserved	Reserved	Reserved
1	1	1	1	0	1	1	1	Reserved	Reserved	Reserved
1	1	1	1	1	0	0	0	Reserved	Reserved	Reserved
1	1	1	1	1	0	0	1	Reserved	Reserved	Reserved
1	1	1	1	1	0	1	0	Reserved	Reserved	Reserved
1	1	1	1	1	0	1	1	Reserved	Reserved	Reserved
1	1	1	1	1	1	0	0	Reserved	Reserved	Reserved
1	1	1	1	1	1	0	1	Reserved	Reserved	Reserved
1	1	1	1	1	1	1	0	Reserved	Reserved	Reserved
1	1	1	1	1	1	1	1	Reserved	Reserved	Reserved

NOTE 1 This operation was added specifically for Hosts that do not support byte writes over the SidebandBus, i.e., that have to write more than one CW at the same time.

NOTE 2 CMD 14 can be used during initialization sequences to start the QCK clocks and enable the QCA outputs in CH_A even when the RCD is not provided with the DCS input pulse shown in the Reset initialization timing diagram.

NOTE 3 CMD 15 can be used during initialization sequences to start the QCK clocks and enable the QCA outputs in CH_B even when the RCD is not provided with the DCS input pulse shown in the Reset initialization timing diagram.

7.7 Clocking Control Words

7.7.1 RW05 - DIMM Operating Speed Global Control Word

Table 98 — RW05: DIMM Operating Speed Global Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	Operating Speed ²	DDR5-3200 (2800 MT/s < f ≤ 3200 MT/s)
x	x	x	x	0	0	0	1		DDR5-3600 (3200 MT/s < f ≤ 3600 MT/s)
x	x	x	x	0	0	1	0		DDR5-4000 (3600 MT/s < f ≤ 4000 MT/s)
x	x	x	x	0	0	1	1		DDR5-4400 (4000 MT/s < f ≤ 4400 MT/s)
x	x	x	x	0	1	0	0		DDR5-4800 (4400 MT/s < f ≤ 4800 MT/s)
x	x	x	x	0	1	0	1		DDR5-5200(4800 MT/s < f ≤ 5200 MT/s)
x	x	x	x	0	1	1	0		DDR5 5600 (5200 MT/s < f ≤ 5600 MT/s)
x	x	x	x	0	1	1	1		DDR5 6000 (5600 MT/s < f ≤ 6000 MT/s)
x	x	x	x	1	0	0	0		DDR5 6400 (6000 MT/s < f ≤ 6400 MT/s)
x	x	x	x	1	0	0	1		DDR5 6800 (6400 MT/s < f ≤ 6800 MT/s)
x	x	x	x	1	0	1	0		DDR5 7200 (6800 MT/s < f ≤ 7200 MT/s)
x	x	x	x	1	0	1	1		DDR5 7600 (7200 MT/s < f ≤ 7600 MT/s)
x	x	x	x	1	1	0	0		DDR5 8000 (7600 MT/s < f ≤ 8000 MT/s)
x	x	x	x	1	1	0	1		Reserved
x	x	x	x	1	1	1	0		Down-bin Data Rate (1980 MT/s ≤ f ≤ 2100 MT/s) ³
x	x	x	x	1	1	1	1		PLL bypass mode enabled
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Register V _{DD} Operating Voltage ⁴	1.1 V
x	x	1	x	x	x	x	x		Reserved for lower voltage
x	0	x	x	x	x	x	x	Context for operation training	Default; Context 1 operation.
x	1	x	x	x	x	x	x		Context 2 operation. ⁵
0	x	x	x	x	x	x	x	Frequency Band Select	Operation (Frequency Band 1)
1	x	x	x	x	x	x	x		Test Mode (Frequency Band 2) ⁶

NOTE 1 The encoding value is used to inform the register the operating speed that it is being run at in a system. It is not an indicator of how fast or slow a register can run.

NOTE 2 RW05[6:5] and RW05[3:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 This setting may or may not support fractional delay settings, Fine Granularity DIMM Operating Speed Control, and will require a longer clock stabilization time.

NOTE 4 RW05[5] will be used to inform DDR5RCD05 under what operating voltage V_{DD} will be used. The RCD can use the information to optimize their functionality and performance at low-voltage conditions.

NOTE 5 The control words listed in Table 28 on page 85 are duplicated by the DDR5RCD05 for the 2nd frequency context.

NOTE 6 RW05[7] shall be set to '1' in order to guarantee PLL Lock when DCK is running in the Band-2 frequency range (i.e., 140 MHz < f_{TEST} < 990 MHz).

7.7.2 RW06 - Fine Granularity DIMM Operating Speed Global Control Word

Table 99 — RW06: Fine Granularity DIMM Operating Speed Global Control Word¹

Setting								Definition	Encoding ²
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Fine Granularity Operating Speed in terms of f_{bin} , where f_{bin} is the top speed for the speed range selected in RW05 OP[3:0] ³	$(f_{bin} - 20 \text{ MT/s}) < f \leq f_{bin}$
x	x	x	0	0	0	0	1		$(f_{bin} - 40 \text{ MT/s}) < f \leq (f_{bin} - 20 \text{ MT/s})$
x	x	x	0	0	0	1	0		$(f_{bin} - 60 \text{ MT/s}) < f \leq (f_{bin} - 40 \text{ MT/s})$
x	x	x	0	0	0	1	1		$(f_{bin} - 80 \text{ MT/s}) < f \leq (f_{bin} - 60 \text{ MT/s})$
x	x	x	0	0	1	0	0		$(f_{bin} - 100 \text{ MT/s}) < f \leq (f_{bin} - 80 \text{ MT/s})$
x	x	x	0	0	1	0	1		$(f_{bin} - 120 \text{ MT/s}) < f \leq (f_{bin} - 100 \text{ MT/s})$
x	x	x	0	0	1	1	0		$(f_{bin} - 140 \text{ MT/s}) < f \leq (f_{bin} - 120 \text{ MT/s})$
x	x	x	0	0	1	1	1		$(f_{bin} - 160 \text{ MT/s}) < f \leq (f_{bin} - 140 \text{ MT/s})$
x	x	x	0	1	0	0	0		$(f_{bin} - 180 \text{ MT/s}) < f \leq (f_{bin} - 160 \text{ MT/s})$
x	x	x	0	1	0	0	1		$(f_{bin} - 200 \text{ MT/s}) < f \leq (f_{bin} - 180 \text{ MT/s})$
x	x	x	0	1	0	1	0		$(f_{bin} - 220 \text{ MT/s}) < f \leq (f_{bin} - 200 \text{ MT/s})$
x	x	x	0	1	0	1	1		$(f_{bin} - 240 \text{ MT/s}) < f \leq (f_{bin} - 220 \text{ MT/s})$
x	x	x	0	1	1	0	0		$(f_{bin} - 260 \text{ MT/s}) < f \leq (f_{bin} - 240 \text{ MT/s})$
x	x	x	0	1	1	0	1		$(f_{bin} - 280 \text{ MT/s}) < f \leq (f_{bin} - 260 \text{ MT/s})$
x	x	x	0	1	1	1	0		$(f_{bin} - 300 \text{ MT/s}) < f \leq (f_{bin} - 280 \text{ MT/s})$
x	x	x	0	1	1	1	1		$(f_{bin} - 320 \text{ MT/s}) < f \leq (f_{bin} - 300 \text{ MT/s})$
x	x	x	1	0	0	0	0		$(f_{bin} - 340 \text{ MT/s}) < f \leq (f_{bin} - 320 \text{ MT/s})$
x	x	x	1	0	0	0	1		$(f_{bin} - 360 \text{ MT/s}) < f \leq (f_{bin} - 340 \text{ MT/s})$
x	x	x	1	0	0	1	0		$(f_{bin} - 380 \text{ MT/s}) < f \leq (f_{bin} - 360 \text{ MT/s})$
x	x	x	1	0	0	1	1		$(f_{bin} - 400 \text{ MT/s}) < f \leq (f_{bin} - 380 \text{ MT/s})$
x	x	x	1	0	1	0	0	Reserved	Reserved
x	x	x	1	0	1	0	1		Reserved
x	x	x	1	0	1	1	0		Reserved
x	x	x	1	0	1	1	1		Reserved
x	x	x	1	1	0	0	0		Reserved
x	x	x	1	1	0	0	1		Reserved
x	x	x	1	1	0	1	0		Reserved
x	x	x	1	1	0	1	1		Reserved
x	x	x	1	1	1	0	0		Reserved
x	x	x	1	1	1	0	1		Reserved
x	x	x	1	1	1	1	0	Reserved	Reserved
x	x	x	1	1	1	1	1		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This control word defines the frequency of the DCK_t - DCK_c input reference clock during normal operation (i.e., when not in test frequency range) in units of 20 MT/s.

NOTE 2 The frequency ranges shown in this column are for the base frequency of the input clock and they do not include SSC modulation effects. In some cases, due to SSC modulation, the actual frequency of the input clock can straddle two adjacent frequency ranges.

NOTE 3 RW06[4:0] will be sticky, cleared by power cycle not Reset.

7.8 Validation and Lockout Control Words

7.8.1 RW07 - Validation Pass-Through and Lockout Protection Global Control Word

Table 100 — RW07: Validation Pass-Through and Lockout Protection Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Lockout Protection Enable ¹	No effect ²
x	x	x	x	x	x	x	1		Protection enabled ^{3,4}
x	x	x	x	x	x	0	x	DNU ⁵	DNU
x	x	x	x	x	x	1	x		DNU
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Validation Pass-Through Feature Enable	Feature disabled
x	x	x	1	x	x	x	x		Feature enabled
x	x	0	x	x	x	x	x	Validation Pass-Through Mode Selection	Process MRW
x	x	1	x	x	x	x	x		Ignore MRW ⁶
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This feature is intended to protect the RCD against lockout state that is unrecoverable with DRST_n Reset and is caused by invalid DCA commands associated with incorrect input signal voltage levels or timing.

NOTE 2 This control bit is type “Write-1 Only” and cannot be written to 0 by the user. It only gets cleared to zero by DRST_n Reset or by internal Power-On Reset.

NOTE 3 When OP[0] = 1, the RCD prevents Writes to vendor specific CW pages (i.e., Pages 80h to FFh) triggered by commands received at the Host DCA interface of the RCD including MRW commands and CW in-band updates enabled when RW32[6] = 1.

NOTE 4 This feature does not affect access performed through SidebandBus.

NOTE 5 This location must not be used in any future revision.

NOTE 6 SidebandBus access to the RCD registers will not be blocked in Validation Pass-Through mode.

7.9 Output Enable Control Words

7.9.1 RW08 - Clock Driver Enable Control Word

Table 101 — RW08: Clock Driver Enable Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Disable QACK_t/QACK_c clock ^{1,2}	QACK_t/QACK_c clock enabled
x	x	x	x	x	x	x	1		QACK_t/QACK_c clock disabled
x	x	x	x	x	x	0	x	Disable QBCK_t/QBCK_c clock ^{1,2}	QBCK_t/QBCK_c clock enabled
x	x	x	x	x	x	1	x		QBCK_t/QBCK_c clock disabled
x	x	x	x	x	0	x	x	Disable QCCK_t/QCCK_c clock ^{1,2}	QCCK_t/QCCK_c clock enabled
x	x	x	x	x	1	x	x		QCCK_t/QDCK_c clock disabled
x	x	x	x	0	x	x	x	Disable QDCK_t/QDCK_c clock ^{1,2}	QDCK_t/QDCK_c clock enabled
x	x	x	x	1	x	x	x		QDCK_t/QDCK_c clock disabled
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 Output clocks may be individually turned on or off to conserve power. The system must read the module SPD to determine which clock outputs are used by the module. The PLL remains locked on DCK_t/DCK_c unless the system stops the clock inputs to the DDR5RCD05 to enter the lowest power mode.

NOTE 2 RW08[5] and RW08[3:0] will be sticky, cleared by power cycle not Reset.

7.9.2 RW09 - Output Address and Control Enable Control Word

Table 102 — RW09: Output Address and Control Enable Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	QACA outputs	Enabled
x	x	x	x	x	x	x	1		Disabled
x	x	x	x	x	x	0	x	QBCA outputs	Enabled
x	x	x	x	x	x	1	x		Disabled
x	x	x	x	x	0	x	x	DCS1_n Input Buffer & QxCS1_n Outputs ¹ (single rank)	DCS1_n & QxCS1_n pins Enabled
x	x	x	x	x	1	x	x		DCS1_n & QxCS1_n pins Disabled
x	x	x	x	0	x	x	x	Reserved (Do not use)	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Q[B:A]CA13 output driver disable	Enabled
x	x	x	1	x	x	x	x		Disabled
x	x	0	x	x	x	x	x	QACS[1:0]_n output	Enable
x	x	1	x	x	x	x	x		Disabled
x	0	x	x	x	x	x	x	QBCS[1:0]_n output	Enabled
x	1	x	x	x	x	x	x		Disabled
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 DCS1 is a required signal for training modes and must be routed even on single rank DIMMs. RW09[2] can be written to 1 to save power in single rank DIMMs during normal operation after initialization and training sequences have been completed. Once RW09[2] is written to 1, it must be written to 0 if and only if additional training is performed. Immediately after the additional training is finished, RW09[2] must be written back to 1.

7.10 Output Driver Strengths

For details on RCD output driver strengths in this section, see Table 262, “Output Driver DC Electrical Characteristics, Entire Operating Temperature Range”.

7.10.1 RW0A - QCK Signals Driver Characteristics Control Word

Table 103 — RW0A: QCK Signals Driver Characteristics Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	QACK_t/QACK_c ¹	Light Drive
x	x	x	x	x	x	0	1		Moderate Drive
x	x	x	x	x	x	1	0		Strong Drive
x	x	x	x	x	x	1	1		Reserved
x	x	x	x	0	0	x	x	QBCK_t/QBCK_c ¹	Light Drive
x	x	x	x	0	1	x	x		Moderate Drive
x	x	x	x	1	0	x	x		Strong Drive
x	x	x	x	1	1	x	x		Reserved
x	x	0	0	x	x	x	x	QCK_t/QCK_c ¹	Light Drive
x	x	0	1	x	x	x	x		Moderate Drive
x	x	1	0	x	x	x	x		Strong Drive
x	x	1	1	x	x	x	x		Reserved
0	0	x	x	x	x	x	x	QDCK_t/QDCK_c ¹	Light Drive
0	1	x	x	x	x	x	x		Moderate Drive
1	0	x	x	x	x	x	x		Strong Drive
1	1	x	x	x	x	x	x		Reserved

NOTE 1 RW0A[7:0] will be sticky, cleared by power cycle not Reset.

7.10.2 RW0C - QxCA and QxCS_n Signals Driver Characteristics Control Word

Table 104 — RW0C: QxCA and QxCS_n Signals Driver Characteristics Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	Address/Command Address for both A&B copies ¹	Light Drive
x	x	x	x	x	x	0	1		Moderate Drive
x	x	x	x	x	x	1	0		Strong Drive
x	x	x	x	x	x	1	1		Reserved
x	x	x	x	0	0	x	x	Reserved	Reserved
x	x	x	x	0	1	x	x		Reserved
x	x	x	x	1	0	x	x		Reserved
x	x	x	x	1	1	x	x		Reserved
x	x	0	0	x	x	x	x	QxCS0_n, QxCS1_n, Outputs ¹	Light Drive
x	x	0	1	x	x	x	x		Moderate Drive
x	x	1	0	x	x	x	x		Strong Drive
x	x	1	1	x	x	x	x		Reserved
0	0	x	x	x	x	x	x	Reserved	Reserved
0	1	x	x	x	x	x	x		Reserved
1	0	x	x	x	x	x	x		Reserved
1	1	x	x	x	x	x	x		Reserved

NOTE 1 RW0C[1:0] and RW0C[5:4] will be sticky, cleared by power cycle not Reset.

7.11 Output Slew Rate Control

The DDR5RCD05 supports output slew rate control per channel, as described in the following control words.

7.11.1 RW0E - QCK, QCA and QCS Output Slew Rate Control Word

Table 105 — RW0E - QCK, QCA and QCS Output Slew Rate Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	QxCK_t / QxCK_c Differential Slew Rate Setting ²	Moderate
x	x	x	x	x	x	0	1		Fast
x	x	x	x	x	x	1	0		Slow ³
x	x	x	x	x	x	1	1		Reserved
x	x	x	x	0	0	x	x	Q[B:A]CA[13:0] Single-Ended Slew Rate setting ⁴	Moderate
x	x	x	x	0	1	x	x		Fast
x	x	x	x	1	0	x	x		Slow ³
x	x	x	x	1	1	x	x		Reserved
x	x	0	0	x	x	x	x	Q[B:A]CS[3:0]_n Single-Ended Slew Rate setting ⁴	Moderate
x	x	0	1	x	x	x	x		Fast
x	x	1	0	x	x	x	x		Slow ³
x	x	1	1	x	x	x	x		Reserved
0	0	x	x	x	x	x	x	Reserved	Reserved
0	1	x	x	x	x	x	x		Reserved
1	0	x	x	x	x	x	x		Reserved
1	1	x	x	x	x	x	x		Reserved

NOTE 1 [RW0E\[5:0\]](#) will be sticky, cleared by power cycle not reset.

NOTE 2 Slew Rate Control encodings of Moderate, Fast and Slow apply to all driver strength settings. The corresponding base range values specified in Table 260 are applicable for only Ron = Strong Drive, VDD = 1.1 V, and 25 °C. Slew rates will be different for other Ron values. The Output slew rate is verified by design and characterization, and may not be subject to production test.

NOTE 3 Slow slew rate setting is not valid for speeds above 7200.

NOTE 4 Slew Rate Control encodings of Moderate, Fast and Slow apply to all driver strength settings. The corresponding base range values specified in Table 260 are applicable for only Ron = Light Drive, VDD = 1.1 V, and 25 °C. Slew rates will be different for other Ron values. The Output slew rate is verified by design and characterization, and may not be subject to production test.

7.12 Input Bus Termination Strengths

7.12.1 RW10 - IBT Global Control Word

Table 106 — RW10: IBT Global Control Word

Setting								Definition ¹	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	DCA[6:0]_[B:A] and	60 Ω
x	x	x	x	x	x	0	1	DPAR_[B:A] Input Bus	48 Ω
x	x	x	x	x	x	1	0	Termination ²	Reserved
x	x	x	x	x	x	1	1		OFF ³
x	x	x	x	0	0	x	x	DCS[1:0]_[B:A]_n Input Bus ² Termination	60 Ω
x	x	x	x	0	1	x	x		48 Ω
x	x	x	x	1	0	x	x		Reserved
x	x	x	x	1	1	x	x		OFF ³
x	x	0	0	x	x	x	x	DCK Input Bus Termination ²	60 Ω
x	x	0	1	x	x	x	x		48 Ω
x	x	1	0	x	x	x	x		Reserved
x	x	1	1	x	x	x	x		OFF ³
0	0	x	x	x	x	x	x	DERROR_IN_[B:A]_n Input Bus Termination ²	60 Ω
0	1	x	x	x	x	x	x		48 Ω
1	0	x	x	x	x	x	x		Reserved
1	1	x	x	x	x	x	x		OFF ³

NOTE 1 These are target IBT values. Acceptable actual values are determined based on tolerances defined in electrical section.

NOTE 2 RW10[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 Not intended for normal operation. For normal operation, Input Bus Termination is always enabled.

7.13 Timing Control Words

7.13.1 RW11 - Command Latency Adder Configuration Control Word

Table 107 — RW11: Command Latency Adder Configuration Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	Latency adder nLadd to all DRAM commands ¹	0 nCK latency adder
x	x	x	x	0	0	0	1		1 nCK ² latency adder to Qn ³
x	x	x	x	0	0	1	0		2 nCK ² latency adder to Qn ³
x	x	x	x	0	0	1	1		3 nCK ² latency adder to Qn ³
x	x	x	x	0	1	0	0		4 nCK ² latency adder to Qn ³
x	x	x	x	0	1	0	1		Reserved
x	x	x	x	0	1	1	0		Reserved
x	x	x	x	0	1	1	1		Reserved
x	x	x	x	1	0	0	0		Reserved
x	x	x	x	1	0	0	1		Reserved
x	x	x	x					Reserved
x	x	x	x	1	1	1	1		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x	Reserved	Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x	Reserved	Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x	Reserved	Reserved

NOTE 1 RW11[3:0] will be sticky, cleared by power cycle not Reset. Latency Equalization Support has been deprecated starting with spec revision 0.9. All RW11 bits will behave as RFU on devices that do not support Latency Equalization.

NOTE 2 The correct frequency range has to be programmed in RW05 before any changes to RW11 from the power-on default are allowed

NOTE 3 Qn = QxCA[13:0]. QxCS[1:0]_n.

7.13.2 RW12 - QACK Output Delay Control Word

Table 108 — RW12: QACK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QACK_t/QACK_c Output Signals ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QACK_t/QACK_c ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW12[7] = 1.

NOTE 2 RW12[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW12[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.13.3 RW13 - QBCK Output Delay Control Word

Table 109 — RW13: QBCK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QBCK_t/QBCK_c Output Signals ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QBCK_t/QBCK_c ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW13[7] = 1.

NOTE 2 RW13[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW13[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.13.4 RW14 - QCCCK Output Delay Control Word

Table 110 — RW14: QCCCK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QCCCK_t/QCCCK_c Output Signals ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64)* t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QCCCK_t/QCCCK_c ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW14[7] = 1.

NOTE 2 RW14[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW14[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.13.5 RW15 - QDCK Output Delay Control Word

Table 111 — RW15: QDCK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QDCK_t/QDCK_c Output Signals ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64)* t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QDCK_t/QDCK_c ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW15[7] = 1.

NOTE 2 RW15[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW15[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.13.6 RW17 - QACS0_n Output Delay Control Word**Table 112 — RW17: QACS0_n Output Delay Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QACS0_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64)* t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QACS0_n ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW17[7] = 1.

NOTE 2 RW17[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW17[6:0] require a time of t_{ODU} for the delay to become stable on the outputs.**7.13.7 RW18 - QACS1_n Output Delay Control Word****Table 113 — RW18: QACS1_n Output Delay Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QACS1_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64)* t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QACS1_n ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW18[7] = 1.

NOTE 2 RW18[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW18[6:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.13.8 RW19 - QBCS0_n Output Delay Control Word

Table 114 — RW19: QBCS0_n Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QBCS0_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64)* t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QBCS0_n output signals ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW19[7] = 1.

NOTE 2 RW19[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW19[6:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.13.9 RW1A - QBCS1_n Output Delay Control Word

Table 115 — RW1A: QBCS1_n Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QBCS1_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64)* t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64) * t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QBCS1_n output signals ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW1A[7] = 1.

NOTE 2 RW1A[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW1A[6:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.13.10 RW1B - QACA Output Delay Control Word**Table 116 — RW1B: QACA Output Delay Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QACA Output Signals ^{1,2}	Delay Outputs by $+(0/64) * t_{CK}$ (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by $+(1/64)* t_{CK}$
x	x	0	0	0	0	1	0		Delay Outputs by $+(2/64) * t_{CK}$
x	x
x	x	1	1	1	1	0	1		Delay Outputs by $+(61/64) * t_{CK}$
x	x	1	1	1	1	1	0		Delay Outputs by $+(62/64) * t_{CK}$
x	x	1	1	1	1	1	1		Delay Outputs by $+(63/64) * t_{CK}$
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QACA ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW1B[7] = 1.

NOTE 2 RW1B[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW1B[6:0] require a time of t_{ODU} for the delay to become stable on the outputs.**7.13.11 RW1C - QBCA Output Delay Control Word****Table 117 — RW1C: QBCA Output Delay Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QBCA Output Signals ^{1,2}	Delay Outputs by $+(0/64) \cdot t_{CK}$ (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by $+(1/64) \cdot t_{CK}$
x	x	0	0	0	0	1	0		Delay Outputs by $+(2/64) \cdot t_{CK}$
x	x
x	x	1	1	1	1	0	1		Delay Outputs by $+(61/64) \cdot t_{CK}$
x	x	1	1	1	1	1	0		Delay Outputs by $+(62/64) \cdot t_{CK}$
x	x	1	1	1	1	1	1		Delay Outputs by $+(63/64) \cdot t_{CK}$
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QBCA ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless RW1C[7] = 1.

NOTE 2 RW1C[7:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in RW1C[6:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.14 RW[24:20] - Error Log Register

Control word locations [RW\[24:20\]](#) function as a 32-bit error log register. Upon occurrence of a CA parity error, the device logs the following sampled command and address bits in the Error Log Register.

Table 118 — RW[24:20]: Error Log Register Encoding for DDR Mode^{1,2}

Control Word	Setting (OP[7:0])							
RW20	CA13 2nd UI	CA12 2nd UI	CA11 2nd UI	CA10 2nd UI	CA9 2nd UI	CA8 2nd UI	CA7 2nd UI	DPAR 2nd UI
RW21	CA6 1st UI	CA5 1st UI	CA4 1st UI	CA3 1st UI	CA2 1st UI	CA1 1st UI	CA0 1st UI	DPAR 1st UI
RW22	CA13 4th UI	CA12 4th UI	CA11 4th UI	CA10 4th UI	CA9 4th UI	CA8 4th UI	CA7 4th UI	DPAR 4th UI
RW23	CA6 3rd UI	CA5 3rd UI	CA4 3rd UI	CA3 3rd UI	CA2 3rd UI	CA1 3rd UI	CA0 3rd UI	DPAR 3rd UI
RW24	> 1 Error ^{3,4}	CA Parity Error Status ^{3,5}	Reserved	CS1_n 1st cycle	CS0_n 1st cycle	CS1_n 2nd cycle	CS0_n 2nd Cycle	Reserved

NOTE 1 The encoding shown in this table is valid when the DCA interface is operating in DDR mode ([RW00\[0\]](#) = 1).

NOTE 2 When command and address bits are logged in the Error Log Register upon occurrence of a CA parity error, all bits in [RW20](#) to [RW24](#) are updated with the corresponding values from the offending command. Four consecutive UI's are always captured because, in some cases, it is not possible to distinguish between 1UI and 2UI commands due to the parity error. [RW20](#) and [RW21](#) always contain the start of the command (qualified by DCS_n assertion) regardless of the UI or cycle within the command where the parity error has been detected.

NOTE 3 This bit will get reset to '0' when "Clear CA Parity Error" command is sent. The Clear CA Parity Error command does not affect any bits in [RW\[23:20\]](#) and [RW24\[4:1\]](#).

NOTE 4 With [RW01\[7\]](#) = 1 and [RW01\[6\]](#) = 1, the device will forward commands and re-enable parity after the ALERT_n pulse. The CA Parity Error Status bit will remain set. If a subsequent parity error is detected, the device will re-enter the parity error state and set the '> 1 Error' bit.

NOTE 5 The DDR5RCD05 will set this bit upon occurrence of a CA parity error.

7.14 RW[24:20] - Error Log Register (cont'd)

Table 119 — RW[24:20]: Error Log Register Encoding for SDR Mode^{1,2}

Control Word	Setting (OP[7:0])							
RW20	CA13 2nd Cycle	CA12 2nd Cycle	CA11 2nd Cycle	CA10 2nd Cycle	CA9 2nd Cycle	CA8 2nd Cycle	CA7 2nd Cycle	DPAR 2nd Cycle
RW21	CA6 1st Cycle	CA5 1st Cycle	CA4 1st Cycle	CA3 1st Cycle	CA2 1st Cycle	CA1 1st Cycle	CA0 1st Cycle	DPAR 1st Cycle
RW22	CA13 4th Cycle	CA12 4th Cycle	CA11 4th Cycle	CA10 4th Cycle	CA9 4th Cycle	CA8 4th Cycle	CA7 4th Cycle	DPAR 4th Cycle
RW23	CA6 3rd Cycle	CA5 3rd Cycle	CA4 3rd Cycle	CA3 3rd Cycle	CA2 3rd Cycle	CA1 3rd Cycle	CA0 3rd Cycle	DPAR 3rd Cycle
RW24	> 1 Error ^{3,4}	CA Parity Error Status ^{3,5}	Reserved	CS1_n 1st cycle	CS0_n 1st cycle	CS1_n 3rd cycle	CS0_n 3rd Cycle	Reserved

NOTE 1 The encoding shown in this table is valid when the DCA interface is operating in SDR mode (RW00[0] = 0).

NOTE 2 When command and address bits are logged in the Error Log Register upon occurrence of a CA parity error, all bits in RW20 to RW24 are updated with the corresponding values from the offending command. Four consecutive cycles are always captured because, in some cases, it is not possible to distinguish between 1UI and 2UI commands due to the parity error. RW20 and RW21 always contain the start of the command (qualified by DCS_n assertion) regardless of the cycle within the command where the parity error has been detected.

NOTE 3 This bit will get reset to '0' when "Clear CA Parity Error" command is sent. The Clear CA Parity Error command does not affect any bits in RW[23:20] and RW24[4:1].

NOTE 4 With RW01[7] = 1 and RW01[6] = 1, the device will forward commands and re-enable parity after the ALERT_n pulse. The CA Parity Error Status bit will remain set. If a subsequent parity error is detected, the device will re-enter the parity error state and set the '> 1 Error' bit.

NOTE 5 The DDR5RCD05 will set this bit upon occurrence of a CA parity error.

7.15 SidebandBus

7.15.1 RW25 - SidebandBus Global Control Word

Table 120 — RW25: SidebandBus Global Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	SidebandBus Interface Disabled	SidebandBus interface is enabled
x	x	x	x	x	x	x	1		SidebandBus interface is disabled. DDR5RCD05 will not claim or acknowledge any access to its SidebandBus address space.
x	x	x	x	x	x	0	x	Vendor Specific ²	Vendor Specific.
x	x	x	x	x	x	1	x		Vendor Specific.
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Vendor Specific ²	Vendor Specific
x	x	x	1	x	x	x	x		Vendor Specific
x	x	0	x	x	x	x	x	SidebandBus Mode ³	I ² C (Max speed of 1 MHz) Enabled
x	x	1	x	x	x	x	x		I3C Basic (Max speed of 12.5 MHz) Enabled
x	0	x	x	x	x	x	x	Vendor Specific ²	Vendor Specific
x	1	x	x	x	x	x	x		Vendor Specific
0	x	x	x	x	x	x	x	Vendor Specific ²	Vendor Specific
1	x	x	x	x	x	x	x		Vendor Specific

NOTE 1 The write (or update) transaction to this register must be followed by STOP operation to allow the DDR5RCD05 device to update the setting.

NOTE 2 This register is vendor specific and must be written to '0' by the Host whenever RW25 is accessed for Writes.

NOTE 3 This is a Read-Only Status register. This is a Sticky register (not cleared by DRST_n). This register is automatically updated to '1' or to '0', respectively, when SETAASA CCC or RSTDAA CCC is registered by the DDR5RCD05 device. This register is automatically cleared to '0' when the Timeout Reset condition described in Clause 6.6, "I2C and I3C Basic Reset" is detected.

7.16 RX Loopback

7.16.1 RW26 - RX Loopback Global Control Word

Table 121 — RW26: RX Loopback Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	0	0	0	RCD RX Loopback Port Selection	Loopback Disabled ¹
x	x	x	x	x	0	0	1		Internal RCD CH_A DCA Port ^{2,5}
x	x	x	x	x	0	1	0		Internal RCD CH_B DCA Port ^{2,5}
x	x	x	x	x	0	1	1		External CH_A Port ³
x	x	x	x	x	1	0	0		External CH_B Port ³
x	x	x	x	x	1	0	1		Internal QCK Loopback ⁴
x	x	x	x	x	1	1	0		Internal RCD CH_A DCS port ⁵
x	x	x	x	x	1	1	1		Internal RCD CH_B DCS port ⁵
x	x	0	0	0	x	x	x	Internal RCD bit selection ⁶	DCA0 if RW26[2:0] = 1 or 2, or DCS0_n if RW26[2:0] = 6 or 7
x	x	0	0	1	x	x	x		DCA1 if RW26[2:0] = 1 or 2, or DCS1_n if RW26[2:0] = 6 or 7
x	x	0	1	0	x	x	x		DCA2 if RW26[2:0] = 1 or 2, or Reserved if RW26[2:0] = 6 or 7
x	x	0	1	1	x	x	x		DCA3 if RW26[2:0] = 1 or 2, or Reserved if RW26[2:0] = 6 or 7
x	x	1	0	0	x	x	x		DCA4 if RW26[2:0] = 1 or 2, or Reserved if RW26[2:0] = 6 or 7
x	x	1	0	1	x	x	x		DCA5 if RW26[2:0] = 1 or 2, or Reserved if RW26[2:0] = 6 or 7
x	x	1	1	0	x	x	x		DCA6 if RW26[2:0] = 1 or 2, or Reserved if RW26[2:0] = 6 or 7
x	x	1	1	1	x	x	x		DPAR if RW26[2:0] = 1 or 2, or Reserved if RW26[2:0] = 6 or 7
x	0	x	x	x	x	x	x	Loopback Data Rate Applied to both Internal and External Loopback Port ^{7,8,9}	Incoming and outgoing signals are 1/2 rate ¹⁰
x	1	x	x	x	x	x	x		Incoming and outgoing signals are 1/4 rate
0	x	x	x	x	x	x	x	Internal Loopback Select Phase, for 1/2 Rate Mode (Lower Select for 1/4 Rate Mode)	Loopback Select Phase A or C ¹¹
1	x	x	x	x	x	x	x		Loopback Select Phase B or D ¹²

NOTE 1 Loopback circuitry is disabled.

NOTE 2 Internal Port contains input Clock and DCA. Loopback signal operation can be configured as 1/4 rate or 1/2 rate modes selected in RW26[6].

NOTE 3 External Port contains input Strobe and Data. A waiting time $t_{Ext_LB_Entry}$ applies when External Loopback is enabled in RW26[2:0].

NOTE 4 The DDR5RCD05 can output its internal PLL clock to the two loopback output pins QLBS and QLBD. The delay from input differential clock DCK_t and DCK_c to the output differential clock on QLBS and QLBD is vendor specific. The slew rate of the output differential clock on QLBS and QLBD is vendor specific. The mode is for 1-UI Rj without BUJ test purpose only. Any other parameters including Tj, Dj and N-UI Rj tests are not supported by the device.

NOTE 5 DCS and SDR DCA Internal Loopback supports Phase A and Phase C only, i.e., when RW26[2:0]=110 or 111, or when RW26[2:0]=001 or 010 in SDR DCA mode, RW26[7] must be 0.

NOTE 6 This field only applies when Internal RCD CH_A or Internal RCD CH_B ports are selected in RW26[2:0].

NOTE 7 For Internal RCD CH A and Internal RCD CHB ports, this bit selects whether 1/2 rate or 1/4 rate Loopback mode is enabled.

NOTE 8 For External CH_A and External CH_B ports, this bit selects whether the incoming and outgoing signals are running in 1/2 rate or 1/4 rate Loopback mode.

NOTE 9 For External CH_A and External CH_B ports, the Host must ensure this bit's setting is consistent with the Loopback signal rate received at the DLBD_N/DLBS_N pins selected in RW26[2:0]. The DDR5RCD05 device is allowed to use the information contained in this bit to configure its External Loopback circuitry.

NOTE 10 The 1/2 rate loopback feature is supported up to DDR5-4800. It is not required above DDR5-4800.

NOTE 11 When RW27[7]=0, Phase A is selected; and when RW27[7]=1, Phase C is selected. Phase C is only supported in 1/4 rate mode (i.e., RW26[6] = '1').

NOTE 12 When RW27[7]=0, Phase B is selected; and when RW27[7]=1, Phase D is selected. Phase D is only supported in 1/4 rate mode (i.e., RW26[6] = '1').

7.16.2 RW27 - Loop-back I/O Global Control Word

Table 122 — RW27: Loop-back I/O Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	RX DLBS Termination	60 Ω
x	x	x	x	x	x	0	1		80 Ω
x	x	x	x	x	x	1	0		40 Ω
x	x	x	x	x	x	1	1		OFF
x	x	x	x	0	0	x	x	RX DLBD Termination	60 Ω
x	x	x	x	0	1	x	x		80 Ω
x	x	x	x	1	0	x	x		40 Ω
x	x	x	x	1	1	x	x		OFF
x	x	0	0	x	x	x	x	TX QLBS and QLBD Drive Strength	RZQ/5 (48 Ω)
x	x	0	1	x	x	x	x		RZQ/7 (34 Ω)
x	x	1	0	x	x	x	x		Reserved
x	x	1	1	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Internal Loopback upper Phase Select for 1/4 Rate ¹	RW26[7] selects between lower phases A and B
1	x	x	x	x	x	x	x		RW26[7] selects between upper phases C and D

NOTE 1 This control bit has no effect unless Internal Loopback is running in 1/4 rate mode (i.e., RW26[2:0] is programmed to '001' or '010' and RW26[6] to 1). This bit must be programmed to 0 in 1/2 Rate mode.

7.17 SidebandBus Error Status

7.17.1 RW28: I²C and I3C Basic Error Status Global Word

Table 123 — RW28: I²C and I3C Basic Error Status Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Error in Parity Check ^{1,2,3}	No PARITY error has been detected
x	x	x	x	x	x	x	1		PARITY error has been detected ⁴
x	x	x	x	x	x	0	x	Error in Packet Error Code Check ^{1,2,5}	No PEC error has been detected
x	x	x	x	x	x	1	x		PEC error has been detected ⁶
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Device Event In-Band Interrupt Status ¹	No Pending IBI ⁷
1	x	x	x	x	x	x	x		Pending IBI ⁸

NOTE 1 This is a Read-Only Status bit. This is a Sticky register (not cleared by DRST_n).

NOTE 2 This register is automatically cleared to '0' when the Timeout Reset condition described in Clause 6.8, "I2C Bus Error Handling" is detected.

NOTE 3 This status bit only applies when I3C Basic mode is enabled or for CCC supported in I²C mode, provided that the Parity Checking function is not disabled.

NOTE 4 The RCD device detected a PARITY error in one or more bytes received.

NOTE 5 This status bit only applies when I3C Basic mode is enabled.

NOTE 6 The RCD device detected a PEC error for one or more data packets received. When a PEC error is detected in I²C mode, this status field will not be updated.

NOTE 7 The IBI status bit gets cleared to '0' when the RCD device processes a complete IBI operation (including uninterrupted IBI payload). This status bit also gets cleared when RW28[0] and RW28[1] become '00' after a Clear command in RW29.

NOTE 8 The IBI status bit gets set to '1' when the RCD sets RW28[0] or RW28[1] to '1' after detecting a Parity Error or a PEC Error.

7.17.2 RW29: I²C and I3C Basic Clear Error Status Global Word

Table 124 — RW29: I²C and I3C Basic Clear Error Status Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Clear Parity Error Status ¹	No effect.
x	x	x	x	x	x	x	1		Clear RW28[0].
x	x	x	x	x	x	0	x	Clear Packet Error Status ¹	No effect.
x	x	x	x	x	x	1	x		Clear RW28[1].
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This is a Write-1 Only register bit, and it self-clears after the target status register has been cleared.

7.17.3 RW2A: Vendor Specific Global Word

Table 125 — RW2A: Vendor Specific Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Reserved	Reserved
x	x	x	x	x	x	x	1		Reserved
x	x	x	x	0	0	0	x	Vendor Specific	Vendor Specific
x	x	x	x	0	0	1	x		Vendor Specific
x	x	x	x	0	1	0	x		Vendor Specific
x	x	x	x	0	1	1	x		Vendor Specific
x	x	x	x	1	0	0	x		Vendor Specific
x	x	x	x	1	0	1	x		Vendor Specific
x	x	x	x	1	1	0	x		Vendor Specific
x	x	x	x	1	1	1	x		Vendor Specific
x	x	x	0	x	x	x	x		Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

7.17.4 RW2B: DRST_n Mask Global Control Word

Table 126 — RW2B: DRST_n Mask Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DRST_n Masking Enable ¹	(Default) Masking disabled. DRST_n in normal operation.
x	x	x	x	x	x	x	1		Masking Enabled, DRST_n input is ignored. No QRST_n assertion due to DRST_n assertion, no reset in the device.
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x	Reserved	Reserved
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x	Reserved	Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x	Reserved	Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x	Reserved	Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x	Reserved	Reserved

NOTE 1 This bit is sticky and cleared by power cycle not reset.

7.18 DFE Control Words

7.18.1 RW2D - 16-bit LFSR Seed for DFE Training Mode Lower Byte Control Word

Table 127 — RW2D 16-bit LFSR Seed for DFE Training Mode Lower Byte Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	16-bit LFSR Seed - Lower Byte	LFSR Seed = xx00h
0	0	0	0	0	0	0	1		LFSR Seed = xx01h
0	0	0	0	0	0	1	0		LFSR Seed = xx02h
...									...
1	1	1	1	1	1	0	0		LFSR Seed = xxFCh
1	1	1	1	1	1	0	1		LFSR Seed = xxFDh
1	1	1	1	1	1	1	0		LFSR Seed = xxFEh
1	1	1	1	1	1	1	1		LFSR Seed = xxFFh

7.18.2 RW2E - 16-bit LFSR Seed for DFE Training Mode Upper Byte Control Word

Table 128 — RW2E 16-bit LFSR Seed for DFE Training Mode Upper Byte Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	16-bit LFSR Seed - Upper Byte	LFSR Seed = 00xxh
0	0	0	0	0	0	0	1		LFSR Seed = 01xxh
0	0	0	0	0	0	1	0		LFSR Seed = 02xxh
...									...
1	1	1	1	1	1	0	0		LFSR Seed = FCxxh
1	1	1	1	1	1	0	1		LFSR Seed = FDxxh
1	1	1	1	1	1	1	0		LFSR Seed = FExxh
1	1	1	1	1	1	1	1		LFSR Seed = FFxxh

7.18.3 RW2F - LFSR State for DFE Training Mode Control Word Upper Byte

Table 129 — RW2F LFSR State for DFE Training Mode Control Word Upper Byte

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	When the 8-bit LFSR is used for DFE Training: Reserved	LFSR State = 0x00*
0	0	0	0	0	0	0	1		LFSR State = 0x01
0	0	0	0	0	0	1	0		LFSR State = 0x02
...								When the 16-bit LFSR is used for DFE Training: LFSR State - Upper Byte (Read Only) ¹	...
1	1	1	1	1	1	0	0		LFSR State = 0xFC
1	1	1	1	1	1	0	1		LFSR State = 0xFD
1	1	1	1	1	1	1	0		LFSR State = 0xFE
1	1	1	1	1	1	1	1		LFSR State = 0xFF

NOTE 1 The LFSR State is the internal state of the Galois LFSR. This read only register is used for debug, and tracks the state of the LFSR associated with the selected DCA/DCS signal for training.

7.18.4 RW30 - DFE_Vref Range Limit Global Status Word

Table 130 — RW30: DFE_Vref Range Limit Global Status Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	DFE_Vref Configuration Limit ^{1,2}	Applies to 8 LSB portion of DFE Vref control in PG[2]RW[62,66,6A,6E,72,76,7A,7E] , PG[6]RW[72,76] (Maximum Setting Supported by Device)
0	0	0	0	0	0	0	1		
0	0	0	0	0	0	1	0		
...		
1	1	1	1	1	1	0	1		
1	1	1	1	1	1	1	0		
1	1	1	1	1	1	1	1		

NOTE 1 Read only register. Returns positive limit. DFE_Vref must have a symmetrical range.

NOTE 2 This is a global status word. The status code can only be accessed from CH_A.

7.18.5 RW31 - DFE Configuration Control Word

Table 131 — RW31: DFE Configuration Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCS and DCA DFE Feature Enable Control ²	(Default) DFE and gain features disabled
x	x	x	x	x	x	x	1		DFE and gain features enabled
x	x	x	x	x	x	0	x	DCS and DCA DFE_Vref Enable ³	DFE_Vref Circuitry Disabled
x	x	x	x	x	x	1	x		DFE_Vref Circuitry Enabled
x	x	x	x	x	0	x	x	DCS and DCA ERROR Counter Enable ^{4, 5}	All Error Counters Disabled
x	x	x	x	x	1	x	x		All Error Counters Enabled
x	x	x	x	0	x	x	x	RW Control Word Writes Broadcast	RW Write to selected DCAn or DPAR ⁶
x	x	x	x	1	x	x	x		RW Writes Broadcast to DCA[6:0] and DPAR ⁷
x	x	x	0	x	x	x	x	Tap 1 Enable ⁸	(Default) Tap 1 disabled
x	x	x	1	x	x	x	x		Tap 1 enabled
x	x	0	x	x	x	x	x	Tap 2 Enable ⁸	(Default) Tap 2 disabled
x	x	1	x	x	x	x	x		Tap 2 enabled
x	0	x	x	x	x	x	x	Tap 3 Enable ⁸	(Default) Tap 3 disabled
x	1	x	x	x	x	x	x		Tap 3 enabled
0	x	x	x	x	x	x	x	Tap 4 Enable ⁸	(Default) Tap 4 disabled
1	x	x	x	x	x	x	x		Tap 4 enabled

NOTE 1 [RW31\[7:0\]](#) will be sticky, cleared by power cycle not Reset.

NOTE 2 This control bit enables DFE circuitry in the RCD.

NOTE 3 To save power, the Host can keep DFE_VREF circuitry disabled when not in use.

NOTE 4 Error Counter Reset is located [RW04](#). CMD 11 for CH_A and CMD 12 for CH_B.

NOTE 5 Avoid changing DFE settings when the error counters are enabled, or reset the error counters after DFE settings are updated.

NOTE 6 When [RW31\[3\]](#) = 0, RW Writes to [PG\[2:0\]](#) are written to a specific receiver selected in MRW command.

NOTE 7 When [RW31\[3\]](#) = 1, RW Writes to any of the DCn Gain, Tap, and DFE_Vref registers in [PG\[2:0\]](#) are written to all DCA receivers DCA[6:0] and DPAR.

NOTE 8 Enables Tap in DPAR and DCA[6:0] receivers.

7.18.6 RW32 - DCS, DPAR and DCA[6:0] DFE Training Mode Control Word**Table 132 — RW32 DCS, DPAR and DCA[6:0] DFE Training Mode Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Global DFE Training Mode Enable ¹	DFE Training Mode disabled
x	x	x	x	x	x	x	1		DFE Training Mode enabled ^{2,3}
x	x	x	x	x	0	0	x	Training Source	Monitor
x	x	x	x	x	0	1	x		Monitor XOR Slicer Output
x	x	x	x	x	1	0	x		LFSR XOR Monitor
x	x	x	x	x	1	1	x		Reserved
x	x	0	0	0	x	x	x	DCS and DCn DFE pin selection ⁴	DCA0 if RW33[5]=0, or DCS0_n if RW33[5]=1
x	x	0	0	1	x	x	x		DCA1 if RW33[5]=0, or DCS1_n if RW33[5]=1
x	x	0	1	0	x	x	x		DCA2 if RW33[5]=0, or Reserved if RW33[5]=1
x	x	0	1	1	x	x	x		DCA3 if RW33[5]=0, or Reserved if RW33[5]=1
x	x	1	0	0	x	x	x		DCA4 if RW33[5]=0, or Reserved if RW33[5]=1
x	x	1	0	1	x	x	x		DCA5 if RW33[5]=0, or Reserved if RW33[5]=1
x	x	1	1	0	x	x	x		DCA6 if RW33[5]=0, or Reserved if RW33[5]=1
x	x	1	1	1	x	x	x		DPAR if RW33[5]=0, or Reserved if RW33[5]=1
x	0	x	x	x	x	x	x	RW In-Band Update Feature Enable ⁵	(Default) Feature disabled. ⁶
x	1	x	x	x	x	x	x		Feature enabled. ⁷
0	x	x	x	x	x	x	x	Exit From RW In-Band Updated Mode ⁵	No action.
1	x	x	x	x	x	x	x		(Default) Take the RCD out from RWUPD state. ⁸

NOTE 1 RW32[5:3] determines the target receiver for DCS and DCA DFE training.

NOTE 2 DFE circuits are configured into training mode for selected pin RW32[5:3].

NOTE 3 Vref generator circuits are configured so that a DFE training reference voltage (DFE_Vref) is controlled by PG[2]RW[62, 66, 6A, 6E, 72, 76, 7A, 7E].

NOTE 4 Logic in DDR5RCD05 device ensures that only one DCS or DCAn receiver is configured in training mode at any given time.

NOTE 5 Default state of RW32[6] is 0, and the default state of RW32[7] is 1.

NOTE 6 DCS1_n ignored during DFE training.

NOTE 7 DCS1_n Low pulse received in idle state of DFE training triggers entry into RW Update Mode.

NOTE 8 Writing a 1 in this bit location takes the RCD out from RWUPD state. The RCD hardware clears this register bit upon entry to RWUPD mode when DCS1_n Low pulse is received. Therefore, a setting RW32[7] = 1 indicates the channel is not in RWUPD mode.

7.18.7 RW33 - Additional Filtering for DFE Training Mode Control Word

Table 133 — RW33 Additional Filtering for DFE Training Mode Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	UI Filtering Enable	UI Filter Disabled
x	x	x	x	x	x	0	1		Enable Per UI Filtering according to OP[4:2]
x	x	x	x	x	x	1	0		Enable Even UI Filtering ¹
x	x	x	x	x	x	1	1		Enable Odd UI Filtering ¹
x	x	x	0	0	0	x	x	Per-UI filtering ²	UI 0
x	x	x	0	0	1	x	x		UI 1
x	x	x	0	1	0	x	x		UI 2
x	x	x	0	1	1	x	x		UI 3
x	x	x	1	0	0	x	x		UI 4
x	x	x	1	0	1	x	x		UI 5
x	x	x	1	1	0	x	x		UI 6
x	x	x	1	1	1	x	x		UI 7
x	x	0	x	x	x	x	x	Extended Pin Selection for DFE Training Mode	Lower Set (DCA)
x	x	1	x	x	x	x	x		Upper Set (DCS)
x	0	x	x	x	x	x	x	Tap 5 Enable ^{3,4}	(Default) Tap 5 disabled
x	1	x	x	x	x	x	x		Tap 5 enabled
0	x	x	x	x	x	x	x	Tap 6 Enable ^{4,5}	(Default) Tap 6 disabled
1	x	x	x	x	x	x	x		Tap 6 enabled

NOTE 1 When selected OP[4:2] is ignored by the DDR5RCD05.

NOTE 2 UI filtering applies to the results in the error counter.

NOTE 3 RW33[6] will be sticky, cleared by power cycle not Reset.

NOTE 4 Enables Tap in DPAR and DCA[6:0] receivers.

NOTE 5 RW33[7] will be sticky, cleared by power cycle not Reset.

7.18.8 RW34 - LFSR DFE Training Mode Control Word

Table 134 — RW34 LFSR DFE Training Mode Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DFE Training Accelerator	Stop DFE Training Accelerator
x	x	x	x	x	x	x	1		Start DFE Training Accelerator
x	x	x	x	x	x	0	x	DFE LFSR selection	(Default) LFSR8 is selected for DCA and DCS DFE Training
x	x	x	x	x	x	1	x		LFSR16 is selected for DCA and DCS DFE Training
x	x	x	x	0	0	x	x	Select Inner Loop Parameter	Select Inner Loop Parameter - NULL ¹
x	x	x	x	0	1	x	x		Select Inner Loop Parameter - DCS or DCA DFE_Vref
x	x	x	x	1	0	x	x		Select Inner Loop Parameter - VrefCS or VrefCA
x	x	x	x	1	1	x	x		Reserved
x	0	0	0	x	x	x	x	Select Outer Loop Parameter	Select Outer Loop Parameter - NULL
x	0	0	1	x	x	x	x		Select Outer Loop Parameter - Tap 1
x	0	1	0	x	x	x	x		Select Outer Loop Parameter - Tap 2
x	0	1	1	x	x	x	x		Select Outer Loop Parameter - Tap 3
x	1	0	0	x	x	x	x		Select Outer Loop Parameter - Tap 4
x	1	0	1	x	x	x	x		Select Outer Loop Parameter - UI
x	1	1	0	x	x	x	x		Select Outer Loop Parameter - Tap 5
x	1	1	1	x	x	x	x		Select Outer Loop Parameter - Tap 6
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 NULL parameter choice means no change. NULL parameter loop can have multiple iterations.

7.18.9 RW35 - LFSR State for DFE Training Mode Control Word Lower Byte

Table 135 — RW35 LFSR State for DFE Training Mode Control Word Lower Byte

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	When the 8-bit LFSR is used for DFE Training: LFSR State	LFSR State = 0x00*
0	0	0	0	0	0	0	1		LFSR State = 0x01
0	0	0	0	0	0	1	0		LFSR State = 0x02
...								When the 16-bit LFSR is used for DFE Training: LFSR State - Lower Byte (Read Only) ¹	...
1	1	1	1	1	1	0	0		LFSR State = 0xFC
1	1	1	1	1	1	0	1		LFSR State = 0xFD
1	1	1	1	1	1	1	0		LFSR State = 0xFE
1	1	1	1	1	1	1	1		LFSR State = 0xFF

NOTE 1 The LFSR State is the internal state of the Galois LFSR. This read only register is used for debug, and tracks the state of the LFSR associated with the selected DCA/DCS signal for training.

7.18.10 RW36 - DFETM Inner Loop Start Value Control Word**Table 136 — RW36 DFETM Inner Loop Start Value Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Inner Loop Start Value ^{1,2}	Inner Loop Start Value = 0x00
0	0	0	0	0	0	0	1		Inner Loop Start Value = 0x01
0	0	0	0	0	0	1	0		Inner Loop Start Value = 0x02
...									...
1	1	1	1	1	1	0	0		Inner Loop Start Value = 0xFC
1	1	1	1	1	1	0	1		Inner Loop Start Value = 0xFD
1	1	1	1	1	1	1	0		Inner Loop Start Value = 0xFE
1	1	1	1	1	1	1	1		Inner Loop Start Value = 0xFF

NOTE 1 Depending on the Inner Loop Parameter Selection, the range may be limited. The DFE Accelerator will only apply the OP bits that are within range for the specific Inner Loop Parameter.

NOTE 2 Even though the tap setting parameter registers are defined as signed magnitude fields, this start value is a two's complement encoding. The RCD must convert this value to a signed magnitude format prior to updating the DFE_Vref when DFE_Vref is chosen for the Inner Loop Parameter.

7.18.11 RW37 - DFETM Outer Loop Start Value Control Word**Table 137 — RW37 DFETM Outer Loop Start Value Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	0	0	0	0	0	0	0	Outer Loop Start Value ^{1,2}	Outer Loop Start Value = 0x00
x	0	0	0	0	0	0	1		Outer Loop Start Value = 0x01
x	0	0	0	0	0	1	0		Outer Loop Start Value = 0x02
x
x	1	1	1	1	1	0	0		Outer Loop Start Value = 0x7C
x	1	1	1	1	1	0	1		Outer Loop Start Value = 0x7D
x	1	1	1	1	1	1	0		Outer Loop Start Value = 0x7E
x	1	1	1	1	1	1	1		Outer Loop Start Value = 0x7F
0	x	x	x	x	x	x	x	RW[36] Inner Loop Start	Inner Loop Start Value[8] = 0
1	x	x	x	x	x	x	x	Value ^{3,4}	Inner Loop Start Value[8] = 1

NOTE 1 Depending on the Outer Loop Parameter Selection, the range may be limited. The DFE Accelerator will only apply the OP bits that are within range for the specific Outer Loop Parameter.

NOTE 2 Even though the tap setting parameter registers are defined as signed magnitude fields, this start value is a two's complement encoding. The RCD must convert this value to a signed magnitude format prior to updating the tap setting when Tap1, Tap2, Tap3, or Tap4 is chosen for the Outer Loop Parameter.

NOTE 3 Depending on the Inner Loop Parameter Selection, the range may be limited. The DFE Accelerator will only apply the OP bits that are within range for the specific Inner Loop Parameter.

NOTE 4 Even though the tap setting parameter registers are defined as signed magnitude fields, this start value is a two's complement encoding. The RCD must convert this value to a signed magnitude format prior to updating the DFE_Vref when DFE_Vref is chosen for the Inner Loop Parameter.

7.18.12 RW38 - DFETM Inner Loop Current Value Control Word

Table 138 — RW38 DFETM Inner Loop Current Value Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Inner Loop Current Value (Read Only)	Inner Loop Current Value = 0x00
0	0	0	0	0	0	0	1		Inner Loop Current Value = 0x01
0	0	0	0	0	0	1	0		Inner Loop Current Value = 0x02
...									...
1	1	1	1	1	1	0	0		Inner Loop Current Value = 0xFC
1	1	1	1	1	1	0	1		Inner Loop Current Value = 0xFD
1	1	1	1	1	1	1	0		Inner Loop Current Value = 0xFE
1	1	1	1	1	1	1	1		Inner Loop Current Value = 0xFF

7.18.13 RW39 - DFETM Outer Loop Current Value Control Word

Table 139 — RW39 DFETM Outer Loop Current Value Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	0	0	0	0	0	0	0	Outer Loop Current Value (Read Only)	Outer Loop Current Value = 0x00
x	0	0	0	0	0	0	1		Outer Loop Current Value = 0x01
x	0	0	0	0	0	1	0		Outer Loop Current Value = 0x02
x
x	1	1	1	1	1	0	0		Outer Loop Current Value = 0x7C
x	1	1	1	1	1	0	1		Outer Loop Current Value = 0x7D
x	1	1	1	1	1	1	0		Outer Loop Current Value = 0x7E
x	1	1	1	1	1	1	1		Outer Loop Current Value = 0x7F
0	x	x	x	x	x	x	x	RW38[8] Inner Loop	Inner Loop Current Value[8] = 0
1	x	x	x	x	x	x	x	Current Value (Read Only)	Inner Loop Current Value[8] = 1

7.18.14 RW3A - DFETM Inner and Outer Loop Step Size Control Word**Table 140 — RW3A DFETM Inner and Outer Loop Step Size Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	Inner Loop Step Size ¹	Inner Loop Step Size = 1
x	x	x	x	0	0	0	1		Inner Loop Step Size = 2
x	x	x	x	0	0	1	0		Inner Loop Step Size = 3
x	x	x	x	0	0	1	1		Inner Loop Step Size = 4
x	x	x	x	0	1	0	0		Inner Loop Step Size = 5
x	x	x	x	0	1	0	1		Inner Loop Step Size = 6
x	x	x	x	0	1	1	0		Inner Loop Step Size = 7
x	x	x	x	0	1	1	1		Inner Loop Step Size = 8
x	x	x	x	1	0	0	0		Inner Loop Step Size = 9
x	x	x	x	1	0	0	1		Inner Loop Step Size = 10
x	x	x	x	1	0	1	0		Inner Loop Step Size = 11
x	x	x	x	1	0	1	1		Inner Loop Step Size = 12
x	x	x	x	1	1	0	0		Inner Loop Step Size = 13
x	x	x	x	1	1	0	1		Inner Loop Step Size = 14
x	x	x	x	1	1	1	0		Inner Loop Step Size = 15
x	x	x	x	1	1	1	1		Inner Loop Step Size = 16
0	0	0	0	x	x	x	x	Outer Loop Step Size ¹	Outer Loop Step Size = 1
0	0	0	1	x	x	x	x		Outer Loop Step Size = 2
0	0	1	0	x	x	x	x		Outer Loop Step Size = 3
0	0	1	1	x	x	x	x		Outer Loop Step Size = 4
0	1	0	0	x	x	x	x		Outer Loop Step Size = 5
0	1	0	1	x	x	x	x		Outer Loop Step Size = 6
0	1	1	0	x	x	x	x		Outer Loop Step Size = 7
0	1	1	1	x	x	x	x		Outer Loop Step Size = 8
1	0	0	0	x	x	x	x		Outer Loop Step Size = 9
1	0	0	1	x	x	x	x		Outer Loop Step Size = 10
1	0	1	0	x	x	x	x		Outer Loop Step Size = 11
1	0	1	1	x	x	x	x		Outer Loop Step Size = 12
1	1	0	0	x	x	x	x		Outer Loop Step Size = 13
1	1	0	1	x	x	x	x		Outer Loop Step Size = 14
1	1	1	0	x	x	x	x		Outer Loop Step Size = 15
1	1	1	1	x	x	x	x		Outer Loop Step Size = 16

NOTE 1 The step size is always positive, and thus the increment is always from lowest to highest value in the sweep. Note that the actual field setting indicates the Step Size – 1. The RCD must account for this in the increment logic.

7.18.15 RW3B - DFETM Inner Loop Number of Increments Control Word

Table 141 — RW3B DFETM Inner Loop Number of Increments Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Inner Loop Number of Increments ¹	Inner Loop Number of Increments = 0x00
0	0	0	0	0	0	0	1		Inner Loop Number of Increments = 0x01
0	0	0	0	0	0	1	0		Inner Loop Number of Increments = 0x02
...									...
1	1	1	1	1	1	0	0		Inner Loop Number of Increments = 0xFC
1	1	1	1	1	1	0	1		Inner Loop Number of Increments = 0xFD
1	1	1	1	1	1	1	0		Inner Loop Number of Increments = 0xFE
1	1	1	1	1	1	1	1		Inner Loop Number of Increments = 0xFF

NOTE 1 Depending on the Inner Loop Parameter Selection and the Inner Loop Step Size, the range may be limited. The DFE Accelerator will only apply the OP bits that are within range for the specific Inner Loop Parameter. When the Number of Increments = 0x00, the Start Value will be applied for a single iteration of the loop.

7.18.16 RW3C - DFETM Outer Loop Number of Increments Control Word

Table 142 — RW3C DFETM Outer Loop Number of Increments Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	0	0	0	0	0	0	0	Outer Loop Number of Increments ¹	Outer Loop Number of Increments = 0x00
x	0	0	0	0	0	0	1		Outer Loop Number of Increments = 0x01
x	0	0	0	0	0	1	0		Outer Loop Number of Increments = 0x02
x
x	1	1	1	1	1	0	0		Outer Loop Number of Increments = 0x7C
x	1	1	1	1	1	0	1		Outer Loop Number of Increments = 0x7D
x	1	1	1	1	1	1	0		Outer Loop Number of Increments = 0x7E
x	1	1	1	1	1	1	1		Outer Loop Number of Increments = 0x7F
0	x	x	x	x	x	x	x	RW3B[8] Inner Loop	Inner Loop Number of Increments = 0
1	x	x	x	x	x	x	x	Number of Increments ²	Inner Loop Number of Increments = 1

NOTE 1 Depending on the Outer Loop Parameter Selection and the Outer Loop Step Size, the range may be limited. The DFE Accelerator will only apply the OP bits that are within range for the specific Outer Loop Parameter. When the Number of Increments = 0x00, the Start Value will be applied for a single iteration of the loop.

NOTE 2 Depending on the Inner Loop Parameter Selection and the Inner Loop Step Size, the range may be limited. The DFE Accelerator will only apply the OP bits that are within range for the specific Inner Loop Parameter. When the Number of Increments = 0x00, the Start Value will be applied for a single iteration of the loop.

7.18.17 RW3D - DFETM Inner Loop Current Increment Control Word**Table 143 — RW3D DFETM Inner Loop Current Increment Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Inner Loop Current Increment (Read Only)	Inner Loop Current Increment = 0x00
0	0	0	0	0	0	0	1		Inner Loop Current Increment = 0x01
0	0	0	0	0	0	1	0		Inner Loop Current Increment = 0x02
...									...
1	1	1	1	1	1	0	0		Inner Loop Current Increment = 0xFC
1	1	1	1	1	1	0	1		Inner Loop Current Increment = 0xFD
1	1	1	1	1	1	1	0		Inner Loop Current Increment = 0xFE
1	1	1	1	1	1	1	1		Inner Loop Current Increment = 0xFF

7.18.18 RW3E - DFETM Outer Loop Current Increment Control Word**Table 144 — RW3E DFETM Outer Loop Current Increment Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	0	0	0	0	0	0	0	Outer Loop Current Increment (Read Only)	Outer Loop Current Increment = 0x00
x	0	0	0	0	0	0	1		Outer Loop Current Increment = 0x01
x	0	0	0	0	0	1	0		Outer Loop Current Increment = 0x02
x
x	1	1	1	1	1	0	0		Outer Loop Current Increment = 0x7C
x	1	1	1	1	1	0	1		Outer Loop Current Increment = 0x7D
x	1	1	1	1	1	1	0		Outer Loop Current Increment = 0x7E
x	1	1	1	1	1	1	1		Outer Loop Current Increment = 0x7F
0	x	x	x	x	x	x	x	RW3D[8] Inner Loop Current Increment (Read Only)	Inner Loop Current Increment = 0
1	x	x	x	x	x	x	x		Inner Loop Current Increment = 1

7.18.19 RW3F - DFE Vref Range Selection Control Word

Table 145 — RW3F DFE Vref Range Selection Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCA0	Positive
x	x	x	x	x	x	x	1		Negative
x	x	x	x	x	x	0	x	DCA1	Positive
x	x	x	x	x	x	1	x		Negative
x	x	x	x	x	0	x	x	DCA2	Positive
x	x	x	x	x	1	x	x		Negative
x	x	x	x	0	x	x	x	DCA3	Positive
x	x	x	x	1	x	x	x		Negative
x	x	x	0	x	x	x	x	DCA4	Positive
x	x	x	1	x	x	x	x		Negative
x	x	0	x	x	x	x	x	DCA5	Positive
x	x	1	x	x	x	x	x		Negative
x	0	x	x	x	x	x	x	DCA6	Positive
x	1	x	x	x	x	x	x		Negative
0	x	x	x	x	x	x	x	DPA0	Positive
1	x	x	x	x	x	x	x		Negative

NOTE 1 RW3F selects the sign for DFE_Vref registers located in PG[2]RW[62, 66, 6A, 6E, 72, 76, 7A, 7E].

7.19 Vref Control Words

7.19.1 RW[47:40] - Internal VrefCA Control Word

Table 146 — RW[47:40]: Internal VrefCA Control Word^{1,2}

Setting								Definition	Encoding VrefCA as% of V _{DD} ³
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	0	0	0	0	0	0	0	Internal VrefCA Control	97.5%
x	0	0	0	0	0	0	1		97.0%
x	0	0	0	0	0	1	0		96.5%
x	0	0	0	0	0	1	1		96.0%
x	0	0	0	0	1	0	0		95.5%
x	0	0	0	0	1	0	1		95.0%
x	0	0	0	0	1	1	0		94.5%
x	0	0	0	0	1	1	1		94.0%
x
x	0	1	0	1	1	0	1		75% (Default)
x
x	1	1	0	0	0	0	1		49.0%
x	1	1	0	0	0	1	0		48.5%
x	1	1	0	0	0	1	1		48.0%
x	1	1	0	0	1	0	0		47.5%
x	1	1	0	0	1	0	1		47.0%
x	1	1	0	0	1	1	0		46.5%
x	1	1	0	0	1	1	1		46.0%
x	1	1	0	1	0	0	0		45.5%
x	1	1	0	1	0	0	1		45.0%
x	1	1	0	1	0	1	0		Reserved
x	1	1	0	1	0	1	1		Reserved
x	...								Reserved
x	1	1	1	1	1	1	1		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 RW[47:40] OP[6:0] will be sticky, cleared by power cycle not Reset.

NOTE 2 Table 81 illustrates the assignment of each control word in the RW[47:40] group to the corresponding input pin it controls.

NOTE 3 These are target VrefCA values. Acceptable actual values are determined based on tolerances defined in electrical section.

7.19.2 RW[49:48] - Internal VrefCS Control Word

Table 147 — RW[49:48]: Internal VrefCS Control Word^{1,2}

Setting								Definition	Encoding VrefCS as% of V _{DD} ³
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	0	0	0	0	0	0	0	Internal VrefCS Control	97.5%
x	0	0	0	0	0	0	1		97.0%
x	0	0	0	0	0	1	0		96.5%
x	0	0	0	0	0	1	1		96.0%
x	0	0	0	0	1	0	0		95.5%
x	0	0	0	0	1	0	1		95.0%
x	0	0	0	0	1	1	0		94.5%
x	0	0	0	0	1	1	1		94.0%
x
x	0	1	0	1	1	0	1		75% (Default)
x
x	1	1	0	0	0	0	1		49.0%
x	1	1	0	0	0	1	0		48.5%
x	1	1	0	0	0	1	1		48.0%
x	1	1	0	0	1	0	0		47.5%
x	1	1	0	0	1	0	1		47.0%
x	1	1	0	0	1	1	0		46.5%
x	1	1	0	0	1	1	1		46.0%
x	1	1	0	1	0	0	0		45.5%
x	1	1	0	1	0	0	1		45.0%
x	1	1	0	1	0	1	0		Reserved
x	1	1	0	1	0	1	1		Reserved
x	...								Reserved
x	1	1	1	1	1	1	1		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 RW[49:48] OP[6:0] will be sticky, cleared by power cycle not Reset.

NOTE 2 Table 81 illustrates the assignment of each control word in the RW[49:48] group to the corresponding input pin it controls.

NOTE 3 These are target VrefCS values. Acceptable actual values are determined based on tolerances defined in electrical section.

7.19.3 RW4A - DERROR_IN_n Vref Control Word

Table 148 — RW4A: DERROR_IN_n Vref Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	0	0	0	DERROR_IN_n Vref Control	0.80 x V _{DD} (Default)
x	x	x	x	x	0	0	1		0.75 x V _{DD}
x	x	x	x	x	0	1	0		0.70 x V _{DD}
x	x	x	x	x	0	1	1		0.60 x V _{DD}
x	x	x	x	x	1	0	0		Reserved
x	x	x	x	x	1	0	1		Reserved
x	x	x	x	x	1	1	0		Reserved
x	x	x	x	x	1	1	1		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

7.20 Loop-Back Vref and Input Delay Control

7.20.1 RW4B - Loop-Back Vref Control Word

Table 149 — RW4B: Loop-Back Vref Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	DLBS Vref Control	0.80 x V _{DD} (Default)
x	x	x	x	0	0	0	1		0.75 x V _{DD}
x	x	x	x	0	0	1	0		0.70 x V _{DD}
x	x	x	x	0	0	1	1		0.60 x V _{DD}
x	x	x	x	0	1	0	0		0.875 x VDD
x	x	x	x	0	1	0	1		0.85 x VDD
x	x	x	x	0	1	1	0		0.825 x VDD
x	x	x	x	0	1	1	1		0.775 x VDD
x	x	x	x	1	0	0	0		0.725 x VDD
x	x	x	x	1	0	0	1		0.675 x VDD
x	x	x	x	1	0	1	0		0.65 x VDD
x	x	x	x	1	0	1	1		0.625 x VDD
x	x	x	x	1	1	0	0		0.575 x VDD
x	x	x	x	1	1	0	1		0.55 x VDD
x	x	x	x	1	1	1	0		0.525 x VDD
x	x	x	x	1	1	1	1		0.5 x VDD
0	0	0	0	x	x	x	x	DLBD Vref Control	0.80 x V _{DD} (Default)
0	0	0	1	x	x	x	x		0.75 x V _{DD}
0	0	1	0	x	x	x	x		0.70 x V _{DD}
0	0	1	1	x	x	x	x		0.60 x V _{DD}
0	1	0	0	x	x	x	x		0.875 x VDD
0	1	0	1	x	x	x	x		0.85 x VDD
0	1	1	0	x	x	x	x		0.825 x VDD
0	1	1	1	x	x	x	x		0.775 x VDD
1	0	0	0	x	x	x	x		0.725 x VDD
1	0	0	1	x	x	x	x		0.675 x VDD
1	0	1	0	x	x	x	x		0.65 x VDD
1	0	1	1	x	x	x	x		0.625 x VDD
1	1	0	0	x	x	x	x		0.575 x VDD
1	1	0	1	x	x	x	x		0.55 x VDD
1	1	1	0	x	x	x	x		0.525 x VDD
1	1	1	1	x	x	x	x		0.5 x VDD

7.20.2 RW4C - Loop-Back Input Delay Control Word

Table 150 — RW4C: Loop-Back Input Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	DLBS Input Delay Control	No delay (Default)
x	x	x	x	x	x	0	1		Delay DLBS input signal by 20ps ¹
x	x	x	x	x	x	1	0		Delay DLBS input signal by 40ps ¹
x	x	x	x	x	x	1	1		Delay DLBS input signal by 60ps ¹
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	0	0	x	x	x	x	DLBD Input Delay Control	No delay (Default)
x	x	0	1	x	x	x	x		Delay DLBD input signal by 20ps ¹
x	x	1	0	x	x	x	x		Delay DLBD input signal by 40ps ¹
x	x	1	1	x	x	x	x		Delay DLBD input signal by 60ps ¹
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 Allowed tolerance of the delay is +/- 35% of the set delay value.

7.20.3 RW4D - DCA Selection in the Enhanced DCATM XOR Control Word

Table 151 — RW4D¹: DCA Selection in the Enhanced DCATM XOR Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCA0 included in XOR	(Default) Not included
x	x	x	x	x	x	x	1		Included
x	x	x	x	x	x	0	x	DCA1 included in XOR	(Default) Not included
x	x	x	x	x	x	1	x		Included
x	x	x	x	x	0	x	x	DCA2 included in XOR	(Default) Not included
x	x	x	x	x	1	x	x		Included
x	x	x	x	0	x	x	x	DCA3 included in XOR	(Default) Not included
x	x	x	x	1	x	x	x		Included
x	x	x	0	x	x	x	x	DCA4 included in XOR	(Default) Not included
x	x	x	1	x	x	x	x		Included
x	x	0	x	x	x	x	x	DCA5 included in XOR	(Default) Not included
x	x	1	x	x	x	x	x		Included
x	0	x	x	x	x	x	x	DCA6 included in XOR	(Default) Not included
x	1	x	x	x	x	x	x		Included
0	x	x	x	x	x	x	x	DPA0 included in XOR	(Default) Not included
1	x	x	x	x	x	x	x		Included

NOTE 1 The settings in RW4D[7:0] are valid only when the Enhanced DCATM is enabled in RW02[7]. During the Enhanced DCATM procedure, the Host will not update the settings in RW4D[7:0].

7.20.4 RW4E - DCS Selection in the Enhanced DCATM XOR Control Word

Table 152 — RW4E¹: DCS Selection in the Enhanced DCATM XOR Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCS0 included in XOR	(Default) Not included
x	x	x	x	x	x	x	1		Included ²
x	x	x	x	x	x	0	x	DCS1 included in XOR	(Default) Not included
x	x	x	x	x	x	1	x		Included ²
x	x	x	x	x	0	x	x	Control (or Qualifier) signal selection ³	(Default) DCS0
x	x	x	x	x	1	x	x		DCS1
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 The settings in RW4E[2:0] are valid only when the Enhanced DCATM is enabled in RW02[7]. During the Enhanced DCATM procedure, the Host will not update the settings in RW4E[2:0].

NOTE 2 If DCS is included in the XOR, the sampling edge on RW02[5:4] should be set to rising edge only.

NOTE 3 Selected signal must not be enabled as part of the XOR computation. Host is responsible for setting this up correctly.

7.21 CTLE Control Words

7.21.1 RW50 - CTLE Configuration Global Control Word

Table 153 — RW50 - CTLE Configuration Global Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	CTLE Feature Enable Control	(Default) CTLE feature disabled in all pins
x	x	x	x	x	x	x	1		CTLE feature enabled ²
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x		Reserved
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
0	0	0	x	x	x	x	x	CTLE Configuration Range Status ³ (Read Only Register)	Range A
0	0	1	x	x	x	x	x		Range B
0	1	0	x	x	x	x	x		Range C
0	1	1	x	x	x	x	x		Range D
1	0	0	x	x	x	x	x		Reserved
1	0	1	x	x	x	x	x		Reserved
1	1	0	x	x	x	x	x		Reserved
1	1	1	x	x	x	x	x		Reserved

NOTE 1 [RW50\[0\]](#) will be sticky, cleared by power cycle not reset.

NOTE 2 The CTLE feature can be enabled per pin based on the settings in [RW51\[7:0\]](#).

NOTE 3 The device can only support one of the CTLE Configuration ranges, A, B, C or D. The Host can read out the supported range from [RW50\[7:5\]](#).

7.21.2 RW51 - CTLE Per-Pin Disable Control Word

Table 154 — RW51 - CTLE Per-Pin Disable Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCA0 CTLE Feature Disable	(Default) CTLE enabled in this pin ²
x	x	x	x	x	x	x	1		CTLE disabled in this pin
x	x	x	x	x	x	0	x	DCA1 CTLE Feature Disable	(Default) CTLE enabled in this pin ²
x	x	x	x	x	x	1	x		CTLE disabled in this pin
x	x	x	x	x	0	x	x	DCA2 CTLE Feature Disable	(Default) CTLE enabled in this pin ²
x	x	x	x	x	1	x	x		CTLE disabled in this pin
x	x	x	x	0	x	x	x	DCA3 CTLE Feature Disable	(Default) CTLE enabled in this pin ²
x	x	x	x	1	x	x	x		CTLE disabled in this pin
x	x	x	0	x	x	x	x	DCA4 CTLE Feature Disable	(Default) CTLE enabled in this pin ²
x	x	x	1	x	x	x	x		CTLE disabled in this pin
x	x	0	x	x	x	x	x	DCA5 CTLE Feature Disable	(Default) CTLE enabled in this pin ²
x	x	1	x	x	x	x	x		CTLE disabled in this pin
x	0	x	x	x	x	x	x	DCA6 CTLE Feature Disable	(Default) CTLE enabled in this pin ²
x	1	x	x	x	x	x	x		CTLE disabled in this pin
0	x	x	x	x	x	x	x	DPAR CTLE Feature Disable	(Default) CTLE enabled in this pin ²
1	x	x	x	x	x	x	x		CTLE disabled in this pin

NOTE 1 RW51 will be sticky, cleared by power cycle not reset.

NOTE 2 CTLE will be enabled in the corresponding input pin provided that RW50[0] is set to 1.

7.21.3 RW52 - CTLE Parameter Set A Control Word

Table 155 — RW52 - CTLE Parameter Set A Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	CTLE Parameter Set A Control ²	Select Setting 0 for Parameter Set A
x	x	x	x	0	0	0	1		Select Setting 1 for Parameter Set A
x	x	x	x	0	0	1	0		Select Setting 2 for Parameter Set A
x	x	x	x
x	x	x	x	1	1	0	1		Select Setting 13 for Parameter Set A
x	x	x	x	1	1	1	0		Select Setting 14 for Parameter Set A
x	x	x	x	1	1	1	1		Select Setting 15 for Parameter Set A
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 RW52[3:0] will be sticky, cleared by power cycle not reset.

NOTE 2 Refer to Table 17 for detailed encoding description.

7.21.4 RW53 - CTLE Parameter Set B Control Word

Table 156 — RW53 - CTLE Parameter Set B Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	CTLE Parameter Set B Control ²	Select Setting 0 for Parameter Set B
x	x	x	x	0	0	0	1		Select Setting 1 for Parameter Set B
x	x	x	x	0	0	1	0		Select Setting 2 for Parameter Set B
x	x	x	x
x	x	x	x	1	1	0	1		Select Setting 13 for Parameter Set B
x	x	x	x	1	1	1	0		Select Setting 14 for Parameter Set B
x	x	x	x	1	1	1	1		Select Setting 15 for Parameter Set B
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x	Reserved	Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x	Reserved	Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x	Reserved	Reserved

NOTE 1 [RW53\[3:0\]](#) will be sticky, cleared by power cycle not reset.

NOTE 2 Refer to Table 17 for detailed encoding description.

7.21.5 RW54 - Per-Pin CTLE Parameter Set Selection Control Word

Table 157 — RW54 - Per-Pin CTLE Parameter Set Selection Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCA0 Parameter Set Selection	(Default) Set A Selected
x	x	x	x	x	x	x	1		Set B Selected
x	x	x	x	x	x	0	x	DCA1 Parameter Set Selection	(Default) Set A Selected
x	x	x	x	x	x	1	x		Set B Selected
x	x	x	x	x	0	x	x	DCA2 Parameter Set Selection	(Default) Set A Selected
x	x	x	x	x	1	x	x		Set B Selected
x	x	x	x	0	x	x	x	DCA3 Parameter Set Selection	(Default) Set A Selected
x	x	x	x	1	x	x	x		Set B Selected
x	x	x	0	x	x	x	x	DCA4 Parameter Set Selection	(Default) Set A Selected
x	x	x	1	x	x	x	x		Set B Selected
x	x	0	x	x	x	x	x	DCA5 Parameter Set Selection	(Default) Set A Selected
x	x	1	x	x	x	x	x		Set B Selected
x	0	x	x	x	x	x	x	DCA6 Parameter Set Selection	(Default) Set A Selected
x	1	x	x	x	x	x	x		Set B Selected
0	x	x	x	x	x	x	x	DPAR Parameter Set Selection	(Default) Set A Selected
1	x	x	x	x	x	x	x		Set B Selected

NOTE 1 [RW54](#) will be sticky, cleared by power cycle not reset.

7.22 Read and Paging Control Words

7.22.1 RW5E - CW Read Pointer Control Word

Table 158 — RW5E - CW Read Pointer Control Word

Read Pointer ¹							
OP7	OP6	OP5	OP4	OP3	OP2	OP1	OP0
MRA7 ²	MRA6	MRA5	MRA4	MRA3	MRA2	MRA1	MRA0

NOTE 1 Points to the RCD Register Control Word to be read.

NOTE 2 MRA7 will always be '0' for RCD Reads.

7.22.2 RW5F - CW Page Control Word

Table 159 — RW5F - CW Page Control Word

Page Control Register ^{1,2}								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Page selection control	PG[0] selected
0	0	0	0	0	0	0	1		PG[1] selected
0	0	0	0	0	0	1	0		PG[2] selected
.....								
1	1	1	1	1	1	0	1		PG[253] selected
1	1	1	1	1	1	1	0		PG[254] selected
1	1	1	1	1	1	1	1		PG[255] selected

NOTE 1 Power on Default is OP[7:0] = 0. This 8-bit control field uses binary encoding and it can be programmed with settings 0x00 (for CW Page 0) through 0xFF (for CW Page 255).

NOTE 2 The Host is responsible to set the page register properly before issuing the MRW write to the DRAM scratch-pad register.

7.23 DFE Paged Control Words

7.23.1 PG[1:0]RW[60, 68, 70, 78] - DPAR and DCA[6:0] Receiver DFE Gain Offset

Table 160 — PG[1:0]RW[60, 68, 70, 78]: DPAR and DCA[6:0] Receiver DFE Gain Offset Adjustment¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	0	0	0	Flat-band (DC) gain adjustment ^{2,3,4,5,6}	Gain Adjustment = 0 dB (default)
x	x	x	x	x	0	0	1		Gain Adjustment = +6 dB
x	x	x	x	x	0	1	0		Gain Adjustment = +4 dB
x	x	x	x	x	0	1	1		Gain Adjustment = +2 dB
x	x	x	x	x	1	0	0		Gain Adjustment = 0 dB (same as default)
x	x	x	x	x	1	0	1		Gain Adjustment = -2 dB
x	x	x	x	x	1	1	0		Gain Adjustment = -4 dB
x	x	x	x	x	1	1	1		Gain Adjustment = -6 dB
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x		Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x		Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x		Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x		Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 [Table 82](#) and [Table 83](#) illustrate the assignment of each control word in the PG[1:0]RW[60, 68, 70, 78] group to the corresponding input pin it controls.

NOTE 2 Flat-band (DC) gain adjustment (up to the Nyquist rate) adjustment control from I/O die pad to latching element in DCA_n.

NOTE 3 The Gain Adjustment is applied to the baseline (default) inherent gain implemented in the receiver.

NOTE 4 Gain Adjustment values shown in Table 3 are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 5 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 13, “DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin,” on page 34.

NOTE 6 PG[1:0]RW[60, 68, 70, 78] will be sticky, cleared by power cycle not reset.

7.23.2 PG[1:0]RW[61, 69, 71, 79] - DPAR and DCA[6:0] Receiver DFE Tap 1 Coefficients

Table 161 — PG[1:0]RW[61, 69, 71, 79]: DPAR and DCA[6:0] Receiver DFE Tap 1 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Tap 1 DFE Coefficient ^{2,3,4}	(Default) Tap 1 DFE bias = 0 mV
x	x	0	0	0	0	0	1		Tap 1 DFE bias +1 Tap Step
x	x	0	0	0	0	1	0		Tap 1 DFE bias +2 Tap Steps
x	x	0	0	0	0	1	1		Tap 1 DFE bias +3 Tap Steps
x	x	0	0	0	1	0	0		Tap 1 DFE bias +4 Tap Steps
x	x	0	0	0	1	0	1		Tap 1 DFE bias +5 Tap Steps
x	x	0	0	0	1	1	0		Tap 1 DFE bias +6 Tap Steps
x	x	0	0	0	1	1	1		Tap 1 DFE bias +7 Tap Steps
x	x	0	0	1	0	0	0		Tap 1 DFE bias +8 Tap Steps
x	x	0	0	1	0	0	1		Tap 1 DFE bias +9 Tap Steps
x	x	0	0	1	0	1	0		Tap 1 DFE bias +10 Tap Steps
x	x	0	0	1	0	1	1		Tap 1 DFE bias +11 Tap Steps
x	x	0	0	1	1	0	0		Tap 1 DFE bias +12 Tap Steps
x	x	0	0	1	1	0	1		Tap 1 DFE bias +13 Tap Steps
x	x	0	0	1	1	1	0		Tap 1 DFE bias +14 Tap Steps
x	x	0	0	1	1	1	1		Tap 1 DFE bias +15 Tap Steps
x	x	0	1	0	0	0	0		Tap 1 DFE bias +16 Tap Steps
x	x	0	1	0	0	0	1		Tap 1 DFE bias +17 Tap Steps
x	x	0	1	0	0	1	0		Tap 1 DFE bias +18 Tap Steps
x	x	0	1	0	0	1	1		Tap 1 DFE bias +19 Tap Steps
x	x	0	1	0	1	0	0		Tap 1 DFE bias +20 Tap Steps
x	x	0	1	0	1	0	1		Tap 1 DFE bias +21 Tap Steps
x	x	0	1	0	1	1	0		Tap 1 DFE bias +22 Tap Steps
x	x	0	1	0	1	1	1		Tap 1 DFE bias +23 Tap Steps
x	x	0	1	1	0	0	0		Tap 1 DFE bias +24 Tap Steps
x	x	0	1	1	0	0	1		Tap 1 DFE bias +25 Tap Steps
x	x	0	1	1	0	1	0		Tap 1 DFE bias +26 Tap Steps
x	x	0	1	1	0	1	1		Tap 1 DFE bias +27 Tap Steps
x	x	0	1	1	1	0	0		Tap 1 DFE bias +28 Tap Steps
x	x	0	1	1	1	0	1		Tap 1 DFE bias +29 Tap Steps
x	x	0	1	1	1	1	0		Tap 1 DFE bias +30 Tap Steps
x	x	0	1	1	1	1	1		Tap 1 DFE bias +31 Tap Steps
x	x	1	0	0	0	0	0		Tap 1 DFE bias +32 Tap Steps
x	x	1	0	0	0	0	1		Tap 1 DFE bias +33 Tap Steps
x	x	1	0	0	0	1	0		Tap 1 DFE bias +34 Tap Steps
x	x	1	0	0	0	1	1		Tap 1 DFE bias +35 Tap Steps
x	x	1	0	0	1	0	0		Tap 1 DFE bias +36 Tap Steps
x	x	1	0	0	1	0	1		Tap 1 DFE bias +37 Tap Steps
x	x	1	0	0	1	1	0		Tap 1 DFE bias +38 Tap Steps
x	x	1	0	0	1	1	1		Tap 1 DFE bias +39 Tap Steps
x	x	1	0	1	0	0	0		Tap 1 DFE bias +40 Tap Steps
x	x	1	0	1	0	0	1		Tap 1 DFE bias +41 Tap Steps
x	x	1	0	1	0	1	0		Tap 1 DFE bias +42 Tap Steps
x	x	1	0	1	0	1	1		Tap 1 DFE bias +43 Tap Steps
x	x	1	0	1	1	0	0		Tap 1 DFE bias +44 Tap Steps
x	x	1	0	1	1	0	1		Tap 1 DFE bias +45 Tap Steps
x	x	1	0	1	1	1	0		Tap 1 DFE bias +46 Tap Steps
x	x	1	0	1	1	1	1		Tap 1 DFE bias +47 Tap Steps
x	x	1	1	0	0	0	0		Tap 1 DFE bias +48 Tap Steps
x	x	1	1	0	0	0	1		Tap 1 DFE bias +49 Tap Steps
x	x	1	1	0	0	1	0		Tap 1 DFE bias +50 Tap Steps
x	x	1	1	0	0	1	1		Reserved
x	x	1	1	0	1	0	0		Reserved
x	x	1	1	0	1	0	1		Reserved
x	x	1	1	0	1	1	0		Reserved

Table 161 — PG[1:0]RW[61, 69, 71, 79]: DPAR and DCA[6:0] Receiver DFE Tap 1 Coefficients¹ (cont'd)

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	1	1	0	1	1	1	Tap 1 DFE Coefficient ^{1,2,3}	Reserved
x	x	1	1	1	0	0	0		Reserved
x	x	1	1	1	0	0	1		Reserved
x	x	1	1	1	0	1	0		Reserved
x	x	1	1	1	0	1	1		Reserved
x	x	1	1	1	1	0	0		Reserved
x	x	1	1	1	1	0	1		Reserved
x	x	1	1	1	1	1	0		Reserved
x	x	1	1	1	1	1	1		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 1 Coefficient Sign Bit	(Default) Positive Tap 1 DFE bias when Tap 1 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 1 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 1 DFE bias when Tap 1 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 1 post-cursor)

NOTE 1 Table 82 and Table 83 illustrate the assignment of each control word in the PG[1:0]RW[61, 69, 71, 79] group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values shown in Table 162 are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 13, “DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin,” on page 34.

NOTE 4 PG[1:0]RW[61, 69, 71, 79]OP[7:0] will be sticky, cleared by power cycle not reset.

7.23.3 PG[1:0]RW[62, 6A, 72, 7A]- DPAR and DCA[6:0] Receiver DFE Tap 2 Coefficients**Table 162 — PG[1:0]RW[62, 6A, 72, 7A]: DPAR and DCA[6:0] Receiver DFE Tap 2 Coefficients¹**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Tap 2 DFE Coefficient ^{2,3,4}	(Default) Tap 2 DFE bias = 0 mV
x	x	0	0	0	0	0	1		Tap 2 DFE bias+1 Tap Step
x	x	0	0	0	0	1	0		Tap 2 DFE bias +2 Tap Steps
x	x	0	0	0	0	1	1		Tap 2 DFE bias +3 Tap Steps
x	x	0	0	0	1	0	0		Tap 2 DFE bias +4 Tap Steps
x	x	0	0	0	1	0	1		Tap 2 DFE bias +5 Tap Steps
x	x	0	0	0	1	1	0		Tap 2 DFE bias +6 Tap Steps
x	x	0	0	0	1	1	1		Tap 2 DFE bias +7 Tap Steps
x	x	0	0	1	0	0	0		Tap 2 DFE bias +8 Tap Steps
x	x	0	0	1	0	0	1		Tap 2 DFE bias +9 Tap Steps
x	x	0	0	1	0	1	0		Tap 2 DFE bias +10 Tap Steps
x	x	0	0	1	0	1	1		Tap 2 DFE bias +11 Tap Steps
x	x	0	0	1	1	0	0		Tap 2 DFE bias +12 Tap Steps
x	x	0	0	1	1	0	1		Tap 2 DFE bias +13 Tap Steps
x	x	0	0	1	1	1	0		Tap 2 DFE bias +14 Tap Steps
x	x	0	0	1	1	1	1		Tap 2 DFE bias +15 Tap Steps
x	x	0	1	0	0	0	0		Tap 2 DFE bias +16 Tap Steps
x	x	0	1	0	0	0	1		Tap 2 DFE bias +17 Tap Steps
x	x	0	1	0	0	1	0		Tap 2 DFE bias +18 Tap Steps
x	x	0	1	0	0	1	1		Tap 2 DFE bias +19 Tap Steps
x	x	0	1	0	1	0	0		Tap 2 DFE bias +20 Tap Steps
x	x	0	1	0	1	0	1	Reserved	Reserved
x	x	0	1	0	1	1	0		Reserved
x	x	0	1	0	1	1	1		Reserved
x	x	0	1	1	0	0	0		Reserved
x	x	0	1	1	0	0	1		Reserved
x	x	0	1	1	0	1	0		Reserved
x	x	0	1	1	0	1	1		Reserved
x	x	0	1	1	1	0	0		Reserved
x	x	0	1	1	1	0	1		Reserved
x	x	0	1	1	1	1	0		Reserved
x	x	0	1	1	1	1	1		Reserved
x	x	1	0	0	0	0	1		Reserved
x	x	1	0	0	0	0	0		Reserved
x	x	1	0	0	0	1	1		Reserved
x	x	1	0	0	0	1	0		Reserved
x	x	1	0	0	1	0	1		Reserved
x	x	1	0	0	1	0	0		Reserved
x	x	1	0	0	1	1	1		Reserved
x	x	1	0	1	0	0	1		Reserved
x	x	1	0	1	0	0	0		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved

Table 162 — PG[1:0]RW[62, 6A, 72, 7A]: DPAR and DCA[6:0] Receiver DFE Tap 2 Coefficients¹ (cont'd)

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	x	x	x	x	x	x	x	Tap 2 Coefficient Sign Bit	(Default) Positive Tap 2 DFE bias when Tap 2 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 2 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 2 DFE bias when Tap 2 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 2 post-cursor)

NOTE 1 [Table 82](#) and [Table 83](#) illustrate the assignment of each control word in the [PG\[1:0\]RW\[62, 6A, 72, 7A\]](#) group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values shown in Table 162 are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 13, “DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin,” on page 34.

NOTE 4 [PG\[1:0\]RW\[62, 6A, 72, 7A\] OP\[7:0\]](#) will be sticky, cleared by power cycle not reset.

7.23.4 PG[1:0]RW[63, 6B, 73, 7B] - DPAR and DCA[6:0] Receiver DFE Tap 3 Coefficients

Table 163 — PG[1:0]RW[63, 6B, 73, 7B]: DPAR and DCA[6:0] Receiver DFE Tap 3 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Tap 3 DFE Coefficient ^{2,3,4}	(Default) Tap 3 DFE bias = 0 mV
x	x	x	0	0	0	0	1		Tap 3 DFE bias +1 Tap Step
x	x	x	0	0	0	1	0		Tap 3 DFE bias +2 Tap Steps
x	x	x	0	0	0	1	1		Tap 3 DFE bias +3 Tap Steps
x	x	x	0	0	1	0	0		Tap 3 DFE bias +4 Tap Steps
x	x	x	0	0	1	0	1		Tap 3 DFE bias +5 Tap Steps
x	x	x	0	0	1	1	0		Tap 3 DFE bias +6 Tap Steps
x	x	x	0	0	1	1	1		Tap 3 DFE bias +7 Tap Steps
x	x	x	0	1	0	0	0		Tap 3 DFE bias +8 Tap Steps
x	x	x	0	1	0	0	1		Tap 3 DFE bias +9 Tap Steps
x	x	x	0	1	0	1	0		Tap 3 DFE bias +10 Tap Steps
x	x	x	0	1	0	1	1		Tap 3 DFE bias +11 Tap Steps
x	x	x	0	1	1	0	0		Tap 3 DFE bias +12 Tap Steps
x	x	x	0	1	1	0	1		Tap 3 DFE bias +13 Tap Steps
x	x	x	0	1	1	1	0		Tap 3 DFE bias +14 Tap Steps
x	x	x	0	1	1	1	1		Tap 3 DFE bias +15 Tap Steps
x	x	x	1	0	0	0	0		Reserved
x	x	x	1	0	0	0	1		Reserved
x	x	x	1	0	0	1	0		Reserved
x	x	x	1	0	0	1	1		Reserved
x	x	x	1	0	1	0	0		Reserved
x	x	x	1	0	1	0	1		Reserved
x	x	x	1	0	1	1	0		Reserved
x	x	x	1	0	1	1	1		Reserved
x	x	x	1	1	0	0	0		Reserved
x	x	x	1	1	0	0	1		Reserved
x	x	x	1	1	0	1	0		Reserved
x	x	x	1	1	0	1	1		Reserved
x	x	0	x	x	x	x	x		Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x		Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 3 Coefficient Sign Bit	(Default) Positive Tap 3 DFE bias when Tap 3 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 3 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 3 DFE bias when Tap 3 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 3 post-cursor)

NOTE 1 Table 82 and Table 83 illustrate the assignment of each control word in the PG[1:0]RW[63, 6B, 73, 7B] group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values shown in Table 163 are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 13, “DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin,” on page 34.

NOTE 4 PG[1:0]RW[63, 6B, 73, 7B] OP[7:0] will be sticky, cleared by power cycle not reset.

7.23.5 PG[1:0]RW[64, 6C, 74, 7C]- DPAR and DCA[6:0] Receiver DFE Tap 4 Coefficients

Table 164 — PG[1:0]RW[64, 6C, 74, 7C]: DPAR and DCA[6:0] Receiver DFE Tap 4 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Tap 4 DFE Coefficient ^{2,3,4}	(Default) Tap 4 DFE bias = 0 mV
x	x	x	0	0	0	0	1		Tap 4 DFE bias +1 Tap Steps
x	x	x	0	0	0	1	0		Tap 4 DFE bias +2 Tap Steps
x	x	x	0	0	0	1	1		Tap 4 DFE bias +3 Tap Steps
x	x	x	0	0	1	0	0		Tap 4 DFE bias +4 Tap Steps
x	x	x	0	0	1	0	1		Tap 4 DFE bias +5 Tap Steps
x	x	x	0	0	1	1	0		Tap 4 DFE bias +6 Tap Steps
x	x	x	0	0	1	1	1		Tap 4 DFE bias +7 Tap Steps
x	x	x	0	1	0	0	0		Tap 4 DFE bias +8 Tap Steps
x	x	x	0	1	0	0	1		Tap 4 DFE bias +9 Tap Steps
x	x	x	0	1	0	1	0		Tap 4 DFE bias +10 Tap Steps
x	x	x	0	1	0	1	1		Tap 4 DFE bias +11 Tap Steps
x	x	x	0	1	1	0	0		Tap 4 DFE bias +12 Tap Steps
x	x	x	0	1	1	0	1		Tap 4 DFE bias +13 Tap Steps
x	x	x	0	1	1	1	0		Tap 4 DFE bias +14 Tap Steps
x	x	x	0	1	1	1	1		Tap 4 DFE bias +15 Tap Steps
x	x	x	1	0	0	0	0		Reserved
x	x	x	1	0	0	0	1		Reserved
x	x	x	1	0	0	1	0		Reserved
x	x	x	1	0	0	1	1		Reserved
x	x	x	1	0	1	0	0		Reserved
x	x	x	1	0	1	0	1		Reserved
x	x	x	1	0	1	1	0		Reserved
x	x	x	1	0	1	1	1		Reserved
x	x	x	1	1	0	0	0		Reserved
x	x	x	1	1	0	0	1		Reserved
x	x	x	1	1	0	1	0		Reserved
x	x	x	1	1	0	1	1		Reserved
x	x	x	1	1	1	0	0		Reserved
x	x	x	1	1	1	0	1		Reserved
x	x	x	1	1	1	1	0		Reserved
x	x	x	1	1	1	1	1		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 4 Coefficient Sign Bit	(Default) Positive Tap 4 DFE bias when Tap 4 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 4 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 4 DFE bias when Tap 4 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 4 post-cursor)

NOTE 1 Table 82 and Table 83 illustrate the assignment of each control word in the PG[1:0]RW[64, 6C, 74, 7C] group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values shown in Table 164 are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 13, “DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin,” on page 34.

NOTE 4 PG[1:0]RW[64, 6C, 74, 7C] OP[7:0] will be sticky, cleared by power cycle not reset.

7.23.6 PG[1:0]RW[65, 6D, 75, 7D]- DPAR and DCA[6:0] Receiver DFE Tap 5 Coefficients

Table 165 — PG[1:0]RW[65, 6D, 75, 7D]: DPAR and DCA[6:0] Receiver DFE Tap 5 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Tap 5 DFE Coefficient ^{2,3,4}	(Default) Tap 5 DFE bias = 0 mV
x	x	x	0	0	0	0	1		Tap 5 DFE bias +1 Tap Steps
x	x	x	0	0	0	1	0		Tap 5 DFE bias +2 Tap Steps
x	x	x	0	0	0	1	1		Tap 5 DFE bias +3 Tap Steps
x	x	x	0	0	1	0	0		Tap 5 DFE bias +4 Tap Steps
x	x	x	0	0	1	0	1		Tap 5 DFE bias +5 Tap Steps
x	x	x	0	0	1	1	0		Tap 5 DFE bias +6 Tap Steps
x	x	x	0	0	1	1	1		Tap 5 DFE bias +7 Tap Steps
x	x	x	0	1	0	0	0		Tap 5 DFE bias +8 Tap Steps
x	x	x	0	1	0	0	1		Tap 5 DFE bias +9 Tap Steps
x	x	x	0	1	0	1	0		Tap 5 DFE bias +10 Tap Steps
x	x	x	0	1	0	1	1		Tap 5 DFE bias +11 Tap Steps
x	x	x	0	1	1	0	0		Tap 5 DFE bias +12 Tap Steps
x	x	x	0	1	1	0	1		Tap 5 DFE bias +13 Tap Steps
x	x	x	0	1	1	1	0		Tap 5 DFE bias +14 Tap Steps
x	x	x	0	1	1	1	1		Tap 5 DFE bias +15 Tap Steps
x	x	x	1	0	0	0	0		Reserved
x	x	x	1	0	0	0	1		Reserved
x	x	x	1	0	0	1	0		Reserved
x	x	x	1	0	0	1	1		Reserved
x	x	x	1	0	1	0	0		Reserved
x	x	x	1	0	1	0	1		Reserved
x	x	x	1	0	1	1	0		Reserved
x	x	x	1	0	1	1	1		Reserved
x	x	x	1	1	0	0	0		Reserved
x	x	x	1	1	0	0	1		Reserved
x	x	x	1	1	0	1	0		Reserved
x	x	x	1	1	0	1	1		Reserved
x	x	x	1	1	1	0	0		Reserved
x	x	x	1	1	1	0	1		Reserved
x	x	x	1	1	1	1	0		Reserved
x	x	x	1	1	1	1	1		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 5 Coefficient Sign Bit	(Default) Positive Tap 5 DFE bias when Tap 5 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 5 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 5 DFE bias when Tap 5 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 5 post-cursor)

NOTE 1 Table 82 and Table 83 illustrate the assignment of each control word in the PG[1:0]RW[65, 6D, 75, 7D] group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values shown in Table 164 are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 13, “DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin.”

NOTE 4 PG[1:0]RW[65, 6D, 75, 7D] OP[7:0] will be sticky, cleared by power cycle not reset.

7.23.7 PG[1:0]RW[66, 6E, 76, 7E]- DPAR and DCA[6:0] Receiver DFE Tap 6 Coefficients**Table 166 — PG[1:0]RW[66, 6E, 76, 7E]: DPAR and DCA[6:0] Receiver DFE Tap 6 Coefficients¹**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Tap 6 DFE Coefficient ^{2,3,4}	(Default) Tap 6 DFE bias = 0 mV
x	x	x	0	0	0	0	1		Tap 6 DFE bias +1 Tap Steps
x	x	x	0	0	0	1	0		Tap 6 DFE bias +2 Tap Steps
x	x	x	0	0	0	1	1		Tap 6 DFE bias +3 Tap Steps
x	x	x	0	0	1	0	0		Tap 6 DFE bias +4 Tap Steps
x	x	x	0	0	1	0	1		Tap 6 DFE bias +5 Tap Steps
x	x	x	0	0	1	1	0		Tap 6 DFE bias +6 Tap Steps
x	x	x	0	0	1	1	1		Tap 6 DFE bias +7 Tap Steps
x	x	x	0	1	0	0	0		Tap 6 DFE bias +8 Tap Steps
x	x	x	0	1	0	0	1		Tap 6 DFE bias +9 Tap Steps
x	x	x	0	1	0	1	0		Tap 6 DFE bias +10 Tap Steps
x	x	x	0	1	0	1	1		Tap 6 DFE bias +11 Tap Steps
x	x	x	0	1	1	0	0		Tap 6 DFE bias +12 Tap Steps
x	x	x	0	1	1	0	1		Tap 6 DFE bias +13 Tap Steps
x	x	x	0	1	1	1	0		Tap 6 DFE bias +14 Tap Steps
x	x	x	0	1	1	1	1		Tap 6 DFE bias +15 Tap Steps
x	x	x	1	0	0	0	0		Reserved
x	x	x	1	0	0	0	1		Reserved
x	x	x	1	0	0	1	0		Reserved
x	x	x	1	0	0	1	1		Reserved
x	x	x	1	0	1	0	0		Reserved
x	x	x	1	0	1	0	1		Reserved
x	x	x	1	0	1	1	0		Reserved
x	x	x	1	0	1	1	1		Reserved
x	x	x	1	1	0	0	0		Reserved
x	x	x	1	1	0	0	1		Reserved
x	x	x	1	1	0	1	0		Reserved
x	x	x	1	1	0	1	1		Reserved
x	x	x	1	1	1	0	0		Reserved
x	x	x	1	1	1	0	1		Reserved
x	x	x	1	1	1	1	0		Reserved
x	x	x	1	1	1	1	1		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 6 Coefficient Sign Bit	(Default) Positive Tap 6 DFE bias when Tap 6 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 6 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 6 DFE bias when Tap 6 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 6 post-cursor)

NOTE 1 Table 82 and Table 83 illustrate the assignment of each control word in the PG[1:0]RW[66, 6E, 76, 7E] group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values shown in Table 164 are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 13, “DCA DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin.”

NOTE 4 PG[1:0]RW[66, 6E, 76, 7E] OP[7:0] will be sticky, cleared by power cycle not reset.

7.23.8 PG[2]RW[60, 64, 68, 6C, 70, 74, 78, 7C] DFE Error Counter Lower 8 Bits

Table 167 — PG[2]RW[60, 64, 68, 6C, 70, 74, 78, 7C]- DFE Error Counter Lower 8 Bit

DFE Error Counter Lower 8 Bit Register ^{1,2,3,4}							
OP7	OP6	OP5	OP4	OP3	OP2	OP1	OP0
EC7	EC6	EC5	EC4	EC3	EC2	EC1	EC0

NOTE 1 Table 84 illustrates the assignment of each control word in the PG[2]RW[60, 64, 68, 6C, 70, 74, 78, 7C] group to the corresponding input pin it controls.

NOTE 2 Power on Default is OP[7:0] = 0.

NOTE 3 Read Only Register.

NOTE 4 Only the Error Counter of the selected DCA pin will run during DCA DFE Training, and the DCA Error Counters will not run during DCS DFE training.

7.23.9 PG[2]RW[61, 65, 69, 6D, 71, 75, 79, 7D] - DFE Error Counter Upper 8 Bits

Table 168 — PG[2]RW[61, 65, 69, 6D, 71, 75, 79, 7D] DFE Error Counter Upper 8 Bit

DFE Error Counter Upper 8 Bit Register ^{1,2,3,4}							
OP7	OP6	OP5	OP4	OP3	OP2	OP1	OP0
EC 15	EC 14	EC 13	EC 12	EC 11	EC 10	EC 9	EC 8

NOTE 1 Table 84 illustrates the assignment of each control word in the PG[2]RW[61, 65, 69, 6D, 71, 75, 79, 7D] group to the corresponding input pin it controls.

NOTE 2 Power on Default is OP[7:0] = 0.

NOTE 3 Read Only Register.

NOTE 4 Only the Error Counter of the selected DCA pin will run during DCA DFE Training, and the DCA Error Counters will not run during DCS DFE training.

Table 169 — PG[2]RW[62, 66, 6A, 6E, 72, 76, 7A, 7E]: DFE Vref

PG02RW[62, 66 .. 7E]							DFE Training VREF in mV ^{1,2,3,4,5}							
OP7	OP6	OP5	OP4	OP3	OP2	RW3F[x ⁶] = 1 (NEG Range)				RW3F[x ⁶] = 0 (POS Range)				
						OP[1:0] = 00	OP[1:0] = 01	OP[1:0] = 10	OP[1:0] = 11	OP[1:0] = 00	OP[1:0] = 01	OP[1:0] = 10	OP[1:0] = 11	
0	0	0	0	0	0	0.0	- 2.5	- 5.0	- 7.5	0.0	+ 2.5	+ 5.0	+ 7.5	
0	0	0	0	0	1	- 10.0	- 12.5	- 15.0	- 17.5	+ 10.0	+ 12.5	+ 15.0	+ 17.5	
0	0	0	0	1	0	- 20.0	- 22.5	- 25.0	- 27.5	+ 20.0	+ 22.5	+ 25.0	+ 27.5	
0	0	0	0	1	1	- 30.0	- 32.5	- 35.0	- 37.5	+ 30.0	+ 32.5	+ 35.0	+ 37.5	
0	0	0	1	0	0	- 40.0	- 42.5	- 45.0	- 47.5	+ 40.0	+ 42.5	+ 45.0	+ 47.5	
0	0	0	1	0	1	- 50.0	- 52.5	- 55.0	- 57.5	+ 50.0	+ 52.5	+ 55.0	+ 57.5	
0	0	0	1	1	0	- 60.0	- 62.5	- 65.0	- 67.5	+ 60.0	+ 62.5	+ 65.0	+ 67.5	
0	0	0	1	1	1	- 70.0	- 72.5	- 75.0	- 77.5	+ 70.0	+ 72.5	+ 75.0	+ 77.5	
0	0	1	0	0	0	- 80.0	- 82.5	- 85.0	- 87.5	+ 80.0	+ 82.5	+ 85.0	+ 87.5	
0	0	1	0	0	1	- 90.0	- 92.5	- 95.0	- 97.5	+ 90.0	+ 92.5	+ 95.0	+ 97.5	
0	0	1	0	1	0	- 100.0	- 102.5	- 105.0	- 107.5	+ 100.0	+ 102.5	+ 105.0	+ 107.5	
0	0	1	0	1	1	- 110.0	- 112.5	- 115.0	- 117.5	+ 110.0	+ 112.5	+ 115.0	+ 117.5	
0	0	1	1	0	0	- 120.0	- 122.5	- 125.0	- 127.5	+ 120.0	+ 122.5	+ 125.0	+ 127.5	
0	0	1	1	0	1	- 130.0	- 132.5	- 135.0	- 137.5	+ 130.0	+ 132.5	+ 135.0	+ 137.5	
0	0	1	1	1	0	- 140.0	- 142.5	- 145.0	- 147.5	+ 140.0	+ 142.5	+ 145.0	+ 147.5	
0	0	1	1	1	1	- 150.0	- 152.5	- 155.0	- 157.5	+ 150.0	+ 152.5	+ 155.0	+ 157.5	
0	1	0	0	0	0	- 160.0	- 162.5	- 165.0	- 167.5	+ 160.0	+ 162.5	+ 165.0	+ 167.5	
0	1	0	0	0	1	- 170.0	- 172.5	- 175.0	- 177.5	+ 170.0	+ 172.5	+ 175.0	+ 177.5	
0	1	0	0	1	0	- 180.0	- 182.5	- 185.0	- 187.5	+ 180.0	+ 182.5	+ 185.0	+ 187.5	
0	1	0	0	1	1	- 190.0	- 192.5	- 195.0	- 197.5	+ 190.0	+ 192.5	+ 195.0	+ 197.5	
0	1	0	1	0	0	- 200.0	- 202.5	- 205.0	- 207.5	+ 200.0	+ 202.5	+ 205.0	+ 207.5	
0	1	0	1	0	1	- 210.0	- 212.5	- 215.0	- 217.5	+ 210.0	+ 212.5	+ 215.0	+ 217.5	
0	1	0	1	1	0	- 220.0	- 222.5	- 225.0	- 227.5	+ 220.0	+ 222.5	+ 225.0	+ 227.5	
0	1	0	1	1	1	- 230.0	- 232.5	- 235.0	- 237.5	+ 230.0	+ 232.5	+ 235.0	+ 237.5	
0	1	1	0	0	0	- 240.0	- 242.5	- 245.0	- 247.5	+ 240.0	+ 242.5	+ 245.0	+ 247.5	
0	1	1	0	0	1	- 250.0	- 252.5	- 255.0	- 257.5	+ 250.0	+ 252.5	+ 255.0	+ 257.5	
0	1	1	0	1	0	- 260.0	- 262.5	- 265.0	- 267.5	+ 260.0	+ 262.5	+ 265.0	+ 267.5	
0	1	1	0	1	1	- 270.0	- 272.5	- 275.0	- 277.5	+ 270.0	+ 272.5	+ 275.0	+ 277.5	
0	1	1	1	0	0	- 280.0	- 282.5	- 285.0	- 287.5	+ 280.0	+ 282.5	+ 285.0	+ 287.5	
0	1	1	1	0	1	- 290.0	- 292.5	- 295.0	- 297.5	+ 290.0	+ 292.5	+ 295.0	+ 297.5	
0	1	1	1	1	0	- 300.0	- 302.5	- 305.0	- 307.5	+ 300.0	+ 302.5	+ 305.0	+ 307.5	
0	1	1	1	1	1	- 310.0	- 312.5	- 315.0	- 317.5	+ 310.0	+ 312.5	+ 315.0	+ 317.5	
1	0	0	0	0	0	- 320.0	- 322.5	- 325.0	- 327.5	+ 320.0	+ 322.5	+ 325.0	+ 327.5	
1	0	0	0	0	1	- 330.0	- 332.5	- 335.0	- 337.5	+ 330.0	+ 332.5	+ 335.0	+ 337.5	
1	0	0	0	1	0	- 340.0	- 342.5	- 345.0	- 347.5	+ 340.0	+ 342.5	+ 345.0	+ 347.5	
1	0	0	0	1	1	- 350.0	- 352.5	- 355.0	- 357.5	+ 350.0	+ 352.5	+ 355.0	+ 357.5	
1	0	0	1	0	0	- 360.0	- 362.5	- 365.0	- 367.5	+ 360.0	+ 362.5	+ 365.0	+ 367.5	
1	0	0	1	0	1	- 370.0	- 372.5	- 375.0	- 377.5	+ 370.0	+ 372.5	+ 375.0	+ 377.5	
1	0	0	1	1	0	- 380.0	- 382.5	- 385.0	- 387.5	+ 380.0	+ 382.5	+ 385.0	+ 387.5	
1	0	0	1	1	1	- 390.0	- 392.5	- 395.0	- 397.5	+ 390.0	+ 392.5	+ 395.0	+ 397.5	
1	0	1	0	0	0	- 400.0	- 402.5	- 405.0	- 407.5	+ 400.0	+ 402.5	+ 405.0	+ 407.5	
1	0	1	0	0	1	- 410.0	- 412.5	- 415.0	- 417.5	+ 410.0	+ 412.5	+ 415.0	+ 417.5	
1	0	1	0	1	0	- 420.0	- 422.5	- 425.0	- 427.5	+ 420.0	+ 422.5	+ 425.0	+ 427.5	
1	0	1	0	1	1	- 430.0	- 432.5	- 435.0	- 437.5	+ 430.0	+ 432.5	+ 435.0	+ 437.5	
1	0	1	1	0	0	- 440.0	- 442.5	- 445.0	- 447.5	+ 440.0	+ 442.5	+ 445.0	+ 447.5	
1	0	1	1	0	1	- 450.0	- 452.5	- 455.0	- 457.5	+ 450.0	+ 452.5	+ 455.0	+ 457.5	
1	0	1	1	1	0	- 460.0	- 462.5	- 465.0	- 467.5	+ 460.0	+ 462.5	+ 465.0	+ 467.5	
1	0	1	1	1	1	- 470.0	- 472.5	- 475.0	- 477.5	+ 470.0	+ 472.5	+ 475.0	+ 477.5	
1	1	0	0	0	0	- 480.0	- 482.5	- 485.0	- 487.5	+ 480.0	+ 482.5	+ 485.0	+ 487.5	
1	1	0	0	0	1	- 490.0	- 492.5	- 495.0	- 497.5	+ 490.0	+ 492.5	+ 495.0	+ 497.5	
1	1	0	0	1	0	- 500.0	Reserved	Reserved	Reserved	+ 500.0	Reserved	Reserved	Reserved	
1	1	0	0	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	0	1	0	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	0	1	0	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	0	1	1	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	0	1	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	0	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	0	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	1	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	0	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	0	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	1	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	

- NOTE 1 [Table 84](#) illustrates the assignment of each control word in the [PG\[2\]RW\[62, 66, 6A, 6E, 72, 76, 7A 7E\]](#) group to the corresponding input pin it controls.
- NOTE 2 These are target DFE_Vref values. Acceptable actual values are determined based on tolerances defined in electrical section.
- NOTE 3 The target DFE_Vref values shown in this table are input referred.
- NOTE 4 Even though each input receiver has a dedicated DFE_Vref control word, only one DFE Vref monitor is allowed to be enabled at the same time in each sub-channel.
- NOTE 5 VrefCA and DFE_Vref are independent. External VrefCA must be adjusted for large input swings.
- NOTE 6 The range selection per Dx is controlled by writing to [RW3F](#).

7.23.11 PG[2]RW[63, 67, 6B, 6F, 73, 77, 7B, 7F] - LFSR Seed for DFE Training Mode Control Word

Table 170 — PG[2]RW[63, 67, 6B, 6F, 73, 77, 7B, 7F] LFSR Seed for DFE Training Mode Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	LFSR Seed	LFSR Seed = 0x00*
0	0	0	0	0	0	0	1		LFSR Seed = 0x01
0	0	0	0	0	0	1	0		LFSR Seed = 0x02
...									...
1	1	1	1	1	1	0	0		LFSR Seed = 0xFC
1	1	1	1	1	1	0	1		LFSR Seed = 0xFD
1	1	1	1	1	1	1	0		LFSR Seed = 0xFE
1	1	1	1	1	1	1	1		LFSR Seed = 0xFF

- NOTE 1 [Table 84](#) illustrates the assignment of each control word in the [PG\[2\]RW\[63, 67, 6B, 6F, 73, 77, 7B, 7F\]](#) group to the corresponding input pin it controls.

7.24 OTP Paged Global Control Words

Page 3 contains Global Read-Only Words that must be accessed through Channel A only.

7.24.1 PG[3]RW60 - Date Code Byte 0 Global Word

Table 171 — PG[3]RW60: Date Code Byte 0 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	Date Code Digit 0 ^{1,2} Year Information - Ones Digit (Read Only)	Digit = 0
x	x	x	x	0	0	0	1		Digit = 1
x	x	x	x	0	0	1	0		Digit = 2
x	x	x	x
x	x	x	x	0	1	1	1		Digit = 7
x	x	x	x	1	0	0	0		Digit = 8
x	x	x	x	1	0	0	1		Digit = 9
x	x	x	x	1	0	1	0		Codes 10 to 15 Reserved
x	x	x	x	...					
x	x	x	x	1	1	1	1		
0	0	0	0	x	x	x	x	Date Code Digit 1 ^{1, 2} Year Information - Tens Digit (Read Only)	Digit = 0
0	0	0	1	x	x	x	x		Digit = 1
0	0	1	0	x	x	x	x		Digit = 2
...				x	x	x	x		...
0	1	1	1	x	x	x	x		Digit = 7
1	0	0	0	x	x	x	x		Digit = 8
1	0	0	1	x	x	x	x		Digit = 9
1	0	1	0	x	x	x	x		Codes 10 to 15 Reserved
...				x	x	x	x		
1	1	1	1	x	x	x	x		

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

NOTE 2 This is year date code byte for RCD. It must be represented in Binary Coded Decimal (BCD). For example, year 2015 would be coded as 0x15 (0001 0101).

7.24.2 PG[3]RW61 - Date Code Byte 1 Global Word

Table 172 — PG[3]RW61: Date Code Byte 1 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	Date Code Digit 2 ^{1,2} Work Week Information - Ones Digit ISO 8601 compliant (Read Only)	Digit = 0
x	x	x	x	0	0	0	1		Digit = 1
x	x	x	x	0	0	1	0		Digit = 2
x	x	x	x
x	x	x	x	0	1	1	1		Digit = 7
x	x	x	x	1	0	0	0		Digit = 8
x	x	x	x	1	0	0	1		Digit = 9
x	x	x	x	1	0	1	0		Codes 10 to 15 Reserved
x	x	x	x	...					
x	x	x	x	1	1	1	1		
0	0	0	0	x	x	x	x	Date Code Digit 3 ^{1, 2} Work Week Information - Tens Digit ISO 8601 compliant (Read Only)	Digit = 0
0	0	0	1	x	x	x	x		Digit = 1
0	0	1	0	x	x	x	x		Digit = 2
...				x	x	x	x		...
0	1	1	1	x	x	x	x		Digit = 7
1	0	0	0	x	x	x	x		Digit = 8
1	0	0	1	x	x	x	x		Digit = 9
1	0	1	0	x	x	x	x		Codes 10 to 15 Reserved
...				x	x	x	x		
1	1	1	1	x	x	x	x		

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

NOTE 2 This is work week date code byte for RCD. It must be represented in Binary Coded Decimal (BCD). For example, week 47 would be coded as 0x47 (0100 0111).

7.24.3 PG[3]RW62 - Date Code Byte 2 Global Word

Table 173 — PG[3]RW62: Date Code Byte 2 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	Date Code Digit 4 ¹ Reserved (Read Only)	Digit = 0
x	x	x	x	0	0	0	1		Digit = 1
x	x	x	x	0	0	1	0		Digit = 2
x	x	x	x
x	x	x	x	0	1	1	1		Digit = 7
x	x	x	x	1	0	0	0		Digit = 8
x	x	x	x	1	0	0	1		Digit = 9
x	x	x	x	1	0	1	0		Codes 10 to 15 Reserved
x	x	x	x	...					
x	x	x	x	1	1	1	1		
0	0	0	0	x	x	x	x	Date Code Digit 5 ¹ Reserved (Read Only)	
0	0	0	1	x	x	x	x		Digit = 1
0	0	1	0	x	x	x	x		Digit = 2
...				x	x	x	x		...
0	1	1	1	x	x	x	x		Digit = 7
1	0	0	0	x	x	x	x		Digit = 8
1	0	0	1	x	x	x	x		Digit = 9
1	0	1	0	x	x	x	x		Codes 10 to 15 Reserved
...				x	x	x	x		
1	1	1	1	x	x	x	x		

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.4 PG[3]RW63 - Vendor Specific Unique Unit Code Byte 0 Global Word

Table 174 — PG[3]RW63: Vendor Specific Unique Unit Code Byte 0 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 0 of Unique Unit Code ¹ (Read Only)	Code 0
0	0	0	0	0	0	0	1		Code 1
0	0	0	0	0	0	1	0		Code 2
...									...
1	1	1	1	1	1	0	1		Code 253
1	1	1	1	1	1	1	0		Code 254
1	1	1	1	1	1	1	1		Code 255

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.5 PG[3]RW64 - Vendor Specific Unique Unit Code Byte 1 Global Word

Table 175 — PG[3]RW64: Vendor Specific Unique Unit Code Byte 1 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 1 of Unique Unit Code ¹ (Read Only)	Code 0
0	0	0	0	0	0	0	1		Code 1
0	0	0	0	0	0	1	0		Code 2
...									...
1	1	1	1	1	1	0	1		Code 253
1	1	1	1	1	1	1	0		Code 254
1	1	1	1	1	1	1	1		Code 255

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.6 PG[3]RW65 - Vendor Specific Unique Unit Code Byte 2 Global Word

Table 176 — PG[3]RW65: Vendor Specific Unique Unit Code Byte 2 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 2 of Unique Unit Code ¹ (Read Only)	Code 0
0	0	0	0	0	0	0	1		Code 1
0	0	0	0	0	0	1	0		Code 2
...									...
1	1	1	1	1	1	0	1		Code 253
1	1	1	1	1	1	1	0		Code 254
1	1	1	1	1	1	1	1		Code 255

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.7 PG[3]RW66 - Vendor Specific Unique Unit Code Byte 3 Global Word

Table 177 — PG[3]RW66: Vendor Specific Unique Unit Code Byte 3 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 3 of Unique Unit Code ¹ (Read Only)	Code 0
0	0	0	0	0	0	0	1		Code 1
0	0	0	0	0	0	1	0		Code 2
...									...
1	1	1	1	1	1	0	1		Code 253
1	1	1	1	1	1	1	0		Code 254
1	1	1	1	1	1	1	1		Code 255

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.8 PG[3]RW67 - Vendor Specific Unique Unit Code Byte 4 Global Word

Table 178 — PG[3]RW67: Vendor Specific Unique Unit Code Byte 4 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 4 of Unique Unit Code ¹ (Read Only)	Code 0
0	0	0	0	0	0	0	1		Code 1
0	0	0	0	0	0	1	0		Code 2
...									...
1	1	1	1	1	1	0	1		Code 253
1	1	1	1	1	1	1	0		Code 254
1	1	1	1	1	1	1	1		Code 255

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.9 PG[3]RW68 - Vendor Specific Unique Unit Code Byte 5 Global Word

Table 179 — PG[3]RW68: Vendor Specific Unique Unit Code Byte 5 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 5 of Unique Unit Code ¹ (Read Only)	Code 0
0	0	0	0	0	0	0	1		Code 1
0	0	0	0	0	0	1	0		Code 2
...									...
1	1	1	1	1	1	0	1		Code 253
1	1	1	1	1	1	1	0		Code 254
1	1	1	1	1	1	1	1		Code 255

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.10 PG[3]RW69 - Vendor Specific Unique Unit Code Byte 6 Global Word

Table 180 — PG[3]RW69: Vendor Specific Unique Unit Code Byte 6 Global Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 6 of Unique Unit Code ¹ (Read Only)	Code 0
0	0	0	0	0	0	0	1		Code 1
0	0	0	0	0	0	1	0		Code 2
...									...
1	1	1	1	1	1	0	1		Code 253
1	1	1	1	1	1	1	0		Code 254
1	1	1	1	1	1	1	1		Code 255

NOTE 1 Programmed and locked in one time programmable memory by DDR5RCD05 vendor.

7.24.11 PG[3]RW6A - Vendor ID Byte 0 Global Word

Table 181 — PG[3]RW6A: Vendor ID Byte 0 Global Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 0 of Vendor ID (Read Only)	VID[7:0] = 0x00h
0	0	0	0	0	0	0	1		VID[7:0] = 0x01h
0	0	0	0	0	0	1	0		VID[7:0] = 0x02h
...									...
1	1	1	1	1	1	0	1		VID[7:0] = 0xFDh
1	1	1	1	1	1	1	0		VID[7:0] = 0xFEh
1	1	1	1	1	1	1	1		VID[7:0] = 0xFFh

NOTE 1 Each vendor will have a specific Vendor ID value assigned by JEDEC.

7.24.12 PG[3]RW6B - Vendor ID Byte 1 Global Word

Table 182 — PG[3]RW6B: Vendor ID Byte 1 Global Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 1 of Vendor ID (Read Only)	VID[15:8] = 0x00h
0	0	0	0	0	0	0	1		VID[15:8] = 0x01h
0	0	0	0	0	0	1	0		VID[15:8] = 0x02h
...									...
1	1	1	1	1	1	0	1		VID[15:8] = 0xFDh
1	1	1	1	1	1	1	0		VID[15:8] = 0xFEh
1	1	1	1	1	1	1	1		VID[15:8] = 0xFFh

NOTE 1 Each vendor will have a specific Vendor ID value assigned by JEDEC.

7.24.13 PG[3]RW6C - Device ID Byte 0 Global Word

Table 183 — PG[3]RW6C: Device ID Byte 0 Global Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 0 of Device ID (Read Only)	DID[7:0] = 0x00h
0	0	0	0	0	0	0	1		DID[7:0] = 0x01h
0	0	0	0	0	0	1	0		DID[7:0] = 0x02h
...									...
1	1	1	1	1	1	0	1		DID[7:0] = 0xFDh
1	1	1	1	1	1	1	0		DID[7:0] = 0xFEh
1	1	1	1	1	1	1	1		DID[7:0] = 0xFFh

NOTE 1 The device ID value is 0x0055.

7.24.14 PG[3]RW6D - Device ID Byte 1 Global Word

Table 184 — PG[3]RW6D: Device ID Byte 1 Global Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Byte 1 of Device ID (Read Only)	DID[15:8] = 0x00h
0	0	0	0	0	0	0	1		DID[15:8] = 0x01h
0	0	0	0	0	0	1	0		DID[15:8] = 0x02h
...									...
1	1	1	1	1	1	0	1		DID[15:8] = 0xFDh
1	1	1	1	1	1	1	0		DID[15:8] = 0xFEh
1	1	1	1	1	1	1	1		DID[15:8] = 0xFFh

NOTE 1 The device ID value is 0x0055.

7.24.15 PG[3]RW6E - Vendor Revision ID Global Word

Table 185 — PG[3]RW6E: Vendor Revision ID Global Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	Vendor Revision ID (Read Only)	RID[7:0] = 0x00h
0	0	0	0	0	0	0	1		RID[7:0] = 0x01h
0	0	0	0	0	0	1	0		RID[7:0] = 0x02h
...									...
1	1	1	1	1	1	0	1		RID[7:0] = 0xFDh
1	1	1	1	1	1	1	0		RID[7:0] = 0xFEh
1	1	1	1	1	1	1	1		RID[7:0] = 0xFFh

NOTE 1 This is a fixed vendor specific register.

7.25 VHost Paged Control Words

7.25.1 PG[4]RW[6E,6C,6A,68,66,64,62,60] - VHost Cmd[3:0] CA[7:0] Control Word

Table 186 — PG[4]RW[6E,6C,6A,68,66,64,62,60] - VHost Cmd[3:0] CA[7:0] Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Cmd[3:0] 1st/2nd UI CA0	QCA0 = 0
x	x	x	x	x	x	x	1		QCA0 = 1
x	x	x	x	x	x	0	x	Cmd[3:0] 1st/2nd UI CA1	QCA1 = 0
x	x	x	x	x	x	1	x		QCA1 = 1
x	x	x	x	x	0	x	x	Cmd[3:0] 1st/2nd UI CA2	QCA2 = 0
x	x	x	x	x	1	x	x		QCA2 = 1
x	x	x	x	0	x	x	x	Cmd[3:0] 1st/2nd UI CA3	QCA3 = 0
x	x	x	x	1	x	x	x		QCA3 = 1
x	x	x	0	x	x	x	x	Cmd[3:0] 1st/2nd UI CA4	QCA4 = 0
x	x	x	1	x	x	x	x		QCA4 = 1
x	x	0	x	x	x	x	x	Cmd[3:0] 1st/2nd UI CA5	QCA5 = 0
x	x	1	x	x	x	x	x		QCA5 = 1
x	0	x	x	x	x	x	x	Cmd[3:0] 1st/2nd UI CA6	QCA6 = 0
x	1	x	x	x	x	x	x		QCA6 = 1
0	x	x	x	x	x	x	x	Cmd[3:0] 1st/2nd UI CA7	QCA7 = 0
1	x	x	x	x	x	x	x		QCA7 = 1

NOTE 1 Table 86 illustrates the assignment of each control word in the PG[4]RW[6E, 6C, 6A, 68, 66, 64, 62, 60] group to the corresponding input pin it controls.

7.25.2 PG[4]RW[6F,6D,6B,69,67,65,63,61] - VHost Cmd[3:0] CS[1:0]/CA[13:8] Control Word

Table 187 — PG[4]RW[6F,6D,6B,69,67,65,63,61] - VHost Cmd[3:0] CA[7:0] Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Cmd[3:0] 1st/2nd UI CA8	QCA8 = 0
x	x	x	x	x	x	x	1		QCA8 = 1
x	x	x	x	x	x	0	x	Cmd[3:0] 1st/2nd UI CA9	QCA9 = 0
x	x	x	x	x	x	1	x		QCA9 = 1
x	x	x	x	x	0	x	x	Cmd[3:0] 1st/2nd UI CA10	QCA10 = 0
x	x	x	x	x	1	x	x		QCA10 = 1
x	x	x	x	0	x	x	x	Cmd[3:0] 1st/2nd UI CA11	QCA11 = 0
x	x	x	x	1	x	x	x		QCA11 = 1
x	x	x	0	x	x	x	x	Cmd[3:0] 1st/2nd UI CA12	QCA12 = 0
x	x	x	1	x	x	x	x		QCA12 = 1
x	x	0	x	x	x	x	x	Cmd[3:0] 1st/2nd UI CA13	QCA13 = 0
x	x	1	x	x	x	x	x		QCA13 = 1
x	0	x	x	x	x	x	x	Cmd[3:0] 1st/2nd UI CS0_n	QCS0_n = 0
x	1	x	x	x	x	x	x		QCS0_n = 1
0	x	x	x	x	x	x	x	Cmd[3:0] 1st/2nd UI CS1_n	QCS1_n = 0
1	x	x	x	x	x	x	x		QCS1_n = 1

NOTE 1 Table 86 illustrates the assignment of each control word in the PG[4]RW[6F, 6D, 6B, 69, 67, 65, 63, 61] group to the corresponding input pin it controls.

7.25.3 PG[4]RW70 - VHost [1:0] Cmd to Cmd Delay Control Word

Table 188 — PG[4]RW70 - VHost [1:0] Cmd to Cmd Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	0	0	0	cmd0 to cmd1 Delay	2 nCK ¹
x	x	x	x	x	0	0	1		4 nCK
x	x	x	x	x	0	1	0		8 nCK
x	x	x	x	x	0	1	1		16 nCK
x	x	x	x	x	1	0	0		64 nCK
x	x	x	x	x	1	0	1		256 nCK
x	x	x	x	x	1	1	0		1024 nCK
x	x	x	x	x	1	1	1		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	0	0	0	x	x	x	x	cmd1 to cmd2 Delay	2 nCK ¹
x	0	0	1	x	x	x	x		4 nCK
x	0	1	0	x	x	x	x		8 nCK
x	0	1	1	x	x	x	x		16 nCK
x	1	0	0	x	x	x	x		64 nCK
x	1	0	1	x	x	x	x		256 nCK
x	1	1	0	x	x	x	x		1024 nCK
x	1	1	1	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This setting is only applicable in DDR mode. It is illegal setting in SDR mode.

7.25.4 PG[4]RW71 - VHost [3:2]Cmd to Cmd Delay Control Word

Table 189 — PG[4]RW71 - VHost [3:2] Cmd to Cmd Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	0	0	0	cmd2 to cmd3 Delay	2 nCK ¹
x	x	x	x	x	0	0	1		4 nCK
x	x	x	x	x	0	1	0		8 nCK
x	x	x	x	x	0	1	1		16 nCK
x	x	x	x	x	1	0	0		64 nCK
x	x	x	x	x	1	0	1		256 nCK
x	x	x	x	x	1	1	0		1024 nCK
x	x	x	x	x	1	1	1		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	0	0	0	x	x	x	x	cmd3 to cmdn Delay	2 nCK ¹
x	0	0	1	x	x	x	x		4 nCK
x	0	1	0	x	x	x	x		8 nCK
x	0	1	1	x	x	x	x		16 nCK
x	1	0	0	x	x	x	x		64 nCK
x	1	0	1	x	x	x	x		256 nCK
x	1	1	0	x	x	x	x		1024 nCK
x	1	1	1	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This setting is only applicable in DDR mode. It is illegal setting in SDR mode.

7.25.5 PG[4]RW72 - VHost Repeat Mode Control Word

Table 190 — PG[4]RW72 - VHost Repeat Mode Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	Repeat Control	Repeat to cmd0 (repeat all 4)
x	x	x	x	x	x	0	1		Repeat to cmd1 (repeat last 3)
x	x	x	x	x	x	1	0		Repeat to cmd2 (repeat last 2)
x	x	x	x	x	x	1	1		Repeat to cmd3 (repeat last 1)
x	x	x	x	x	0	x	x	Repeat Enable	Do not repeat
x	x	x	x	x	1	x	x		Repeat as defined in RW72[1:0]
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

7.25.6 PG[4]RW73 - VHost Start and Stop Global Control Word

All control word bits are global, accessible via sub-channel A only.

Table 191 — PG[4]RW73 - VHost Start and Stop Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	VHost Selection	CH_A only
x	x	x	x	x	x	0	1		CH_B only
x	x	x	x	x	x	1	0		CH_A and CH_B Start and Stop at the same time
x	x	x	x	x	x	1	1		Reserved
x	x	x	x	x	0	x	x	VHost Start/Stop ¹	Stop VHost
x	x	x	x	x	1	x	x		Start VHost
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 PG[4]RW73 is only accessible from CH_A.

7.26 PG[5]RW[7B:60] Per-bit QCA Output Delay Control Words

Table 192 — PG[5]RW[7B:60] Per-bit QCA Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Per-bit QCA Output Delay ¹	(Default) Delay output by 0 ps
x	x	x	0	0	0	0	1		Delay output by 2.5 ps
x	x	x	0	0	0	1	0		Delay output by 5 ps
x	x	x	0	0	0	1	1		Delay output by 7.5 ps
x	x	x	0	0	1	0	0		Delay output by 10 ps
x	x	x	0	0	1	0	1		Delay output by 12.5 ps
x	x	x	0	0	1	1	0		Delay output by 15 ps
x	x	x	0	0	1	1	1		Delay output by 17.5 ps
x	x	x	0	1	0	0	0		Delay output by 20 ps
x	x	x	0	1	0	0	1		Delay output by 22.5 ps
x	x	x	0	1	0	1	0		Delay output by 25 ps
x	x	x	0	1	0	1	1		Delay output by 27.5 ps
x	x	x	0	1	1	0	0		Delay output by 30 ps
x	x	x	0	1	1	0	1		Delay output by 32.5 ps
x	x	x	0	1	1	1	0		Delay output by 35 ps
x	x	x	0	1	1	1	1		Delay output by 37.5 ps
x	x	x	1	0	0	0	0		Delay output by 40 ps
x	x	x	1	0	0	0	1		Codes 0x11 to 0x15 Reserved
x	x	x		
x	x	x	1	1	1	1	1		
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Per-bit QCA Output Delay	(Default) Feature Disabled
1	x	x	x	x	x	x	x	feature enable	Feature Enabled ²

NOTE 1 PG[5]RW[7B:60] will be sticky, cleared by power cycle not reset.

NOTE 2 When feature is enabled the delay settings in PG[5]RW[7B:60][6:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.27 PG[6] DCS DFE Control Words

7.27.1 PG[6]RW[60, 68] - DCS0_n and DCS1_n Receiver DFE Gain Offset

Table 193 — PG[6]RW[60, 68]: DCS0_n and DCS1_n Receiver DFE Gain Offset Adjustment¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	0	0	0	Flat-band (DC) gain adjustment ^{2, 3,4,5,6}	Gain Adjustment = 0 dB (default)
x	x	x	x	x	0	0	1		Gain Adjustment = +6 dB
x	x	x	x	x	0	1	0		Gain Adjustment = +4 dB
x	x	x	x	x	0	1	1		Gain Adjustment = +2 dB
x	x	x	x	x	1	0	0		Gain Adjustment = 0 dB (same as default)
x	x	x	x	x	1	0	1		Gain Adjustment = -2 dB
x	x	x	x	x	1	1	0		Gain Adjustment = -4 dB
x	x	x	x	x	1	1	1		Gain Adjustment = -6 dB
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x		Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x		Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x		Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x		Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 Table 88 illustrates the assignment of each control word in the PG[6]RW[60, 68] group to the corresponding input pin it controls.

NOTE 2 Flat-band (DC) gain adjustment (up to the Nyquist rate) adjustment control from I/O die pad to latching element in DCS.

NOTE 3 The Gain Adjustment is applied to the baseline (default) inherent gain implemented in the receiver.

NOTE 4 Gain Adjustment values are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 5 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 16, “DCS DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin.”

NOTE 6 PG[6]RW[60, 68] will be sticky, cleared by power cycle not reset.

7.27.2 PG[6]RW[61, 69] - DCS0_n and DCS1_n Receiver DFE Tap 1 Coefficients

Table 194 — PG[6]RW[61, 69]: DCS0_n and DCS1_n Receiver DFE Tap 1 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Tap 1 DFE Coefficient ^{2,3,4}	(Default) Tap 1 DFE bias = 0 mV
x	x	0	0	0	0	0	1		Tap 1 DFE bias +1 Tap Step
x	x	0	0	0	0	1	0		Tap 1 DFE bias +2 Tap Steps
x	x	0	0	0	0	1	1		Tap 1 DFE bias +3 Tap Steps
x	x	0	0	0	1	0	0		Tap 1 DFE bias +4 Tap Steps
x	x	0	0	0	1	0	1		Tap 1 DFE bias +5 Tap Steps
x	x	0	0	0	1	1	0		Tap 1 DFE bias +6 Tap Steps
x	x	0	0	0	1	1	1		Tap 1 DFE bias +7 Tap Steps
x	x	0	0	1	0	0	0		Tap 1 DFE bias +8 Tap Steps
x	x	0	0	1	0	0	1		Tap 1 DFE bias +9 Tap Steps
x	x	0	0	1	0	1	0		Tap 1 DFE bias +10 Tap Steps
x	x	0	0	1	0	1	1		Tap 1 DFE bias +11 Tap Steps
x	x	0	0	1	1	0	0		Tap 1 DFE bias +12 Tap Steps
x	x	0	0	1	1	0	1		Tap 1 DFE bias +13 Tap Steps
x	x	0	0	1	1	1	0		Tap 1 DFE bias +14 Tap Steps
x	x	0	0	1	1	1	1		Tap 1 DFE bias +15 Tap Steps
x	x	0	1	0	0	0	0		Tap 1 DFE bias +16 Tap Steps
x	x	0	1	0	0	0	1		Tap 1 DFE bias +17 Tap Steps
x	x	0	1	0	0	1	0		Tap 1 DFE bias +18 Tap Steps
x	x	0	1	0	0	1	1		Tap 1 DFE bias +19 Tap Steps
x	x	0	1	0	1	0	0		Tap 1 DFE bias +20 Tap Steps
x	x	0	1	0	1	0	1		Tap 1 DFE bias +21 Tap Steps
x	x	0	1	0	1	1	0		Tap 1 DFE bias +22 Tap Steps
x	x	0	1	0	1	1	1		Tap 1 DFE bias +23 Tap Steps
x	x	0	1	1	0	0	0		Tap 1 DFE bias +24 Tap Steps
x	x	0	1	1	0	0	1		Tap 1 DFE bias +25 Tap Steps
x	x	0	1	1	0	1	0		Tap 1 DFE bias +26 Tap Steps
x	x	0	1	1	0	1	1		Tap 1 DFE bias +27 Tap Steps
x	x	0	1	1	1	0	0		Tap 1 DFE bias +28 Tap Steps
x	x	0	1	1	1	0	1		Tap 1 DFE bias +29 Tap Steps
x	x	0	1	1	1	1	0		Tap 1 DFE bias +30 Tap Steps
x	x	0	1	1	1	1	1		Tap 1 DFE bias +31 Tap Steps
x	x	1	0	0	0	0	0		Tap 1 DFE bias +32 Tap Steps
x	x	1	0	0	0	0	1		Tap 1 DFE bias +33 Tap Steps
x	x	1	0	0	0	1	0		Tap 1 DFE bias +34 Tap Steps
x	x	1	0	0	0	1	1		Tap 1 DFE bias +35 Tap Steps
x	x	1	0	0	1	0	0		Tap 1 DFE bias +36 Tap Steps
x	x	1	0	0	1	0	1		Tap 1 DFE bias +37 Tap Steps
x	x	1	0	0	1	1	0		Tap 1 DFE bias +38 Tap Steps
x	x	1	0	0	1	1	1		Tap 1 DFE bias +39 Tap Steps
x	x	1	0	1	0	0	0		Tap 1 DFE bias +40 Tap Steps
x	x	1	0	1	0	0	1		Tap 1 DFE bias +41 Tap Steps
x	x	1	0	1	0	1	0		Tap 1 DFE bias +42 Tap Steps
x	x	1	0	1	0	1	1		Tap 1 DFE bias +43 Tap Steps
x	x	1	0	1	1	0	0		Tap 1 DFE bias +44 Tap Steps
x	x	1	0	1	1	0	1		Tap 1 DFE bias +45 Tap Steps
x	x	1	0	1	1	1	0		Tap 1 DFE bias +46 Tap Steps
x	x	1	0	1	1	1	1		Tap 1 DFE bias +47 Tap Steps
x	x	1	1	0	0	0	0		Tap 1 DFE bias +48 Tap Steps
x	x	1	1	0	0	0	1		Tap 1 DFE bias +49 Tap Steps
x	x	1	1	0	0	1	0		Tap 1 DFE bias +50 Tap Steps
x	x	1	1	0	0	1	1		Reserved
x	x	1	1	0	1	0	0		Reserved
x	x	1	1	0	1	0	1		Reserved
x	x	1	1	0	1	1	0		Reserved

Table 194 — PG[6]RW[61, 69]: DCS0_n and DCS1_n Receiver DFE Tap 1 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	1	1	0	1	1	1	Tap 1 DFE Coefficient ^{1,2,3}	Reserved
x	x	1	1	1	0	0	0		Reserved
x	x	1	1	1	0	0	1		Reserved
x	x	1	1	1	0	1	0		Reserved
x	x	1	1	1	0	1	1		Reserved
x	x	1	1	1	1	0	0		Reserved
x	x	1	1	1	1	0	1		Reserved
x	x	1	1	1	1	1	0		Reserved
x	x	1	1	1	1	1	1		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 1 Coefficient Sign Bit	(Default) Positive Tap 1 DFE bias when Tap 1 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 1 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 1 DFE bias when Tap 1 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 1 post-cursor)

- NOTE 1 [Table 88](#) illustrates the assignment of each control word in the PG[6]RW[61, 69] group to the corresponding input pin it controls.
- NOTE 2 Tap coefficient values are verified by design and the measurement from device pins is defined in a separate specification.
- NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 16, “DCS DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin.”.
- NOTE 4 PG[6]RW[61, 69]OP[7:0] will be sticky, cleared by power cycle not reset.

7.27.3 PG[6]RW[62, 6A]- DCS0_n and DCS1_n Receiver DFE Tap 2 Coefficients

Table 195 — PG[6]RW[62, 6A]: DCS0_n and DCS1_n Receiver DFE Tap 2 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Tap 2 DFE Coefficient ^{2,3,4}	(Default) Tap 2 DFE bias = 0 mV
x	x	0	0	0	0	0	1		Tap 2 DFE bias+1 Tap Step
x	x	0	0	0	0	1	0		Tap 2 DFE bias +2 Tap Steps
x	x	0	0	0	0	1	1		Tap 2 DFE bias +3 Tap Steps
x	x	0	0	0	1	0	0		Tap 2 DFE bias +4 Tap Steps
x	x	0	0	0	1	0	1		Tap 2 DFE bias +5 Tap Steps
x	x	0	0	0	1	1	0		Tap 2 DFE bias +6 Tap Steps
x	x	0	0	0	1	1	1		Tap 2 DFE bias +7 Tap Steps
x	x	0	0	1	0	0	0		Tap 2 DFE bias +8 Tap Steps
x	x	0	0	1	0	0	1		Tap 2 DFE bias +9 Tap Steps
x	x	0	0	1	0	1	0		Tap 2 DFE bias +10 Tap Steps
x	x	0	0	1	0	1	1		Tap 2 DFE bias +11 Tap Steps
x	x	0	0	1	1	0	0		Tap 2 DFE bias +12 Tap Steps
x	x	0	0	1	1	0	1		Tap 2 DFE bias +13 Tap Steps
x	x	0	0	1	1	1	0		Tap 2 DFE bias +14 Tap Steps
x	x	0	0	1	1	1	1		Tap 2 DFE bias +15 Tap Steps
x	x	0	1	0	0	0	0		Tap 2 DFE bias +16 Tap Steps
x	x	0	1	0	0	0	1		Tap 2 DFE bias +17 Tap Steps
x	x	0	1	0	0	1	0		Tap 2 DFE bias +18 Tap Steps
x	x	0	1	0	0	1	1		Tap 2 DFE bias +19 Tap Steps
x	x	0	1	0	1	0	0		Tap 2 DFE bias +20 Tap Steps
x	x	0	1	0	1	0	1		Reserved
x	x	0	1	0	1	1	0		Reserved
x	x	0	1	0	1	1	1		Reserved
x	x	0	1	1	0	0	0		Reserved
x	x	0	1	1	0	0	1		Reserved
x	x	0	1	1	0	1	0		Reserved
x	x	0	1	1	0	1	1		Reserved
x	x	0	1	1	1	0	0		Reserved
x	x	0	1	1	1	1	0		Reserved
x	x	0	0	1	1	1	1		Reserved
x	x	1	0	0	0	0	1		Reserved
x	x	1	0	0	0	0	0		Reserved
x	x	1	0	0	0	0	1		Reserved
x	x	1	0	0	0	1	0		Reserved
x	x	1	0	0	1	0	0		Reserved
x	x	1	0	0	1	1	1		Reserved
x	x	1	0	0	1	1	0		Reserved
x	x	1	0	1	0	0	1		Reserved
x	x	1	0	1	0	0	0		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved

Table 195 — PG[6]RW[62, 6A]: DCS0_n and DCS1_n Receiver DFE Tap 2 Coefficients¹ (cont'd)

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	x	x	x	x	x	x	x	Tap 2 Coefficient Sign Bit	(Default) Positive Tap 2 DFE bias when Tap 2 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 2 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 2 DFE bias when Tap 2 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 2 post-cursor)

NOTE 1 [Table 88](#) illustrates the assignment of each control word in the [PG\[6\]RW\[62, 6A\]](#) group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 16, “DCS DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin.”.

NOTE 4 [PG\[6\]RW\[62, 6A\] OP\[7:0\]](#) will be sticky, cleared by power cycle not reset.

7.27.4 PG[6]RW[63, 6B] - DCS0_n and DCS1_n Receiver DFE Tap 3 Coefficients

Table 196 — PG[6]RW[63, 6B]: DCS0_n and DCS1_n Receiver DFE Tap 3 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Tap 3 DFE Coefficient ^{2,3,4}	(Default) Tap 3 DFE bias = 0 mV
x	x	x	0	0	0	0	1		Tap 3 DFE bias +1 Tap Step
x	x	x	0	0	0	1	0		Tap 3 DFE bias +2 Tap Steps
x	x	x	0	0	0	1	1		Tap 3 DFE bias +3 Tap Steps
x	x	x	0	0	1	0	0		Tap 3 DFE bias +4 Tap Steps
x	x	x	0	0	1	0	1		Tap 3 DFE bias +5 Tap Steps
x	x	x	0	0	1	1	0		Tap 3 DFE bias +6 Tap Steps
x	x	x	0	0	1	1	1		Tap 3 DFE bias +7 Tap Steps
x	x	x	0	1	0	0	0		Tap 3 DFE bias +8 Tap Steps
x	x	x	0	1	0	0	1		Tap 3 DFE bias +9 Tap Steps
x	x	x	0	1	0	1	0		Tap 3 DFE bias +10 Tap Steps
x	x	x	0	1	0	1	1		Tap 3 DFE bias +11 Tap Steps
x	x	x	0	1	1	0	0		Tap 3 DFE bias +12 Tap Steps
x	x	x	0	1	1	0	1		Tap 3 DFE bias +13 Tap Steps
x	x	x	0	1	1	1	0		Tap 3 DFE bias +14 Tap Steps
x	x	x	0	1	1	1	1		Tap 3 DFE bias +15 Tap Steps
x	x	x	1	0	0	0	0		Reserved
x	x	x	1	0	0	0	1		Reserved
x	x	x	1	0	0	1	0		Reserved
x	x	x	1	0	0	1	1		Reserved
x	x	x	1	0	1	0	0		Reserved
x	x	x	1	0	1	0	1		Reserved
x	x	x	1	0	1	1	0		Reserved
x	x	x	1	0	1	1	1		Reserved
x	x	x	1	1	0	0	0		Reserved
x	x	x	1	1	0	0	1		Reserved
x	x	x	1	1	0	1	0		Reserved
x	x	x	1	1	0	1	1		Reserved
x	x	x	1	1	1	0	0		Reserved
x	x	x	1	1	1	0	1		Reserved
x	x	x	1	1	1	1	0		Reserved
x	x	x	1	1	1	1	1		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 3 Coefficient Sign Bit	(Default) Positive Tap 3 DFE bias when Tap 3 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 3 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 3 DFE bias when Tap 3 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 3 post-cursor)

NOTE 1 Table 88 illustrates the assignment of each control word in the PG[6]RW[63, 6B] group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 16, “DCS DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin.”.

NOTE 4 PG[6]RW[63, 6B] OP[7:0] will be sticky, cleared by power cycle not reset.

7.27.5 PG[6]RW[64, 6C]- DCS0_n and DCS1_n Receiver DFE Tap 4 Coefficients

Table 197 — PG[6]RW[64, 6C]: DCS0_n and DCS1_n Receiver DFE Tap 4 Coefficients¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	0	0	0	0	0	Tap 4 DFE Coefficient ^{2,3,4}	(Default) Tap 4 DFE bias = 0 mV
x	x	x	0	0	0	0	1		Tap 4 DFE bias +1 Tap Steps
x	x	x	0	0	0	1	0		Tap 4 DFE bias +2 Tap Steps
x	x	x	0	0	0	1	1		Tap 4 DFE bias +3 Tap Steps
x	x	x	0	0	1	0	0		Tap 4 DFE bias +4 Tap Steps
x	x	x	0	0	1	0	1		Tap 4 DFE bias +5 Tap Steps
x	x	x	0	0	1	1	0		Tap 4 DFE bias +6 Tap Steps
x	x	x	0	0	1	1	1		Tap 4 DFE bias +7 Tap Steps
x	x	x	0	1	0	0	0		Tap 4 DFE bias +8 Tap Steps
x	x	x	0	1	0	0	1		Tap 4 DFE bias +9 Tap Steps
x	x	x	0	1	0	1	0		Tap 4 DFE bias +10 Tap Steps
x	x	x	0	1	0	1	1		Tap 4 DFE bias +11 Tap Steps
x	x	x	0	1	1	0	0		Tap 4 DFE bias +12 Tap Steps
x	x	x	0	1	1	0	1		Tap 4 DFE bias +13 Tap Steps
x	x	x	0	1	1	1	0		Tap 4 DFE bias +14 Tap Steps
x	x	x	0	1	1	1	1		Tap 4 DFE bias +15 Tap Steps
x	x	x	1	0	0	0	0		Reserved
x	x	x	1	0	0	0	1		Reserved
x	x	x	1	0	0	1	0		Reserved
x	x	x	1	0	0	1	1		Reserved
x	x	x	1	0	1	0	0		Reserved
x	x	x	1	0	1	0	1		Reserved
x	x	x	1	0	1	1	0		Reserved
x	x	x	1	0	1	1	1		Reserved
x	x	x	1	1	0	0	0		Reserved
x	x	x	1	1	0	0	1		Reserved
x	x	x	1	1	0	1	0		Reserved
x	x	x	1	1	0	1	1		Reserved
x	x	x	1	1	1	0	0		Reserved
x	x	x	1	1	1	0	1		Reserved
x	x	x	1	1	1	1	0		Reserved
x	x	x	1	1	1	1	1		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Tap 4 Coefficient Sign Bit	(Default) Positive Tap 4 DFE bias when Tap 4 post-cursor is Logic 1 (Negative bias for Logic 0 Tap 4 post-cursor)
1	x	x	x	x	x	x	x		Negative Tap 4 DFE bias when Tap 4 post-cursor is Logic 1 (Positive bias for Logic 0 Tap 4 post-cursor)

NOTE 1 Table 88 illustrates the assignment of each control word in the PG[6]RW[64, 6C] group to the corresponding input pin it controls.

NOTE 2 Tap coefficient values are verified by design and the measurement from device pins is defined in a separate specification.

NOTE 3 Allowable Differential nonlinearity (DNL) and the allowable Integral nonlinearity (INL) are defined in Table 16, “DCS DFE Gain and Tap Coefficient Step Parameters Required per Speed Bin.”.

NOTE 4 PG[6]RW[64, 6C] OP[7:0] will be sticky, cleared by power cycle not reset.

7.27.6 PG[6]RW[70, 74] DCS DFE Error Counter Lower 8 Bits**Table 198 — PG[6]RW[70, 74]- DCS DFE Error Counter Lower 8 Bit**

DCS DFE Error Counter Lower 8 Bit Register ^{1,2,3,4}							
OP7	OP6	OP5	OP4	OP3	OP2	OP1	OP0
EC7	EC6	EC5	EC4	EC3	EC2	EC1	EC0

NOTE 1 Table 88 illustrates the assignment of each control word in the PG[6]RW[70, 74] group to the corresponding input pin it controls.

NOTE 2 Power on Default is OP[7:0] = 0.

NOTE 3 Read Only Register.

NOTE 4 Error counters of a DCS will run only when this DCS is selected for DFE training.

7.27.7 PG[6]RW[71, 75] - DCS DFE Error Counter Upper 8 Bits**Table 199 — PG[6]RW[71, 75] DCS DFE Error Counter Upper 8 Bit**

DCS DFE Error Counter Upper 8 Bit Register ^{1,2,3,4}							
OP7	OP6	OP5	OP4	OP3	OP2	OP1	OP0
EC 15	EC 14	EC 13	EC 12	EC 11	EC 10	EC 9	EC 8

NOTE 1 Table 88 illustrates the assignment of each control word in the PG[6]RW[71, 75] group to the corresponding input pin it controls.

NOTE 2 Power on Default is OP[7:0] = 0.

NOTE 3 Read Only Register.

NOTE 4 Error counters of a DCS will run only when this DCS is selected for DFE training.

PG02RW[62, 66 .. 7E]							DCS DFE Training VREF in mV ^{1,2,3,4,5}							
OP7	OP6	OP5	OP4	OP3	OP2	PG[6]RW79[x ⁶] = 1 (NEG Range)				PG[6]RW79[x ⁶] = 0 (POS Range)				
						OP[1:0] = 00	OP[1:0] = 01	OP[1:0] = 10	OP[1:0] = 11	OP[1:0] = 00	OP[1:0] = 01	OP[1:0] = 10	OP[1:0] = 11	
0	0	0	0	0	0	0.0	- 2.5	- 5.0	- 7.5	0.0	+ 2.5	+ 5.0	+ 7.5	
0	0	0	0	0	1	- 10.0	- 12.5	- 15.0	- 17.5	+ 10.0	+ 12.5	+ 15.0	+ 17.5	
0	0	0	0	1	0	- 20.0	- 22.5	- 25.0	- 27.5	+ 20.0	+ 22.5	+ 25.0	+ 27.5	
0	0	0	0	1	1	- 30.0	- 32.5	- 35.0	- 37.5	+ 30.0	+ 32.5	+ 35.0	+ 37.5	
0	0	0	1	0	0	- 40.0	- 42.5	- 45.0	- 47.5	+ 40.0	+ 42.5	+ 45.0	+ 47.5	
0	0	0	1	0	1	- 50.0	- 52.5	- 55.0	- 57.5	+ 50.0	+ 52.5	+ 55.0	+ 57.5	
0	0	0	1	1	0	- 60.0	- 62.5	- 65.0	- 67.5	+ 60.0	+ 62.5	+ 65.0	+ 67.5	
0	0	0	1	1	1	- 70.0	- 72.5	- 75.0	- 77.5	+ 70.0	+ 72.5	+ 75.0	+ 77.5	
0	0	1	0	0	0	- 80.0	- 82.5	- 85.0	- 87.5	+ 80.0	+ 82.5	+ 85.0	+ 87.5	
0	0	1	0	0	1	- 90.0	- 92.5	- 95.0	- 97.5	+ 90.0	+ 92.5	+ 95.0	+ 97.5	
0	0	1	0	1	0	- 100.0	- 102.5	- 105.0	- 107.5	+ 100.0	+ 102.5	+ 105.0	+ 107.5	
0	0	1	0	1	1	- 110.0	- 112.5	- 115.0	- 117.5	+ 110.0	+ 112.5	+ 115.0	+ 117.5	
0	0	1	1	0	0	- 120.0	- 122.5	- 125.0	- 127.5	+ 120.0	+ 122.5	+ 125.0	+ 127.5	
0	0	1	1	0	1	- 130.0	- 132.5	- 135.0	- 137.5	+ 130.0	+ 132.5	+ 135.0	+ 137.5	
0	0	1	1	1	0	- 140.0	- 142.5	- 145.0	- 147.5	+ 140.0	+ 142.5	+ 145.0	+ 147.5	
0	0	1	1	1	1	- 150.0	- 152.5	- 155.0	- 157.5	+ 150.0	+ 152.5	+ 155.0	+ 157.5	
0	1	0	0	0	0	- 160.0	- 162.5	- 165.0	- 167.5	+ 160.0	+ 162.5	+ 165.0	+ 167.5	
0	1	0	0	0	1	- 170.0	- 172.5	- 175.0	- 177.5	+ 170.0	+ 172.5	+ 175.0	+ 177.5	
0	1	0	0	1	0	- 180.0	- 182.5	- 185.0	- 187.5	+ 180.0	+ 182.5	+ 185.0	+ 187.5	
0	1	0	0	1	1	- 190.0	- 192.5	- 195.0	- 197.5	+ 190.0	+ 192.5	+ 195.0	+ 197.5	
0	1	0	1	0	0	- 200.0	- 202.5	- 205.0	- 207.5	+ 200.0	+ 202.5	+ 205.0	+ 207.5	
0	1	0	1	0	1	- 210.0	- 212.5	- 215.0	- 217.5	+ 210.0	+ 212.5	+ 215.0	+ 217.5	
0	1	0	1	1	0	- 220.0	- 222.5	- 225.0	- 227.5	+ 220.0	+ 222.5	+ 225.0	+ 227.5	
0	1	0	1	1	1	- 230.0	- 232.5	- 235.0	- 237.5	+ 230.0	+ 232.5	+ 235.0	+ 237.5	
0	1	1	0	0	0	- 240.0	- 242.5	- 245.0	- 247.5	+ 240.0	+ 242.5	+ 245.0	+ 247.5	
0	1	1	0	0	1	- 250.0	- 252.5	- 255.0	- 257.5	+ 250.0	+ 252.5	+ 255.0	+ 257.5	
0	1	1	0	1	0	- 260.0	- 262.5	- 265.0	- 267.5	+ 260.0	+ 262.5	+ 265.0	+ 267.5	
0	1	1	0	1	1	- 270.0	- 272.5	- 275.0	- 277.5	+ 270.0	+ 272.5	+ 275.0	+ 277.5	
0	1	1	1	0	0	- 280.0	- 282.5	- 285.0	- 287.5	+ 280.0	+ 282.5	+ 285.0	+ 287.5	
0	1	1	1	0	1	- 290.0	- 292.5	- 295.0	- 297.5	+ 290.0	+ 292.5	+ 295.0	+ 297.5	
0	1	1	1	1	0	- 300.0	- 302.5	- 305.0	- 307.5	+ 300.0	+ 302.5	+ 305.0	+ 307.5	
0	1	1	1	1	1	- 310.0	- 312.5	- 315.0	- 317.5	+ 310.0	+ 312.5	+ 315.0	+ 317.5	
1	0	0	0	0	0	- 320.0	- 322.5	- 325.0	- 327.5	+ 320.0	+ 322.5	+ 325.0	+ 327.5	
1	0	0	0	0	1	- 330.0	- 332.5	- 335.0	- 337.5	+ 330.0	+ 332.5	+ 335.0	+ 337.5	
1	0	0	0	1	0	- 340.0	- 342.5	- 345.0	- 347.5	+ 340.0	+ 342.5	+ 345.0	+ 347.5	
1	0	0	0	1	1	- 350.0	- 352.5	- 355.0	- 357.5	+ 350.0	+ 352.5	+ 355.0	+ 357.5	
1	0	0	1	0	0	- 360.0	- 362.5	- 365.0	- 367.5	+ 360.0	+ 362.5	+ 365.0	+ 367.5	
1	0	0	1	0	1	- 370.0	- 372.5	- 375.0	- 377.5	+ 370.0	+ 372.5	+ 375.0	+ 377.5	
1	0	0	1	1	0	- 380.0	- 382.5	- 385.0	- 387.5	+ 380.0	+ 382.5	+ 385.0	+ 387.5	
1	0	0	1	1	1	- 390.0	- 392.5	- 395.0	- 397.5	+ 390.0	+ 392.5	+ 395.0	+ 397.5	
1	0	1	0	0	0	- 400.0	- 402.5	- 405.0	- 407.5	+ 400.0	+ 402.5	+ 405.0	+ 407.5	
1	0	1	0	0	1	- 410.0	- 412.5	- 415.0	- 417.5	+ 410.0	+ 412.5	+ 415.0	+ 417.5	
1	0	1	0	1	0	- 420.0	- 422.5	- 425.0	- 427.5	+ 420.0	+ 422.5	+ 425.0	+ 427.5	
1	0	1	0	1	1	- 430.0	- 432.5	- 435.0	- 437.5	+ 430.0	+ 432.5	+ 435.0	+ 437.5	
1	0	1	1	0	0	- 440.0	- 442.5	- 445.0	- 447.5	+ 440.0	+ 442.5	+ 445.0	+ 447.5	
1	0	1	1	0	1	- 450.0	- 452.5	- 455.0	- 457.5	+ 450.0	+ 452.5	+ 455.0	+ 457.5	
1	0	1	1	1	0	- 460.0	- 462.5	- 465.0	- 467.5	+ 460.0	+ 462.5	+ 465.0	+ 467.5	
1	0	1	1	1	1	- 470.0	- 472.5	- 475.0	- 477.5	+ 470.0	+ 472.5	+ 475.0	+ 477.5	
1	1	0	0	0	0	- 480.0	- 482.5	- 485.0	- 487.5	+ 480.0	+ 482.5	+ 485.0	+ 487.5	
1	1	0	0	0	1	- 490.0	- 492.5	- 495.0	- 497.5	+ 490.0	+ 492.5	+ 495.0	+ 497.5	
1	1	0	0	1	0	- 500.0	Reserved	Reserved	Reserved	+ 500.0	Reserved	Reserved	Reserved	
1	1	0	0	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	0	1	0	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	0	1	0	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	0	1	1	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	0	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	0	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	1	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	0	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	0	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	0	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	1	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	
1	1	1	1	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	

NOTE 1 Table 88 illustrates the assignment of each control word in the PG[6]RW[72, 76] group to the corresponding input pin it controls.

NOTE 2 These are target DFE_Vref values. Acceptable actual values are determined based on tolerances defined in electrical section.

NOTE 3 The target DFE_Vref values shown in this table are input referred.

NOTE 4 Even though each input receiver has a dedicated DFE_Vref control word, only one DFE Vref monitor is allowed to be enabled at the same time in each sub-channel.

NOTE 5 VrefCS and DFE_Vref are independent. External VrefCS must be adjusted for large input swings.

NOTE 6 The range selection per DCSx is controlled by writing to PG[6]RW79[OP1:OP0].

7.27.9 PG[6]RW[73, 77] - 8-bit LFSR Seed for DCS DFE Training Mode Control Word

Table 201 — PG[6]RW[73, 77] 8-bit LFSR Seed for DCS DFE Training Mode Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
0	0	0	0	0	0	0	0	8-bit LFSR Seed	LFSR Seed = 0x00*
0	0	0	0	0	0	0	1		LFSR Seed = 0x01
0	0	0	0	0	0	1	0		LFSR Seed = 0x02
...									...
1	1	1	1	1	1	0	0		LFSR Seed = 0xFC
1	1	1	1	1	1	0	1		LFSR Seed = 0xFD
1	1	1	1	1	1	1	0		LFSR Seed = 0xFE
1	1	1	1	1	1	1	1		LFSR Seed = 0xFF

NOTE 1 Table 88 illustrates the assignment of each control word in the PG[6]RW[73, 77] group to the corresponding input pin it controls.

7.27.10 PG[6]RW78 - DCS DFE Configuration Register Control Word

Table 202 — PG[6]RW78 - DCS DFE Configuration Register Control Word^{1,2}

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Reserved	Reserved
x	x	x	x	x	x	x	1		Reserved
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x		Reserved
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Tap 1 Enable for DCS0_n and DCS1_n	(Default) Tap 1 disabled
x	x	x	1	x	x	x	x	Tap 2 Enable for DCS0_n and DCS1_n	Tap 1 enabled
x	x	0	x	x	x	x	x	Tap 3 Enable for DCS0_n and DCS1_n	(Default) Tap 2 disabled
x	x	1	x	x	x	x	x	Tap 4 Enable for DCS0_n and DCS1_n	Tap 2 enabled
x	0	x	x	x	x	x	x	Tap 3 Enable for DCS0_n and DCS1_n	(Default) Tap 3 disabled
x	1	x	x	x	x	x	x	Tap 4 Enable for DCS0_n and DCS1_n	Tap 3 enabled
0	x	x	x	x	x	x	x	Tap 4 Enable for DCS0_n and DCS1_n	(Default) Tap 4 disabled
1	x	x	x	x	x	x	x	Tap 4 Enable for DCS0_n and DCS1_n	Tap 4 enabled

NOTE 1 When DCS0_n is selected, DCS1_n is the qualifier. When DCS1_n is selected, DCS0_n is the qualifier. RWUPD mode is not supported for DCS DFE training.

NOTE 2 PG[6]RW78[7:4] will be sticky, cleared by power cycle not reset.

7.27.11 PG[6]RW79 - DCS DFE_Vref Range Selection Control Word

Table 203 — PG[6]RW79 - DCS DFE_Vref Range Selection Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCS0_n DFE_Vref Range Select	Positive
x	x	x	x	x	x	x	1		Negative
x	x	x	x	x	x	0	x	DCS1_n DFE_Vref Range Select	Positive
x	x	x	x	x	x	1	x		Negative
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 PG[6]RW79[1:0] selects the sign for DCS DFE_Vref registers located in PG[6]RW[72, 76].

7.28 PG[7] DESTM, HIT-SR, Enhanced CTLE Control Words

7.28.1 PG[7]RW60 - (DESTM) Control Global Control Word

All control word bits are global, accessible via sub-channel A only.

Table 204 — PG[7]RW60: (DESTM) Control Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Device Equalization Self-Train Mode Enable ¹	(Default) Disabled
x	x	x	x	x	x	x	1		Enabled
x	x	x	x	x	x	0	x	Training Start ²	(Default) Stop Training
x	x	x	x	x	x	1	x		Start Training
x	x	x	x	x	0	x	x	Continuous Mode ³	(Default) Disabled
x	x	x	x	x	1	x	x		Enabled ⁴
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	0	0	0	x	x	x	x	Training pattern length select ⁵	LFSR8 (Default)
x	0	0	1	x	x	x	x		LFSR16
x	0	1	0	x	x	x	x		Reserved for future use
x	0	1	1	x	x	x	x		Reserved for future use
x	1	0	0	x	x	x	x		Reserved for future use
x	1	0	1	x	x	x	x		Reserved for future use
x	1	1	0	x	x	x	x		Reserved for future use
x	1	1	1	x	x	x	x		Reserved for future use
0	x	x	x	x	x	x	x	ALERT_n or QLBD/QLBS low assertion enabled ⁶	(Default) Low assertion disabled
1	x	x	x	x	x	x	x		Low assertion enabled

NOTE 1 If this bit is set to the default “0”, then MRCD will not start the DESTM even if the PG[7]RW60[1] is set to “1”.

NOTE 2 Before the Host configures this bit to “1”, the LFSR patterns on the selected bits should already be running. When the Host configures this bit to “1”, the device will start the Self-Train on the selected DCS and DCA bits. When the training is finished, the device will clear this bit back to the default “0”. If the Host writes a “0” to this bit, the training will be stopped no matter if it is finished or not, and ALERT_n or QLBD/QLBS will be driven back to HIGH.

NOTE 3 When this bit is configured to “0”, the continuous mode is disabled, and the device will self stop the internal training state machine when it is done. When this bit is configured to “1”, the continuous training mode is enabled, and the device will repeatedly run the internal training state machine until the Host configures PG[7]RW60[1]=“0” to stop the training. When the continuous training mode is enabled, the ALERT_n or QLBD/QLBS will not be asserted during the training procedure.

NOTE 4 Low assertion feature must be disabled PG[7]RW60[7]=“0” prior to entering Continuous mode.

NOTE 5 If multiple DCS and DCA bits are selected for Self-Train, the LFSR patterns for these bits should be independent of one another. The LFSR seeds of these bit lanes should be staggered, with multiple steps away from each other. With dependent patterns for different bits, the crosstalk among these bits may be treated as ISI, therefore the training results of DFE taps may be incorrect and suboptimal. For the unselected DQ lanes, the Host should drive static HIGH.

NOTE 6 The Host uses RW01[5] to choose either ALERT_n or QLBD/QLBS to feedback the self train status. If PG[7]RW60[7] is configured to “1”, ALERT_n or QLBD/QLBS will be asserted during the Self-Train procedure, and will be de-asserted when the training procedure is finished. This is for the device to signal the Host the training status.

7.28.2 PG[7]RW62 - DESTM CTLE Control Word

Table 205 — PG[7]RW62: DESTM CTLE Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	CTLE select	(Default) Selected to be trained
x	x	x	x	x	x	x	1		Not selected to be trained
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x		Reserved
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

7.28.3 PG[7]RW63 - DESTM DCS Select Control Word

Table 206 — PG[7]RW63: DESTM DCS Select Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCS0_n select	(Default) Not selected to be trained
x	x	x	x	x	x	x	1		Selected to be trained
x	x	x	x	x	x	0	x	DCS1_n select	(Default) Not selected to be trained
x	x	x	x	x	x	1	x		Selected to be trained
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	DCS0 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	1	x	x	x	x	x	x		Failure occurred
0	x	x	x	x	x	x	x	DCS1 Fail Status Bit (Read Only) ^{2,3}	Executed normally
1	x	x	x	x	x	x	x		Failure occurred

NOTE 1 This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

NOTE 2 DESTM did not execute correctly. This register bit gets updated when DESTM training stops [PG\[7\]RW60\[1\]](#) = 0, either by Host or RCD self-clear.

NOTE 3 The Fail Status bits self-clear on DESTM start.

7.28.4 PG[7]RW64 - DESTM DCA Select Control Word

Table 207 — PG[7]RW64: DESTM DCA Select Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCA0 select	(Default) Not selected to be trained
x	x	x	x	x	x	x	1		Selected to be trained
x	x	x	x	x	x	0	x	DCA1 select	(Default) Not selected to be trained
x	x	x	x	x	x	1	x		Selected to be trained
x	x	x	x	x	0	x	x	DCA2 select	(Default) Not selected to be trained
x	x	x	x	x	1	x	x		Selected to be trained
x	x	x	x	0	x	x	x	DCA3 select	(Default) Not selected to be trained
x	x	x	x	1	x	x	x		Selected to be trained
x	x	x	0	x	x	x	x	DCA4 select	(Default) Not selected to be trained
x	x	x	1	x	x	x	x		Selected to be trained
x	x	0	x	x	x	x	x	DCA5 select	(Default) Not selected to be trained
x	x	1	x	x	x	x	x		Selected to be trained
x	0	x	x	x	x	x	x	DCA6 select	(Default) Not selected to be trained
x	1	x	x	x	x	x	x		Selected to be trained
0	x	x	x	x	x	x	x	DPAR select	(Default) Not selected to be trained
1	x	x	x	x	x	x	x		Selected to be trained

NOTE 1 This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

7.28.5 PG[7]RW65- DESTM DCA Status Control Word

Table 208 — PG[7]RW65: DESTM DCA Status Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	DCA0 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	x	x	x	x	x	x	1		Failure occurred
x	x	x	x	x	x	0	x	DCA1 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	x	x	x	x	x	1	x		Failure occurred
x	x	x	x	x	0	x	x	DCA2 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	x	x	x	x	1	x	x		Failure occurred
x	x	x	x	0	x	x	x	DCA3 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	x	x	x	1	x	x	x		Failure occurred
x	x	x	0	x	x	x	x	DCA4 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	x	x	1	x	x	x	x		Failure occurred
x	x	0	x	x	x	x	x	DCA5 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	x	1	x	x	x	x	x		Failure occurred
x	0	x	x	x	x	x	x	DCA6 Fail Status Bit (Read Only) ^{2,3}	Executed normally
x	1	x	x	x	x	x	x		Failure occurred
0	x	x	x	x	x	x	x	DPAR Fail Status Bit (Read Only) ^{2,3}	Executed normally
1	x	x	x	x	x	x	x		Failure occurred

NOTE 1 This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

NOTE 2 DESTM did not execute correctly. This register bit gets updated when DESTM training stops, either by Host or RCD self-clear.

NOTE 3 The Fail Status bits self-clear on DESTM start.

7.28.6 PG[7]RW68 - Host interface training support during Self-Refresh (HIT-SR) Mode Global Control Word

All control word bits are global, accessible via sub-channel A only.

Table 209 — PG[7]RW68- HIT-SR Global Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Host interface training support during Self-Refresh mode ²	Disabled (Default)
x	x	x	x	x	x	x	1		Enabled
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x		Reserved
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This control word is global for sub-channels A and B

NOTE 2 This feature must be enabled or disabled for both sub-channels. When this feature is enabled, the two sub-channels can be trained separately.

7.28.7 PG[7]RW70 - Enhanced CTLE Control Global Control Word

All control word bits are global, accessible via sub-channel A only.

Table 210 — PG[7]RW70: Enhanced CTLE Control Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Enhanced CTLE Enable 1,2	(Default) Enhanced CTLE disabled
x	x	x	x	x	x	x	1		Enhanced CTLE enabled
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x		Reserved
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This bit is sticky, cleared by power cycle not Reset. If this bit is set to the default “0”, then the device continues to use the legacy CTLE. If this bit is set to “1”, then the Enhanced CTLE is enabled.

NOTE 2 RW50[0] must be set to 1 for PG[7]RW70[0] = 1 to be valid. When Enhanced CTLE is enabled, RW51 is used for per-pin CTLE disable. PG[7]RW[75:71] are ignored if PG[7]RW70[0] = 0.

7.28.8 PG[7]RW71 - Enhanced CTLE DCS Select Control Word

Table 211 — PG[7]RW71: Enhanced CTLE DCS Select Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	DCS0_n CTLE setting	(Default) Setting 0 selected
x	x	x	x	0	0	0	1		Setting 1 selected
x	x	x	x	0	0	1	0		Setting 2 selected
x	x	x	x	0	0	1	1		Setting 3 selected
x	x	x	x	0	1	0	0		Setting 4 selected
x	x	x	x	0	1	0	1		Setting 5 selected
x	x	x	x	0	1	1	0		Setting 6 selected
x	x	x	x	0	1	1	1		Setting 7 selected
x	x	x	x	1	0	0	0		Setting 8 selected
x	x	x	x	1	0	0	1		Setting 9 selected
x	x	x	x	1	0	1	0		Setting 10 selected
x	x	x	x	1	0	1	1		Setting 11 selected
x	x	x	x	1	1	0	0		Setting 12 selected
x	x	x	x	1	1	0	1		Setting 13 selected
x	x	x	x	1	1	1	0		Setting 14 selected
x	x	x	x	1	1	1	1		Setting 15 selected
0	0	0	0	x	x	x	x	DCS1_n CTLE setting	(Default) Setting 0 selected
0	0	0	1	x	x	x	x		Setting 1 selected
0	0	1	0	x	x	x	x		Setting 2 selected
0	0	1	1	x	x	x	x		Setting 3 selected
0	1	0	0	x	x	x	x		Setting 4 selected
0	1	0	1	x	x	x	x		Setting 5 selected
0	1	1	0	x	x	x	x		Setting 6 selected
0	1	1	1	x	x	x	x		Setting 7 selected
1	0	0	0	x	x	x	x		Setting 8 selected
1	0	0	1	x	x	x	x		Setting 9 selected
1	0	1	0	x	x	x	x		Setting 10 selected
1	0	1	1	x	x	x	x		Setting 11 selected
1	1	0	0	x	x	x	x		Setting 12 selected
1	1	0	1	x	x	x	x		Setting 13 selected
1	1	1	0	x	x	x	x		Setting 14 selected
1	1	1	1	x	x	x	x		Setting 15 selected

NOTE 1 OP[7:0] are sticky, cleared by power cycle not Reset. This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

7.28.9 PG[7]RW72 - Enhanced CTLE DCA[1:0] Select Control Word

Table 212 — PG[7]RW72: Enhanced CTLE DCA[1:0] Select Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	DCA0 CTLE setting	(Default) Setting 0 selected
x	x	x	x	0	0	0	1		Setting 1 selected
x	x	x	x	0	0	1	0		Setting 2 selected
x	x	x	x	0	0	1	1		Setting 3 selected
x	x	x	x	0	1	0	0		Setting 4 selected
x	x	x	x	0	1	0	1		Setting 5 selected
x	x	x	x	0	1	1	0		Setting 6 selected
x	x	x	x	0	1	1	1		Setting 7 selected
x	x	x	x	1	0	0	0		Setting 8 selected
x	x	x	x	1	0	0	1		Setting 9 selected
x	x	x	x	1	0	1	0		Setting 10 selected
x	x	x	x	1	0	1	1		Setting 11 selected
x	x	x	x	1	1	0	0		Setting 12 selected
x	x	x	x	1	1	0	1		Setting 13 selected
x	x	x	x	1	1	1	0		Setting 14 selected
x	x	x	x	1	1	1	1		Setting 15 selected
0	0	0	0	x	x	x	x	DCA1 CTLE setting	(Default) Setting 0 selected
0	0	0	1	x	x	x	x		Setting 1 selected
0	0	1	0	x	x	x	x		Setting 2 selected
0	0	1	1	x	x	x	x		Setting 3 selected
0	1	0	0	x	x	x	x		Setting 4 selected
0	1	0	1	x	x	x	x		Setting 5 selected
0	1	1	0	x	x	x	x		Setting 6 selected
0	1	1	1	x	x	x	x		Setting 7 selected
1	0	0	0	x	x	x	x		Setting 8 selected
1	0	0	1	x	x	x	x		Setting 9 selected
1	0	1	0	x	x	x	x		Setting 10 selected
1	0	1	1	x	x	x	x		Setting 11 selected
1	1	0	0	x	x	x	x		Setting 12 selected
1	1	0	1	x	x	x	x		Setting 13 selected
1	1	1	0	x	x	x	x		Setting 14 selected
1	1	1	1	x	x	x	x		Setting 15 selected

NOTE 1 OP[7:0] are sticky, cleared by power cycle not Reset. This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

7.28.10 PG[7]RW73 - Enhanced CTLE DCA[3:2] Select Control Word

Table 213 — PG[7]RW73: Enhanced CTLE DCA[3:2] Select Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	DCA2 CTLE setting	(Default) Setting 0 selected
x	x	x	x	0	0	0	1		Setting 1 selected
x	x	x	x	0	0	1	0		Setting 2 selected
x	x	x	x	0	0	1	1		Setting 3 selected
x	x	x	x	0	1	0	0		Setting 4 selected
x	x	x	x	0	1	0	1		Setting 5 selected
x	x	x	x	0	1	1	0		Setting 6 selected
x	x	x	x	0	1	1	1		Setting 7 selected
x	x	x	x	1	0	0	0		Setting 8 selected
x	x	x	x	1	0	0	1		Setting 9 selected
x	x	x	x	1	0	1	0		Setting 10 selected
x	x	x	x	1	0	1	1		Setting 11 selected
x	x	x	x	1	1	0	0		Setting 12 selected
x	x	x	x	1	1	0	1		Setting 13 selected
x	x	x	x	1	1	1	0		Setting 14 selected
x	x	x	x	1	1	1	1		Setting 15 selected
0	0	0	0	x	x	x	x	DCA3 CTLE setting	(Default) Setting 0 selected
0	0	0	1	x	x	x	x		Setting 1 selected
0	0	1	0	x	x	x	x		Setting 2 selected
0	0	1	1	x	x	x	x		Setting 3 selected
0	1	0	0	x	x	x	x		Setting 4 selected
0	1	0	1	x	x	x	x		Setting 5 selected
0	1	1	0	x	x	x	x		Setting 6 selected
0	1	1	1	x	x	x	x		Setting 7 selected
1	0	0	0	x	x	x	x		Setting 8 selected
1	0	0	1	x	x	x	x		Setting 9 selected
1	0	1	0	x	x	x	x		Setting 10 selected
1	0	1	1	x	x	x	x		Setting 11 selected
1	1	0	0	x	x	x	x		Setting 12 selected
1	1	0	1	x	x	x	x		Setting 13 selected
1	1	1	0	x	x	x	x		Setting 14 selected
1	1	1	1	x	x	x	x		Setting 15 selected

NOTE 1 OP[7:0] are sticky, cleared by power cycle not Reset. This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

7.28.11 PG[7]RW74 - Enhanced CTLE DCA[5:4] Select Control Word

Table 214 — PG[7]RW74: Enhanced CTLE DCA[5:4] Select Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	DCA4 CTLE setting	(Default) Setting 0 selected
x	x	x	x	0	0	0	1		Setting 1 selected
x	x	x	x	0	0	1	0		Setting 2 selected
x	x	x	x	0	0	1	1		Setting 3 selected
x	x	x	x	0	1	0	0		Setting 4 selected
x	x	x	x	0	1	0	1		Setting 5 selected
x	x	x	x	0	1	1	0		Setting 6 selected
x	x	x	x	0	1	1	1		Setting 7 selected
x	x	x	x	1	0	0	0		Setting 8 selected
x	x	x	x	1	0	0	1		Setting 9 selected
x	x	x	x	1	0	1	0		Setting 10 selected
x	x	x	x	1	0	1	1		Setting 11 selected
x	x	x	x	1	1	0	0		Setting 12 selected
x	x	x	x	1	1	0	1		Setting 13 selected
x	x	x	x	1	1	1	0		Setting 14 selected
x	x	x	x	1	1	1	1		Setting 15 selected
0	0	0	0	x	x	x	x	DCA5 CTLE setting	(Default) Setting 0 selected
0	0	0	1	x	x	x	x		Setting 1 selected
0	0	1	0	x	x	x	x		Setting 2 selected
0	0	1	1	x	x	x	x		Setting 3 selected
0	1	0	0	x	x	x	x		Setting 4 selected
0	1	0	1	x	x	x	x		Setting 5 selected
0	1	1	0	x	x	x	x		Setting 6 selected
0	1	1	1	x	x	x	x		Setting 7 selected
1	0	0	0	x	x	x	x		Setting 8 selected
1	0	0	1	x	x	x	x		Setting 9 selected
1	0	1	0	x	x	x	x		Setting 10 selected
1	0	1	1	x	x	x	x		Setting 11 selected
1	1	0	0	x	x	x	x		Setting 12 selected
1	1	0	1	x	x	x	x		Setting 13 selected
1	1	1	0	x	x	x	x		Setting 14 selected
1	1	1	1	x	x	x	x		Setting 15 selected

NOTE 1 OP[7:0] are sticky, cleared by power cycle not Reset. This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

7.28.12 PG[7]RW75 - Enhanced CTLE DPAR, DCA6 Select Control Word

Table 215 — PG[7]RW75: Enhanced CTLE DPAR, DCA6 Select Control Word ¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	0	0	0	0	DCA6 CTLE setting	(Default) Setting 0 selected
x	x	x	x	0	0	0	1		Setting 1 selected
x	x	x	x	0	0	1	0		Setting 2 selected
x	x	x	x	0	0	1	1		Setting 3 selected
x	x	x	x	0	1	0	0		Setting 4 selected
x	x	x	x	0	1	0	1		Setting 5 selected
x	x	x	x	0	1	1	0		Setting 6 selected
x	x	x	x	0	1	1	1		Setting 7 selected
x	x	x	x	1	0	0	0		Setting 8 selected
x	x	x	x	1	0	0	1		Setting 9 selected
x	x	x	x	1	0	1	0		Setting 10 selected
x	x	x	x	1	0	1	1		Setting 11 selected
x	x	x	x	1	1	0	0		Setting 12 selected
x	x	x	x	1	1	0	1		Setting 13 selected
x	x	x	x	1	1	1	0		Setting 14 selected
x	x	x	x	1	1	1	1		Setting 15 selected
0	0	0	0	x	x	x	x	DPAR CTLE setting	(Default) Setting 0 selected
0	0	0	1	x	x	x	x		Setting 1 selected
0	0	1	0	x	x	x	x		Setting 2 selected
0	0	1	1	x	x	x	x		Setting 3 selected
0	1	0	0	x	x	x	x		Setting 4 selected
0	1	0	1	x	x	x	x		Setting 5 selected
0	1	1	0	x	x	x	x		Setting 6 selected
0	1	1	1	x	x	x	x		Setting 7 selected
1	0	0	0	x	x	x	x		Setting 8 selected
1	0	0	1	x	x	x	x		Setting 9 selected
1	0	1	0	x	x	x	x		Setting 10 selected
1	0	1	1	x	x	x	x		Setting 11 selected
1	1	0	0	x	x	x	x		Setting 12 selected
1	1	0	1	x	x	x	x		Setting 13 selected
1	1	1	0	x	x	x	x		Setting 14 selected
1	1	1	1	x	x	x	x		Setting 15 selected

NOTE 1 OP[7:0] are sticky, cleared by power cycle not Reset. This control word is defined per sub-channel, and can be accessed through CH_A and CH_B.

7.28.13 PG[7]RW7F - Enhanced RWUPD Mode Control Word**Table 216 — PG[7]RW7F - Enhanced RWUPD Mode Control Word¹**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Enhanced RWUPD Feature Enable ²	Disabled
x	x	x	x	x	x	x	1		Enabled
x	x	x	x	x	x	0	x	Enhanced RWUPD DCS qualifier select	DCS0 is selected as the qualifier
x	x	x	x	x	x	1	x		DCS1 is selected as the qualifier
x	x	x	x	x	0	x	x	Reserved	Reserved
x	x	x	x	x	1	x	x		Reserved
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Exit From Enhanced RW In-Band Updated State	No action.
1	x	x	x	x	x	x	x		(Default) Take the RCD out from Enhanced RWUPD state into train wait state. ³

NOTE 1 PG[7]RW7F - Enhanced RWUPD Mode Control Word is not a global control word there will be two copies one for each sub-channel.

NOTE 2 Default state of PG[7]RW7F[0] is 0, and the default state of PG[7]RW7F[7] is 1.

NOTE 3 Writing a 1 in this bit location takes the RCD out from Enhanced RWUPD state. The RCD hardware clears this register bit upon entry to RWUPD mode when DCS qualifier Low pulse is received. Therefore, a setting PG[7]RW7F[7] = 1 indicates the channel is not in Enhanced RWUPD mode.

7.29 PG[70] Scrambling DCA Control and Upper QCK/QCS Control Words

7.29.1 PG[70]RW60 - Scrambling DCA Control Global Control Word

All control word bits are global, accessible via sub-channel A only.

Table 217 — PG[70]RW60 - Scrambling DCA Control Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Reserved	Reserved
x	x	x	x	x	x	x	1		Reserved
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x		Reserved
x	x	x	x	x	0	x	x	DCA Scramble Enable ¹	Disabled
x	x	x	x	x	1	x	x		Enabled (Resets LFSR on next NOP)
x	x	x	x	0	x	x	x	Reserved	Reserved
x	x	x	x	1	x	x	x		Reserved
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x		Disabled
x	1	x	x	x	x	x	x	Scrambler Reset Enable ^{2,3}	Enabled. The scrambler will be reset automatically following the error flow and also after Self Refresh without clock stop.
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 This bit is NOT sticky

NOTE 2 These bits are sticky, cleared by Power-on Reset not DRST_n

NOTE 3 PG[70]RW60[2] must be set for this mode to take effect.

7.29.2 PG[70]RW61 - Scrambling DCA Error Handling Control Global Control Word

All control word bits are global, accessible via sub-channel A only.

Table 218 — PG[70]RW61 - Scrambling DCA Error Handling Control Global Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Reserved	Reserved
x	x	x	x	x	x	x	1	Reserved	Reserved
x	x	x	x	x	x	0	x	Reserved	Reserved
x	x	x	x	x	x	1	x	Reserved	Reserved
x	x	x	x	x	0	x	x	Scramble Disable on Error ^{1,2}	Disabled
x	x	x	x	x	1	x	x		Enabled
x	x	x	x	0	x	x	x	Scrambler Reset on DERROR_IN_n	Disabled
x	x	x	x	1	x	x	x	Assertion ^{1,2}	Enabled
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x	Reserved	Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x	Reserved	Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x	Reserved	Reserved

NOTE 1 PG[70]RW60[6] must be set for this mode to take effect.

NOTE 2 These bits are sticky, cleared by Power-on Reset not DRST_n

7.29.3 PG[70]RW62 - Upper QCS Enable Global Control Word

All control word bits are global, accessible via sub-channel A only.

Table 219 — PG[70]RW62 - Upper QCS Enable Global Control Word^{1,2}

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	Reserved	Reserved
x	x	x	x	x	x	x	1	Reserved	Reserved
x	x	x	x	x	x	0	x	QACS2_n Output	Disabled
x	x	x	x	x	x	1	x	QACS2_n Output	Enabled. When enabled, this is a copy of QACS0_n.
x	x	x	x	x	0	x	x	QBCS2_n Output	Disabled
x	x	x	x	x	1	x	x	QBCS2_n Output	Enabled. When enabled, this is a copy of QBCS0_n.
x	x	x	x	0	x	x	x	QACS3_n Output	Disabled
x	x	x	x	1	x	x	x	QACS3_n Output	Enabled. When enabled, this is a copy of QACS1_n.
x	x	x	0	x	x	x	x	QBCS3_n Output	Disabled
x	x	x	1	x	x	x	x	QBCS3_n Output	Enabled. When enabled, this is a copy of QBCS1_n.
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x	Reserved	Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x	Reserved	Reserved

NOTE 1 PG[70]RW62[4;1] are sticky, cleared by Power-on Reset not DRST_n.

NOTE 2 The Host needs to wait for tQCK_QCS_EN before normal operation when the upper QCS output is enabled.

7.29.4 PG[70]RW63 - Upper QCK Enable Control Word

Table 220 — PG[70]RW63 - Upper QCK Enable Control Word^{1,2}

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	x	0	QWCK Enable	Disabled
x	x	x	x	x	x	x	1		Enabled
x	x	x	x	x	x	0	x	QXCK Enable	Disabled
x	x	x	x	x	x	1	x		Enabled
x	x	x	x	x	0	x	x	QYCK Enable	Disabled
x	x	x	x	x	1	x	x		Enabled
x	x	x	x	0	x	x	x	QZCK Enable	Disabled
x	x	x	x	1	x	x	x		Enabled
x	x	x	0	x	x	x	x	Reserved	Reserved
x	x	x	1	x	x	x	x		Reserved
x	x	0	x	x	x	x	x	Reserved	Reserved
x	x	1	x	x	x	x	x		Reserved
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Reserved	Reserved
1	x	x	x	x	x	x	x		Reserved

NOTE 1 PG[70]RW63[3;0] are sticky, cleared by Power-on Reset not DRST_n.

NOTE 2 The Host needs to wait for tQCK_QCS_EN before normal operation when the upper QCK output is enabled.

7.29.5 PG[70]RW6A - Upper QCK Driver Characteristics Control Word

Table 221 — PG[70]RW6A - Upper QCK Driver Characteristics Control Word¹

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	x	x	x	x	0	0	QWCK_t/QWCK_c ²	Light Drive
x	x	x	x	x	x	0	1		Moderate Drive
x	x	x	x	x	x	1	0		Strong Drive
x	x	x	x	x	x	1	1		Reserved
x	x	x	x	0	0	x	x	QXCK_t/QXCK_c ²	Light Drive
x	x	x	x	0	1	x	x		Moderate Drive
x	x	x	x	1	0	x	x		Strong Drive
x	x	x	x	1	1	x	x		Reserved
x	x	0	0	x	x	x	x	QYCK_t/QYCK_c ²	Light Drive
x	x	0	1	x	x	x	x		Moderate Drive
x	x	1	0	x	x	x	x		Strong Drive
x	x	1	1	x	x	x	x		Reserved
0	0	x	x	x	x	x	x	QZCK_t/QZCK_c ²	Light Drive
0	1	x	x	x	x	x	x		Moderate Drive
1	0	x	x	x	x	x	x		Strong Drive
1	1	x	x	x	x	x	x		Reserved

NOTE 1 PG[70]RW6A[7;0] are sticky, cleared by Power-on Reset not DRST_n.

NOTE 2 See Table 261, “Output Ron Drive,” for values.

7.29.6 PG[70]RW78 - QWCK Output Delay Control Word

Table 222 — PG[70]RW78 - QWCK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QWCK_t/QWCK_c Output Signals ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64)* t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable	(Default) Feature Disabled
1	x	x	x	x	x	x	x	for QWCK_t/QWCK_c ²	Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW78[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.29.7 PG[70]RW79 - QXCK Output Delay Control Word

Table 223 — PG[70]RW79 - QXCK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QXCK_t/QXCK_c Output Signals ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64)* t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x		Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QXCK_t/QXCK_c ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW79[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.29.8 PG[70]RW7A - QYCK Output Delay Control Word

Table 224 — PG[70]RW7A - QYCK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QYCK_t/QYCK_c Output Signals ^{1,2}	Delay Outputs by $+(0/64) * t_{CK}$ (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by $+(1/64) * t_{CK}$
x	x	0	0	0	0	1	0		Delay Outputs by $+(2/64) * t_{CK}$
x	x
x	x	1	1	1	1	0	1		Delay Outputs by $+(61/64) * t_{CK}$
x	x	1	1	1	1	1	0		Delay Outputs by $+(62/64) * t_{CK}$
x	x	1	1	1	1	1	1		Delay Outputs by $+(63/64) * t_{CK}$
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QYCK_t/QYCK_c ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW7A[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.29.9 PG[70]RW7B - QZCK Output Delay Control Word

Table 225 — PG[70]RW7B - QZCK Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QZCK_t/QZCK_c Output Signals ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64)* t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Reserved	Reserved
x	1	x	x	x	x	x	x	Reserved	Reserved
0	x	x	x	x	x	x	x	Output Delay Feature Enable	(Default) Feature Disabled
1	x	x	x	x	x	x	x	for QZCK_t/QZCK_c ²	Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW7B[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.29.10 PG[70]RW7C - QACS2_n Output Delay Control Word**Table 226 — PG[70]RW7C - QACS2_n Output Delay Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QACS2_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64)* t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QACS2_n ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW7C[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.**7.29.11 PG[70]RW7D - QBCS2_n Output Delay Control Word****Table 227 — PG[70]RW7D - QBCS2_n Output Delay Control Word**

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QBCS2_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64)* t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QBCS2_n ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW7D[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.29.12 PG[70]RW7E - QAC3_n Output Delay Control Word

Table 228 — PG[70]RW7E - QAC3_n Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QACS3_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64)* t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1tCK additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QACS3_n ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW7E[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

7.29.13 PG[70]RW7F - QBC3_n Output Delay Control Word

Table 229 — PG[70]RW7F - QBC3_n Output Delay Control Word

Setting								Definition	Encoding
OP 7	OP 6	OP 5	OP 4	OP 3	OP 2	OP 1	OP 0		
x	x	0	0	0	0	0	0	Output Delay Control for QBCS3_n ^{1,2}	Delay Outputs by +(0/64) * t _{CK} (Same as Default)
x	x	0	0	0	0	0	1		Delay Outputs by +(1/64) * t _{CK}
x	x	0	0	0	0	1	0		Delay Outputs by +(2/64)* t _{CK}
x	x
x	x	1	1	1	1	0	1		Delay Outputs by +(61/64) * t _{CK}
x	x	1	1	1	1	1	0		Delay Outputs by +(62/64) * t _{CK}
x	x	1	1	1	1	1	1		Delay Outputs by +(63/64) * t _{CK}
x	0	x	x	x	x	x	x	Full cycle delay ¹	Disabled
x	1	x	x	x	x	x	x		Enabled adds 1t _{CK} additional delay to OP[5:0]
0	x	x	x	x	x	x	x	Output Delay Feature Enable for QBCS3_n ²	(Default) Feature Disabled
1	x	x	x	x	x	x	x		Feature Enabled ³

NOTE 1 These control bits do not have any effect unless OP7 = 1.

NOTE 2 PG[70]RW7F[7,5:0] will be sticky, cleared by power cycle not Reset.

NOTE 3 When feature is enabled the delay settings in OP[5:0] require a time of t_{ODU} for the delay to become stable on the outputs.

8 Absolute Maximum Ratings

Table 230 — Absolute Maximum Ratings over Operating Free-air Temperature Range¹

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	Supply voltage		−0.3	1.4	V
V_{IN}	Receiver input voltage ²	See Note 4 and 5	−0.3	$V_{DD} + 0.5$	V
V_{OUT}	Driver output voltage ³	See Note 4 and 5	−0.3	$V_{DD} + 0.5$	V
I_{IK}	Input clamp current	$V_{IN} < 0$ or $V_{IN} > V_{DD}$	-	−50	mA
I_{OK}	Output clamp current	$V_{OUT} < 0$ or $V_{OUT} > V_{DD}$	-	±50	mA
I_{OUT}	Continuous output current	$0 < V_{OUT} < V_{DD}$	-	±50	mA
I_{CCC}	Continuous current through each V_{DD} or V_{SS} pin		-	±100	mA
T_{stg}	Storage temperature		−55	+100	°C

NOTE 1 Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 2 This parameter does not apply to SCL. See Management Bus Interface chapter for voltage specifications for these inputs.

NOTE 3 This parameter does not apply to SDA. See Management Bus Interface chapter for voltage specifications for these inputs.

NOTE 4 The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

NOTE 5 This value is limited to 1.4 V maximum.

9 Electrical - Timing Requirements

9.1 Operating Electrical Characteristics

The DDR5RCD05 parametric values are specified for the device default control word settings, unless otherwise stated.

Table 231 — Operating Electrical Characteristics

Symbol	Parameter	Condition	Min	Nom	Max	Unit
V_{DD}	DC Supply voltage ¹	1.1 V Operation	1.067 (-3%)	1.1	1.166 (+6%)	V
V_{DDIO}	DDR5RCD05 Sideband Interface I/O Supply Voltage		0.95	1.0	1.05	V
T_j	Junction temperature ²		0	-	125	°C
T_{case}	Case temperature	Measurement procedure JESD51-2	0	-	103 ³	°C

NOTE 1 DC bandwidth limited to 20 MHz.

NOTE 2 For operation beyond T_j min and max datasheet values are not guaranteed and may de-rate. For operation above T_j max lifetime could be affected. All parametric measurements are performed at 0 °C, 25 °C, and 95 °C.

NOTE 3 This spec is meant to guarantee a T_j of 125 °C by the DDR5RCD05. Since T_j cannot be measured or observed by users, T_{case} is specified instead. Under all thermal condition, the T_j of a DDR5RCD05 shall not be higher than 125 °C.

Table 232 — Input Timing Requirements (cont'd)

Symbol	Parameter	Conditions	DDR5-3200/ 3600/4000		DDR5-4400/ 4800		DDR5-5200/ 5600		DDR5-6000/ 6400		DDR5-6800/ 7200		DDR5-7600/ 8000		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
tDRST_R W2B	DRST_n de-assertion to MRW write to RW2B[0]=0 delay	Waiting time between DRST_n de-assertion and the MRW write to RW2B[0]=0	300	-	300	-	300	-	300	-	300	-	300	-	ns
tDCS_EN	DCS1_n enable time	Time between MRW to RW09[2] to enable DCS1_n and the next pulse on DCS1_n	800	-	800	-	800	-	800	-	800	-	800	-	ns
tQCK_QCS _EN	QCK and QCS enable time	The time that the Host needs to wait for before normal operation when the QCK and QCS output are enabled in PG[70]RW[63:62]	300	-	300	-	300	-	300	-	300	-	300	-	ns
tMRD_L4	Control word to control word delay for DFE Vref Settling Time	Waiting time between an access to RW31[1:0], RW3F, PG02RW[62, 66, 6A, 6E, 72, 76, 7A, 7E], PG[6]RW[72, 76, 79] and the next input DCS_n assertion.	300	-	300	-	300	-	300	-	300	-	300	-	ns
tMRD_CTL E	Control Word to Control Word or DRAM Command delay for CTLE control and setting updates	Number of clock cycles between an access to RW[54:50], PG[7]RW[75:70] and the next control word access or DRAM command ⁹	64	-	64	-	64	-	64	-	64	-	64	-	t _{CK}
tMRC	Register command word to CW or DRAM command delay	Number of clock cycles between register command word (RW04) and CW or any DRAM command	32	-	32	-	40	-	48	-	56	-	64	-	t _{CK}
tExt_LB_En try	External Loopback Entry Time	Delay from MRW (RW26) that enables External Loopback and start of valid QLBD/QLBS forwarded from selected DLBD/DLBS.	-	300	-	300	-	300	-	300	-	300	-	300	ns
tMRD2N	Control word to control word delay in SDR/2N mode.	Same condition as tMRD parameter	16	-	16	-	20	-	24	-	28	-	32	-	
tMRD2N_L	Control word to control word delay in SDR/2N mode	Same condition as tMRD_L parameter	24	-	24	-	30	-	36	-	42	-	48	-	t _{CK}
tMRD2N_L 2	Control word to control word delay in SDR/2N mode	Same condition as tMRD_L2 parameter	50	-	50	-	65	-	75	-	85	-	95	-	t _{CK}
tMRC2N	Register command word to CW or DRAM command delay in SDR/2N mode	Same condition as tMRC parameter	40	-	40	-	50	-	60	-	70	-	80	-	t _{CK}
tRWUPDInit	Time needed from enter into RWUPD to being able to receive in band RW updates		500	-	500	-	500	-	500	-	500	-	500	-	ns

Table 232 — Input Timing Requirements (cont'd)

[illegible]

Table 232 — Input Timing Requirements (cont'd)

Symbol	Parameter	Conditions	DDR5-3200/ 3600/4000		DDR5-4400/ 4800		DDR5-5200/ 5600		DDR5-6000/ 6400		DDR5-6800/ 7200		DDR5-7600/ 8000		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{DCATM_CS_Exit} ¹²	Time DCS0_n must be held LOW to exit from DCATM training mode		2	8	2	8	2	8	2	8	2	8	2	8	t _{CK}
t _{DCATM_Valid}	Time from sample evaluation to output on ALERT_n or QLBx		-	20	-	20	-	20	-	20	-	20	-	20	t _{CK}
t _{DCATM_ALERT_Window}	Time output is available ¹¹ on ALERT_n or QLBx		2	-	2	-	2	-	2	-	2	-	2	-	t _{CK}
t _{DFET-M_Interval}	Number of cycles for DCS and DCA DFE Training data comparison for each output result.	DDR DCA (RW00[0]=1) DFE Training	4	4	4	4	4	4	4	4	4	4	4	4	t _{CK}
		SDR DCA (RW00[0]=0) or DCS DFE Training	8	8	8	8	8	8	8	8	8	8	8	8	
t _{DFET-M_Valid}	Time from end of CA DFE Training data comparison to valid result output.		-	20	-	20	-	20	-	20	-	24	-	24	t _{CK}
t _{DFETM_RSP_Window}	Duration of CA DFE Training output result signal pulse.		2	-	2	-	2	-	2	-	2	-	2	-	t _{CK}
t _{DFET-M_Pattern_Wait_Accel} ¹³	Time between de-assertion of DCS0_n for one pattern to DCS0_n assertion of the next pattern.	DFE Training Accelerator enabled.	64	-	64	-	64	-	64	-	64	-	64	-	t _{CK}
t _{DFET-M_Pattern_Wait} ¹⁴	Time between de-assertion of DCS0_n for one pattern to DCS0_n assertion of the next pattern.	DFE Training Accelerator disabled.	16	-	16	-	16	-	16	-	16	-	16	-	t _{CK}
t _{DFETA_Exit_Wait_Loop_Value}	Minimum wait time after DFETA exit to when inner/outer loop parameters are returned to the values prior to enabling accelerator		24	-	24	-	24	-	24	-	24	-	24	-	t _{CK}
t _{CSALT}	Chip select assertion before and after ALERT_n Pulse Width deassertion	Number of clock cycles between DCSx assertion and rising edge of ALERT_n when RW01[6]=1	8	-	8	-	8	-	8	-	8	-	8	-	t _{CK}
t _{CPDED}	Minimum time between SRE and DCS pulse to drive QCS LOW.	DCS[1:0]_n = HIGH; DRST_n = HIGH; DCK_t/DCK_c = Toggling.	Min: max(8 nCK, 5 ns); Max: (-)												t _{CK}

Table 232 — Input Timing Requirements (cont'd)

Symbol	Parameter	Conditions	DDR5-3200/ 3600/4000		DDR5-4400/ 4800		DDR5-5200/ 5600		DDR5-6000/ 6400		DDR5-6800/ 7200		DDR5-7600/ 8000		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{RINIT2}	Min DCS_n LOW time to DRST_n HIGH.		20	-	20	-	20	-	20	-	20	-	20	-	ns
t _{RINIT3}	Minimum DCS LOW time after DRST_n HIGH.		20	-	20	-	20	-	20	-	20	-	20	-	ns
t _{CKACT}	Maximum time from DCS_n transition HIGH to start of valid DCK.		-	16	-	16	-	16	-	16	-	16	-	16	t _{CK}
t _{XPR}	DRAM minimum time from Exit Reset to first valid Configuration Command		Min: max(5 nCK, t _{RFC} (min) + 10 ns); Max: (-), See DDR5 DRAM Specification												ns
t _{ZQCAL}	ZQ Calibration Time		1	-	1	-	1	-	1	-	1	-	1	-	μs
t _{ZQLAT}	ZQ Calibration Latch Time		Min: max(30 ns, 8 nCK); Max: (-)												ns
t _{RWUPDInit} _ENH	Time needed from enter into Enhanced RWUPD to being able to receive in band RW updates		500	-	500	-	500	-	500	-	500	-	500	-	ns
t _{RWUPDA2} D_ENH	Time between address transfer and data transfer in Enhanced RWUPD mode		16	-	16	-	16	-	16	-	16	-	16	-	nCK
t _{RWUPDD2} A_ENH	Time between data transfer and next operation address transfer in Enhanced RWUPD mode		16	-	16	-	16	-	16	-	16	-	16	-	nCK
t _{DCS_N_Q} UAL_CHG_ENH	Time between the DCS_n qualifier change and next operation in Enhanced RWUPD mode		64	-	64	-	64	-	64	-	64	-	64	-	nCK
t _{RWUPDExi} t_ENH	Time needed between last RWUPD CS1_n de-assertion and the first CS0_n assertion of DFE training mode or any other operation. ¹⁵		500	-	500	-	500	-	500	-	500	-	500	-	ns
t _{RWUPD_D} CSPW_ENH	DCS_n Pulse Width in Enhanced RWUPD mode		3	8	3	8	3	8	3	8	3	8	3	8	nCK

Table 232 — Input Timing Requirements (cont'd)

Symbol	Parameter	Conditions	DDR5-3200/ 3600/4000		DDR5-4400/ 4800		DDR5-5200/ 5600		DDR5-6000/ 6400		DDR5-6800/ 7200		DDR5-7600/ 8000		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{HIT_SU}	Minimum time after the NOP to begin HIT-SR		32	-	32	-	40	-	48	-	56	-	64	-	t _{CK}
t _{DESTM}	Max time required for RCD to complete Self Train after receiving Start Training Command		Min: -; Max: 2500												ms

NOTE 1 Including SSC according Table 239, “SSC and PLL Loop Filter Characteristics.”

NOTE 2 All specified timing parameters apply

NOTE 3 Timing parameters specified for frequency band 2 apply

NOTE 4 Since RW0A, RW0C, RW0E, PG[70]RW6A affect output driver operation and RW10 affects termination, it is necessary for these settings to be updated during initialization when Bits OP[1] in RCD control word RW01 is still configured to block all commands at the DRAM interface.

NOTE 5 When Vref settings for DLBD, DLBS, DERR0R_IN_n, DCA[6:0], DPAR, and DCS[1:0]_n are updated, it is necessary to meet the Vref settling times defined in Table 234 in addition to meeting t_{MRD_L}.

NOTE 6 Applies to the timing between MRW to RW5E or RW5F in RCD space and an MRW to MR63 in DRAM space only during an RCD Control Word Read sequence. Also applies to the timing between an MRW to any control word selected for read via RW5E and RW5F and an MRW to MR63 during an RCD Control Word Read sequence. Otherwise this parameter does not apply to RW5E or RW5F.

NOTE 7 A t_{STAB} waiting time is required when changing the setting in RW00[0] (Command Address SDR/DDR Rate selection), RW05[3:0] (RDIMM Operating Speed), RW05[7] (Frequency Band Select), and RW06 (Fine Granularity Operating Speed).

NOTE 8 When exiting from RW In-Band Update mode (i.e., when writing a 1 to RW32[7]), it is necessary to meet the t_{RWUPDExit} timing parameter defined in Table 232 in addition to meeting t_{MRD_L2}.

NOTE 9 If DFE Gain is enabled by RW31[0]=1, then tMRD_L3 must be met.

NOTE 10 This parameter also covers the exit latency if exit is triggered through SidebandBus operation.

NOTE 11 As shown in Figure 137 on page 316, this is the minimum guaranteed LOW pulse (i.e., below [V_{OH} + V_{OL}]/2, where V_{OH} and V_{OL} are the measured Logic HIGH and LOW DC voltage levels) into the test load. Logically, the minimum pulse width out of the RCD in DCS or DCA training modes is four DCK clock cycles wide.

NOTE 12 For the double CS Exit the corresponding Host Interface TM selection in RW02 will be reset to default (Normal Operating Mode).

NOTE 13 When the DFE Training Acceleration is enabled, the minimum waiting time between de-assertion of DCS0_n for one pattern and assertion of DCS0_n of the next pattern is determined by the larger of tDFETM_Pattern_Wait_Accel [min] specified in this table and the minimum settling time for the parameter setting updated by the Training Accelerator logic (e.g., for DFE_Vref or VrefCA, the minimum settling time could be much larger than tDFETM_Pattern_Wait_Accel [min]).

NOTE 14 When the DFE Training Acceleration is disabled, there is a different minimum spacing between patterns, since there is no need to account for automated parameter changes.

NOTE 15 This parameter also covers the exit latency if exit is triggered through SBB operation.

9.3 Output Timing Requirements

Table 233 — Output Timing Requirements¹

Symbol	Parameter	Conditions	DDR5-3200 to 4800		DDR5-5200 to 5600		DDR5-6000/ 6400		DDR5-6800/ 7200		DDR5-7600/ 8000		Unit	Note
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
t _{PDM}	Propagation delay, single bit switching; DCK_t/DCK_c falling edge crosspoint to output in DDR DCA Mode (RW00[0] = 1), or DCK_t/DCK_c rising edge crosspoint to output in SDR DCA Mode (RW00[0] = 0)	1.1 V Operation, DDR Mode (RW00[0] = 1) or SDR Mode (RW00[0] = 0)	0.9	1.2	0.9	1.2	0.9	1.2	0.9	1.2	0.9	1.2	ns	2
t _{PDM_LB}	Propagation delay; External Loopback signals	1.1 V Operation	-	2	-	2	-	2	-	2	-	2	ns	3
t _{QLBSL_2PH_ext}	1/2 rate Loopback QLBS Output Low Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	vs ⁴	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	4
t _{QLBSH_2P_H_ext}	1/2 rate Loopback QLBS Output High Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	vs ⁵	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	4
t _{QLBS2Q_2P_H_ext}	1/2 rate Loopback QLBS to QLBD Skew	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	-	0.15	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	4
t _{QLBDH_2P_H_ext}	1/2 rate Loopback QLBD Output Hold Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	vs ⁵	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	4
t _{QLBDVW_2_PH_ext}	1/2 rate Loopback QLBD Valid Window (t _{QLBDH} - t _{QLBS2Q})	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	vs ⁵	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	4
t _{QLBSL_2PH_int}	1/2 rate Loopback QLBS Output Low Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	0.4	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	5
t _{QLBSH_2P_H_int}	1/2 rate Loopback QLBS Output High Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	0.4	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	5
t _{QLBDST_2P_H_int}	1/2 rate Loopback QLBD Output Setup time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	0.35	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	5
t _{QLBDHD_2_PH_int}	1/2 rate Loopback QLBD Output Hold Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	0.35	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	5
t _{QLBDVW_2_PH_int}	1/2 rate Loopback QLBD Valid Window	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 0	0.7	-	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	t _{CK}	5
t _{QLBSL_4PH}	1/4 rate Loopback QLBS Output Low Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 1	0.4	-	0.4	-	0.45	-	0.45	-	0.45	-	t _{CK}	6
t _{QLBSH_4P_H}	1/4 rate Loopback QLBS Output High Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 1	0.4	-	0.4	-	0.45	-	0.45	-	0.45	-	t _{CK}	6

Table 233 — Output Timing Requirements¹ (cont'd)

Symbol	Parameter	Conditions	DDR5-3200 to 4800		DDR5-5200 to 5600		DDR5-6000/ 6400		DDR5-6800/ 7200		DDR5-7600/ 8000		Unit	Note
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
tQLBDST_4P H	1/4 rate Loopback QLBD Output Setup Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 1	0.35	-	0.35	-	0.4	-	0.4	-	0.4	-	t _{CK}	6
tQLBDHD_4 PH	1/4 rate Loopback QLBD Output Hold Time	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 1	0.35	-	0.35	-	0.4	-	0.4	-	0.4	-	t _{CK}	6
tQLBDVW_4 PH	1/4 rate Loopback QLBD Valid Window (tQLBDH - tQLBS2Q)	1.1 V Operation, DDR Mode (RW00[0] = 1), RW26[6] = 1	1.6	-	1.6	-	1.6	-	1.6	-	1.6	-	t _{CK}	6
tInt_LB_Entr y	Delay from MRW enabling internal loopback mode to valid data driven on QLBS and QLBD	1.1 V Operation	-	32	-	32	-	32	-	32	-	32	t _{CK}	
tDCK2QLBS	Internal Loopback Propagation Delay from Rising (RW26[7] = 0) or Falling (RW26[7] = 1) DCK crossing point to the Corresponding QLBS Rising Edge	1.1 V Operation, DDR Mode (RW00[0] = 1), Applies to Internal Loopback only (RW26[2:0] = '001' or '010')	-	10	-	16	-	16	-	16	-	16	t _{CK}	
t _{QSK}	Total magnitude of Qn Output to Output Clock tolerance within the same A or B group (in the same unit) t _{QSK} = t _{QSK_static} + t _{QSK_dynamic}	Across the supported voltage-temperature range and with SSO conditions and pattern dependence included	0	0.385	0	0.39	0	0.4	0	0.4	0	0.4	t _{CK}	7,8
t _{QSK_static}	Magnitude of Qn Output to Output Clock tolerance within the same A or B group (in the same unit) under quiet conditions	Measured with quiet conditions, only one output switching, and nominal V-T conditions of V _{DD} = 1.1 V and 25°C	0	0.3	0	0.3	0	0.3	-	0.3	0	0.3	t _{CK}	8,9
t _{QSK_dynamic} ic	Magnitude of t _{QSK} change (additive to t _{QSK_static}) under noisy conditions	Across the supported voltage-temperature range and with SSO conditions and pattern dependence included	0	0.085	0	0.09	0	0.1	0	0.1	0	0.1	t _{CK}	8,10, 11
t _{Q2Q}	Earliest Qn Output to Latest Qn Output Skew Tolerance, using the DCK differential signal at 0.0 V as the common reference, within the same A or B group (in the same unit)	Measured with quiet conditions, only one output switching, and nominal V-T conditions of V _{DD} = 1.1 V and 25°C	0	0.15	0	0.1	0	0.1	0	0.1	0	0.1	t _{CK}	8,11,12
t _{Qerr}	Total magnitude of t _{QSK} error t _{Qerr} = 2 x t _{QSK_dynamic} + t _{Q2Q}	Across the supported voltage-temperature range and with SSO conditions and pattern dependence included	0	0.25	0	0.25	0	0.25	0	0.25	0	0.25	t _{CK}	8,11
p.pin DNL	Per-Pin deskew deviation from ideal value	Across the supported voltage-temperature range under quiet conditions with single-output switching.	-2	2	-2	2	-2	2	-2	2	-2	2	ps	

Table 233 — Output Timing Requirements¹ (cont'd)

Symbol	Parameter	Conditions	DDR5-3200 to 4800		DDR5-5200 to 5600		DDR5-6000/ 6400		DDR5-6800/ 7200		DDR5-7600/ 8000		Unit	Note
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
p.pin INL	Per-Pin deskew deviation from ideal value	Across the supported voltage-temperature range under quiet conditions with single-output switching.	-8	8	-8	8	-8	8	-8	8	-8	8	ps	
p.group DNL	Per-Group tQSK adjustment step deviation	Across the supported voltage-temperature range under quiet conditions with single-output switching.	-0.75	0.75	-0.75	0.75	-0.75	0.75	-0.75	0.75	-0.75	0.75	LSB	
p.group INL	Per-Group tQSK adjustment deviation with respect to the ideal line, based on two endpoints, where the endpoints are the min and max values.	Across the supported voltage-temperature range under quiet conditions with single-output switching.	-1.5	1.5	-1.5	1.5	-1.5	1.5	-1.5	1.5	-1.5	1.5	LSB	
tERR_tot	total magnitude of tQSK error including training error and all tolerances. tERR_tot = 2 x tQSK_dynamic + per-pin_step_size + p.pin_DNL + per-group_step_size + p.group_DNL + p.group_INL	Across the supported voltage-temperature range and with SSO conditions and pattern dependence included.	-	0.25	-	0.22	-	0.22	-	0.22	-	0.22	tCK	13
t _{ALERT}	ALERT_n propagation delay	DERROR_IN_n LOW to ALERT_n LOW	-	2	-	2	-	2	-	2	-	2	ns	14
t _{ALERT_HL}	ALERT_n assertion delay from DCK_t/DCK_c	DCK_t/DCK_c to ALERT_n LOW	-	1.5	-	1.5	-	1.5	-	1.5	-	1.5	ns	15
t _{RST}	RESET propagation delay	DRST_n LOW to QRST_n LOW	-	20	-	20	-	20	-	20	-	20	ns	
t _{QDIS}	Output buffers (except for QxCK_t/ QxCK_c, QxCSn) hi-z after QCS[1:0]_n goes LOW following SRE command. It does not apply to Alert_n output.	QCS[1:0]_n = LOW; DRST_n = HIGH; DCK_t/DCK_c = toggling.	2	-	2	-	2	-	2	-	2	-	tCK	
t _{SRX2QCK}	Number of cycles from NOP command to QCK clocks running	DRST_n = HIGH; DCK_t/DCK_c = Toggling	-	16 + t _{PDM}	-	16 + t _{PDM}	-	16 + t _{PDM}	-	16 + t _{PDM}	-	16 + t _{PDM}	tCK	
t _{SRX2QCS}	Number of cycles from NOP command to release QCS.	DRST_n = HIGH; DCK_t/DCK_c = Toggling	-	16 + t _{PDM}	-	16 + t _{PDM}	-	16 + t _{PDM}	-	16 + t _{PDM}	-	16 + t _{PDM}	tCK	
t _{CASRX}	QCA HIGH to QCS HIGH when exiting Self-Refresh		0	-	0	-	0	-	0	-	0	-	ns	
t _{ODU}	Output Delay Update time	OP7 = 1 for RW12 to RW1C, PG[5]RW[7B:60], PG[70]RW[7F:78]	-	100	-	100	-	100	-	100	-	100	ns	16

- NOTE 1 See diagram (Figure 138, “Test Load,” on page 317).
- NOTE 2 See diagram (Figure 7, “One UI DRAM Command Timing Diagram” on page 16). t_{PDM} is defined for 0 nCK command latency adder (RW11[2:0] = ‘000’), default (Moderate) output slew rate control settings in RW0E, and output delay features are all enabled in RW12 - RW1A but set to zero delay.
- NOTE 3 Applies to External Loopback Only (RW26[2:0] = ‘011’ or ‘100’) only.
- NOTE 4 The value is vendor specific.
- NOTE 5 Applies to Internal Loopback (RW26[2:0] = ‘001’ or ‘010’) only.
- NOTE 6 Applies to both Internal Loopback (RW26[2:0] = ‘001’ or ‘010’) and External Loopback (RW26[2:0] = ‘011’ or ‘100’).
- NOTE 7 This skew represents the absolute Qn skew compared to the output clock QxCK and contains the register pad skew, clock skew, package routing skew and SSO noise (See Figure 10, “Qn Output Skew,” on page 17). The output clock jitter is not included in this skew. The measurement is averaged. The Qn output can be either early or late relative to the output clocks in the channel. For outputs QxCA[13:0]_N, QxCS[1:0]_N_n, this parameter applies to each of the two A/B output groups independently per channel.
- NOTE 8 The values for this parameter are defined for default settings in the output delay control words RW12 to RW1C and default settings in the driver characteristics and slew rate control words RW0A through RW0E.
- NOTE 9 This skew represents the absolute Qn skew compared to the output clock QxCK and contains the register pad skew, clock skew, and package routing skew at nominal V-T conditions of VDD = 1.1 V and 25°C (See Figure 10, “Qn Output Skew,” on page 17). The output clock jitter is not included in this skew. The measurement is averaged. The Qn output can be either early or late relative to the output clocks in the channel. For outputs QxCA[13:0]_N, QxCS[1:0]_N_n, this parameter applies to each of the two A/B output groups independently per channel.
- NOTE 10 $t_{QSK_dynamic}$ represents the largest change in output skew (relative to t_{QSK_static}) within an output signal group in either direction (i.e., early signals moving to an earlier time or late signals moving to a later time). The output clock jitter is not included in this skew. The measurement is averaged. In this test, all outputs send patterns simultaneously to excite realistic on-die noise and crosstalk.
- NOTE 11 t_{Qerr} imposes an additional constraint on the maximum value for the total of $2 \times t_{QSK_dynamic} + t_{Q2Q}$ measured per individual unit. The device shall meet $t_{Qerr}(max)$ in addition to meeting $t_{QSK_dynamic}(max)$ and $t_{Q2Q}(max)$.
- NOTE 12 This parameter represents the absolute Qn skew between earliest and latest signals within the same A/B group and contains the register pad skew and package routing skew (See Figure 10, “Qn Output Skew,” on page 17). The measurement is averaged. For outputs QxCA[13:0]_N, this parameter applies to each of the two A/B output groups independently per channel. Similarly, for outputs QxCS[1:0]_N_n, this parameter applies to each of the two A/B output groups independently per channel.
- NOTE 13 t_{ERR_tot} imposes an additional constraint on the maximum value for the total of $(2 \times t_{QSK_dynamic} + \text{per-pin_step_size} + \text{p.pin_DNL} + \text{per-group_step_size} + \text{p.group_DNL} + \text{p.group_INL})$ measured per individual unit. The device shall meet $t_{ERR_tot}(max)$ in addition to meeting $t_{QSK_dynamic}(max)$, $t_{Q2Q}(max)$, $\text{p.pin_DNL}(max)$, $\text{p.pin_INL}(max)$, $\text{p.group_DNL}(max)$ and $\text{p.group_INL}(max)$.
- NOTE 14 See Figure 135, “Voltage Waveforms, tALERT Measurement,” on page 316.
- NOTE 15 See Figure 138, “Test Load,” on page 317 and Figure 136, “Voltage Waveforms, tALERT_HL Measurement,” on page 316.
- NOTE 16 This is the time the RCD requires to update delay timing setting to the output after it receives RW write.

10 VrefCA and Vref CS Specifications

10 VrefCA and Vref CS Specifications (cont'd)

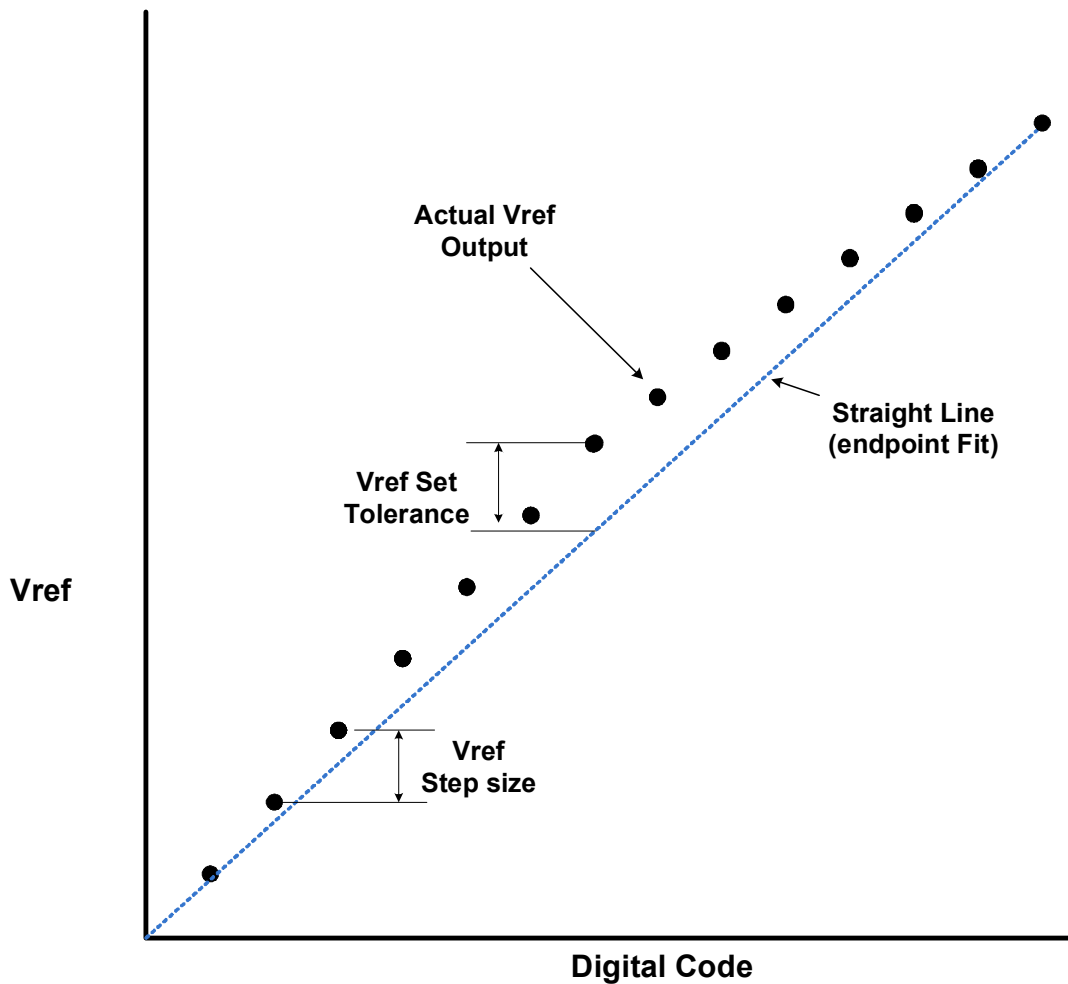


Figure 76 — Example of Vref Set Tolerance (Only Max Case is Shown) and Step Size

The Vref increment/decrement step times are defined by Vref_time. Vref_time is defined from t0 to t1 as shown in Figure 77 below where t0 is referenced to when the RW write occurs and t1 is referenced to when the Vref voltage is at the final DC level within the Vref valid tolerance (Vref_val_tol).

The Vref valid level is defined by Vref_val_tol to qualify the step time t1 as shown in Figure 78. This parameter is used to insure an adequate RC time constant behavior of the voltage level change after any Vref increment/decrement adjustment. This parameter is only applicable for component level validation/characterization.

Vref_time is the time including up to Vrefmin to Vrefmax or Vrefmax to Vrefmin change in Vref voltage.

t0 - is referenced to RW write command clock

t1 - is referenced to the Vref_val_tol

10 VrefCA and Vref CS Specifications (cont'd)

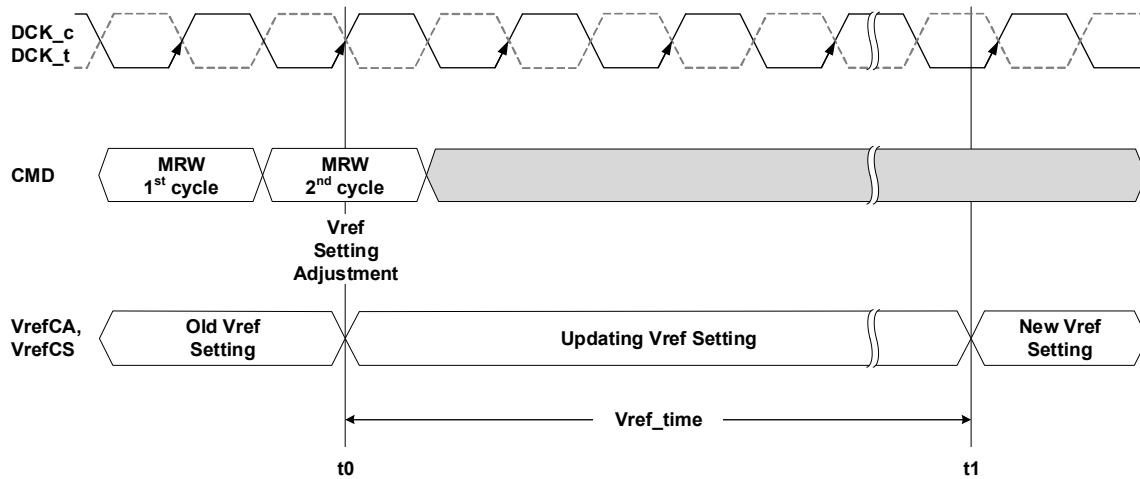


Figure 77 — Vref_time Timing Diagram

An MRW write to the (Internal Vref Control Word) is used to program the Vref value.

The minimum time required between two Vref MRW commands is Vref_time for single step and Vref_time for a full voltage range step.

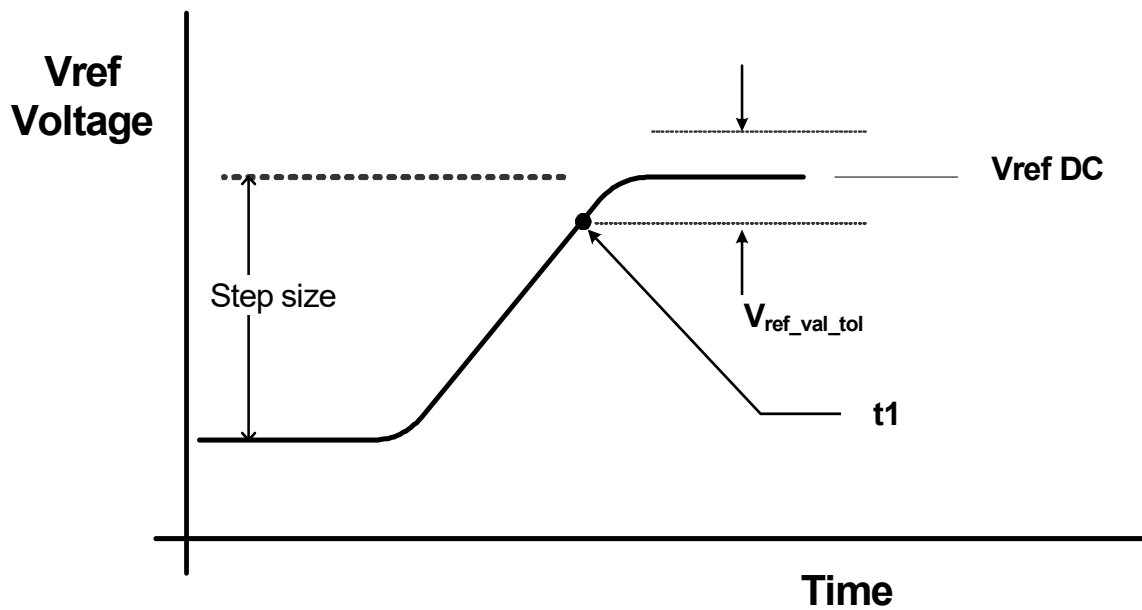


Figure 78 — Vref Step Single Step Size Increment Case

10 VrefCA and Vref CS Specifications (cont'd)

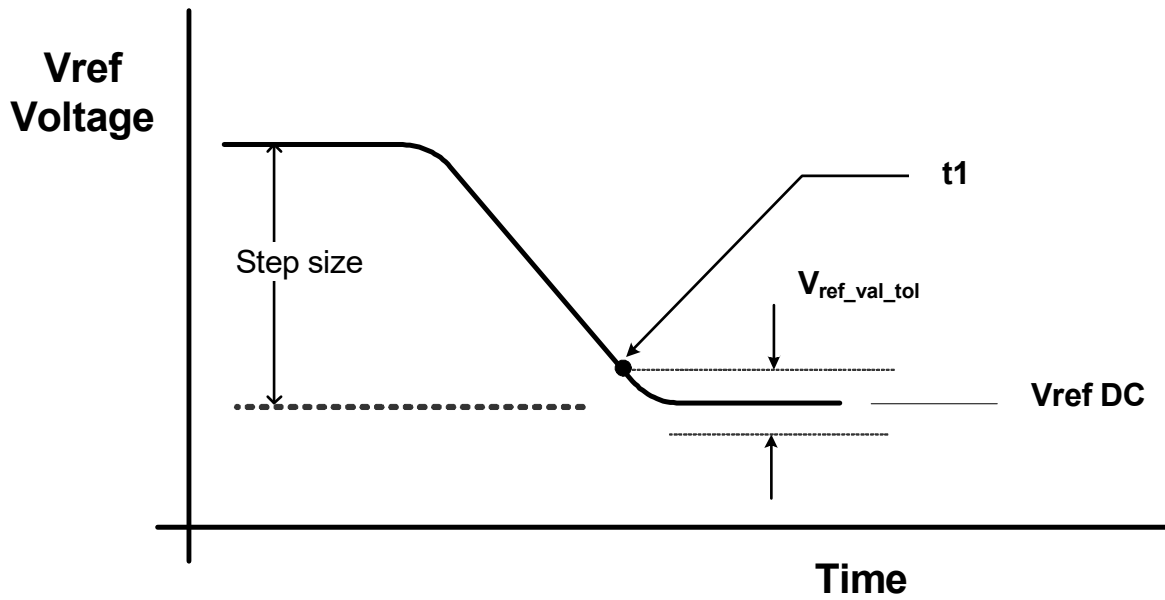


Figure 79 — Vref Step Single Step Size Decrement Case

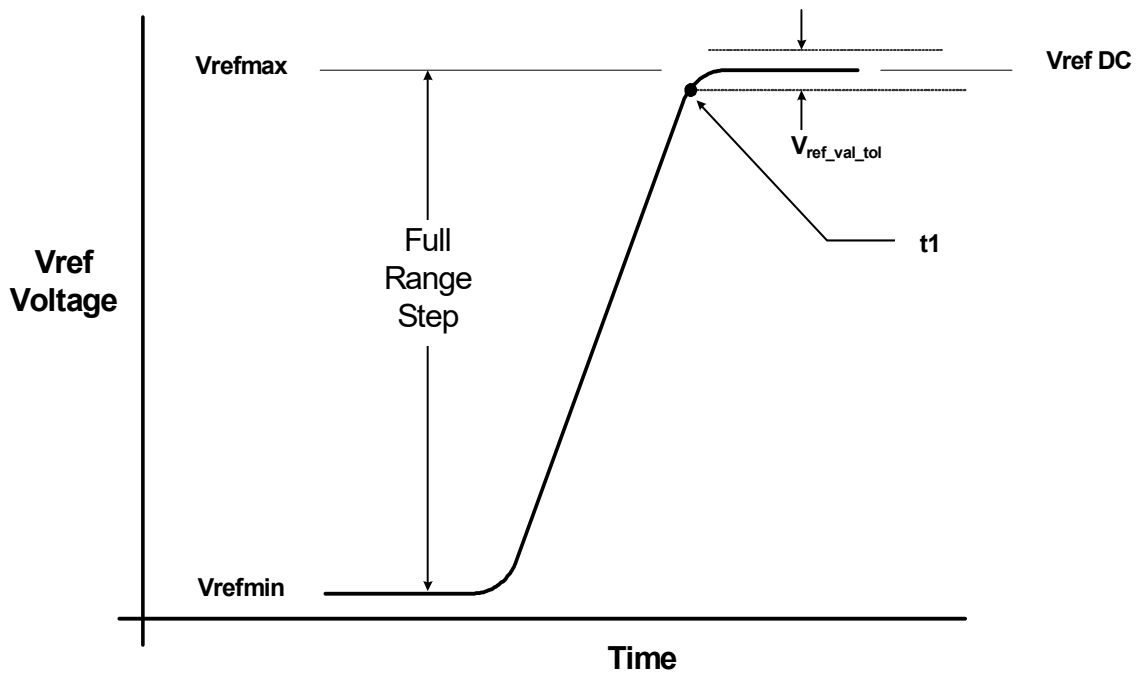


Figure 80 — Vref Full Step from Vrefmin to Vrefmax Case

10 VrefCA and Vref CS Specifications (cont'd)

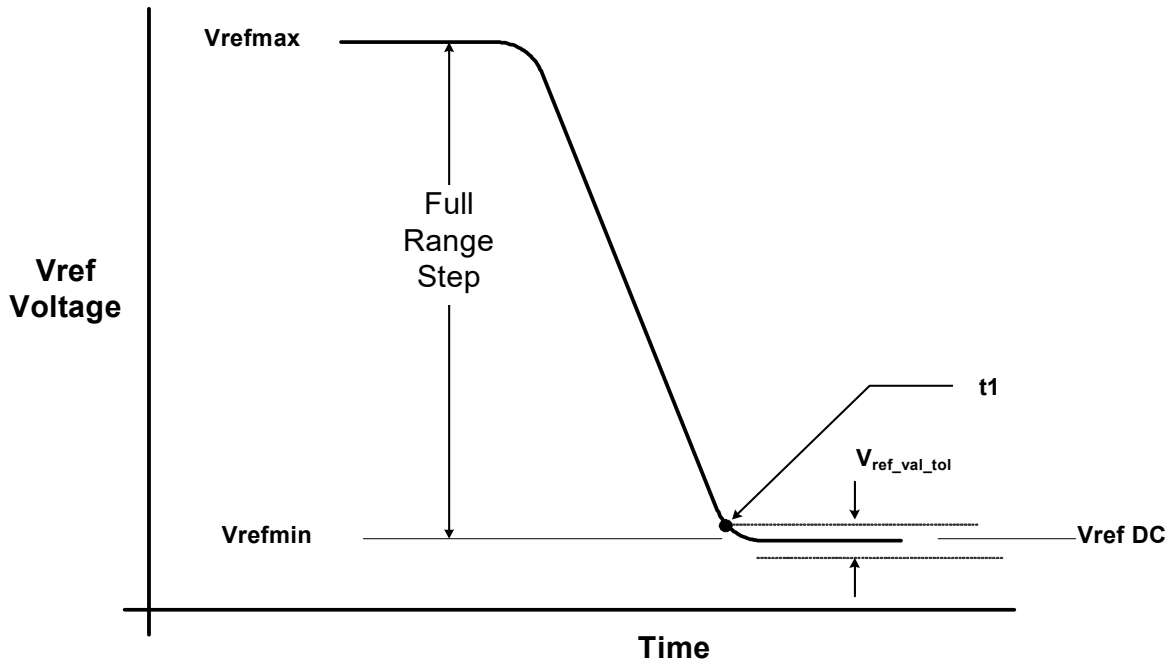


Figure 81 — Vref Full Step from Vrefmax to Vrefmin Case

Table 234, “Internal VrefCA and VrefCS Specifications,” below contains the internal VrefCA specifications that will be characterized at the component level for compliance. The characterization method is defined in a separate specification.

Table 234 — Internal VrefCA and VrefCS Specifications

Parameter	Symbol	Min	Typ	Max	Unit	NOTE
Vref Max Operating Point	Vref_max	97.5%	-	-	V _{DD}	1
Vref Min Operating Point	Vref_min	-	-	45%	V _{DD}	1
Vref Step size	Vref_step	0.41%	0.50%	0.59%	V _{DD}	2
Vref Set Tolerance	Vref_set_tol_long	-1.625%	0.0%	1.625%	V _{DD}	3, 4, 6
	Vref_set_tol_short	-0.15%	0.0%	0.15%	V _{DD}	3, 5, 7
Vref Step Time	Vref_time_short	-	-	300	ns	8, 9
	Vref_time_long	-	-	500	ns	8, 9
Vref Valid Tolerance	Vref_val_tol	-0.15%	0.0%	0.15%	V _{DD}	

NOTE 1 Vref DC voltage referenced to VDD.

NOTE 2 Vref step size increment/decrement range. Vref at DC level. $Vref_step(avg) = (Vref_max - Vref_min) / 105$.

NOTE 3 $Vref_new = Vref_old + n * Vref_step$; n= number of steps; if increment use “+”; If decrement use “-”.

NOTE 4 The minimum value of Vref setting tolerance = $Vref_new - 1.625\% * VDD$. The maximum value of Vref setting tolerance = $Vref_new + 1.625\% * VDD$. For $n > 4$.

NOTE 5 The minimum value of Vref setting tolerance = $Vref_new - 0.15\% * VDD$. The maximum value of Vref setting tolerance = $Vref_new + 0.15\% * VDD$. For $n < 4$.

NOTE 6 Measured by recording the min and max values of the Vref output over the full range, drawing a straight line between those points and comparing all other Vref output settings to that line.

NOTE 7 Measured by recording the min and max values of the Vref output across 4 consecutive steps ($n=4$), drawing a straight line between those points and comparing all other Vref output settings to that line.

NOTE 8 Time from MRW command to Vref stable. Applicable for component level test/characterization purposes. Vref valid is to qualify the step times which will be characterized at the component level.

NOTE 9 The maximum value of VrefCA or VrefCS step time = 300 ns for $n < 16$ and 500 ns for $n \geq 16$, where n = number of steps.

10.1 DFE_Vref INL Tolerance

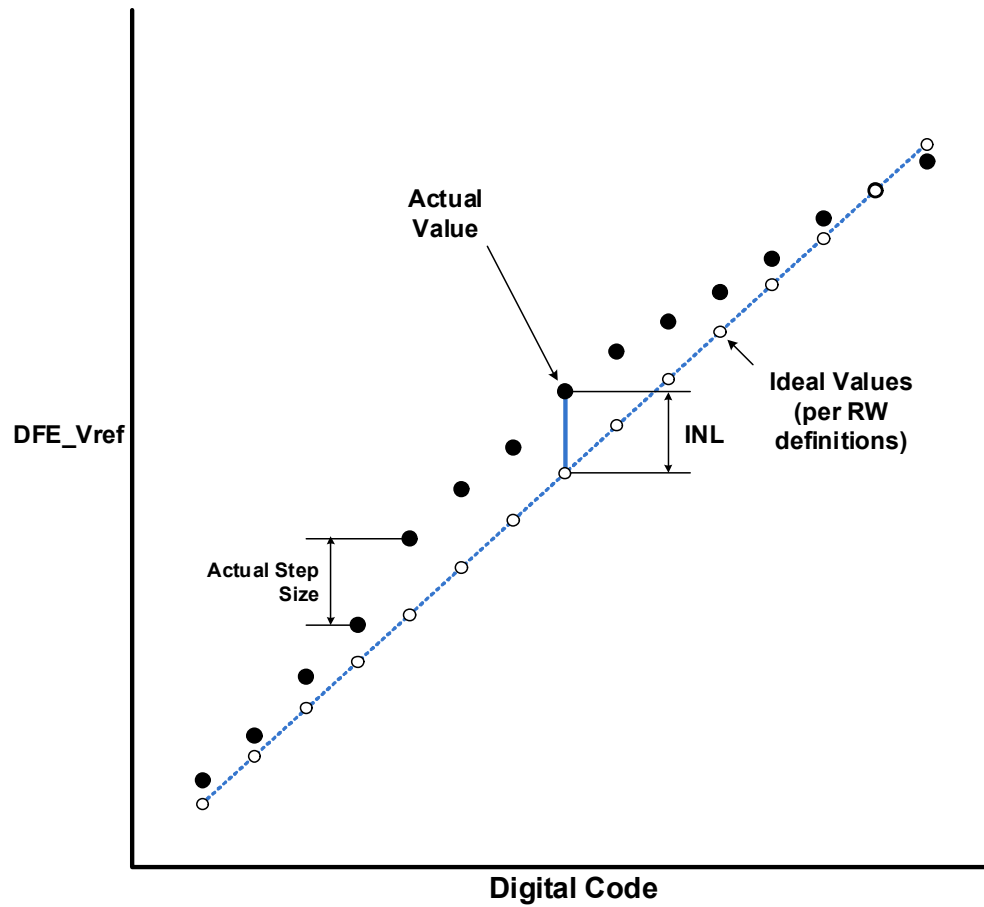


Figure 82 — Example of DFE_Vref INL Tolerance

Integral nonlinearity (INL) is the deviation between effective analog values and expected ideal values for the corresponding settings in Receiver DFE_Vref Control words as defined in [RW3F](#) and [PG02RW](#)[62, 66, 6A,6E, 72, 76,7A, 7E].

10.1 DFE_Vref INL Tolerance (cont'd)

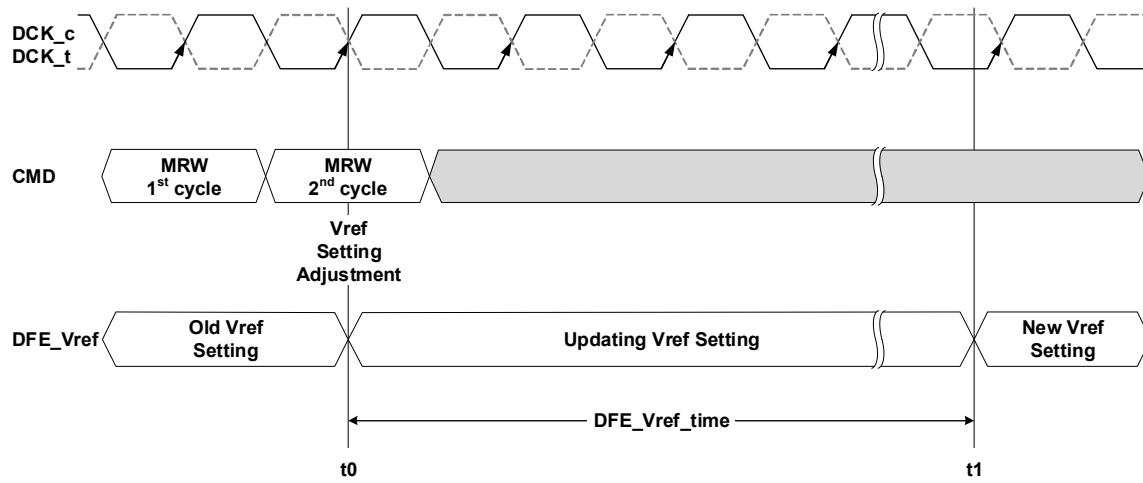


Figure 83 — DFE_Vref_step Time Timing Diagram

An MRW write to the (Internal Vref Control Word) is used to program the Vref value.

The minimum time required between two DFE_Vref MRW commands is DFE_Vref Step Time.

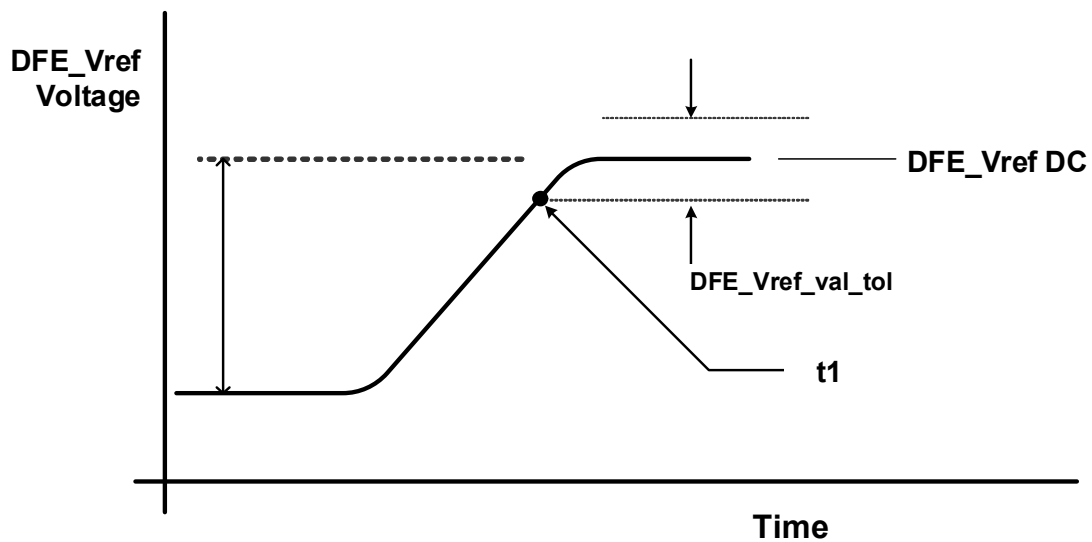


Figure 84 — DFE_Vref Increment Case

10.1 DFE_Vref INL Tolerance (cont'd)

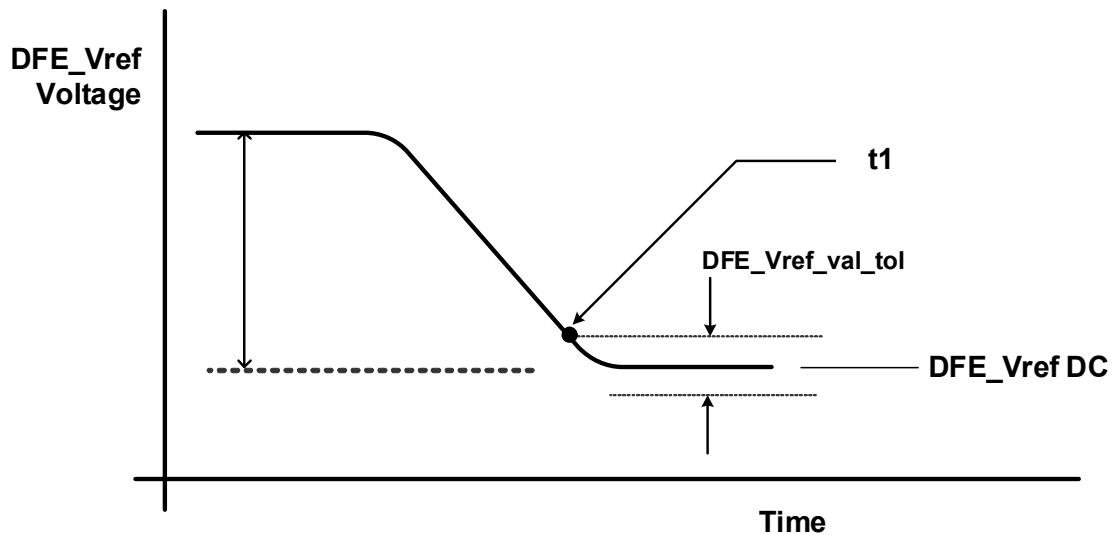


Figure 85 — DFE_Vref Decrement Case

Table 235 below contains the DFE Training Vref specifications that will be characterized at the component level for compliance. The characterization method is defined in a separate specification.

Table 235 — DFE_Vref Specification

Parameter	Symbol	Min	Typ	Max	Unit	NOTE
DFE_Vref Step Time Short	DFE_Vref_Short_16	-	-	200	ns	1, 2
	DFE_Vref_Short_32	-	-	300	ns	1, 3
DFE_Vref Step Time Long	DFE_Vref_Long	-	-	600	ns	1, 4
DFE_Vref Valid Tolerance	DFE_Vref_val_tol	-1.65	0	1.65	mV	1

NOTE 1 Only applicable for component level test/characterization purpose. Not applicable for normal mode of operation. Vref valid is used to qualify the step times which will be characterized at the component level.

NOTE 2 The maximum value of DFE_Vref step time = 200 ns for $n < 16$, where n = number of steps.

NOTE 3 The maximum value of DFE_Vref step time = 300 ns for $16 \leq n < 32$, where n = number of steps.

NOTE 4 The maximum value of DFE_Vref step time = 600 ns for $n \geq 32$, where n = number of steps.

Table 236 — DFE_Vref INL Tolerance

DFE_Vref Setting	Lower Limit	Upper Limit	NOTE
- 500 mV ~ 300 mV	-	$V_{ideal} * 80\%$	1,3,4
- 300 mV ~ 0 mV	$\text{Min}(V_{ideal} * 120\%, V_{ideal} - 4 * \text{LSB})$	$\text{Max}(V_{ideal} * 80\%, V_{ideal} + 4 * \text{LSB})$	1,2,3,4
0 mV ~ + 300 mV	$\text{Min}(V_{ideal} * 80\%, V_{ideal} - 4 * \text{LSB})$	$\text{Max}(V_{ideal} * 120\%, V_{ideal} + 4 * \text{LSB})$	1,2,3,4
+300 mV ~ + 500 mV	$V_{ideal} * 80\%$	-	1,3,4

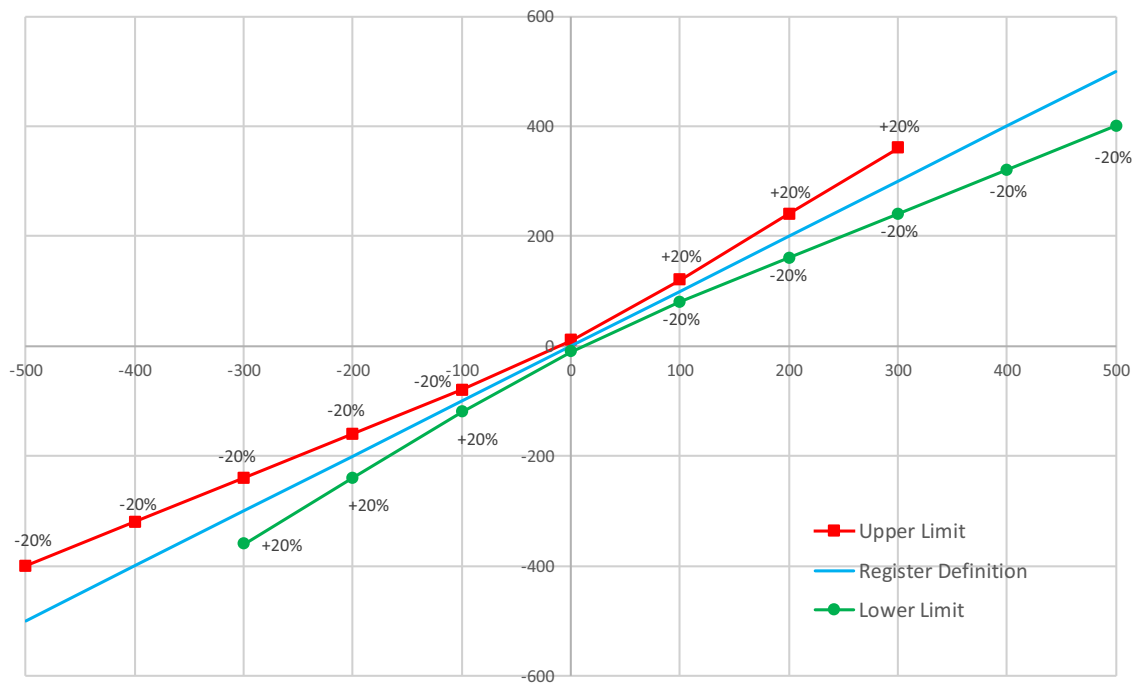
NOTE 1 V_{ideal} refers to the ideal DFE_Vref value based on the setting.

NOTE 2 LSB is 2.5 mV.

NOTE 3 DFE_Vref must be monotonic.

NOTE 4 The range values specified in the table are applicable for default VrefCA and DFE Gain Offset setting, under $V_{DD} = 1.1 \text{ V}$ and 25°C ambient temperature.

10.1 DFE_Vref INL Tolerance (cont'd)



X axis = ideal control word setting value
Y axis = actual implementation value

Figure 86 — Illustration Example of DFE_Vref INL Tolerance

10.2 Measurement Steps

1. Make sure VrefCA are at default setting, DFE_Vref setting is 0, power supply is 1.1 V.
Configure Margin Monitor [RW32\[2:0\]](#) to 3'b001.
2. Sweep input signal from 1.1 V to 0 V to find the lowest level for HIGH and record this input signal HIGH level as V1 when HIGH-to-LOW transition starts.
3. Sweep input signal from 0 V to 1.1 V to find the highest level for LOW and record this input signal LOW level as V2 when LOW-to-HIGH transition starts.
4. Transition level $V = (V1 + V2)/2$.
5. Set DFE_Vref, wait for DFE_Vref_Step_Time to let the new setting settle.
6. Repeat steps 2 ~ 4, to get a new transition level V'.
7. Validate $(V' - V)$ is within specification.
8. Repeat steps 2 ~ 7 until all the settings of DFE_Vref are measured.

10.3 DFE Tap Coefficient and Gain Adjustment tolerances (DNL and INL)

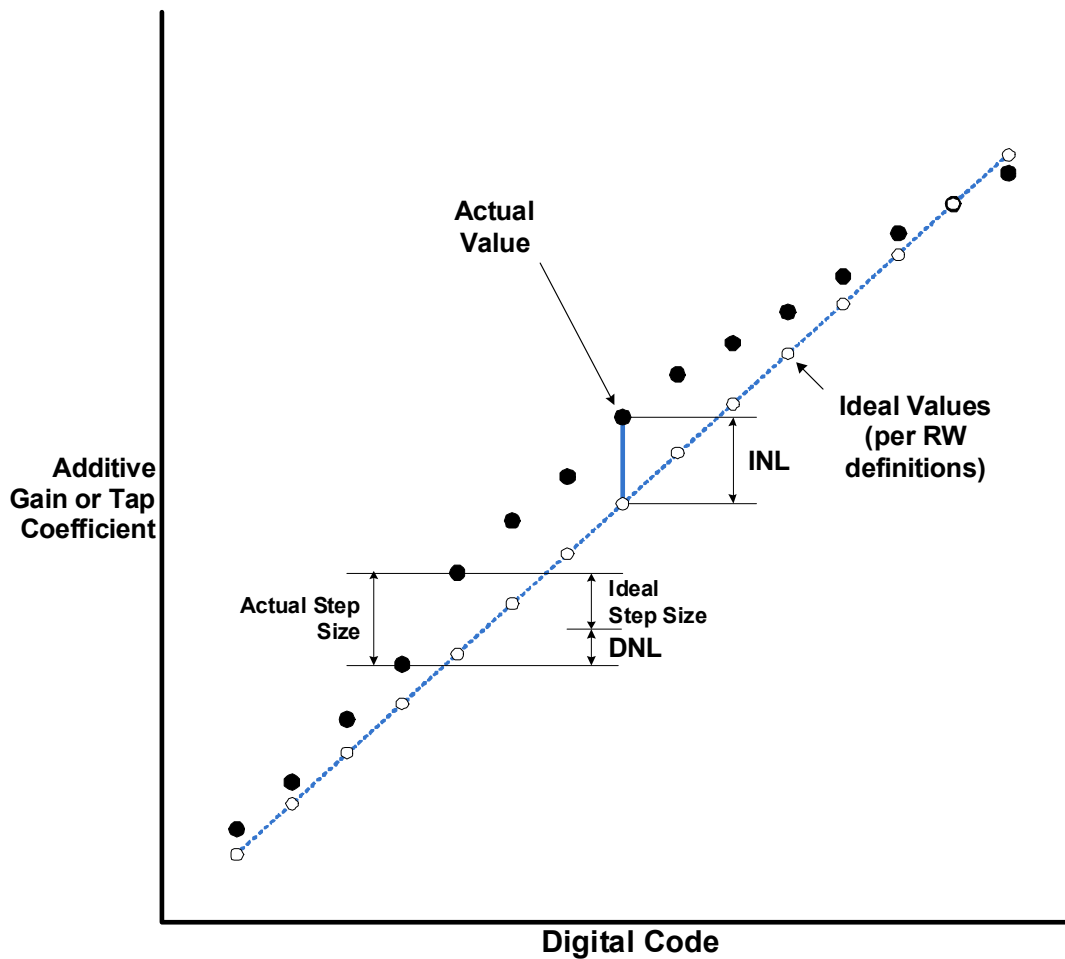


Figure 87 — Example of Tap Coefficient and Gain Adjustment Tolerances (DNL and INL)

Differential nonlinearity (DNL) is the deviation between effective and ideal control step sizes for any pair of analog values resulting from adjacent settings in Receiver DFE Tap Coefficient and Gain Adjustment control words as defined in [PG\[1:0\]RW\[7E:78, 76:70, 6E:68, 66:60\]](#) and [PG\[6\]RW\[60:64, 68:6C, 78\]](#).

Integral nonlinearity (INL) is the deviation between effective analog values and expected ideal values for the corresponding settings in Receiver DFE Tap Coefficient and Gain Adjustment control words as defined in [PG\[1:0\]RW\[7E:78, 76:70, 6E:68, 66:60\]](#) and [PG\[6\]RW\[60:64, 68:6C, 78\]](#).

11 AC and DC Global Definitions

11.1 Transmitter (Tx), Receiver (Rx), and Channel Definitions

Transmitter (Tx): Input to the transmitter is the DCA from the logical portion of the RCD Core and output is at the package pins. The normal components contained in the transmitter are, but not limited to, the pre-driver and the output driver with the transmitter package.

The DDR5 RCD uses a differential re driven clock-source, and single-ended CA.

The transmitter for a forwarded clock based source synchronous system must include specification and test methodology for low and high frequency random and deterministic jitter and duty cycle error and must consider Bounded Uncorrelated Jitter (BUJ), Duty cycle error, etc.

For single-ended signaling cases, crosstalk and Simultaneous switching noise often impact the measurement of the Transmitter. Therefore, the Transmitter's decimated jitter component parameters and the BER must be specified.

Receiver (Rx): The normal components contained in the clock receiver are: (1) receiver package, (2) input amplifier (to receive the clock), and (3) optionally, a PLL and time adjustment circuitry. The data input receives the single-ended data and measures it against a reference voltage. The difference between the received signal and reference voltage is then sampled. However, the link may need some form of receiver equalization at the speeds that the DDR5 link needs to operate. Since there may be no input eye margin at the receiver pin, the receiver equalization specification may be defined based on a virtual receive sampler/slicer. This means that components of the receiver, which have nothing to do with inter symbol interference (ISI), will have to be specified in such a way as to avoid the impact of ISI. Hence items like receiver jitter, receiver jitter sensitivity, receiver amplitude sensitivity, which are typically orthogonal to ISI, will have to be specified in an ISI free environment. Either the infrastructure, or the test methodology will ensure that the correct amount of ISI, or no ISI, as the case may be, for that specific Rx parameter is used. The validation of the receiver is also dependent on either loop-back of data being enabled or restricting to receiver testing to be dependent on a pre-specified set of patterns and the accompanying pattern checker and error counters. The Receiver equalization will be evaluated in the presence of a set of pre-specified receiver testing golden channels. These receiver testing golden channels will attempt to span the ISI range to which the receiver needs to be designed. The key measurement parameter in this test is the stressed eye and the receiver's error sensitivity to the stressed eye.

Channel: The channel is defined from the transmitter package pin to the receiver package pin and includes all the interconnect topology components included in the channel definition (connectors, sockets, and so on). However, this spec will not specify system platform level channel models, but restrict itself to specifying the Golden Reference Transmitter and Receiver evaluation channels.

Applicability:

The parameters defined in this section apply to the appropriate sections of the RCD irrespective of the system, platform or the topology of the system where the RCD is situated. The parameters, however, are defined separately for each of the speeds that the DDR5RCD05 is expected to operate.

11.1.1 Bit Error Rate

Introduction:

This clause provides an overview of the Bit Error Rate (BER) and the desired Statistical Level of Confidence.

11.1.2 General Equation

$$n = \left(\frac{1}{BER} \right) \left[-\ln(1 - SLC) + \ln \left(\sum_{k=0}^N \frac{(n \cdot BER)^k}{k!} \right) \right]$$

Where:

n = number of bits in a trial

SLC = statistical level of confidence

BER = Bit Error Rate

k = intermediate number of specific errors found in trial

N = number of errors recorded during trial

If no errors are assumed in a given test period, the second term drops out and the equation becomes:

$$n = \left(\frac{1}{BER} \right) [-\ln(1 - SLC)]$$

Testing to 99.5% confidence levels is recommended; however, one may choose a number that is viable for their own manufacturing levels. To determine how many bits of data should be sent (again, assuming zero errors, or $N = 0$), using $BER = 10^{-9}$ and confidence level $SLC = 99.5\%$, the result is $n = (1/BER)(-\ln(1 - 0.995)) = 5.298 \times 10^9$.

Results for commonly used confidence levels of 99.5% down to 70% are shown in Table 237.

Table 237 — Estimated Number of Transmitted Bits (n) for Confidence Level of 70% to 99.5%

Number of Error	n = ln(1 - SLC)/BER							
	99.5%	99%	95%	90%	85%	80%	75%	70%
0	5.298/BER	4.61/BER	2.99/BER	2.3/BER	1.90/BER	1.61/BER	1.39/BER	1.20/BER

11.1.3 Minimum Bit Error Rate (BER) Requirements

Table 238 specifies the UI_{AVG} and Bit Error Rate requirements over which certain receiver timing and voltage specifications need to be validated assuming a 99.5% confidence level at $BER = 10^{-9}$.

Table 238 — Minimum BER Requirements for RX and TX Timing and Voltage Tests

Symbol	Parameter	DDR5-3200 - 8000			Unit	NOTE
		Min	Nom	Max		
UI_{AVG}	Average UI	0.999* nominal	1.000/f	1.001* nominal	ps	1
$N_{MIN_UI_Validation}$	Number of UI (min)	5.3×10^9		-	UI	2
BER_{Lane}	Bit Error Rate	-		10^{-16}	Events	3, 4, 5, 6
NOTE 1 Average UI size, “f” is data rate.						
NOTE 2 # of UI over which certain Rx/Tx timing and voltage specifications need to be validated assuming a 99.5% confidence level at $BER = 10^{-9}$.						
NOTE 3 This is a system parameter. It is the raw bit error rate for every lane before any logical PHY or link layer based correction. It may not be possible to have a validation methodology for this parameter for a standalone transmitter or standalone receiver, therefore, this parameter has to be validated in selected systems using a suitable methodology as deemed by the platform.						
NOTE 4 Bit Error Rate per lane. This is a raw bit error rate before any correction. This parameter is primarily used to determine electrical margins during electrical analysis and measurements that are located between two interconnected devices.						
NOTE 5 This is the minimum BER requirements for testing timing and voltage parameters listed in Input Clock Jitter, Rx CA Voltage Sensitivity, Rx Clock Jitter Sensitivity, Rx CA Stressed Eye, Tx Clock Jitter, Tx QCA Jitter, and Tx QCA Stressed EH/EW specifications.						
NOTE 6 The BER for DDR5 during normal operation is 10^{-16} . For validation purposes, the BER used is 10^{-9} .						

11.1.4 Unit Interval and Jitter Definitions

This document describes the UI and NUI Jitter definitions associated with the Jitter parameters specified in Rx Stressed Eye, Tx QCK Jitter, and Input Clock Jitter specifications.

11.1.5 Unit Interval

The times at which the differential crossing points of the clock occur are defined at $t_1, t_2, \dots, t_{n-1}, t_n, \dots, t_K$.

The UI at index “n” is defined as shown in Figure 88 (with $n = 1, 2, \dots$) from an arbitrary time in steady state, where $n = 0$ is chosen as the starting crossing point.

Mathematical definition of UI is shown in Figure 88 and Figure 89.

$$UI_n = t_n - t_{n-1}$$

Figure 88 — UI Definition in Terms of Adjacent Edge Timings

For the Single-Ended data, the unit interval time starts when the signal crosses a pre-specified reference voltage. For the differential clock, the unit interval time starts when the DCK_t and DCK_c intersect (see Figure 89).

11.1.5 Unit Interval (cont'd)

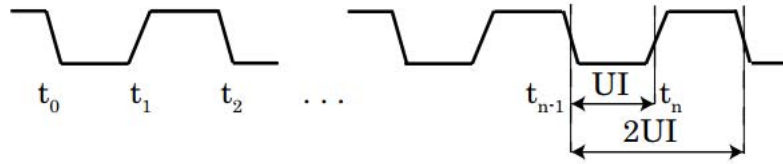


Figure 89 — UI Definition using Clock Waveforms

11.1.6 UI Jitter Definition

If a number of UI edges are computed or measured at times $t_1, t_2, \dots, t_{n-1}, t_n, \dots, t_K$, where K is the maximum number of samples, then the UI jitter at any instance “ n ” is defined in Figure 90, where T = the ideal UI size.

$$UI_{(jit)n} = (t_n - t_{n-1}) - T; n = 1, 2, 3, \dots, K$$

Figure 90 — UI Jitter of the “ n th” UI Definition (in Terms of Ideal UI)

In a large sample with random Gaussian-like jitter (therefore very close to symmetric distribution), the average of all UI sizes usually turns out to be very close to the ideal UI size.

The equation described in Figure 90 assumes starting from an instant of steady state, where $n = 0$ is chosen as the starting point. 1 UI = one bit, which means 2 UI = one full cycle or time period of the forwarded clock.

Example: For 6.4 GT/s signaling, the forwarded clock frequency is 3.2 GHz, or 1 UI = 156.25 ps.

Deterministic jitter is analyzed in terms of the peak-to-peak value and in terms of specific frequency components present in the jitter, isolating the causes for each frequency. Random jitter is unbounded and analyzed in terms of statistical distribution to convert to a bit error rate (BER) for the link.

11.1.7 UI-UI Jitter Definition

UI-UI (read as “UI to UI”) jitter is defined to be the jitter between two consecutive UI as shown in Figure 91.

$$UI_n = UI_n - UI_{n-1}; n = 2, 3, \dots, K$$

Figure 91 — UI - UI Jitter Definitions

11.1.8 Accumulated Jitter (over “ N ” UI)

Accumulated jitter is defined as the jitter accumulated over any consecutive “ N ” UI as shown in Figure 92.

$$T_{acc}^N = \sum_{p=m}^{m+N-1} (UI_p - \overline{UI}), \text{ where } m = 1, 2, \dots, K-N$$

Figure 92 — Definition of Accumulated Jitter (over “ N ” UI)

where UI is defined in the equation shown in Figure 93.

11.1.8 Accumulated Jitter (over “N” UI) (cont’d)

$$\overline{\text{UI}} = \frac{\sum_{p=1}^K \text{UI}_p}{K}, \text{ where } p = 1, 2, \dots, N, \dots, K$$

Figure 93 — Definition of UI

12 Electrical - Input AC and DC Specifications

12.1 Input Clock Architecture

The RCD is provided a clock by the entity that is controlling it, i.e., memory controller, or any test equipment. This clock is used by the RCD to generate all the IO specific timing, and is the same clock used by the controlling entity as the one and only deterministic source of all the response timings to and from the RCD. This allows the memory controller to have a deterministic control of every event in the RCD. Spread Spectrum Clocking (SSC) Capability

12.1.1 Input Clock SSC and PLL Loop Filter

The system platform uses a reference clock, which is used to synthesize the RCD clock. Spread Spectrum Clock (SSC) with up to 0.5% down-spread in frequency must be supported by the clocking system. The frequency of the reference clock, and therefore bit rate, can be modulated from 0% to –0.5% of the nominal data rate/frequency at a modulation rate in the range of 30 KHz to 33 KHz. The modulation profile of SSC must provide optimal or close to optimal EMI reduction. Typical profiles include a triangular profile. The RCD must ensure that it functions normally even in the presence of SSC and truthfully lets SSC related components pass through to its output signals.

Table 239 — SSC and PLL Loop Filter Characteristics

Symbol	Parameter	Conditions	DDR5-3200 to 8000		Unit
			Min	Max	
f_{SSC}	SSC modulation frequency ¹		30	33	KHz
a_{SSC}	SSC amplitude ¹		0	-0.5	%
f_{band}	PLL loop bandwidth ²	-3dB bandwidth ³	$0.01 \times f_{clock}$	-	MHz

NOTE 1 The DDR5RCD05 must meet all parameters defined in this specification while supporting input clock SSC requirements described in this table

NOTE 2 The DDR5RCD05 PLL must fulfill this loop filter requirement in order to track typical system clock synthesizer output clock signals

NOTE 3 Implies a jitter peaking of <3 dB

12.1.2 Input Slew Rate for Differential Clock

Input slew rate for differential signals DCK_t/DCK_c are defined and measured as shown in Table 240.

Table 240 — Differential Input Slew Rate Definition for DCK_t/DCK_c

Symbol	Parameter	Measured		Units	Notes
		Min	Max		
V_{IHdiff_CK}	Differential Input High	$0.75 \times V_{DIFFpp}$	-	mV	1, 2, 3, 4
V_{ILdiff_CK}	Differential input Low	-	$0.25 \times V_{DIFFpp}$	mV	1, 2, 3, 4

NOTE 1 Clock V_{DIFFpp} , V_{ILdiff_CK} and V_{IHdiff_CK} are defined in Figure 94.

NOTE 2 V_{DIFFpp} is the mean HIGH voltage minus the mean LOW voltage over 1e6 samples.

NOTE 3 Differential signal rising edge from V_{ILdiff_CK} to V_{IHdiff_CK} must be monotonic slope.

NOTE 4 Differential signal falling edge from V_{IHdiff_CK} to V_{ILdiff_CK} must be monotonic slope.

12.1.2 Input Slew Rate for Differential Clock (cont'd)

Table 241 — Differential Input Slew Rate DCK_t/DCK_c

Symbol	Parameter	Measured		Units	Notes
		Min	Max		
SRIdiff	Differential Input Slew Rate	2	18	V/ns	1

NOTE 1 All parameters are defined over the entire clock common mode range.

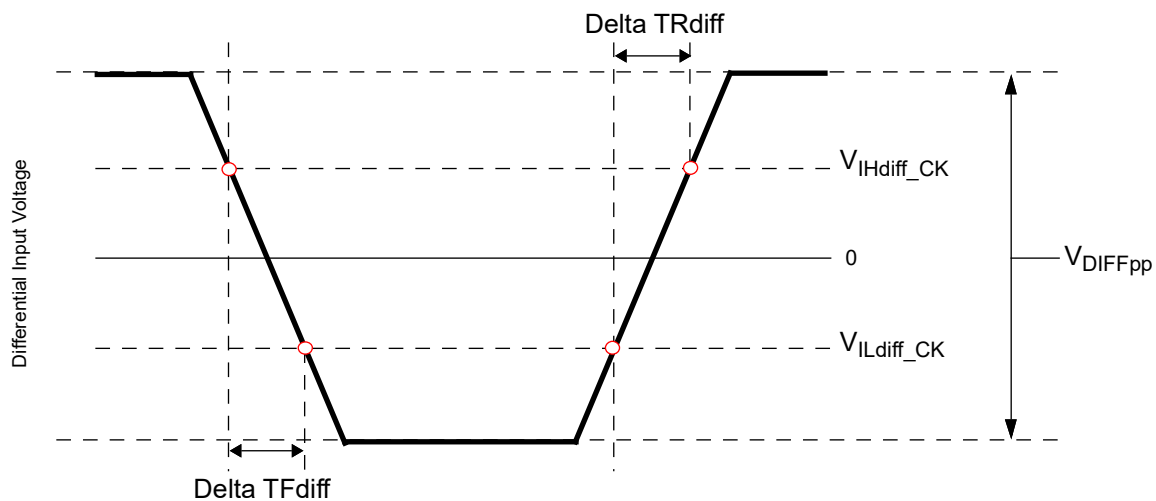


Figure 94 — Differential Input Slew Rate Definition for DCK_t/DCK_c

12.1.3 Differential Input Clock Cross Point Voltage

To achieve tight CA Rx Mask input requirements as well as output skew parameters with respect to clock, the cross point voltage of differential input clock signals (DCK_t, DCK_c) must meet the requirements in Figure 95. The differential input cross point voltage V_{IX_CK} ($V_{IX_CK_FR}$ and $V_{IX_CK_RF}$) is measured from the actual cross point of DCK_t, DCK_c relative to the $V_{swing}/2$ of the DCK_t and DCK_c signals.

12.1.2 Input Slew Rate for Differential Clock (cont'd)

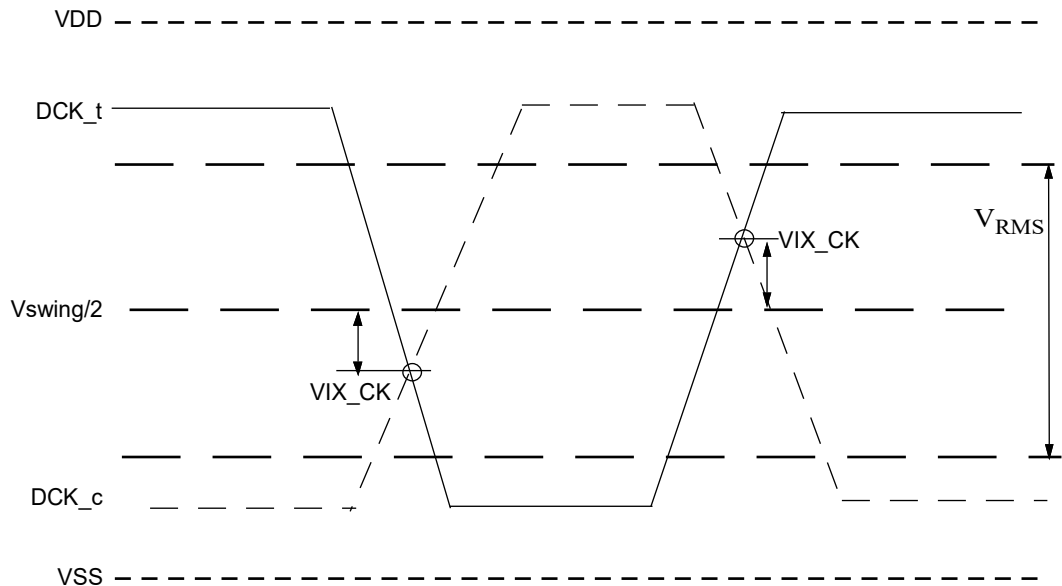


Figure 95 — VIX Definition (DCK)

Table 242 — Cross Point Voltage (VIX) for Differential Input Signals (DCK)

Symbol	Parameter	DDR5-3200~8000		Unit	NOTE
		Min	Max		
VIX_CK_Ratio	Clock differential input crosspoint voltage ratio	-	50	%	1, 2, 3

- NOTE 1 The VIX_CK voltage is referenced to $V_{swing}/2(\text{mean}) = (\text{DCK_t voltage} + \text{DCK_c voltage}) / 2$, where the mean is over 8 UI.
- NOTE 2 $VIX_CK_Ratio = (|VIX_CK| / |V_{RMS}|) * 100\%$, where $V_{RMS} = \text{RMS}(\text{DCK_t voltage} - \text{DCK_c voltage})$.
- NOTE 3 Only applies when both DCK_t and DCK_c are transitioning.

12.2 Input Voltage Levels for DERROR_IN_n Signals

Table 243 — Input Voltage Levels for DERROR_IN_n Signals

Symbol	Parameter	Min	Max	Unit	NOTE
V _{IH.ERROR}	HIGH-level input voltage	V _{ref} + 75	-	mV	1
V _{IL.ERROR}	LOW-level input voltage	-	V _{ref} - 75	mV	1

- NOTE 1 V_{ref} refers to the target setting selected in Table 148, “RW4A: DERROR_IN_n V_{ref} Control Word,” on page 178.

12.3 Input Bus Termination (IBT) Characteristics for DCA, DPAR, DCS, DCK, and DERROR_IN_n

A functional representation of the input bus termination is shown in Figure 96.

$$RTT = \frac{V_{DD} - V_{IN}}{|I_{IN}|}$$

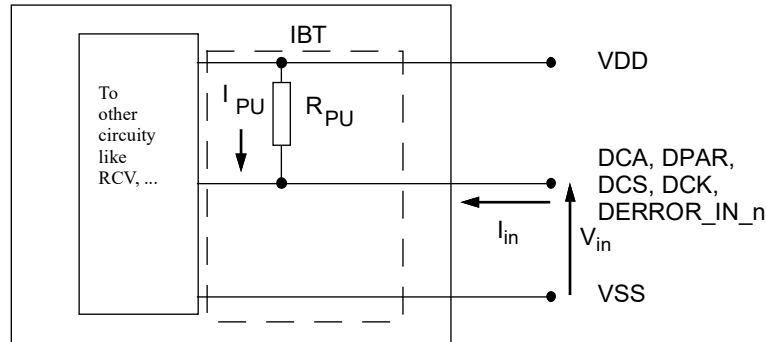


Figure 96 — Input Bus Termination: Definition of Voltages and Currents

The DDR5RCD05 device supports an effective Input Bus Termination Rtt value of 48 and 60 ohms (in addition to RTT_OFF).

Table 244 — IBT Electrical Characteristics for DCA, DPAR, DCS, DCK, and DERROR_IN_n

RTT	V _{in}	Min	Nom	Max	Unit	NOTE
48 Ω	VILdc = 0.5 * VDD	0.9	1	1.25	RZQ/5	1,2
	VIMdc = 0.8 * VDD	0.9	1	1.1	RZQ/5	1,2
	VIHdc = 0.95 * VDD	0.8	1	1.1	RZQ/5	1,2
60 Ω	VILdc = 0.5 * VDD	0.9	1	1.25	RZQ/4	1,2
	VIMdc = 0.8 * VDD	0.9	1	1.1	RZQ/4	1,2
	VIHdc = 0.95 * VDD	0.8	1	1.1	RZQ/4	1,2
DCA-DCA Mismatch within sub-channel	VIMdc = 0.8 * VDD	0	-	8	%	1,3,4

NOTE 1 For the behavior of the tolerance limits if temperature or voltage changes, see Clause 13.6, “Output Driver and Termination Resistor Temperature and Supply Voltage Sensitivity,” on page 292.

NOTE 2 Applies to DCA[6:0]_[B:A], DPAR_[B:A], DCS[1:0]_[B:A]_n, DCK_t, DCK_c, and DERROR_IN_[B:A]_n.

NOTE 3 DCA to DCA mismatch within sub-channel variation for a given component including DCA[6:0], DPAR, and DCS[1:0]_n but excluding DCK_t, DCK_c, and DERROR_IN_n (characterized).

NOTE 4 RTT variance range ratio to RTT Nominal value in a given component, including DCA[6:0], DPAR, and DCS[1:0]_n but excluding DCK_t, DCK_c, and DERROR_IN_n.

$$\text{DCA-DCA Mismatch in a Sub-channel} = \frac{RTT_{MAX} - RTT_{MIN}}{RTT_{NOM}} \times 100$$

12.4 DLBD and DLBS Loopback Input Termination

The DDR5RCD05 device includes On-Die termination resistance for DLBD and DLBS Loopback inputs.

A functional representation of the on-die termination is shown in Figure 97.

$$R_{TT} = \frac{V_{DD} - V_{IN}}{|I_{IN}|}$$

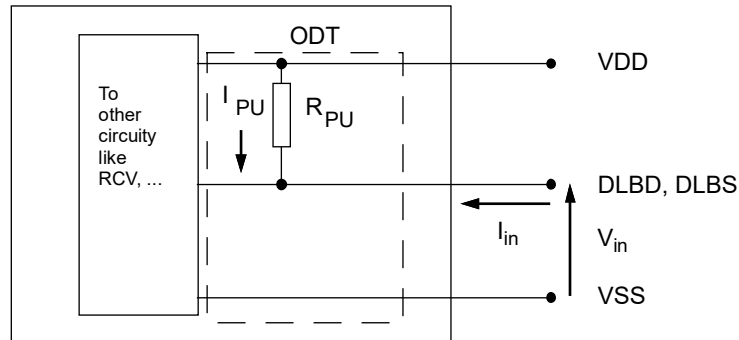


Figure 97 — DLBD and DLBS Termination: Definition of Voltages and Currents

The DDR5RCD05 device supports effective On-Die Termination R_{tt} values of 80, 60, and 40 ohms (in addition to R_{TT_OFF}).

Table 245 — Electrical Characteristics for DLBD and DLBS Input Termination

RTT	V _{in}	Min	Nom	Max	Unit	NOTE
80 Ω	V _{ILdc} = 0.5 * VDD	0.9	1	1.25	RZQ/3	1,2
	V _{IMdc} = 0.8 * VDD	0.9	1	1.1	RZQ/3	1,2
	V _{IHdc} = 0.95 * VDD	0.8	1	1.1	RZQ/3	1,2
60 Ω	V _{ILdc} = 0.5 * VDD	0.9	1	1.25	RZQ/4	1,2
	V _{IMdc} = 0.8 * VDD	0.9	1	1.1	RZQ/4	1,2
	V _{IHdc} = 0.95 * VDD	0.8	1	1.1	RZQ/4	1,2
40 Ω	V _{ILdc} = 0.5 * VDD	0.9	1	1.25	RZQ/6	1,2
	V _{IMdc} = 0.8 * VDD	0.9	1	1.1	RZQ/6	1,2
	V _{IHdc} = 0.95 * VDD	0.8	1	1.1	RZQ/6	1,2
DLBD-DLBS Mismatch within sub-channel	V _{IMdc} = 0.8 * VDD	0	-	8	%	1,2,3

NOTE 1 For the behavior of the tolerance limits if temperature or voltage changes, see Clause 13.6, “Output Driver and Termination Resistor Temperature and Supply Voltage Sensitivity,” on page 292.

NOTE 2 DLBD to DLBS mismatch within sub-channel for a given component (characterized).

NOTE 3 R_{TT} variance range ratio to R_{TT} Nominal value in a given component.

$$\text{DLBD-DLBS Mismatch in a Sub-channel} = \frac{R_{TT_{MAX}} - R_{TT_{MIN}}}{R_{TT_{NOM}}} \times 100$$

12.5 Input CMOS Rail-to-Rail Levels for DRST_n

Table 246 — CMOS Rail-to-Rail Input Levels for DRST_n

Symbol	Parameter	Min	Max	Unit	NOTE
VIH(AC)_RESET	AC Input High Voltage	$0.8 * V_{DD}$	V_{DD}	V	6
VIH(DC)_RESET	DC Input HIGH Voltage	$0.7 * V_{DD}$	V_{DD}	V	2
VIL(DC)_RESET	DC Input LOW Voltage	VSS	$0.3 * V_{DD}$	V	1
VIL(AC)_RESET	AC Input LOW Voltage	VSS	$0.2 * V_{DD}$	V	7
TR_RESET	Rise Time	-	1.0	μs	4
V_{SLPR_p2p}	Peak to peak voltage of slope reversal which must be suppressed	-	100	mV	4
t_{SLPRPW}	Peak to peak width of slope reversal which must be suppressed	-	10	ns	4
t_{PW_RESET}	RESET pulse width	1.0	-	μs	3, 5, 8

NOTE 1 After DRST_n is registered LOW, DRST_n level shall be maintained below VIL(DC)_RESET during t_{PW_RESET} , otherwise, the RCD may not be reset.

NOTE 2 Once DRST_n is registered HIGH, DRST_n level must be maintained above VIH(DC)_RESET, otherwise, RCD operation will not be guaranteed until it is reset asserting DRST_n signal LOW.

NOTE 3 DRST_n will clear all register settings to their default values with the exception of sticky registers listed in Clause 7.4.9.

NOTE 4 Slope reversal (ringback) must remain below V_{SLPR_p2p} with the pulse width below t_{SLPRPW} .

NOTE 5 This definition is applied only “Reset Procedure with Power Stable.”

NOTE 6 Overshoot may occur. It should be limited by the Absolute Maximum DC Ratings.

NOTE 7 Undershoot may occur. It should be limited by Absolute Maximum DC Ratings.

NOTE 8 t_{PW_RESET} is equivalent to parameter t_{RINIT1} (see Table 232 on page 240).

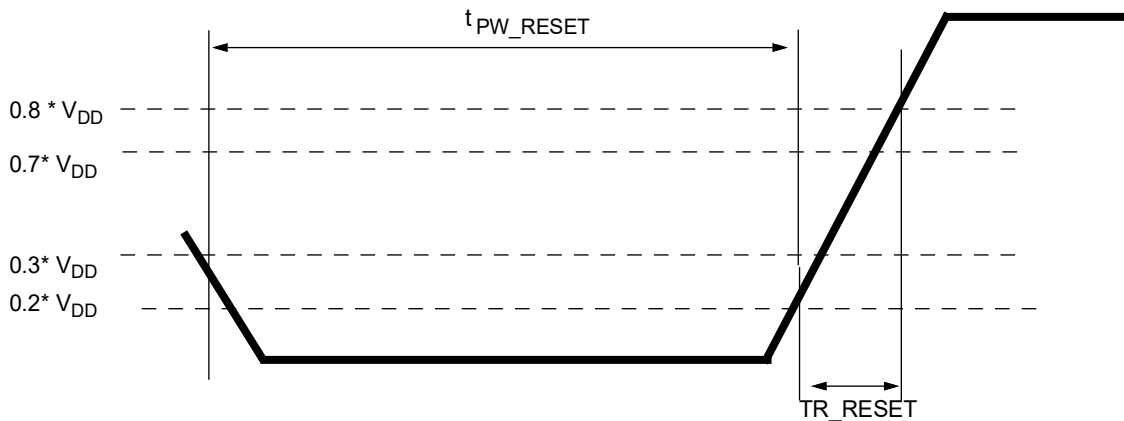


Figure 98 — DRST_n Input Slew Rate Definition

12.5 Input CMOS Rail-to-Rail Levels for DRST_n (cont'd)

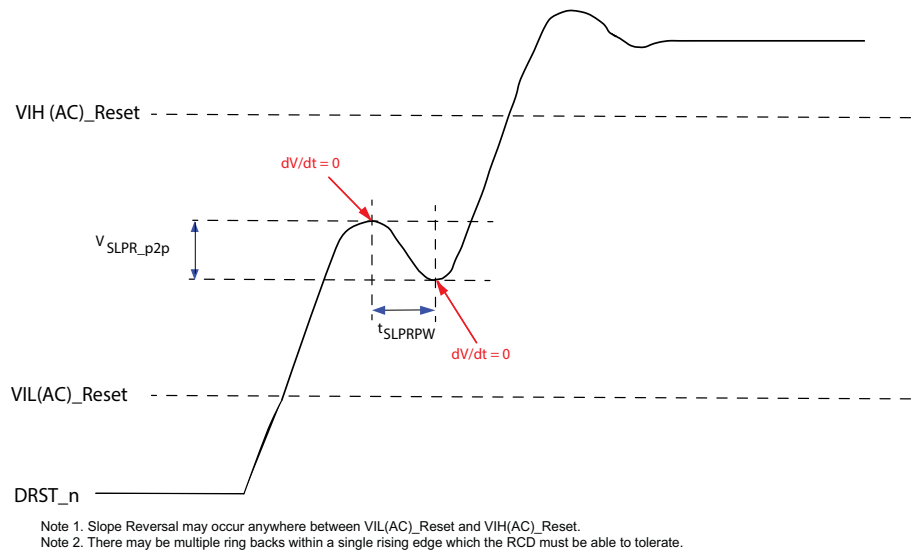


Figure 99 — DRST_n Slope Reversal Definition

12.6 Differential Input Clock and DCA Voltage Sensitivity

The differential input clock voltage sensitivity test provides the methodology for testing the receiver's sensitivity to clock by varying input voltage in the absence of Inter-Symbol Interference (ISI), jitter (R_j , D_j , DCD) and crosstalk noise.

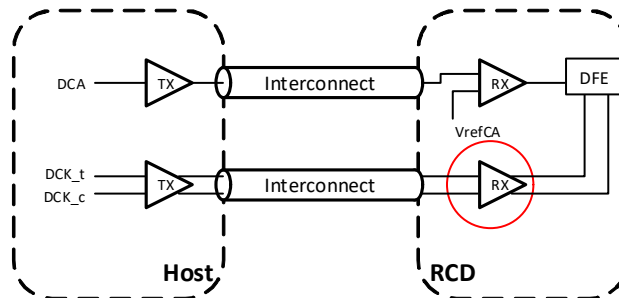


Figure 100 — Example of DDR5 Memory Interconnect

12.6.1 Differential Input Clock and DCA Voltage Sensitivity Parameter

Differential input clock (DCK_t, DCK_c) VRx_CK is defined and measured as shown below. The clock receiver must pass the minimum BER requirements for DDR5.

Table 247 — Rx Input Voltage Sensitivity Parameters

Symbol	Parameter	DDR5-3200		DDR5-3600		DDR5-4000		DDR5-4400		DDR5-4800		DDR5-5200		DDR5-5600		DDR5-6000 - 7200		DDR5-7600 - 8000		Unit	NOTE
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
VRx_CK_1	Differential DCK_t/DCK_c Rx input voltage sensitivity (differential p-p).	-	130	-	115	-	105	-	100	-	100	-	90	-	80	-	75	-	75	mV	1, 3, 4, 5, 7, 8
VRx_CK_2	Differential DCK_t/DCK_c Rx input voltage sensitivity (differential p-p).	-	100	-	90	-	85	-	80		75	-	65	-	65	-	60	-	60	mV	1, 3, 4, 6, 7, 8
VRx_DCA_V	Minimum Voltage Amplitude (p-p) that needs to be applied around VrefCA.	-	75	-	70	-	65	-	60	-	55	-	50	-	50	-	50	-	50	mV	1, 2, 3, 7, 8
VRx_DLBS	Minimum Voltage Amplitude (p-p) that needs to be applied around DLBS Vref.	-	100	-	100	-	100	-	100	-	100	-	90	-	90	-	90	-	90	mV	1, 3, 7
NOTE 1 Refer to the minimum BER 1e-9 requirements for DDR5.																					
NOTE 2 This Parameter applies to DCA[6:0]_B:A and DPAR_B:A].																					
NOTE 3 Test using clock-like pattern of repeating 3 “1s” and 3 “0s” without applying cross-talk or SSO conditions.																					
NOTE 4 The DDR5RCD05 device is required to meet either VRx_CK_1 or VRx_CK_2.																					
NOTE 5 VRx_CK_1 only applies to devices that meet Option-1 Rx Clock Jitter Sensitivity specification defined in Table 249.																					
NOTE 6 VRx_CK_2 only applies to devices that meet Option-2 Rx Clock Jitter Sensitivity specification defined in Table 250.																					
NOTE 7 This test should be done in typical temperature and voltage conditions (i.e., V _{DD} = 1.1 V, 25 °C).																					
NOTE 8 tRx_DCA_tMargin condition does not need to be met.																					

12.6.1 Differential Input Clock and DCA Voltage Sensitivity Parameter (cont'd)

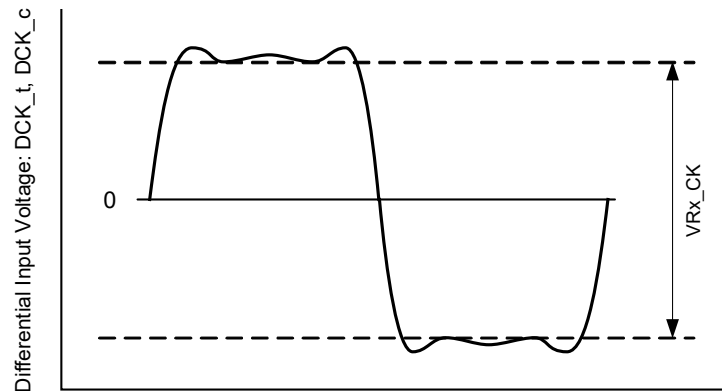


Figure 101 — VRx_CK

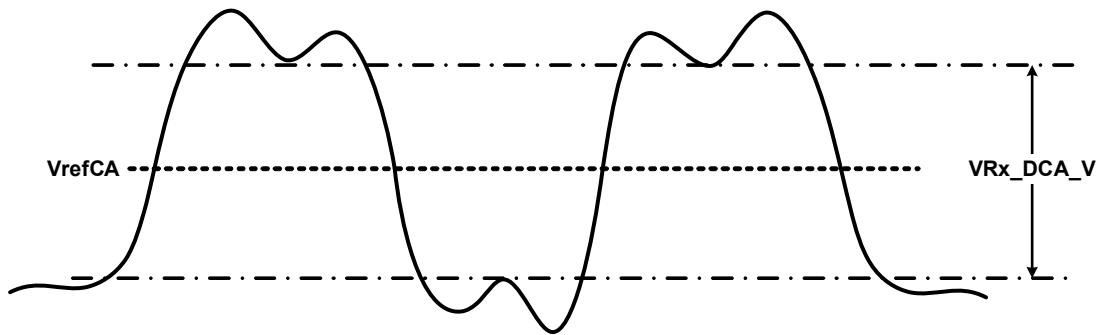


Figure 102 — VRx_DCA_V

12.7 Input Clock Jitter

12.7.1 Overview

The clock is being driven to the RCD for L/RDIMM modules, Figure 103.

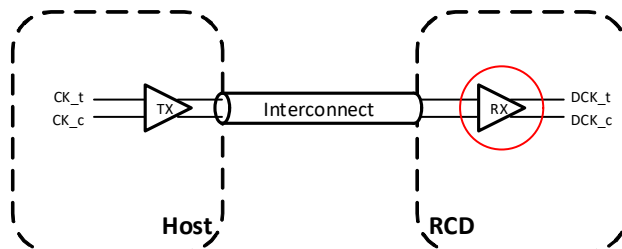


Figure 103 — Host Driving Clock Signals to the RCD

12.7.2 Specification for RCD Input Clock Jitter

The Random Jitter (Rj) specified is a random jitter meeting a Gaussian distribution. The Deterministic Jitter (Dj) specified is bounded. Input clock violating the min/max jitter values may result in malfunction of the DDR5RCD05 device. Input clock duty cycle and duty cycle error are not defined. It is the responsibility of the Host to train the phase offset between DCK and DCS/DCA, so that the device can use the DCK rising and falling edges to sample DCS/DCA signals properly.

Table 248 — Input Clock Differential Jitter

[BUJ = Bounded Uncorrelated Jitter; DCD = Duty Cycle Distortion; Dj = Deterministic Jitter; Rj = Random Jitter; Tj = Total jitter; pp = Peak-to-Peak]

Symbol	Parameter	DDR5-3200 to 8000		Unit	NOTE
		Min	Max		
tCK	RCD Reference clock frequency	$0.9999 \cdot f_0$	$1.0001 \cdot f_0$	MHz	1, 8
tCK_1UI_Rj_NoBUJ	Rj value of 1-UI Jitter	-	0.0037	UI (RMS)	3, 4, 8
tCK_1UI_Dj_NoBUJ	Dj pp value of 1-UI Jitter	-	0.030	UI	3, 5, 8
tCK_1UI_Tj_NoBUJ	Tj value of 1-UI Jitter	-	0.090	UI	3, 5, 8
tCK_NUI_Rj_NoBUJ	Rj value of N-UI Jitter	-	0.004	UI (RMS)	3, 6, 8, 9
tCK_NUI_Dj_NoBUJ	Dj pp value of N-UI Jitter	-	0.074	UI	3, 7, 8, 9
tCK_NUI_Tj_NoBUJ	Tj value of N-UI Jitter	-	0.140	UI	3, 7, 8, 9

Unit UI = tCK(avg).min/2

NOTE 1 f_0 = Data Rate/2, example: if data rate is 3200MT/s, then $f_0=1600$.

NOTE 2 Rise and fall time slopes (V / nsec) are measured between +100 mV and -100 mV of the differential output of reference clock.

NOTE 3 When there is no socket in transmitter measurement setup, in many cases, the contribution of the cross-talk is not significant or cannot be estimated within tolerable error even with all the transmitter lanes sending patterns. When a socket is present, such as DUT being DRAM component, the contribution of the cross-talk could be significant. To minimize the impact of crosstalk on the measurement results, a small group of selected lanes in the vicinity of the lane under test may be turned off (sending DC), while the remaining Tx lanes send patterns to the corresponding Rx receivers so as to excite realistic on-die noise profile from device switching. Note that there may be cases when one of Dj and Rj specs is met and another violated in which case the signaling analysis should be run to determine link feasibility.

NOTE 4 Rj RMS value of 1-UI jitter without BUJ. This extraction is to be done after software correction of DCD.

NOTE 5 Dj pp value of 1-UI jitter (after software assisted DCC). Without BUJ. Dj indicates Djdd of dual-Dirac fitting, after software correction of DCD.

NOTE 6 Rj RMS value of N-UI jitter without BUJ, but on-die system like noise present. This extraction is to be done after software correction of DCD.

NOTE 7 Dj pp value of N-UI jitter without BUJ, but on-die system like noise present. Dj indicates Djdd of dual-Dirac fitting, after software correction of DCD.

NOTE 8 The validation methodology for these parameters will be covered in future ballots.

NOTE 9 When frequency is less than or equal to 4800 MT/s $1 < N < 4$. When frequency is greater than 4800 MT/s $1 < N < 6$.

12.8 RX Clock Jitter Sensitivity

The receiver clock jitter sensitivity test provides the methodology for testing the receiver's clock sensitivity to an applied duty cycle distortion (DCD) and/or random jitter (Rj) at the forwarded clock input while keeping the data crosstalk free, input jitter free, noise free and ISI free. The receiver must pass the appropriate BER rate when the equivalent cross-talk pattern is applied through the combination of applied DCD and Rj.

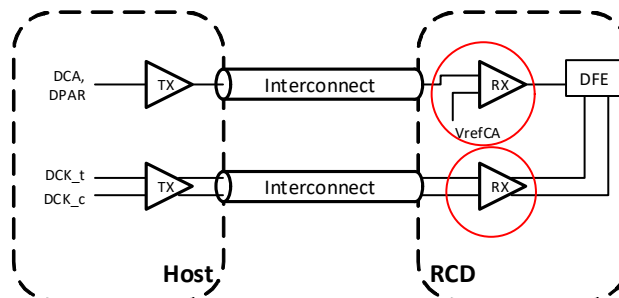


Figure 104 — RCD RX Forward Clock for Jitter Sensitivity

The following tables provide Rx DCK Jitter Sensitivity Specification for the DDR5RCD05 receivers when operating at various possible transfer rates. These parameters are tested with neither additive gain nor Rx Equalization set. The DDR5RCD05 device is required to meet only one of the following two options: the Option-1 requirements defined in Table 249 or the Option-2 requirements defined in Table 250 (as applicable for the implemented receiver architecture).

Table 249 — Rx Clock Jitter Sensitivity Option-1 Specification

[illegible]

12.8.1 Rx Clock Jitter Sensitivity Specification (cont'd)

Table 250 — Rx Clock Jitter Sensitivity Option-2 Specification

Symbol	Parameter	DDR5-3200 to 4800		DDR5-5200 to 5600		DDR5-6000 - 7200		DDR5-7600 - 8000		Unit	NOTE
		Min	Max	Min	Max	Min	Max	Min	Max		
tRx_DCA_tMargin_Ref	DCA Timing Width target for design and simulation, assuming ideal fixture with no Rj or DCD	0.9	-	0.9	-	0.9	-	0.875	-	UI	1, 2, 7, 8, 9
ΔtRx_DCA_tMargin_Rj_DCK_Ref	Degradation of timing width compared to tRx_DCA_tMargin_Ref, with Rj injection in DCK. Target for design and simulation.	-	0.075	-	0.075	-	0.075	-	0.075	UI	1, 4, 7, 8, 9
ΔtRx_DCA_tMargin_DCD_Rj_DCK_Ref	Degradation of timing width compared to tRx_DCA_tMargin_Ref with both DCD and Rj injection in DCK. Target for design and simulation.	-	0.1	-	0.125	-	0.125	-	0.125	UI	1, 5, 7, 8, 9
tRx_DCA_tMargin_Rj_DCK	DCA Timing Width with Rj injection in DCK	Min: 0.825; Max: -							Min: 0.8; Max: -	UI	1, 2, 7, 8, 9
ΔtRx_DCA_tMargin_DCD_DCK	Degradation of timing width compared to tRx_DCA_tMargin_Rj_DCK, with DCD injection in DCK	Min: -; Max: 0.05								UI	1, 3, 7, 8, 9
tRx_DCK2DCA_Skew	Delay of any DCA or DCS lane relative to the DCK_t/DCK_c crossing within a sub-channel.	0	1	0	1	0	2	0	2	UI	1, 6, 7, 8, 9
Unit UI = tCK(avg).min/2											
NOTE 1 Validation methodology will be defined in future ballots.											
NOTE 2 DCA Timing Width - timing width for any data lane using repetitive patterns (check notes 3 to 5 for the pattern) measured at BER=E-9.											
NOTE 3 Magnitude of degradation of timing width for any data lane using repetitive no ISI patterns with DCD injection in forwarded clock compared to tRx_DCA_tMargin, measured at BER=E-9. The magnitude of DCD is specified under Test Conditions for Rx clock Jitter Sensitivity Testing. Test using clock-like pattern of repeating 3 “1s” and 3 “0s”.											
NOTE 4 Magnitude of degradation of timing width for any data lane using repetitive no ISI patterns with only Rj injection in forwarded clock measured at BER=E-9, compared to tRx_tMargin. The magnitude of Rj is specified under Test Conditions for Rx Clock Jitter Sensitivity Testing. Test using clock-like pattern of repeating 3 “1s” and 3 “0s”.											
NOTE 5 Magnitude of degradation of timing width for any data lane using repetitive no ISI patterns with DCD and Rj injection in forwarded clock measured at BER=E-9, compared to tRx_tMargin. The magnitudes of DCD and Rj are specified under Test Conditions for Rx Clock Jitter Sensitivity Testing. Test using clock-like pattern of repeating 3 “1s” and 3 “0s”.											
NOTE 6 Delay of any data lane relative to the clock lane, as measured at the end of Tx+Channel. This parameter is a collective sum of effects of data clock mismatches in Tx and on the medium connecting Tx and Rx.											
NOTE 7 All measurements at BER=E-9.											
NOTE 8 This test should be done in typical temperature and voltage conditions (i.e., V _{DD} = 1.1 V, 25 °C) with default VrefCA settings.											
NOTE 9 The user has the freedom to set the voltage swing and slew rates, as well as the CTLE settings on device, for clock and DCA signals as long as they meet the specification.											

12.8.2 Test Conditions for RX Clock Jitter Sensitivity Tests

Table 251 lists the amount of Duty Cycle Distortion (DCD) and/or Random Jitter (Rj) that must be applied to the forwarded clock when measuring the Rx Clock Jitter Sensitivity parameters specified in Table 250.

Table 251 — Rx Clock Jitter Sensitivity Specification

Symbol	Parameter	DDR5-3200 to 8000		Unit	NOTE
		Min	Max		
tRx_DCK_DCD	Applied DCD to the DCK	-	0.045	UI	1, 2, 3, 6, 7, 10
tRx_DCK_Rj	Applied Rj RMS to the DCK	-	0.00625	UI (RMS)	1, 2, 4, 6, 8, 10
tRx_DCK_DCD_Rj	Applied DCD and Rj RMS to the DCK	-	0.045 UI DCD + 0.00625 UI (RMS) Rj	UI	1, 2, 5, 6, 7, 9, 10
Unit UI = tCK(avg).min/2					
NOTE 1 While imposing this spec, the clock lane is stressed, but the data input is kept large amplitude and no jitter or ISI injection. The specified voltages are at the Rx input pin. The DCK and DCA input voltage swing and/or slew rate can be adjusted, without exceeding the specifications, for this test.					
NOTE 2 The jitter response of the forwarded clock channel will depend on the input voltage, primarily due to bandwidth limitations of the clock receiver. For this revision, no separate specification of jitter as a function of input amplitude is specified, instead the response characterization done at the specified clock amplitude only. The specified voltages are at the Rx input pin.					
NOTE 3 Various DCD values should be tested, complying within the maximum limits.					
NOTE 4 Various Rj values should be tested, complying within the maximum limits.					
NOTE 5 Various combinations of DCD and Rj should be tested, complying within the maximum limits. The maximum timing margin degradation as a result of these injected jitter is specified in a separate table.					
NOTE 6 Although DDR5 has bursty traffic, in order to ensure that current available BERTs can be used for this test, a continuous clock and continuous DCA are used for this parameter. The clock like pattern repeating 3 “1s” and 3 “0s” is used for this test.					
NOTE 7 Duty Cycle Distortion (in UI DCD) as applied to the input forwarded clock from BERT (UI).					
NOTE 8 RMS value of Rj (specified as Edge jitter) applied to the input forwarded clock from BERT (values of the edge jitter RMS values specified as % of UI).					
NOTE 9 Duty cycle distortion (specified as UI DCD) and rms values of Rj (specified as edge jitter) applied to the input forwarded clock from BERT (values of the edge jitter RMS values specified as % of UI).					
NOTE 10 The user has the freedom to set the voltage swing and slew rates for clock and DCA signals as long as they meet the specification.					

12.9 Input Stressed Eye

12.9.1 Overview

The stressed eye tests provide the methodology for creating the appropriate stress for the RCD's receiver with the combination of ISI (both loss and reflective), jitter (Rj, Dj, DCD), and crosstalk noise. The receiver must pass the appropriate BER rate when the equivalent stressed eye is applied through the combination of ISI, jitter and crosstalk.

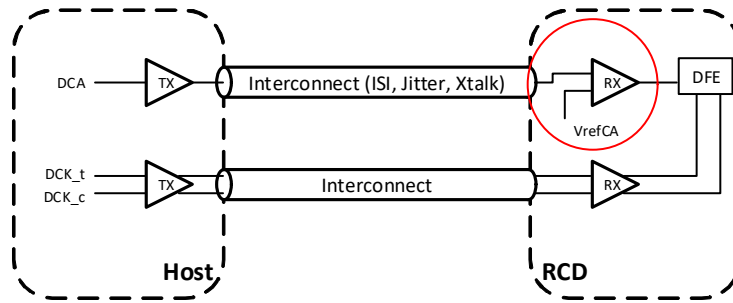


Figure 105 — Example of Rx Stressed Test Setup in Presence of ISI, Jitter, and Crosstalk

12.9.2 Input Stressed Eye Parameters

Table 252 — Test Conditions for Rx Stressed Eye Tests

[BER = Bit Error Rate; DCD = Duty Cycle Distortion; Rj = Random Jitter; Sj = Sinusoidal Jitter; p-p = peak to peak]

Symbol	Parameter	DDR5-3200 to 4000		DDR5-4400 to 4800		DDR5-5200 to 5600		DDR5-6000 - 8000		Unit	NOTE
		Min	Max	Min	Max	Min	Max	Min	Max		
RxEH_Stressed_Eye	Eye height of stressed eye	65	-	55	-	50	-	50	-	mV	1, 2, 3, 4, 5, 6, 7
RxEW_Stressed_Eye	Eye width of stressed eye	0.20	-	0.20	-	0.20	-	0.15	-	UI	1, 2, 3, 4, 5, 6, 7
VSwing_Stressed_Eye	Vswing stress to meet above data eye	0	600	0	600	0	600	0	600	mV	1, 2
Sj_Stressed_Eye	Injected sinusoidal jitter at 200 MHz to meet above data eye	0	0.45	0	0.45	0	0.45	0	0.45	UI (p-p)	1, 2
Rj_Stressed_Eye	Injected Random wide band (10 MHz-1 GHz) Jitter to meet above data eye	0	0.04	0	0.04	0	0.04	0	0.04	UI RMS	1, 2
V_Noise_Stressed_Eye	Injected voltage noise at 2.1 GHz to meet above eye	0	125	0	125	0	125	0	125	mV (p-p)	1, 2

Unit UI = tCK(avg).min/2

NOTE 1 Must meet minimum BER 1e-9 requirement with eye measured at the input of CA Slicer (i.e., node CA_Sum_p/n in Figure 52, “DFE Training Circuitry” on page 67).

NOTE 2 These parameters are applied on the reference channel.

NOTE 3 Evaluated with no DC supply voltage drift.

NOTE 4 Evaluated with no temperature drift.

NOTE 5 Supply voltage noise limited according to DC bandwidth spec, see Recommended DC Operating Conditions.

NOTE 6 The stressed eye is to be assumed to have a diamond shape.

NOTE 7 The VrefCA, DFE Gain Bias Step, and DFE Taps 1,2,3,4 Bias Step can be adjusted as needed, without exceeding the specifications, for this test.

12.10 DCS Input Receiver Specification

The DCS input receiver mask for voltage and timing is shown in Figure 106. The receiver mask (Rx Mask) defines area the input signal must not encroach in order for the DDR5RCD05 input receiver to successfully capture a valid input signal. The mask is a receiver property for each pin and it is not the valid data eye.

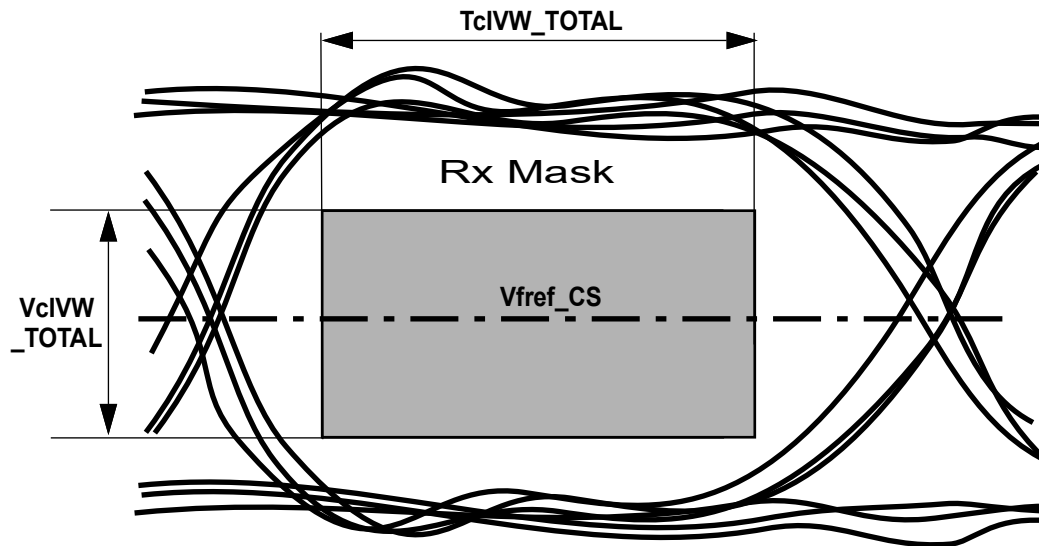


Figure 106 — DCS Receiver (RX) Mask

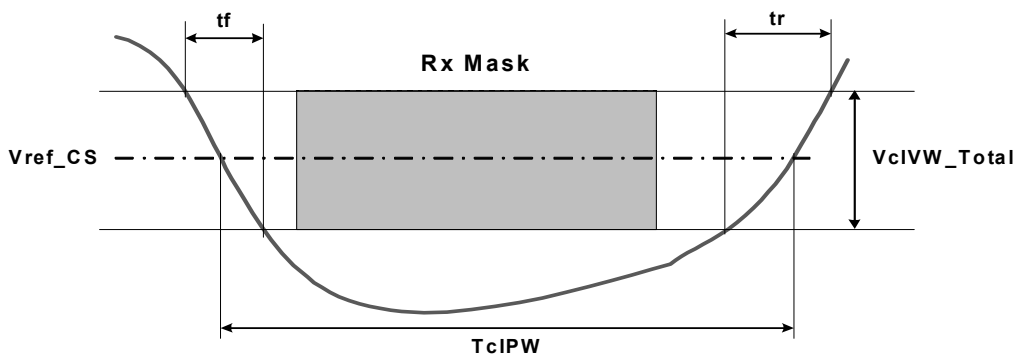


Figure 107 — DCS TcIPW and SRIN_cIVW Definition (for each Input Pulse)

Table 253 — DCS Input Receiver Voltage Margin and AC Timing by Speed Bin

Speed		DDR5- 3200		DDR5- 3600 to 4000		DDR5- 4400 to 4800		DDR5- 5200 to 7200		DDR5- 7600 to 8000		Unit	NOTE
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
VcIVW_TOTAL	Rx Mask p-p voltage total	-	100	-	95	-	90	-	85	-	85	mV	1,2,3
TcIVW_TOTAL	Rx timing window total	-	0.135	-	0.130	-	0.125	-	0.125	-	0.125	UI	1
VIHL_AC	DCS AC input pulse amplitude pk-pk	120	-	115	-	110	-	105	-	105	-	mV	4
TcIPW	DCS input pulse width	0.3	-	0.29	-	0.28	-	0.28	-	0.28	-	UI	5
SRIN_cIVW	Input Slew Rate over VcIVW_TOTAL	1	5	1	5	1	5	1	5	1	5	V/ns	6

Unit UI = tCK(avg).min

NOTE 1 DCS Rx mask voltage and timing total input valid window where VcIVW is centered around VrefCS). The data Rx mask is applied per bit and includes voltage and temperature drift terms.

NOTE 2 Rx mask voltage AC swing peak-peak requirement over TcIVW_TOTAL with at least half of VcIVW_TOTAL(max) above VrefCS and at least half of VcIVW_TOTAL(max) below VrefCS.

NOTE 3 The VcIVW voltage levels are centered around VrefCS.

NOTE 4 DCS input pulse signal swing into the receiver must meet or exceed VIHL_AC for at least one point over the duration of TcIPW for any UI during which there is a signal transition. No timing requirement above level. VIHL_AC is the peak to peak voltage centered around VrefCS, which is defined in Figure 106.

NOTE 5 DCS minimum input pulse width defined at the VrefCS).

NOTE 6 Input slew rate over VcIVW Mask centered at VrefCS. For a given measurement, under the same conditions, the applied slew rate for all transition edges (slowest to fastest) must be within 2V/ns of each other.

12.11 DLBD Input Receiver Specification

The Loopback input receiver mask for voltage and timing is shown in Figure 108. The receiver mask (Rx Mask) defines area the input signal must not encroach in order for the DDR5RCD05 input receiver to successfully capture a valid input signal. The mask is a receiver property for each pin and it is not the valid data eye.

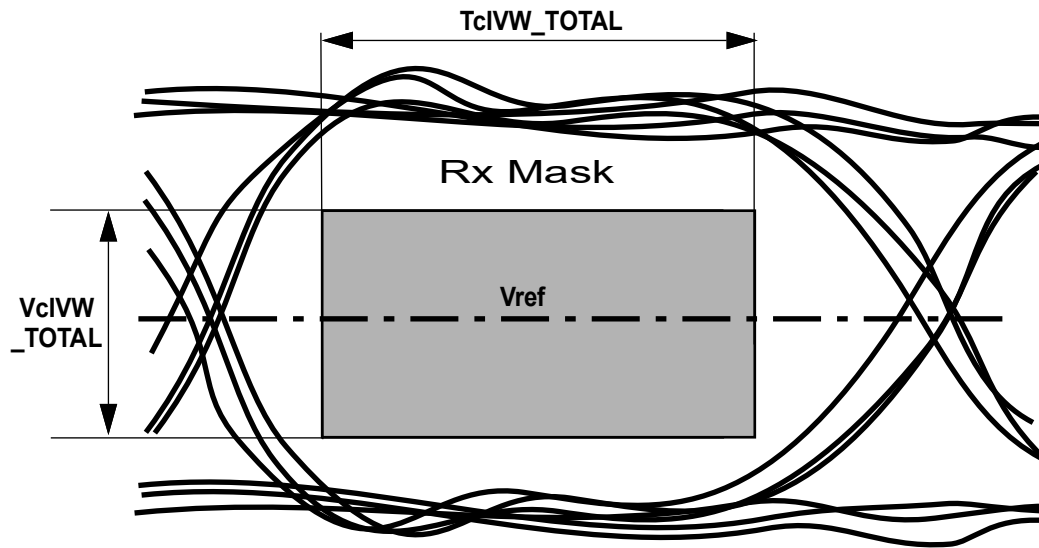
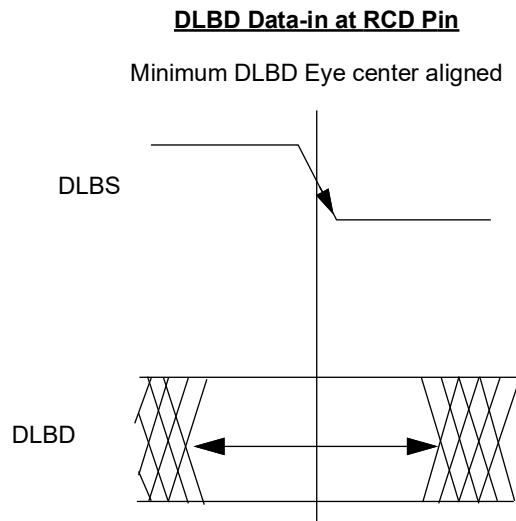


Figure 108 — DLBD Receiver (RX) Mask



TcIVW for DLBD is defined as centered on the DLBS falling edge at the RCD pin

Figure 109 — DLBD Timings at the RCD

12.11 DLBD Input Receiver Specification (cont'd)

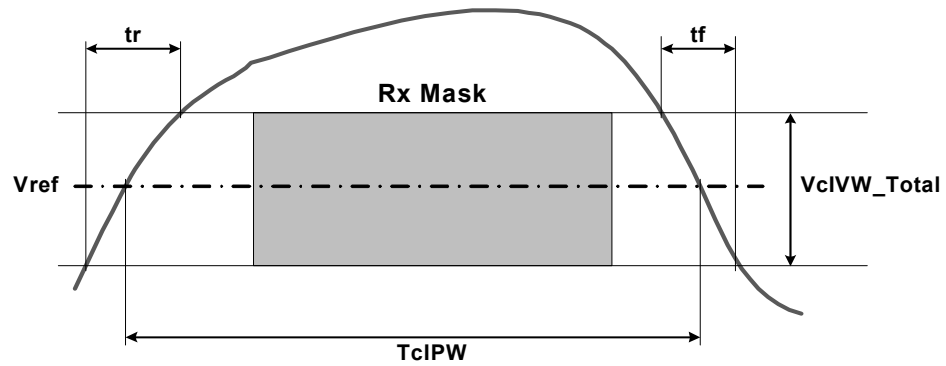


Figure 110 — DLBD TcIPW Definition (for each Input Pulse)

12.11 DLBD Input Receiver Specification (cont'd)

Table 254 — Loopback RX Receiver Voltage Margin and AC Timing by Speed Bin

Speed		DDR5-3200-4800		DDR5-5200-5600		DDR5-6000 - 8000		Unit	Note
Symbol	Parameter	Min	Max	Min	Max	Min	Max		
Data Voltage and Timing									
VcIVW_TOTAL	DLBD Rx Mask p-p voltage total	-	90	-	100	-	90	mV	1,2,3,4,7
TcIVW_TOTAL	DLBD Rx timing window total	-	0.3	-	0.45	-	0.45	tCK(avg)min	1,4,7
tDLBS2DLBD	DLBS to DLBD offset	-	0.1	-	0.2	-	0.2	tCK(avg)min	5,7
TdlbsIPW_2PH	DLBS input pulse width in 2-phase loopback mode	0.25	-	N/A	N/A	N/A	N/A	tCK(avg)min	6,7
TdlbsIPW_4PH	DLBS input pulse width in 4-phase loopback mode	0.55	-	0.55	-	0.55	-	tCK(avg)min	6,7
NOTE 1	Loopback Rx mask voltage and timing total input valid window where VcIVW is centered around the effective Vref level. The Loopback Rx mask is applied per bit and includes voltage and temperature drift terms. The BER for DDR5 during normal operation is 1e-16. For validation purpose, the BER used is 1e-9.								
NOTE 2	Rx mask voltage AC swing peak-peak requirement over TcIVW_TOTAL with at least half of VcIVW_TOTAL(max) above effective Vref and at least half of VcIVW_TOTAL(max) below effective Vref.								
NOTE 3	The VcIVW voltage levels are centered around the effective Vref level.								
NOTE 4	DLBD minimum input pulse width defined at the effective Vref level.								
NOTE 5	DLBS to DLBD is defined as the input offset for each Loopback input in the DDR5RCD05 device measured at the package balls. Includes all DDR5RCD05 process, voltage and temperature variation. Measured from the falling edge of DLBS to the center (midpoint) of the DLBD TcIVW_TOTAL window. See Figure 109 on page 282.								
NOTE 6	DLBS minimum input pulse width defined at the effective Vref level.								
NOTE 7	At DDR5-5200, DDR5-5600, DDR5-6000 and DDR5-6400, only 1/4 rate loopback is required.								

13 Electrical - Output AC and DC Specifications

13.1 Single-Ended Output Slew Rate

With the reference load for timing measurements, output slew rate for falling and rising edges is defined and measured between 75% and 25% of the Total swing as shown in Table 255 and Figure 111.

Table 255 — Output Single-ended Slew Rate Definition

Description	Measured		Defined by
	from	to	
Single-ended output slew rate for rising edge	25%	75%	$[(25\% - 75\%)] / \Delta TR_{se}$
Single-ended output slew rate for falling edge	75%	25%	$[(75\% - 25\%)] / \Delta TF_{se}$
NOTE 1 Output slew rate is verified by design and characterization, and may not be subject to production test.			

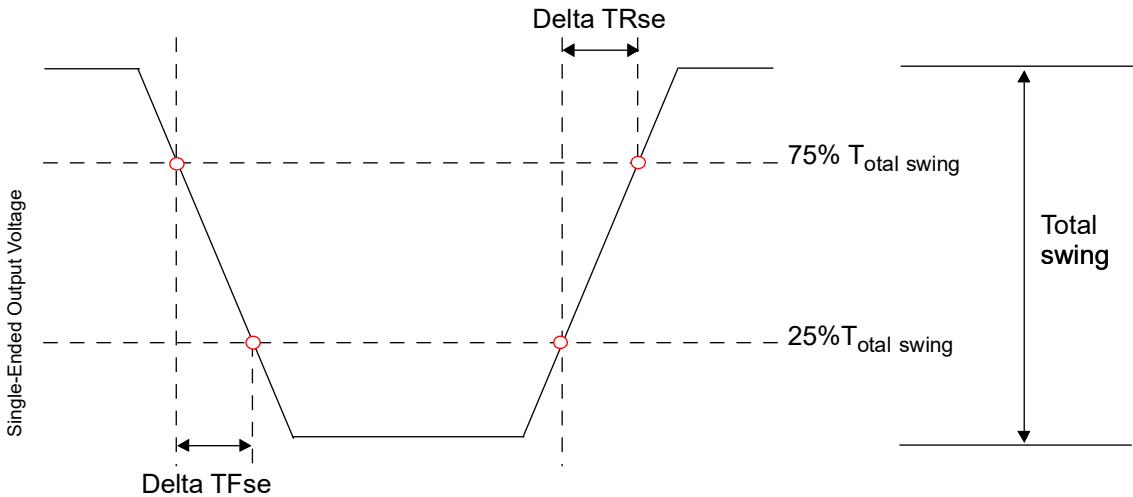


Figure 111 — Output Single-Ended Slew Rate Definition

13.1 Single-Ended Output Slew Rate (cont'd)

Table 256 — Output Single-Ended Edge Rates over Specified Operating Temperature Range

Symbol	Parameter	Conditions	DDR5-3200 - 8000		Unit
			Min	Max	
dV/dt_{rQCA}	QCA rising edge slew rate ^{1,2}	1.1V operation	2.5	12	V/ns
dV/dt_{fQCA}	QCA falling edge slew rate ^{1,2}	1.1V operation	2.5	12	V/ns
dV/dt_{rQCS}	QCS rising edge slew rate ²	1.1V operation	2.5	12	V/ns
dV/dt_{fQCS}	QCS falling edge slew rate ²	1.1V operation	2.5	12	V/ns
dV/dt_{fAlert_n}	Alert_n falling edge slew rate ²	1.1V operation	2.5	12	V/ns
dV/dt_{rQRST_n}	QRST_n rising edge slew rate ²	1.1V operation	0.1	3.0	V/ns
dV/dt_{fQRST_n}	QRST_n falling edge slew rate ²	1.1V operation	0.1	1.0	V/ns
dV/dt_D^3	absolute difference between dV/dt_r and dV/dt_f	1.1V operation	-	2	V/ns

NOTE 1 These parameters are for the QCA outputs.

NOTE 2 Measured into 50 Ω or 1 k Ω reference load terminated to V_{DD} , as shown in Figure 138.

NOTE 3 Difference between dV/dt_r (rising edge rate) and dV/dt_f (falling edge rate)

13.2 Output Clock Differential Slew Rate

Output slew rates for differential signals QnCKx_t / QnCKx_c are defined and measured as shown in Table 257 and Figure 112.

Table 257 — Output Clock Differential Slew Rate Definition for QnCK_t / QnCK_c

Description	Measured		Defined by
	From	To	
Differential output slew rate for rising edge (QnCK_t / QnCK_c).	25%	75%	$[25\% - 75\%] / \Delta TR_{diff}$
Differential output slew rate for falling edge (QnCK_t / QnCK_c).	75%	25%	$[75\% - 25\%] / \Delta TF_{diff}$
NOTE 1 Differential output slew rate is verified by design and characterization, and may not be subject to production test.			

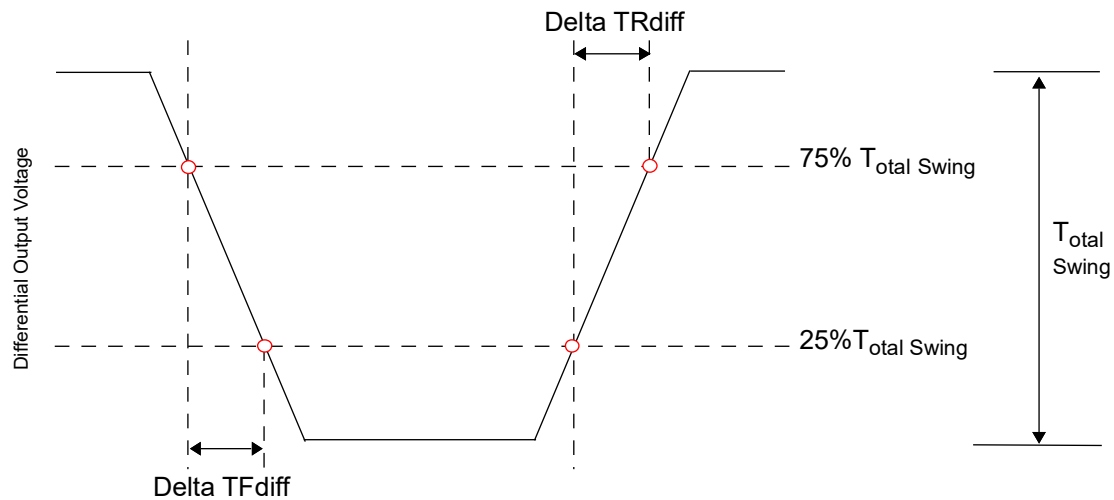


Figure 112 — Differential Output Slew Rate Definition for QnCK_t / QnCK_c

Table 258 — Output Differential Edge Rates¹

Symbol	Parameter	Conditions	DDR5-3200 - 8000		Unit
			Min	Max	
dV/dt_r	QCK rising edge differential Slew Rate	1.1V operation	12	39	V/ns
dV/dt_f	QCK falling edge differential Slew Rate	1.1V operation	12	39	V/ns

NOTE 1 There are two selectable output slew rate ranges defined for QCK in RW0E. See Table 105 on page 149, for operating conditions.

13.3 Differential Output Clock Cross Point Voltage

The differential output clock cross point voltage is defined as the cross point voltage measured on the differential signals QnCK_t / QnCK_c with respect to the output common mode voltage (V_{OCM}).

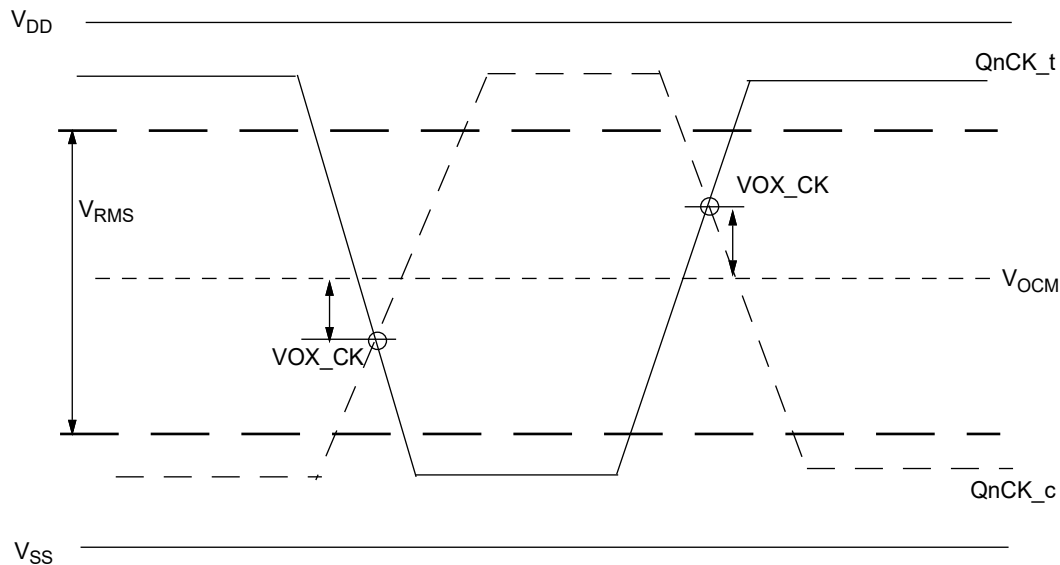


Figure 113 — VOX Definition (QnCKx)

Table 259 — Output Cross Point Voltage for QnCK_t/QnCK_c

Symbol	Parameter	DDR5-3200~5600		DDR5-6000~8000		Unit	NOTE
		Min	Max	Min	Max		
VOX_CK_Ratio	QnCK Differential Output Cross-Point Voltage Ratio	-	10	-	20	%	1, 2, 3

NOTE 1 Referenced to $V_{OCM} = \text{avg}(QnCK_t + QnCK_c)/2$, where the average is over 8 UI.

NOTE 2 $VOX_{CK_Ratio} = (|VOX_{CK}| / |V_{RMS}|) * 100\%$, where $V_{RMS} = \text{RMS}(QnCK_t \text{ voltage} - QnCK_c)$.

NOTE 3 Only applies when both QnCK_t QnCK_c are transitioning. Measured into 50-Ω reference load terminated to V_{DD} , as shown in Figure 138.

13.4 QCK, QCA, QCS Output Slew Rate Specifications per Control Words Settings

Table 260 — QCK, QCA, QCS Output Slew Rate

Symbol	Parameter	Min	Max	Unit
QxCK_t / QxCK_c Differential Slew Rate				
SR _{QCK_M}	Moderate slew rate	16	30	V/ns
SR _{QCK_F}	Fast slew rate	20	39	V/ns
SR _{QCK_L}	Slow slew rate ¹	12	22	V/ns
Q[B:A]CA[13:0] Single-Ended Slew Rate				
SR _{QCA_M}	Moderate slew rate	4.2	8.1	V/ns
SR _{QCA_F}	Fast slew rate	5.6	12	V/ns
SR _{QCA_L}	Slow slew rate ¹	2.5	5.4	V/ns
Q[B:A]CS[3:0]_n Single-Ended Slew Rate				
SR _{QCS_M}	Moderate slew rate	4.2	8.1	V/ns
SR _{QCS_F}	Fast slew rate	5.6	12	V/ns
SR _{QCS_L}	Slow slew rate ¹	2.5	5.4	V/ns

NOTE 1 Setting not valid for speeds above 7200.

13.5 Output R-on Drive Specifications per Drive Strength Setting

Table 261 — Output Ron Drive

Symbol	Parameter	DDR5-3200 to 8000			Unit
		Min	Nom	Max	
ALERT_n					
R _{on} (ALERT)Pd	ALERT_n Pull-down Impedance	see Table 262	R _{ZQ} /17	see Table 262	Ω
R _{on} (ALERT)Pu	ALERT_n Pull-up Impedance		R _{ZQ}		Ω
QRST_n					
RON _{RST} Pd	QRST_n Pull-down Impedance	see Table 262	R _{ZQ} /8	see Table 262	Ω
RON _{RST} Pu	QRST_n Pull-up Impedance		R _{ZQ} /8		Ω
QLBS, QLBD					
R _{on} _LBL	Light Drive Impedance	see Table 262	R _{ZQ} /5	see Table 262	Ω
R _{on} _LBM	Moderate Drive Impedance		R _{ZQ} /7		Ω
QxCA[13:0]/QxCS[1:0]_n/QnCK_t/QnCK_c					
R _{on} _QL	Light Drive Impedance	see Table 262	R _{ZQ} /9	see Table 262	Ω
R _{on} _QM	Moderate Drive Impedance		R _{ZQ} /12		Ω
R _{on} _QS	Strong Drive Impedance		R _{ZQ} /17		Ω

NOTE 1 A functional representation of the output buffer is shown in Figure 114. Output impedance RON is defined by the value of the external reference resistor R_{ZQ} as defined in Table 262.

13.5 Output R-on Drive Specifications per Drive Strength Setting (cont'd)

The individual pull-up and pull-down resistors ($R_{ON_{Pu}}$ and $R_{ON_{Pd}}$) are defined as follows:

$$R_{ON_{Pu}} = \frac{V_{DD} - V_{Out}}{|I_{Out}|} \quad \text{under the condition that } R_{ON_{Pd}} \text{ is turned off.}$$

$$R_{ON_{Pd}} = \frac{V_{Out}}{|I_{Out}|} \quad \text{under the condition that } R_{ON_{Pu}} \text{ is turned off.}$$

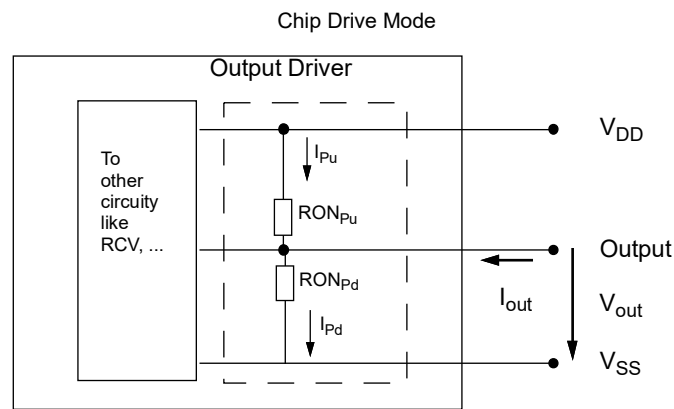


Figure 114 — Output Driver: Definition of Voltages and Currents

NOTE 2 Assuming $R_{ZQ} = 240 \Omega \pm 1\%$

Table 262 — Output Driver DC Electrical Characteristics, Entire Operating Temperature Range

$R_{ON_{Nom}}$	Resistor	V_{Out}	Min	Nom	Max	Unit	NOTE
48 Ω	$R_{ON_{48Pd}}$	$V_{OLdc} = 0.5 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/5$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/5$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/5$	1, 2
	$R_{ON_{48Pu}}$	$V_{OLdc} = 0.5 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/5$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/5$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/5$	1, 2
34 Ω	$R_{ON_{34Pd}}$	$V_{OLdc} = 0.5 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/7$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/7$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/7$	1, 2
	$R_{ON_{34Pu}}$	$V_{OLdc} = 0.5 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/7$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/7$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/7$	1, 2

Table 262 — Output Driver DC Electrical Characteristics, Entire Operating Temperature Range (cont'd)

RON_{Nom}	Resistor	V_{Out}	Min	Nom	Max	Unit	NOTE
20 Ω	RON_{20Pd}	$V_{OLdc} = 0.5 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/12$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/12$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/12$	1, 2
	RON_{20Pu}	$V_{OLdc} = 0.5 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/12$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/12$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/12$	1, 2
14 Ω	RON_{14Pd}	$V_{OLdc} = 0.5 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/17$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/17$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/17$	1, 2
	RON_{14Pu}	$V_{OLdc} = 0.5 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/17$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/17$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/17$	1, 2
27 Ω	RON_{27Pd}	$V_{OLdc} = 0.5 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/9$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/9$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/9$	1, 2
	RON_{27Pu}	$V_{OLdc} = 0.5 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/9$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/9$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/9$	1, 2
14 Ω (for ALERT_n pulldown only)	$RON_{ALERTPd}$	$V_{OLdc} = 0.5 \times V_{DD}$	0.8	1.0	1.1	$R_{ZQ}/17$	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.9	1.0	1.1	$R_{ZQ}/17$	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.9	1.0	1.25	$R_{ZQ}/17$	1, 2
240 Ω (for ALERT_n pullup only)	$RON_{ALERTPu}$	$V_{OLdc} = 0.5 \times V_{DD}$	0.85	1.0	1.25	R_{ZQ}	1, 2
		$V_{OMdc} = 0.8 \times V_{DD}$	0.85	1.0	1.1	R_{ZQ}	1, 2
		$V_{OHdc} = 0.95 \times V_{DD}$	0.6	1.0	1.1	R_{ZQ}	1, 2
30 Ω (for QRST_n only)	RON_{RSTPd}	$V_{OLdc} = 0.2 \times V_{DD}$	0.6	1.0	1.25	$R_{ZQ}/8$	1, 2
		$V_{OMdc} = 0.5 \times V_{DD}$	0.75	1.0	1.25	$R_{ZQ}/8$	1, 2
		$V_{OHdc} = 0.8 \times V_{DD}$	0.75	1.0	1.4	$R_{ZQ}/8$	1, 2
	RON_{RSTPu}	$V_{OLdc} = 0.2 \times V_{DD}$	0.75	1.0	1.4	$R_{ZQ}/8$	1, 2
		$V_{OMdc} = 0.5 \times V_{DD}$	0.75	1.0	1.25	$R_{ZQ}/8$	1, 2
		$V_{OHdc} = 0.8 \times V_{DD}$	0.6	1.0	1.25	$R_{ZQ}/8$	1, 2
Mismatch between pull-up and pull-down, MM_{PuPd}		$V_{OMdc} = 0.8 \times V_{DD}$	-10		10	%	1, 2, 3
Mismatch within component variation pull-up, MM_{Pudd}		$V_{OMdc} = 0.8 \times V_{DD}$	0		10	%	1, 2, 4
Mismatch within component variation pull-down, MM_{Pddd}		$V_{OMdc} = 0.8 \times V_{DD}$	0		10	%	1, 2, 4

- NOTE 1 The tolerance limits are specified after calibration with stable voltage and temperature. For the behavior of the tolerance limits if temperature or voltage changes after calibration, see Clause 13.6, “Output Driver and Termination Resistor Temperature and Supply Voltage Sensitivity,” on page 292.
- NOTE 2 Pull-up and pull-down output driver impedances are recommended to be calibrated at $0.5 \times V_{DD}$ (for $R_{ON_{RSTPd}}$ and $R_{ON_{RSTPu}}$), or $0.8 \times V_{DD}$ (for the other impedances). Other calibration schemes may be used to achieve the linearity spec shown above, e.g., calibration at $0.5 \times V_{DD}$ and $0.95 \times V_{DD}$. RON variance range ratio to RON nominal value in a given component.
- NOTE 3 Measurement definition for mismatch between pull-up and pull-down, MM_{PuPd} : Measure $R_{ON_{Pu}}$ and $R_{ON_{Pd}}$, both at $0.5 \times V_{DD}$ (for $R_{ON_{RSTPd}}$ and $R_{ON_{RSTPu}}$), or $0.8 \times V_{DD}$ (for the other impedances) separately. Ron-nom is the nominal Ron value:

Table 262 — Output Driver DC Electrical Characteristics, Entire Operating Temperature Range (cont'd)

$$MM_{PuPd} = \frac{RON_{Pu} - RON_{Pd}}{RON_{Nom}} \times 100$$

NOTE 4 RON variance range ratio to RON nominal value in a given component:

$$MM_{Pudd} = \frac{RON_{PuMax} - RON_{PuMin}}{RON_{Nom}} \times 100$$

$$MM_{Pddd} = \frac{RON_{PdMax} - RON_{PdMin}}{RON_{Nom}} \times 100$$

13.6 Output Driver and Termination Resistor Temperature and Supply Voltage Sensitivity

If temperature and/or voltage change after calibration, the tolerance limits widen according to the tables shown below.

Table 263 — Output Driver and Termination Resistor Sensitivity Definition

Resistor	Definition Point	Min	Max	Unit	Note
R _{ONPD}	0.8 x VDD	90 - (dR _{ONPD} dT x ΔT) - (dR _{ONPD} dV x ΔV)	110 + (dR _{ONPD} dT x ΔT) + (dR _{ONPD} dV x ΔV)	%	1,2
R _{ONPU}	0.8 x VDD	90 - (dR _{ONPU} x ΔT) - (dR _{ONPU} x ΔV)	110 + (dR _{ONPU} x ΔT) + (dR _{ONPU} x ΔV)	%	1,2
R _{IBT}	0.8 x VDD	90 - (dR _{IBT} dT x ΔT) - (dR _{IBT} dV x ΔV)	110 + (dR _{IBT} dT x ΔT) + (dR _{IBT} dV x ΔV)	%	1,2,3

NOTE 1 ΔT = T - T(@ Calibration), ΔV = V - V(@ Calibration)

NOTE 2 dR_{ONPD}dT, dR_{ONPD}dV, dR_{ONPU}dT, dR_{ONPU}dV, dR_{IBT}dV, and dR_{IBT}dT are not subject to production test but are verified by design and characterization.

NOTE 3 This parameter applies to Input pins such as DCA[6:0], DPAR, DCS[1:0]_n, DCK_t/DCK_c, DERROR_IN_n, DLBD, and DLBS.

Table 264 — Output Driver and Termination Resistor Temperature and Voltage Sensitivity

Symbol	Parameter	Min	Max	Unit
dR _{ONPD} dT	R _{ONPD} Temperature Sensitivity	0.00	0.1	%/°C
dR _{ONPD} dV	R _{ONPD} Voltage Sensitivity	0.00	0.1	%/mV
dR _{ONPU} dT	R _{ONPU} Temperature Sensitivity	0.00	0.1	%/°C
dR _{ONPU} dV	R _{ONPU} Voltage Sensitivity	0.00	0.1	%/mV
dR _{IBT} dT	R _{IBT} Temperature Sensitivity	0.00	0.1	%/°C
dR _{IBT} dV	R _{IBT} Voltage Sensitivity	0.00	0.1	%/mV

13.7 Output Clock Driver Characteristics

Table 265 — Output Clock Driver Characteristics at Application Mode (Frequency Band 1)

Symbol	Parameter	Conditions	DDR5-3200		DDR5-3600		DDR5-4000~6400		DDR5-6800~7200		DDR5-7600~8000		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{STAB01} ¹	RCD Stabilization time from start of DCK toggle to PLL lock	DCK_t/DCK_c stable	-	3.5	-	3.5	-	3.5	-	3.5	-	3.5	μs
t_{STAB02}	RCD Stabilization time from control word write to PLL lock ²	DCK_t/DCK_c stable	-	25.0	-	25.0	-	25.0	-	25.0	-	25.0	μs
t_{CKsk}	Fractional Clock Output Skew ³		-	20	-	20	-	20	-	20	-	20	ps
t_{staoff} ⁴	Clock delay through the register between the input clock and output clock ⁵		Min: ($t_{\text{PDM}}(\text{min}) + 1/2 \text{ tCK}$); Max: ($t_{\text{PDM}}(\text{max}) + 1/2 \text{ tCK}$)										ps
t_{dynoff} ⁶	Maximum re-driven dynamic clock offset ⁷		-	40	-	35	-	35	-	30	-	25	ps

NOTE 1 At Down-bin Data Rate ($1980 \text{ MT/s} \leq f \leq 2100 \text{ MT/s}$), the max value of t_{STAB01} is 10μs.

NOTE 2 This parameter applies to control word writes to RW05/RW06 and Bit OP0 in RW00. Since application of RW05/RW06 is postponed in the frequency change sequence defined in Clause 5.7.2, a t_{STAB01} waiting time is always sufficient after exit from Self Refresh with Clock Stop (i.e., t_{STAB02} is not required). See timing diagrams in Figure 40 on page 54 and Figure 41 on page 55.

NOTE 3 This skew represents the absolute output clock skew and contains the pad skew and package skew (See Figure 117). This parameter is specified for the clock pairs on each side of the register independently. The skew is applicable to left side clock pairs between QACK_A_t/QACK_A_c and QCKK_A_t/QCKK_A_c, between QWCK_A_t/QWCK_A_c and QYCK_A_t/QYCK_A_c, as well as right side of the clock pairs between QACK_B_t/QACK_B_c and QCKK_B_t/QCKK_B_c, between QWCK_B_t/QWCK_B_c and QYCK_B_t/QYCK_B_c. Similarly, to left side clock pairs between QBCK_A_t/QBCK_A_c and QDCK_A_t/QDCK_A_c, between QXCK_A_t/QXCK_A_c and QZCK_A_t/QZCK_A_c, as well as right side of the clock pairs between QBCK_B_t/QBCK_B_c and QDCK_B_t/QDCK_B_c, between QXCK_B_t/QXCK_B_c and QZCK_B_t/QZCK_B_c. This is not a tested parameter and has to be considered as a design goal only.

NOTE 4 RW05/RW06 must be set to correct speed and the device must run at one of the speed nodes defined in Table 232 on page 240. See Figure 115 and Figure 116.

NOTE 5 This measures the delay from the rising differential input clock which samples incoming DCA to the rising differential output clock that will be used to sample the same QCA data. The parameter describes the maximum and minimum QxCK clock t_{PD} .

NOTE 6 V_{DD} measurement DC bandwidth is limited to 20 MHz.

NOTE 7 See Figure 115 and Figure 116.

13.7 Output Clock Driver Characteristics (cont'd)

Table 266 — Output Clock Driver Characteristics at Test Mode (Frequency Band 2)

Symbol	Parameter	Conditions	Test Frequency (140 to 990 MHz)		Unit
			Min	Max	
tSTAB01	RCD Stabilization time from start of DCK toggle to PLL lock	DCK_t/DCK_c stable	-	50	μs
tSTAB02	RCD Stabilization time from control word write to PLL lock ¹	DCK_t/DCK_c stable	-	50	μs
tCKsk	Fractional Clock Output Skew ²		-	100	ps
tstaoff ³	Clock delay through the register between the input clock and output clock ⁴		Min:(t _{PDM} (min) + 1/2 tCK); Max: (t _{PDM} (max) + 1/2 tCK)		ps
tdynoff ⁵	Maximum re-driven dynamic clock offset ⁶		-	500	ps

NOTE 1 This parameter applies to control word writes to [RW05](#) and Bit OP0 in [RW00](#).

NOTE 2 This skew represents the absolute output clock skew and contains the pad skew and package skew (See Figure 117). This parameter is specified for the clock pairs on each side of the register independently. The skew is applicable to left side clock pairs between QACK_A_t/QACK_A_c and QCCK_A_t/QCCK_A_c, as well as right side of the clock pairs between QACK_B_t/QACK_B_c and QCCK_B_t/QCCK_B_c. Similarly, to left side clock pairs between QBCK_A_t/QBCK_A_c and QDCK_A_t/QDCK_A_c, as well as right side of the clock pairs between QBCK_B_t/QBCK_B_c and QDCK_B_t/QDCK_B_c. This is not a tested parameter and has to be considered as a design goal only.

NOTE 3 [RW05](#) must not be set to enable PLL bypass mode and the device must run within the Test Frequency range defined in Table 232 on page 240. See Figure 115 and Figure 116.

NOTE 4 This measures the delay from the rising differential input clock which samples incoming DCA to the rising differential output clock that will be used to sample the same QCA data. The parameter describes the maximum and minimum QxCK clock t_{PD}.

NOTE 5 V_{DD} measurement DC bandwidth is limited to 20 MHz.

NOTE 6 See Figure 115 and Figure 116.

13.7 Output Clock Driver Characteristics (cont'd)

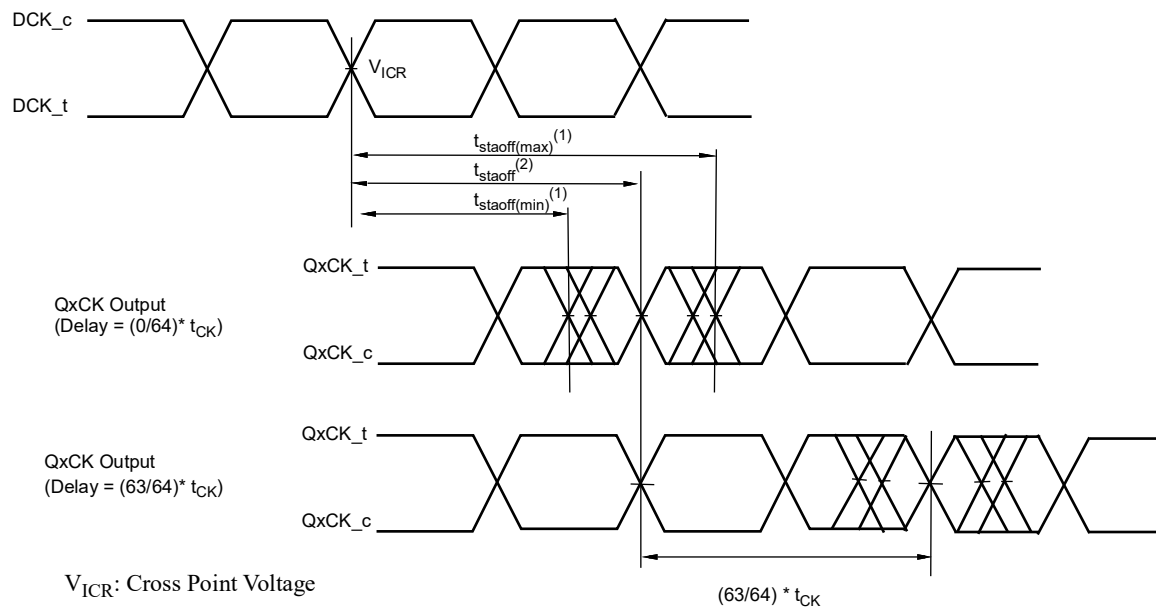


Figure 115 — Definition for t_{staoﬀ} and t_{dynoﬀ} in DDR Mode

1. $t_{\text{staoﬀ}}^{(\text{max/min})}$ = propagation delay specification limits for clock signal (falling DCK input clock edge to rising QxCK output clock edge for corresponding data cycles) over process, voltage and temperature.
2. $t_{\text{staoﬀ}}$ = measured propagation delay for clock signal (falling DCK input clock edge to rising QxCK output clock edge for corresponding data cycles).
3. $t_{\text{dynoﬀ}}$ = maximum propagation delay variation over voltage and temperature within $t_{\text{staoﬀ}}$ window. This includes all sources of jitter and drift (e.g., thermal noise, supply noise, voltage/temperature drift, SSC tracking, SSO, etc.) except reference clock noise.

13.7 Output Clock Driver Characteristics (cont'd)

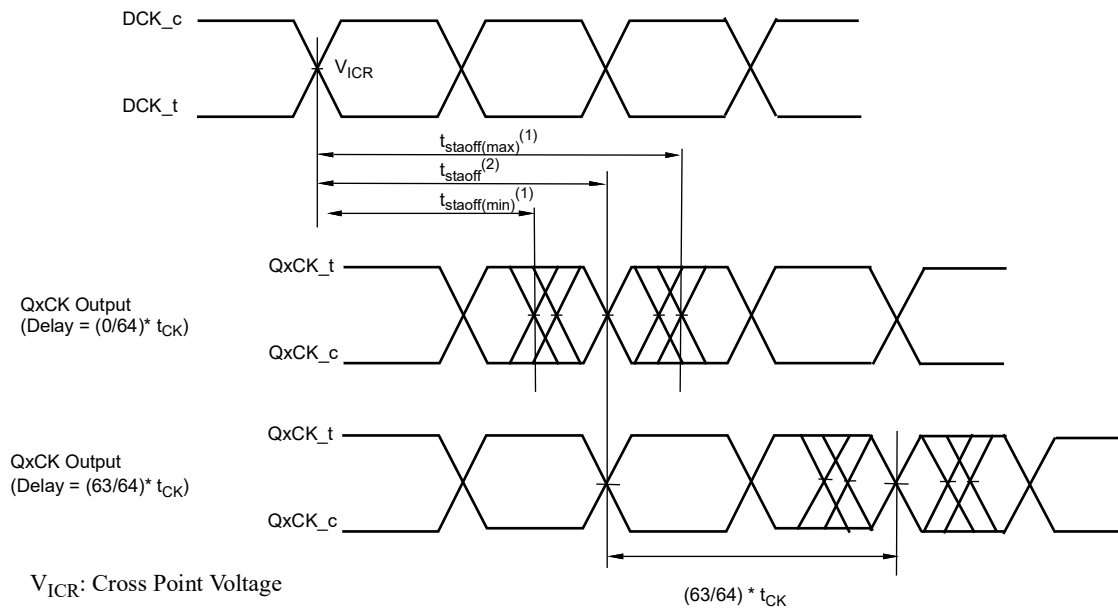


Figure 116 — Definition for t_{staoff} and t_{dynoff} in SDR Mode

1. $t_{staoff(max/min)}$ = propagation delay specification limits for clock signal (rising DCK input clock edge to rising QxCK output clock edge for corresponding data cycles) over process, voltage and temperature.
2. t_{staoff} = measured propagation delay for clock signal (rising DCK input clock edge to rising QxCK output clock edge for corresponding data cycles).
3. t_{dynoff} = maximum propagation delay variation over voltage and temperature within t_{staoff} window. This includes all sources of jitter and drift (e.g., thermal noise, supply noise, voltage/temperature drift, SSC tracking, SSO, etc.) except reference clock noise.

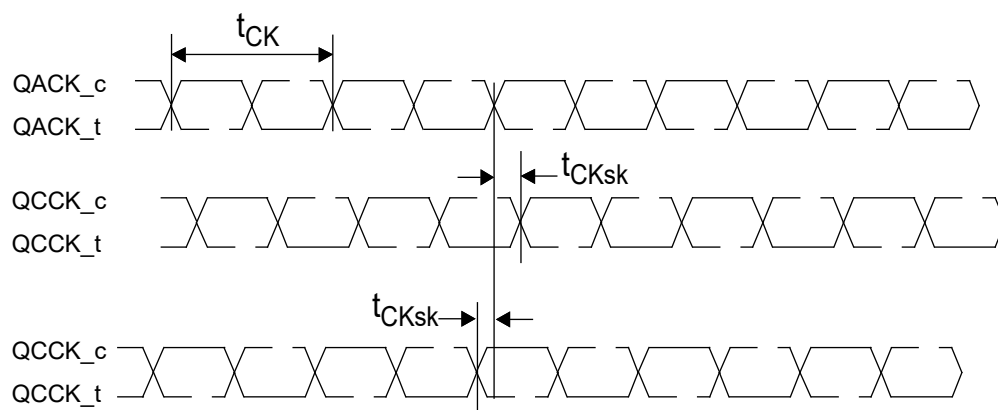


Figure 117 — Clock Output (QxCK) Skew

13.8 Differential Output Clock Driver Jitter Characteristics

13.8.1 Overview

The Random Jitter (Rj) specified is a random jitter meeting Gaussian distribution. The Deterministic Jitter (Dj) specified is bounded. The DDR5 device output jitter must not exceed maximum values specified in Table 248.

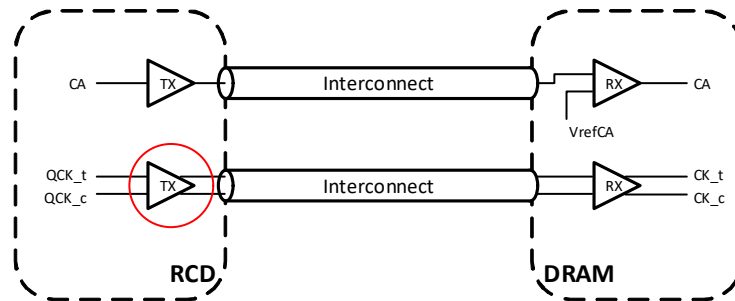


Figure 118 — Example of QCK TX Interconnect

13.8.2 Output Clock Jitter Parameters

Table 267 — Tx QCK Jitter Specifications

[BUJ = Bounded Uncorrelated Jitter; DCD = Duty Cycle Distortion; Dj = Deterministic Jitter; Rj = Random Jitter; pp = Peak-to-Peak]

Symbol	Parameter	DDR5-3200 to 4800		DDR5-5200 to 5600		DDR5-6000 to 8000		Unit	NOTE
		Min	Max	Min	Max	Min	Max		
tTx_QCK_1UI_Rj_NoBUJ	Rj value of 1-UI Jitter without BUJ	-	0.0035	-	0.003	-	0.003	UI (RMS)	1, 2, 3, 8, 9
tTx_QCK_1UI_Dj_NoBUJ	Dj pp value of 1-UI Jitter without BUJ	-	0.025	-	0.025	-	0.030	UI	2, 3, 4, 8, 9
tTx_QCK_NUI_Rj_NoBUJ	Rj value of N-UI Jitter without BUJ	-	0.0035	-	0.003	-	0.003	UI (RMS)	1, 3, 5, 7, 8, 9
tTx_QCK_NUI_Dj_NoBUJ	Dj pp value of N-UI Jitter without BUJ	-	0.07	-	0.07	-	0.07	UI	2, 3, 6, 7, 8, 9
Unit UI = tCK(avg).min/2									
NOTE 1	The test should be run under quiet conditions with single output switching.								
NOTE 2	When there is no socket in transmitter measurement setup, in many cases, the contribution of the cross-talk is not significant or cannot be estimated within tolerable error even with all the transmitter lanes sending patterns. When a socket is present, such as DUT being DRAM component, the contribution of the cross-talk could be significant. To minimize the impact of crosstalk on the measurement results, a small group of selected lanes in the vicinity of the lane under test may be turned off (sending DC), while the remaining Tx lanes send patterns to the corresponding Rx receivers so as to excite realistic on-die noise profile from device switching. Note that there may be cases when one of Dj and Rj specs is met and another violated in which case the signaling analysis should be run to determine link feasibility. Rj RMS value of 1-UI jitter without BUJ. This extraction is to be done after software correction of DCD.								
NOTE 3	This test should be done in typical temperature and voltage conditions (i.e., V _{DD} = 1.1 V, 25 °C).								
NOTE 4	Dj pp value of 1-UI jitter (after software assisted DCC). Without BUJ. Dj indicates Djdd of dual-Dirac fitting.								
NOTE 5	Rj RMS value of N-UI jitter without BUJ, but on-die system like noise present. This extraction is to be done after software correction of DCD.								
NOTE 6	Dj pp value of N-UI jitter without BUJ, but on-die system like noise present. Dj indicates Djdd of dual-Dirac fitting, after software correction of DCD.								
NOTE 7	When frequency is less than or equal to 4800 MT/s 1 < N < 4. When frequency is greater than 4800 MT/s 1 < N < 6.								
NOTE 8	Measurements are done with default R-on and fast slew rate settings for all parameters.								
NOTE 9	All parameters in Table 267 may not be subject to production test.								

13.9 ALERT_n Output Driver DC Electrical Characteristic

Table 268 — ALERT_n Output Driver DC Electrical Characteristics

Symbol	Parameter	Applicable Signals	Condition	Min	Nom	Max	Unit
I _{OL}	LOW-level output current ALERT_n	Measured at V _{OL} of 0.4 V	-	25	-	-	mA
V _{OL}	Output LOW voltage ALERT_n	Measured at I _{OL} = 25 mA	-	-	-	0.4	V

14 IDD Specification Parameters

14.1 IDD Specification Parameters and Test Conditions

In this chapter, IDD measurement conditions, such as test load and patterns, are defined. Figure 119 shows the setup and test load for IDD measurements.

- IDD currents (such as IDD3NA, IDD4A, IDD6R and IDD6S) are measured as time-averaged currents with all V_{DD} balls of the DDR5RCD05 under test tied together.
- IDD currents can be measured for each speed bin. Each measurement shall use the minimum tCK (avg) for each speed bin.
- **ATTENTION:** IDD values cannot be directly used to calculate IO power of the DDR5RCD05. They can be used to support correlation of simulated IO power to actual IO power as outlined in Figure 120.

For IDD measurements, the following definitions apply:

- “0” and “LOW” is defined as $V_{IN} \leq V_{IL(AC).max}$.
- “1” and “HIGH” is defined as $V_{IN} \geq V_{IH(AC).min}$.
- Basic IDD Measurement Conditions are described in Table 269.
- Detailed IDD Measurement-Loop Patterns are described in Table 270 and Table .

IDD Measurements are done after properly initializing the DDR5RCD05. This includes but is not limited to the following settings:

- All four lower clock outputs enabled per channel in [RW08](#).
- IBT enabled in [RW10](#)
- All output driver strength set to RZQ/17
- Parity checking disabled in [RW01\[0\]](#)
- SidebandBus interface enabled
- QCA13 enabled
- 60 Ω IBT enabled for DCA[6:0], DPAR, DCS[1:0]
- Per-group Qx output delay control feature enabled in control words [RW12](#), [RW13](#), [RW14](#), [RW15](#), [RW17](#), [RW18](#), [RW19](#), [RW1A](#), [RW1B](#), [RW1C](#), PG[70]RW[7F:78]. When enabled, the delay codes remain at the default 0.
- Per-bit QCA output delay control feature enabled in control words [PG\[05\]RW\[7B:60\]](#). When enabled, the delay codes remain at the default 0.
- DCA DFE feature enabled in control words [RW31\[7:4, 0\]](#), [RW33\[7:6\]](#). When enabled, the gain and tap codes remain at the default 0.
- DCS DFE feature enabled in control words [RW31\[0\]](#), [PG\[6\]RW78\[7:4\]](#). When enabled, the gain and tap codes remain at the default 0.
- CTLE feature enabled in control words [RW50\[0\]](#), [RW51](#). When enabled, the settings remain at the default value.

Note: Output Delay Control, DCA DFE, DCS DFE and CTLE have an impact on IDD current and may or may not be enabled in certain systems. To correlate RCD device IDD data to a system environment, the user must enable a combination that matches the target system configuration.

14.1 IDD Specification Parameters and Test Conditions (cont'd)

ATTENTION: The IDD Measurement-Loop Patterns need to be executed at least one time before actual IDD measurement is started.

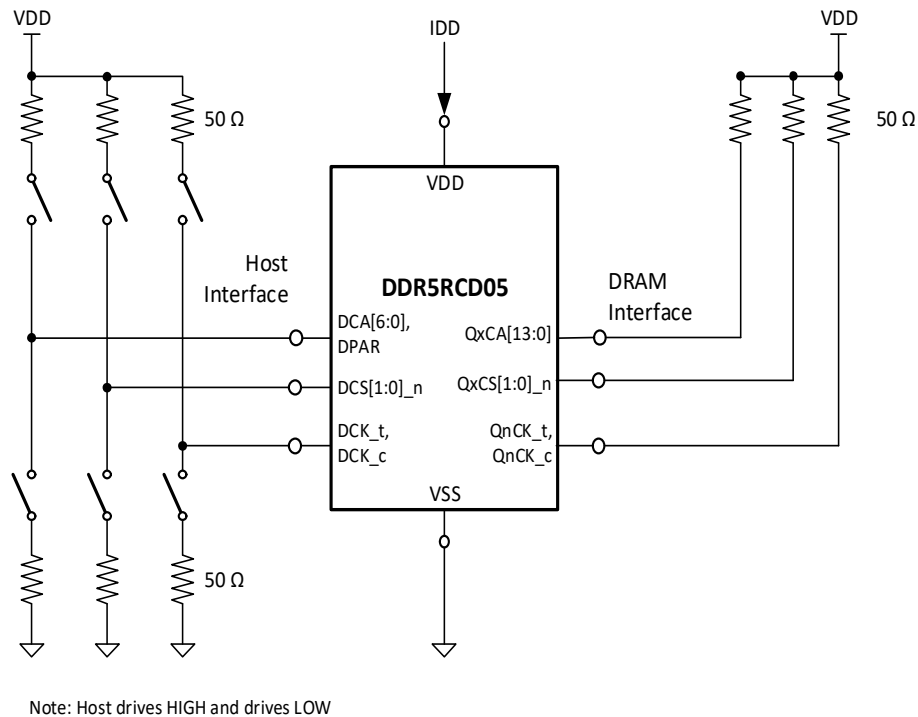


Figure 119 — Measurement Setup and Test Load for IDD Measurements

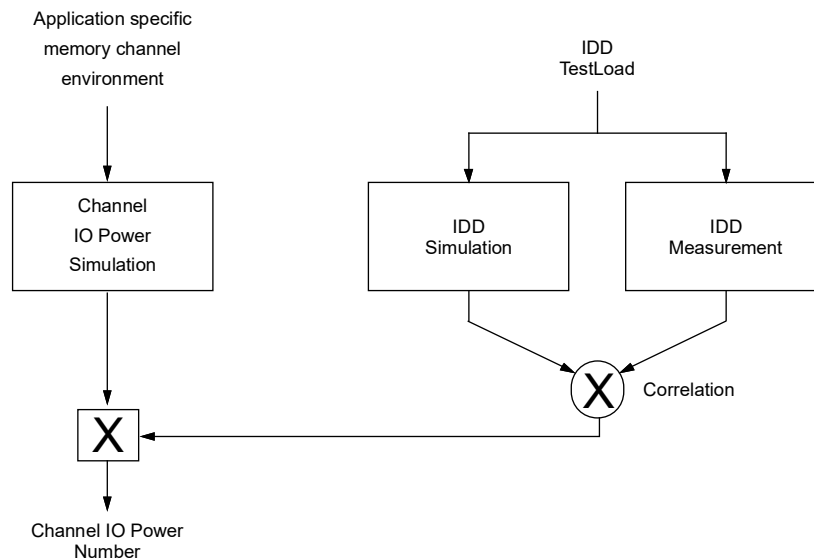


Figure 120 — Correlation from Simulated Channel IO Power to Actual Channel IO Power Supported by IDD Measurement

14.1 IDD Specification Parameters and Test Conditions (cont'd)

Table 269 — Basic IDD Measurement Conditions¹

Symbol	Description
IDD3NA	Active Idle Current Q[D:A]CK: Enabled; Q[Z:W]CK: Disabled in PG[70]RW63[3:0]; QxCS[1:0]: Enabled; QxCS[3:2]_n: Disabled in PG[70]RW62[4:1]; Data IO & Pattern Details: see Table 270
IDD4A	Active Current Q[D:A]CK: Enabled; Q[Z:W]CK: Disabled in PG[70]RW63[3:0]; QxCS[1:0]: Enabled; QxCS[3:2]_n: Disabled in PG[70]RW62[4:1]; Data IO & Pattern Details: see Table
IDD4A_UpperQCKQCS	Active Current Q[D:A]CK: Enabled; Q[Z:W]CK: Enabled in PG[70]RW63[3:0]; QxCS[1:0]: Enabled; QxCS[3:2]_n: Enabled in PG[70]RW62[4:1]; Data IO & Pattern Details: see Table
IDD6R	Static Reset Current DRST_n: LOW; DCK_t and DCK_c: LOW; DCS: LOW; Outputs Hi-Z (except QRST, QCS)
IDD6S	Clock Stopped Power Down Current DRST_n: HIGH after being LOW for t_{RINIT1} with described input conditions (i.e., DCK_t = DCK_c = DCS_n = LOW) applied; DCK_t and DCK_c: LOW; DCS: LOW; Outputs Hi-Z (except QCS: LOW)

NOTE 1 All tests use termination setup depicted in Figure 119.

Table 270 — IDD3NA Measurement-Loop Pattern

		DCK_t, DCK_c
Toggle	0	Cycle Number
	0	UI Number
	1	Command
	0	DCS[0]_n
	1	DCS[1]_n
	0	DCA0
	1	DCA1
	0	DCA2
	1	DCA3
	0	DCA4
	1	DCA5
	0	DCA6
	1	DPAR

15 Input/Output Capacitance

Table 272 — Silicon Pad I/O Capacitance Values

Symbol	Parameter	DDR5 - 3200-8000		Unit	Notes
		Min	Max		
C_I	Input capacitance, Data inputs	0	0.75	pF	1, 2
C_O	Output capacitance	0.45	1.6	pF	1,3
C_{CK}	Input capacitance, DCK_t, DCK_c	0.2	0.75	pF	1
C_{DCK}	Input capacitance delta DCK_t and DCK_c	-	0.1	pF	1, 4
C_{IDCA}	Delta capacitance over all DCA inputs, per sub-channel	-	0.15	pF	1
C_{IDCS}	Delta capacitance over all DCS inputs, per sub-channel	-	0.15	pF	1
C_{ILB}	Input capacitance DLB	0.2	0.8	pF	1
C_{OLB}	Output capacitance QLB	0.45	1.5	pF	1
C_{IR}	Input capacitance, DRST_n	0.5	2.0	pF	1, 5
C_{OR}	Output Capacitance of QRST_n	0.5	2.0	pF	1
C_{ALERT}	Output capacitance of ALERT_n	0.4	2.0	pF	1
C_{DERROR_IN}	Input capacitance of DERROR_IN_n	0.4	1.5	pF	1

- NOTE 1 This parameter does not include package capacitance.
 NOTE 2 Data inputs are DCAy_N, DPAR_N, DCSy_N_n.
 NOTE 3 Applies to QxCAy_N, QxCSy_N_n, QxCKy_N_t, and QxCKy_N_c.
 NOTE 4 Absolute value of DCK_t - DCK_c
 NOTE 5 Parameter specified at VI = VDD or VSS; VDD = 1.1 V

15 Input/Output Capacitance (cont'd)**Table 273 — Package Electrical Parameters**

Symbol	Parameter	DDR5 - 3200 to 8000		Unit	Notes
		Min	Max		
ZI _{DCS}	Input DCS pins Zpkg	30	60	Ω	1, 2, 4
TdI _{DCS}	Input DCS pins Pkg Delay	14	55	ps	1, 3, 4
DZI _{DCS}	Delta DCS pins Zpkg	-	15	Ω	1, 2, 4, 5
DTdI _{DCS}	Delta DCS pins Pkg Delay	-	20	ps	1,3, 4, 6
ZI _{DCA}	Input DCA pins Zpkg	30	60	Ω	1, 2, 7
TdI _{DCA}	Input DCA pins Pkg Delay	14	55	ps	1, 3, 7
DZI _{DCA}	Delta DCA pins Zpkg	-	15	Ω	1, 2, 7, 8
DTdI _{DCA}	Delta DCA input pins Pkg Delay	-	20	ps	1, 3, 7, 9
ZO _{QCS}	Output QCS pins Zpkg	30	60	Ω	1, 2, 10
TdO _{QCS}	Output QCS pins Pkg Delay	14	65	ps	1, 3, 10
DZO _{QCS}	Delta QCS pins Zpkg	-	15	Ω	1, 2, 10, 11
DTdO _{QCS}	Delta QCS input pins Pkg Delay	-	20	ps	1, 3, 10, 12
ZO _{QCA}	Output QCA pins Zpkg	30	60	Ω	1, 2, 13
TdO _{QCA}	Output QCA pins Pkg Delay	14	65	ps	1, 3, 13
DZO _{QCA}	Delta QCA pins Zpkg	-	15	Ω	1, 2, 13, 14
DTdO _{QCA}	Delta QCA output pins Pkg Delay	-	20	ps	1, 3, 13, 15
ZI _{DCK}	Input DCK pins Zpkg	20	55	Ω	1, 2, 16
TdI _{DCK}	Input DCK pins Pkg Delay	14	55	ps	1, 3
ZO _{QCK}	Output QnCK pins Zpkg	20	60	Ω	1, 2, 16
TdO _{QCK}	Output QnCK pins Pkg Delay	12	55	ps	1, 3
DTdO _{ALL_QCK}	Delta Delay between all QxCKy_N for a sub-channel	-	25	ps	1, 3, 21
DZI _{DCK}	Delta Zpkg DCK_t and DCK_c	-	8	Ω	1, 2, 16, 17
DTdI _{DCK}	Delta Delay DCK_t and DCK_c	-	5	ps	1, 3, 18
DZO _{QCK}	Delta Zpkg QxCK_t and QxCK_c	-	8	Ω	1, 2, 16, 19
DTdO _{QCK}	Delta Delay QxCK_t and QxCKn_c	-	5	ps	1, 3, 20
ZO _{ZQ}	Output ZQCAL Zpkg	30	70	Ω	1, 2
ZI _{DLB}	Input DLB pins Zpkg	40	70	Ω	1, 2
TdI _{DLB}	Input DLB pins Pkg Delay	14	75	ps	1, 3
ZO _{QLB}	Output QLB pins Zpkg	25	60	Ω	1, 2
TdO _{QLB}	Output QLB pins Pkg Delay	14	55	ps	1, 3
ZO _{ALERT}	Output ALERT_n Zpkg	40	70	Ω	1, 2
TdO _{ALERT}	Output ALERT_n Pkg Delay	14	75	ps	1, 3
ZI _{DERROR_IN}	Input Error in Zpkg	40	70	Ω	1,2
TdI _{DERROR_IN}	Input Error in Pkg Delay	14	55	ps	1,3
ZO _{QRST}	Output QRST Zpkg	40	70	Ω	1,2
TdO _{QRST}	Output QRST Pkg Delay	14	55	ps	1,3
ZI _{DRST}	Input DRST Zpkg	40	70	Ω	1,2
TdI _{DRST}	Input DRST Pkg Delay	14	55	ps	1,3
ZI _{SDA_SCL}	Input SDA/SCL Zpkg	40	70	Ω	1,2
TdI _{SDA_SCL}	Input SDA/SCL Pkg Delay	14	75	ps	1,3

- NOTE 1 This parameter is not subject to production test. It is verified by design and characterization.
- NOTE 2 This parameter is measured by using vendor specific measurement methodology to calculate the average Z_{pkg_xx} over the interval $T_{pkg_delay_xx}$.
- NOTE 3 This parameter is measured by using vendor specific measurement methodology.
- NOTE 4 This value applies to DCS.
- NOTE 5 Absolute value of $MAX(ZI_{DCS})-MIN(ZI_{DCS})$ per sub-channel.
- NOTE 6 Absolute value of $MAX(TdI_{DCS})-MIN(TdI_{DCS})$ per sub-channel.
- NOTE 7 This value applies to DCA and DPAR.
- NOTE 8 Absolute value of $MAX(ZI_{DCA})-MIN(ZI_{DCA})$ per sub-channel.
- NOTE 9 Absolute value of $MAX(TdI_{DCA})-MIN(TdI_{DCA})$ per sub-channel.
- NOTE 10 This value applies to QxCS.
- NOTE 11 Absolute value of $MAX(ZI_{QCS})-MIN(ZI_{QCS})$ per sub-channel.
- NOTE 12 Absolute value of $MAX(TdI_{QCS})-MIN(TdI_{QCS})$ within A or B output group per sub-channel.
- NOTE 13 This value applies to QxCA.
- NOTE 14 Absolute value of $MAX(ZI_{QCA})-MIN(ZI_{QCA})$ per sub-channel.
- NOTE 15 Absolute value of $MAX(TdI_{QCA})-MIN(TdI_{QCA})$ within A or B output group per sub-channel.
- NOTE 16 Single-ended impedance.
- NOTE 17 Absolute value of $ZI_{DCK_t} - ZI_{DCK_c}$.
- NOTE 18 Absolute value of $TdI_{DCK_t} - TdI_{DCK_c}$.
- NOTE 19 Absolute value of $ZO_{QxCK_N_t} - ZO_{QxCK_N_c}$.
- NOTE 20 Absolute value of $TdI_{QxCK_N_t} - TdI_{QxCK_N_c}$.
- NOTE 21 Absolute value of $MAX(TdO_{QCK})-MIN(TdO_{QCK})$ within all QCK signals per sub-channel.

15.1 Electrostatic Discharge Sensitivity Characteristics

Table 274 — Electrostatic Discharge Sensitivity Characteristics

Parameter	Symbol	Min	Max	Unit	Notes
Human body model (HBM)	ESD_{HBM}	1000	-	V	1, 2
Charged-device model (CDM)	ESD_{CDM}	250	-	V	1, 3

- NOTE 1 State-of-the-art basic ESD control measures have to be in place when handling devices.
- NOTE 2 Refer to JEDEC / ESDA Joint Standard JS-001 for measurement procedures.
- NOTE 3 Refer to ANSI / ESDA / JEDEC Joint Standard JS-002 f for measurement procedures.

15.2 EOS Requirement

Table 275 — EOS Requirement¹

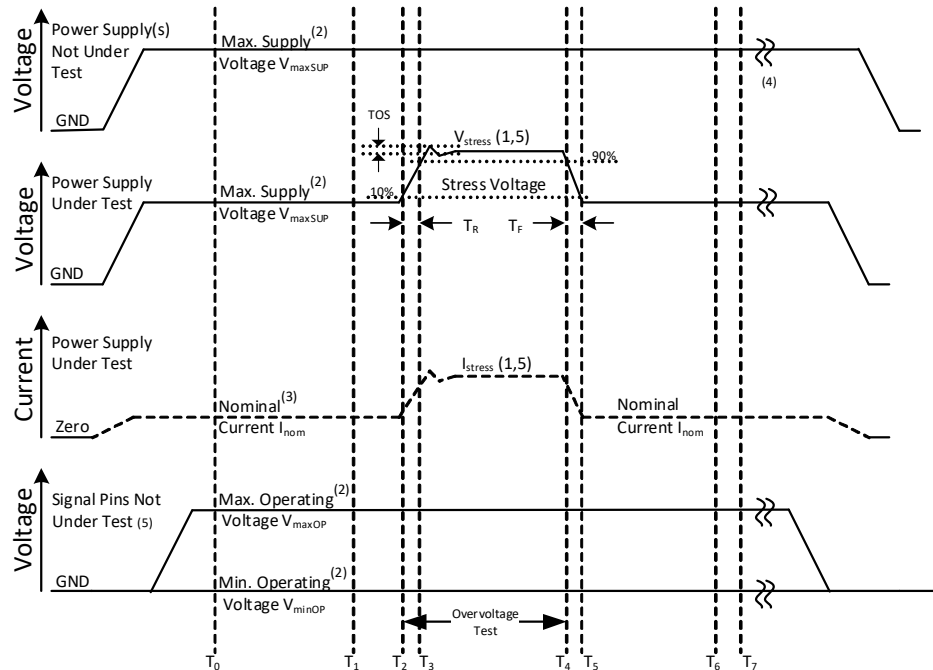
Pin	Maximum Stress Voltage	Maximum Stress Current	Stress Pulse Duration
VDD	12 V	3 A	10 ms

- NOTE 1 During the stress, neither voltage nor current should exceed the specified maximum values.

NOTE Refer to JESD78F.02 for measurement procedure. The following figures are references from JESD78F.02.

15.2 EOS Requirement (cont'd)

Figure 121 visualizes the waveform during the EOS test with the timing requirements defined in Table 276.



- (1) The waveforms when shown in a solid line are the forced voltages or currents and when shown in dashed lines are the measured voltages or currents.
- (2) During the Supply Test, the supply currents for all supply groups are monitored before and after the stress pulse. Latch-up occurs if any supply current meets the failure criteria shown in Table 3 of JESD78F.02.
- (3) The pre-stress and post-stress current I_{psPRE} and I_{psPOST} depend on the state and the circuitry of the V_{supply} pin (or pin group).
- (4) At the conclusion of the stress, returning all power supplies to ground is an option to reset the DUT. Resetting supplies is recommended for stability during testing.
- (5) Input pins Not Under Test shall be considered Signal Pins Not Under Test and should be controlled according to V_{maxOP} or V_{minOP} . Output pins are not included and floated when not under test.

NOTE: In this Supply Test example, the V_{stress} reaches the intended Trigger Voltage of Table 278, and the I_{limit} is not reached. During the full waveform (including pre-stress, stress, and post-stress), the voltage is at set values, therefore the full voltage waveform is a solid line. The current is being measured; thus the full current waveform is drawn as a dashed line.

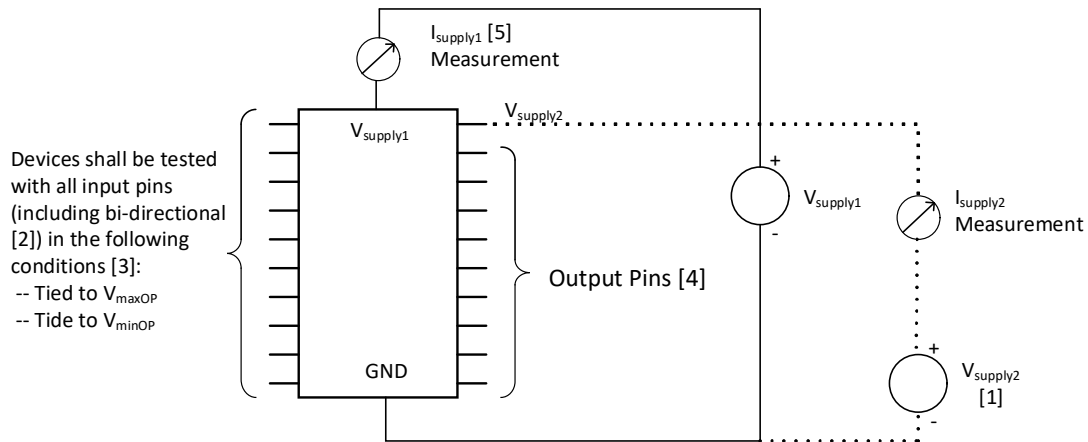
Figure 121 — Test Waveform for Supply Test

Note that V_{maxSUP} , V_{maxOP} , and V_{minOP} should refer to Table 231 for operating electrical characteristics for VDD voltage range.

15.2 EOS Requirement (cont'd)

Table 276 — Timing Requirements

Symbol	Time Interval	Parameter	Limits	
			Min	Max
t_{wait}	T0 to T1 T5 to T6	Wait time before measuring I_{supply} . The wait time shall be sufficient to allow for power supply ramp up/down and stabilization of I_{supply}	3 ms	5 s
$t_{measure}$	T1 & T6	Measure I_{supply}	Measurement Point	
t_r	T2 to T3	Trigger rise time	87 μ s	5 ms
t_{width}	T3 to T4	Trigger duration	10 ms	
t_f	T4 to T5	Trigger fall time	87 μ s	5 ms
t_{cool}	T7 to Next Pulse	Cool down time		
TOS		Trigger overshoot	+/- 5% of pulse	



- [1] DUT biasing includes additional V_{supply} sources as required.
- [2] DUT is preconditioned so that all signal pins are placed in a valid state. Signal pins in the output state are open circuit.
- [3] V_{maxOP} and V_{minOP} shall be per the device specification. When bias levels are used with respect to a non-digital device, it means the maximum high (V_{maxOP}) or minimum low (V_{minOP}) voltage that can be supplied to the pin per the device specifications, unless these conditions violate device setup condition requirements.
- [4] Output pins are open circuit.
- [5] The trigger test condition is defined in Figure 121 and Table 276.

Figure 122 — Equivalent Circuit for Supply Test

16 SidebandBus Interface Electrical and Timing Specifications

This section summarizes the operating and measurement conditions, and the DC and AC characteristics of the DDR5RCD05 SidebandBus interface. The parameter in the DC and AC Characteristics tables that follow are derived from tests performed under the Measurement Conditions summarized in the relevant tables. Designers should check that the operating conditions in their circuits match the measurement conditions when relying on the quoted parameters.

16.1 Operating Conditions

Table 277 — Operating Conditions for the SidebandBus Interface

Symbol	Parameter	Min	Typ	Max	Unit
V _{DDIO}	DDR5RCD05 Sideband Interface I/O Supply Voltage	0.95	1.0	1.05	V

16.2 Measurement Test Conditions

Table 278 — AC Measurement Conditions for SidebandBus interface

Symbol	Parameter	Min	Max	Unit
C _L	Load capacitance	40		pF
	Input rise and fall times (Open Drain)	--	120	ns
	Input rise and fall times (Push-Pull)	--	5	ns
	Input Signal (Swing) Levels	0.2 to 0.8		V
	Input Levels for Timing Reference	0.3 to 0.7		V

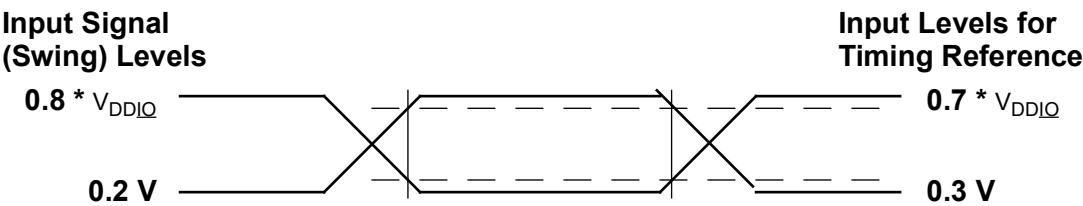


Figure 123 — AC Measurement I/O Waveform

16.3 DC Electrical Characteristics

Table 279 — Output Ron Spec

Symbol	Parameter	Min	Max	Unit	Notes
R_{ON}	SDA Output Pullup and Pulldown Driver Impedance	20	100	Ω	1
NOTE 1 Pull-down $R_{on} = V_{out}/I_{out}$; Pull-up $R_{on} = (V_{DDIO} - V_{out})/I_{out}$					

Table 280 — Input Parameters for SidebandBus interface

Symbol	Parameter ^{1,2}	Test Condition	Min	Max	Unit
C_{IN}	Input capacitance (SDA)	--	--	5	pF
C_{IN}	Input capacitance (SCL)	--	--	5	pF
NOTE 1 $T_A = 25^\circ\text{C}$, $f = 1000\text{ kHz}$					
NOTE 2 Verified by design and characterization, not necessarily tested on all devices					

Table 281 — DC Characteristics for SidebandBus Interface

Symbol	Parameter	Test Condition (in addition to those in Table 277)	Min	Max	Unit
I_{LI}	Input leakage current (SCL, SDA)	$V_{IN} = V_{SS}$ or V_{DDIO}	--	± 5	μA
I_{LO}	Output leakage current	$V_{OUT} = V_{SS}$ or V_{DDIO} ; SDA in Hi-Z	--	± 5	μA
I_{DDIO}	Supply current	$V_{DDIO} = 1.0\text{ V}$, $f_C = 12.5\text{ MHz}$ (rise/fall time $< 5\text{ ns}$)	--	5	mA
V_{IL}	Input LOW voltage (SCL, SDA)	--	-0.35	0.3	V
V_{IH}	Input HIGH voltage (SCL, SDA)	--	0.7	1.3	V
V_{OL}	Output LOW voltage (SDA)	3-mA sink current	--	0.3	V
V_{OH}	Output HIGH voltage (SDA)	3-mA source current	$V_{DDIO} - 0.3$	--	V
I_{OL}	LOW-level output current	$V_{OL} = 0.3\text{ V}$	3	--	mA
I_{OH}	HIGH-level output current	$V_{OH} = V_{DDIO} - 0.3$	--	-3	mA
Slew_Rate	Output Slew Rate (SDA)	See Note 3	0.1	1.0	V/ns
NOTE 1 Undershoot may occur. It should be limited by the Absolute Maximum DC Ratings.					
NOTE 2 Overshoot may occur. It should be limited by Absolute Maximum DC Ratings					
NOTE 3 Output slew rate is guaranteed by design and/or characterization. The output slew rate reference load is shown in Figure 129 and Figure 128 shows the timing measurement points.					

16.4 AC Electrical Characteristics

Table 282 — AC Characteristics for SidebandBus Interface

Symbol	Parameter	I ² C Mode (Open Drain) ¹		I3C Basic Push-Pull ² (12.5 MHz)		Unit
		Min	Max	Min	Max	
f _{SCL}	Clock frequency	0.01	1	0.01	12.5	MHz
t _{HIGH}	Clock pulse width HIGH time	260	--	35	--	ns
t _{LOW} ³	Clock pulse width LOW time	500	--	35	--	ns
t _{TIMEOUT} ^{4,5}	Detect clock LOW timeout	10	50	10	50	ms
t _R ^{6,7,8}	SDA rise time	--	120	--	5	ns
t _F ^{6,7,8}	SDA fall time	--	120	--	5	ns
t _{SU:DAT} ^{6,9}	Data in setup time	50	--	8	--	ns
t _{HD:DI} ^{6,9}	Data in hold time	0	--	3	--	ns
t _{SU:STA} ^{6,10}	START condition setup time	260	--	12	--	ns
t _{HD:STA} ⁶	START condition hold time	260	--	30	--	ns
t _{SU:STO} ⁶	STOP condition setup time	260	--	12	--	ns
t _{BUF} ⁶	Time between STOP Condition and next START Condition	500	--	500	--	ns
t _{HD:DAT} ¹¹	Data out hold time	0.5	350	N/A	N/A	ns
t _{DOUT} ^{12,13}	SCL Falling Clock In to Valid SDA Data Out Time	N/A	N/A	0.5	12	ns
t _{DOFFT} ^{12,14}	SCL Rising Clock In to Target SDA Output Off	N/A	N/A	0.5	12	ns
t _{DOFFC} ^{12,15}	SCL Rising Clock In to Controller SDA Output Off	N/A	N/A	0.5	12	ns
t _{CL_r_DAT_f} ¹⁶	SCL Rising Clock In to Controller Driving Data Signal LOW	N/A	N/A	40	--	ns
t _{AVAIL}	Bus Available Time (no edges seen on SDA and SCL)	N/A	N/A	1	--	μs
t _{IBI_Issue}	Time to issue IBI after an event is detected when Bus is available	-	-	-	15	μs
t _{CLR_I3C_CMD_Delay}	Time from Clear Register Status to any I3C operation with Start condition to avoid IBI generation (PEC Disabled)	-	-	4	-	μs
	Time from Clear Register Status to any I3C operation with Start condition to avoid IBI generation (PEC Enabled)	-	-	15	-	μs
t _{DEVCTRLCCC_DE-LAY_PEC_DIS}	DEVCTRL CCC Followed by DEVCTRL CCC or Register Read/Write Command Delay ^{17,18,19}	3	--	3	--	μs
t _{WR_RD_DE-LAY_PEC_EN}	Register Write Command Followed by Register Read Command Delay in PEC Enabled Mode ^{18,19,20}	N/A	N/A	8	--	μs
t _{I2C_CCC_Update_Delay}	Minimum delay from SETHID CCC or SETAASA CCC to any other CCC or Read/Write Command	2.5	-	N/A	N/A	μs
t _{I3C_CCC_Update_Delay}	Minimum delay from ENEC/DISEC CCC or RSTDAA CCC to any other CCC or Read/Write Command	N/A	N/A	2.5	-	μs
t _{CCC_Delay}	Delay from any CCC to RSTDAA CCC	N/A	N/A	2.5	-	μs

- NOTE 1 The timing parameters listed under this column correspond to Fast-mode Plus from the I²C specification. The DDR5RCD05 device must also support the values and conditions corresponding to the other (lower) speed modes supported by I²C specification. Namely, Standard-mode and Fast-mode.
- NOTE 2 I3C Basic mode with Open Drain operation follows timing values as shown in I²C Mode - Open Drain column.
- NOTE 3 The DDR5RCD05 I²C/I3C Basic interface logic shall not initiate clock stretching.
- NOTE 4 The DDR5RCD05 must support bus timeout on I²C/I3C Basic access.
- NOTE 5 Devices participating in a transfer can abort the transfer in progress and release the bus by forcing SCL LOW. A timeout condition can only be ensured if the device forcing the timeout holds SCL LOW for $t_{\text{TIMEOUT,MAX}}$ or longer. After the controller in a transaction detects this condition, it must generate a STOP condition within or after the current data byte in the transfer process. Devices that have detected this condition must reset their communication and be able to receive a new START condition no later than 10ms after the controller generates the STOP condition.
- NOTE 6 See Figure 124 for input timing definitions.
- NOTE 7 See Figure 127 for voltage threshold definitions for rise and fall times.
- NOTE 8 Guaranteed by design and characterization, not necessarily tested.
- NOTE 9 The input setup time is referenced from SDA V_{IL} or V_{IH} threshold to SCL V_{IL} threshold as shown in Figure 124. The input hold time is referenced from SCL V_{IL} threshold to SDA V_{IL} or V_{IH} threshold as shown in Figure 124.
- NOTE 10 For a reSTART condition, or following a write cycle.
- NOTE 11 The DDR5RCD05 device guarantees $t_{\text{HD:DAT}}$ value in I²C mode of operation. See Figure 125 for I²C output timing definitions as well as SCL clock input threshold level and SDA data output threshold levels.
- NOTE 12 This timing parameter is guaranteed into output timing reference load as shown in Figure 129.
- NOTE 13 The DDR5RCD05 must be configured in I3C Basic mode to guarantee t_{DOUT} value. See Figure 126 for I3C Basic output timing definition as well as SCL clock input threshold level and SDA data output threshold levels. See Figure 129 for output timing parameter measurement reference load.
- NOTE 14 The DDR5RCD05 must be configured in I3C Basic mode to guarantee t_{DOFFT} value. See Figure 130. See Figure 129 for output timing parameter measurement reference load.
- NOTE 15 The DDR5RCD05 must be configured in I3C Basic mode to guarantee t_{DOFFC} value. See Figure 131. See Figure 129 for output timing parameter measurement reference load.
- NOTE 16 The DDR5RCD05 must be configured in I3C Basic mode to guarantee $t_{\text{CL_r_DAT_f}}$ value. See Figure 133.
- NOTE 17 From STOP condition of DEVCTRL CCC to START condition for Register Read or Register Write Command Data Packet delay.
- NOTE 18 The device may send NACK if Host does not satisfy this timing parameter.
- NOTE 19 This timing constraint is only applicable when PEC is disabled. If PEC is enabled, this timing parameter does not apply.
- NOTE 20 From STOP condition for Register Write Command Data Packet to START condition for Register Read Command Data Packet delay.

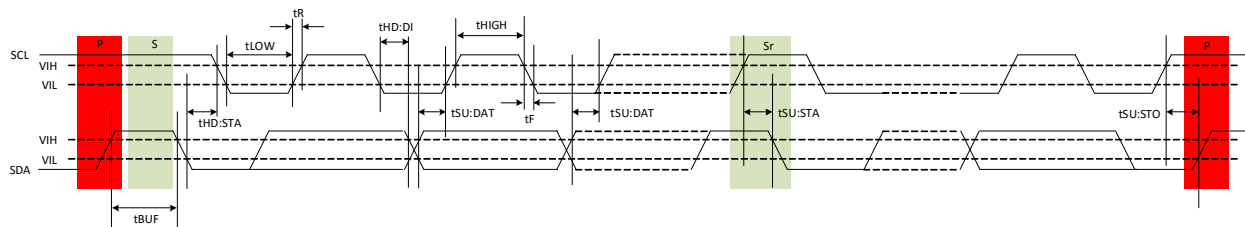


Figure 124 — I²C and I3C Basic AC Input Timing Parameter Definitions

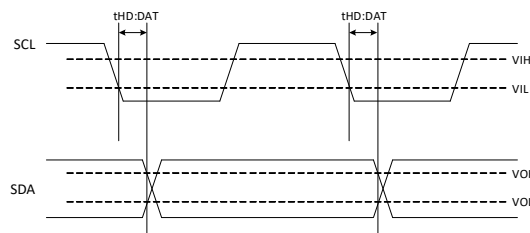


Figure 125 — I²C Bus AC Output Timing Parameter Definitions

16.4 AC Electrical Characteristics (cont'd)

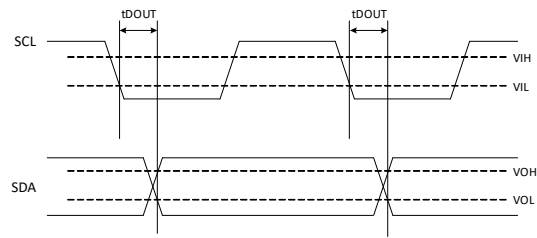


Figure 126 — I3C Basic AC Output Timing Parameter Definitions

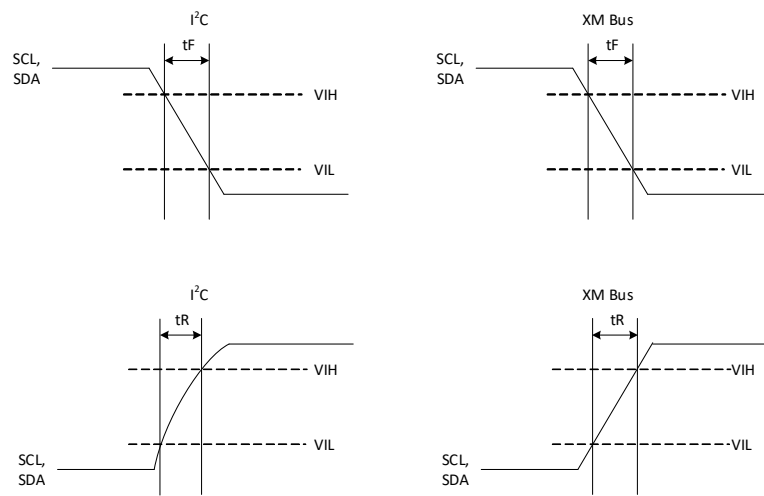


Figure 127 — Rise and Fall Timing Parameter Definitions

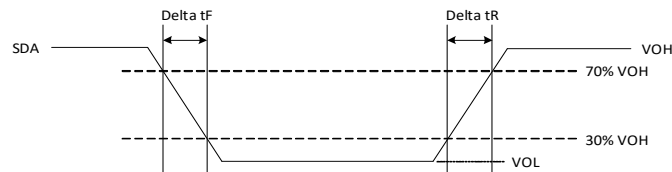


Figure 128 — Output Slew Rate Measurement Points

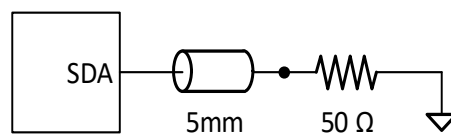


Figure 129 — Test Load for Output Slew Rate and Output Timing Measurement

16.4 AC Electrical Characteristics (cont'd)

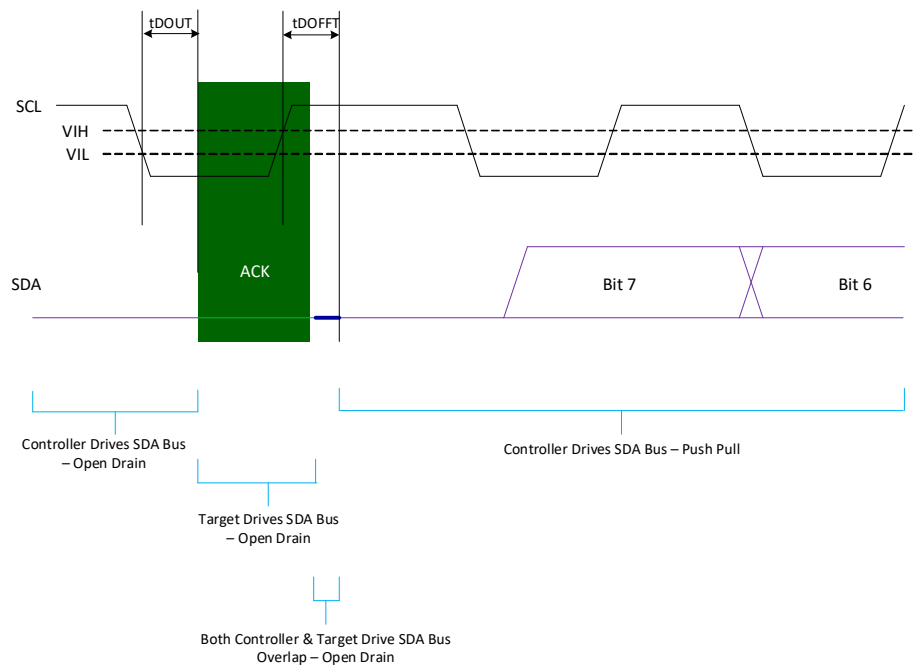


Figure 130 — I3C Basic Hand-off Operation - RCD Open Drain (ACK) to Controller Push-Pull

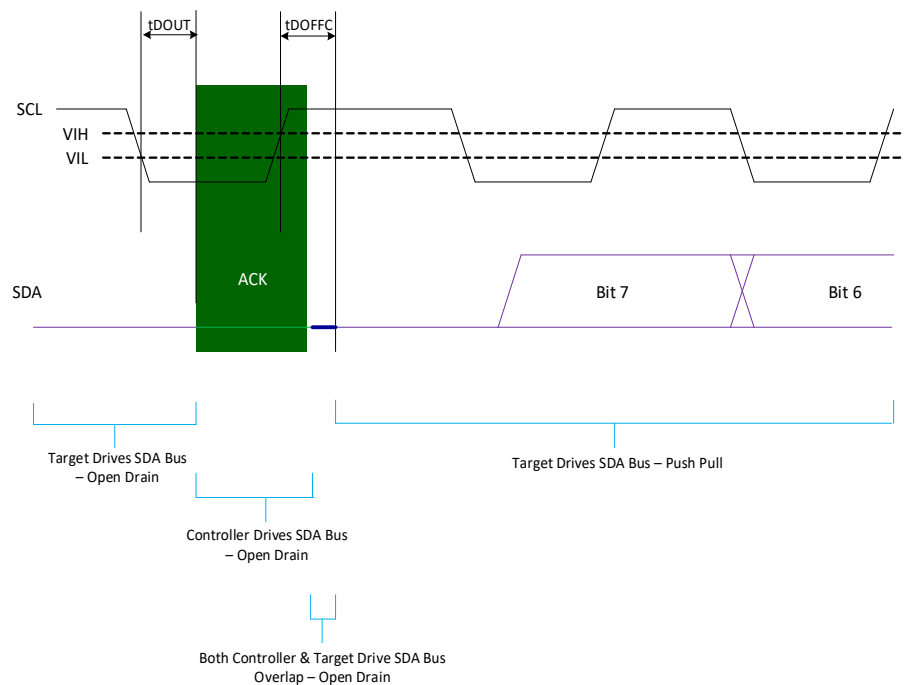


Figure 131 — I3C Basic Hand-off Operation - Controller Open Drain (ACK) to RCD Push-Pull

16.4 AC Electrical Characteristics (cont'd)

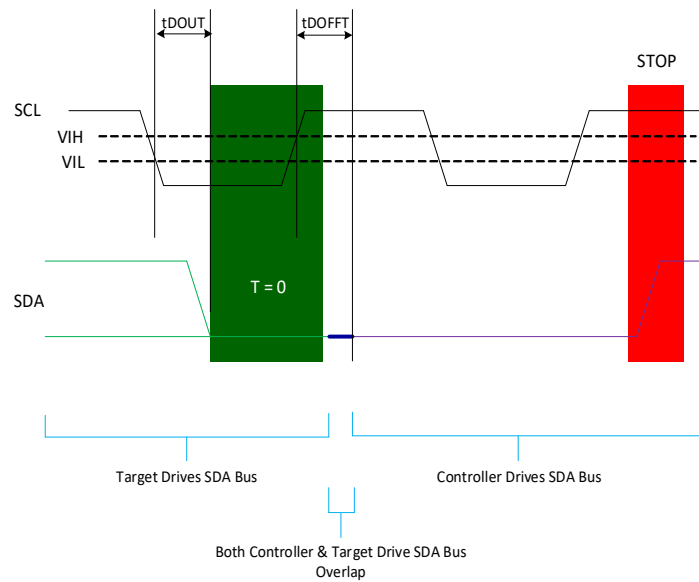


Figure 132 — I3C Basic T=0 Transition from RCD Read Operation to Controller STOP Bit

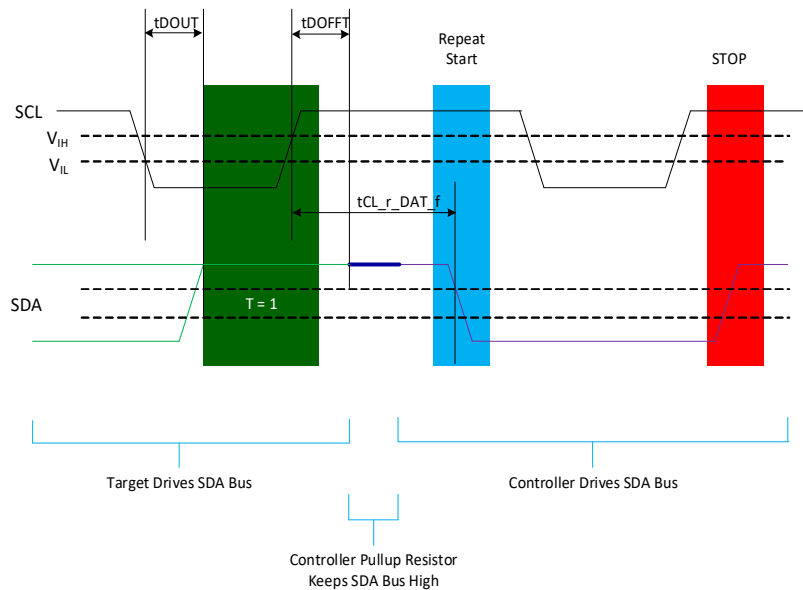


Figure 133 — I3C Basic T = 1 Transition from RCD Read Operation Interrupted by Controller Repeated START and STOP Bit

16.4 AC Electrical Characteristics (cont'd)

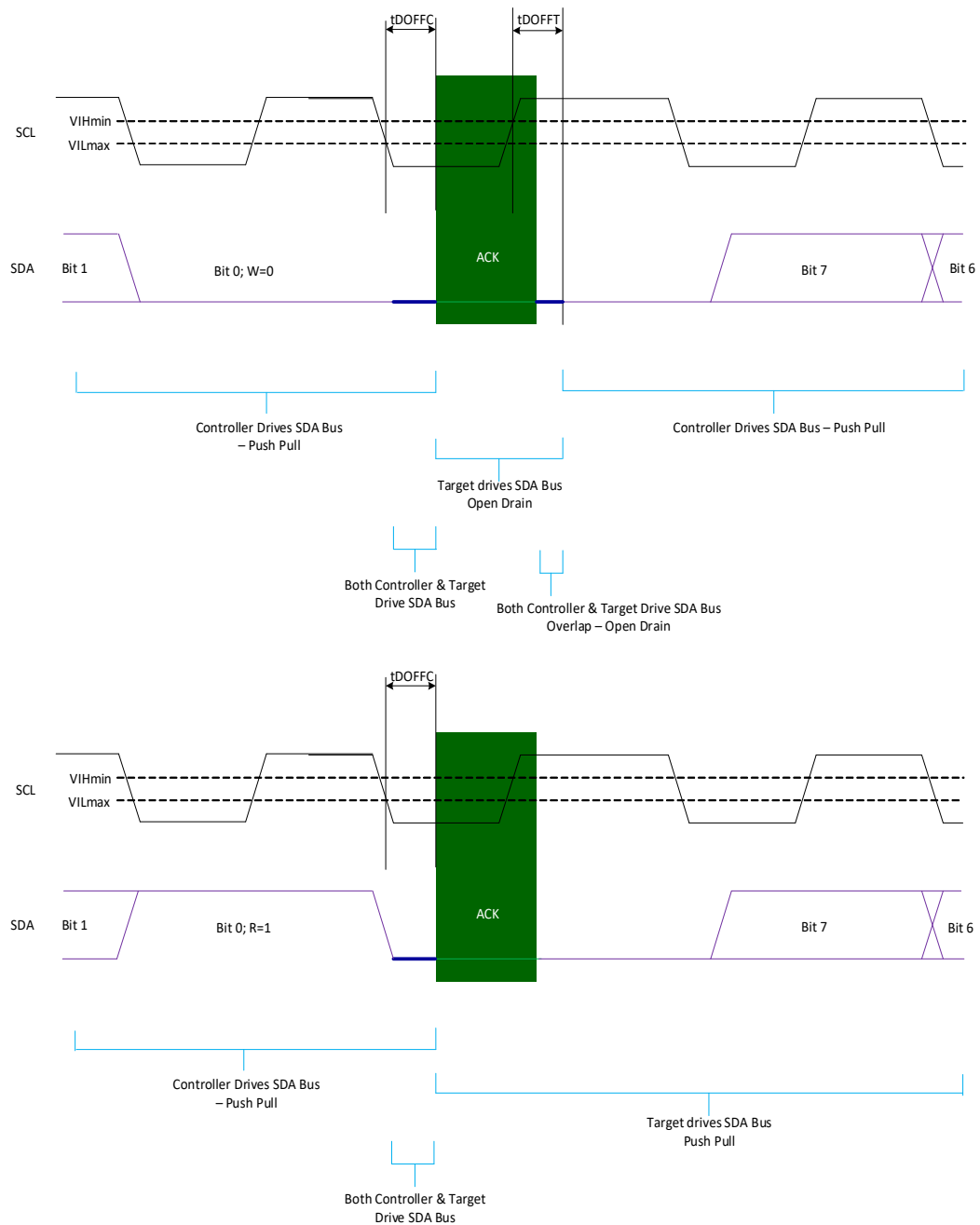
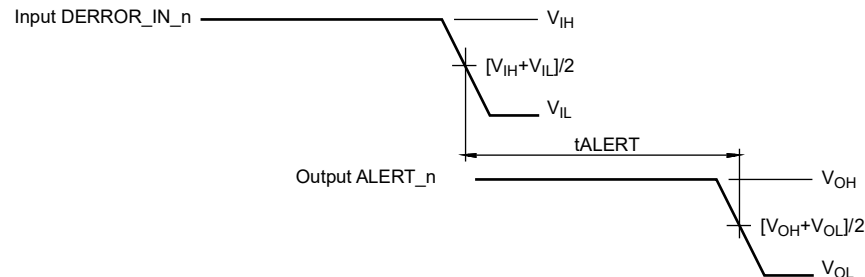


Figure 134 — Controller Push Pull to Target Open Drain Hand Off Operation

17 Test Circuits and Switching Waveforms

17.1 Alert Output Voltage Measurement Information

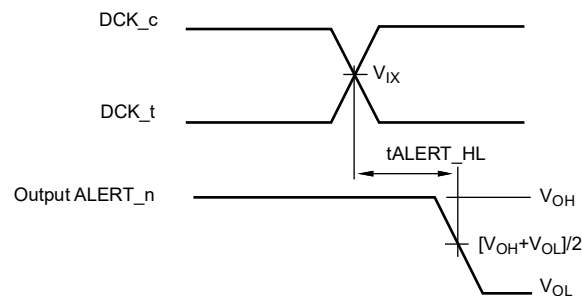
All input pulses are supplied by generators having the following characteristics: $1000 \text{ MHz} \leq \text{PRR}$ (Pulse Repetition Rate) $\leq 2436 \text{ MHz}$; $Z_o = 50 \text{ } \Omega$; input slew rate = $1 \text{ V/ns} \pm 20\%$, unless otherwise specified.



NOTE 1 V_{IH} and V_{IL} represent the applied Logic HIGH and LOW input DC voltage levels resulting from $50\text{-}\Omega$ driver into the default on-die termination ($60 \text{ } \Omega$).

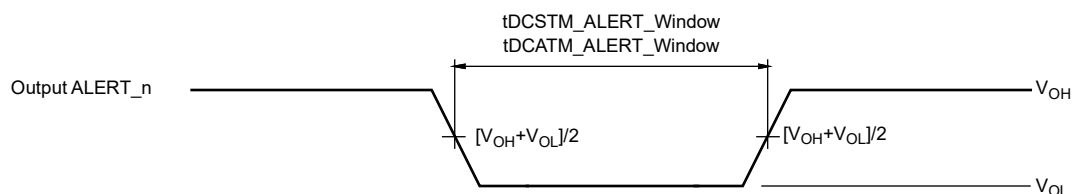
NOTE 2 V_{OH} and V_{OL} represent the measured Logic HIGH and LOW output DC voltage levels into the test load ($50 \text{ } \Omega$).

Figure 135 — Voltage Waveforms, t_{ALERT} Measurement



NOTE 1 V_{OH} and V_{OL} represent the measured Logic HIGH and LOW output DC voltage levels into the test load ($50 \text{ } \Omega$).

Figure 136 — Voltage Waveforms, $t_{\text{ALERT_HL}}$ Measurement



NOTE 1 V_{OH} and V_{OL} represent the measured Logic HIGH and LOW output DC voltage levels into the test load ($50 \text{ } \Omega$).

Figure 137 — Voltage Waveforms, $t_{\text{DCSTM_ALERT_Window}}$ and $t_{\text{DCATM_ALERT_Window}}$ Measurements

17.2 DDR5RCD05 Reference Load

The following circuit represents the effective reference load of 50 ohms used in defining the relevant AC timing parameters of the device as well as output slew rate measurements.

It is not intended as a precise representation of any particular system environment or a depiction of the actual load presented by a production tester. System designers should use IBIS or other simulation tools to correlate the timing reference load to a system environment. Manufacturers correlate to their production test conditions, generally one or more coaxial transmission lines terminated at the tester electronics.

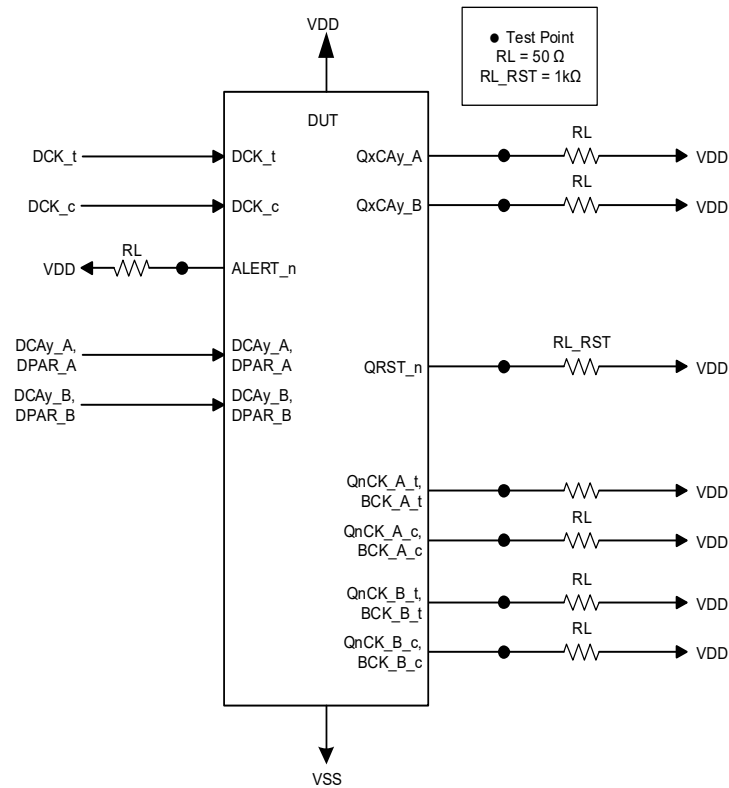


Figure 138 — Test Load

18 tQSK Specification Parameters

18.1 tQSK Specification Parameters and Test Conditions

In this chapter, tQSK measurement conditions such as test load and patterns are defined. Figure 139 shows the setup and test load for tQSK measurements.

- tQSK can be measured for each speed bin. Each measurement shall use the minimum tCK (avg) for each speed bin.
- De-embedding may be needed if QCA/QCS pulses are not sufficiently wide to avoid ISI caused by loss from test fixture.

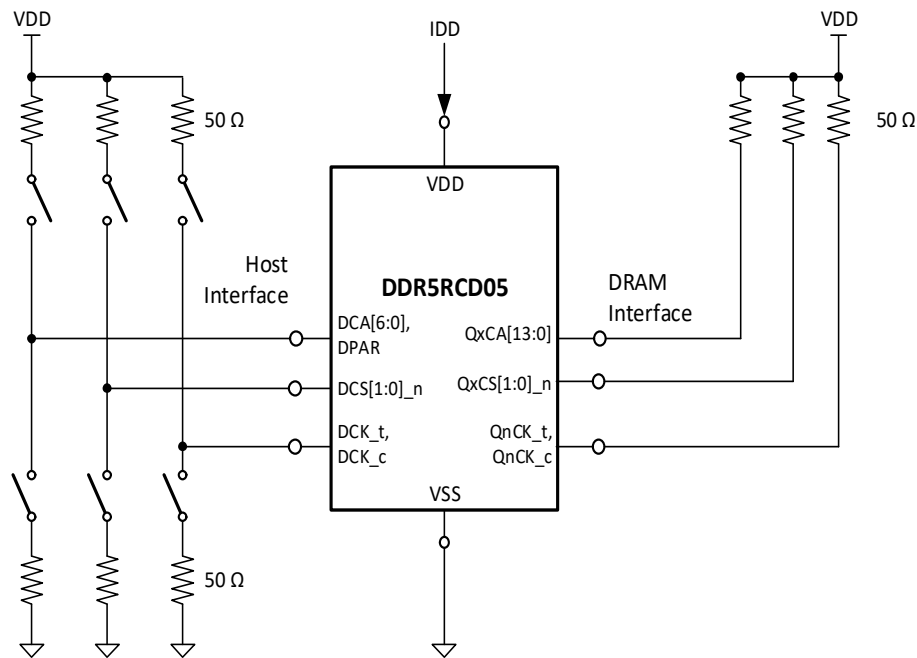
For tQSK measurements, the following definitions apply:

- Basic tQSK Measurement Conditions are described in Table 283.
- Detailed tQSK Measurement-Loop Patterns are described in Table 284, Table 285, and Table 286.
- These are informative patterns for component testing. The possibility of other patterns is not precluded.

tQSK Measurements are done after properly initializing the DDR5RCD05. This includes but is not limited to setting

- All eight clock outputs enabled per channel in RW08 and PG[70]RW63;
- IBT enabled and set to 60 Ohm in RW10 for DCA[6:0], DPAR, DCS[1:0];
- Output drive strengths set as follows: RW0A = 0xAA, RW0C[5:0] = 0x00, PG[70]RW6A = 0xAA;
- Slew rate for all outputs is set to Moderate;
- Parity checking disabled in RW01[0];
- DRAM Interface unblocked in RW01[1];
- Output inversion enabled in RW00[5];
- CA Pass Through Mode and Transparent Mode disabled in RW00[2] and RW00[7].

18.1 tQSK Specification Parameters and Test Conditions (cont'd)



Note: Host drives HIGH and drives LOW

Figure 139 — Measurement Setup and Test Load for tQSK Measurements

Table 283 — Basic tQSK Measurement Conditions¹

Symbol	Description
tQSK_static	<p>Single-Bit Switching for DDR/1N Mode</p> <p>QnCK: Enabled;</p> <p>DDR Mode Enabled in RW00[0]=1'b1;</p> <p>Data IO & Pattern Details: see Table 284 and Table 270</p> <p>Test each set of QCS copies separately by running the pattern in Table 284 and Table 270 once with RW09[6:5] = 00 and PG[70]RW62[4:1] = 0000 and again with RW09[6:5] = 11 and PG[70]RW62[4:1] = 1111.</p> <p>Test Each Sub-Channel Independently (CHA while CHB idle, then CHB while CHA idle)</p>
tQSK_dynamic	<p>SSO</p> <p>QnCK: Enabled;</p> <p>DDR Mode Enabled in RW00[0]=1'b1;</p> <p>Data IO & Pattern Details: see Table</p> <p>Test each set of QCS copies separately by running the pattern in Table once with RW09[6:5] = 00 and PG[70]RW62[4:1] = 0000 and again with RW09[6:5] = 11 and PG[70]RW62[4:1] = 1111.</p> <p>Test Each Sub-Channel Simultaneously (drive pattern on both CHA & CHB together)</p>

NOTE 1 All tests use termination setup depicted in Figure 139.

18.1 tQSK Specification Parameters and Test Conditions (cont'd)

Table 284 — tQSK_static QCS Measurement-Loop Pattern

Loop	Repeats (Cycles)	UI Number	DCS[0]_n	DCS[1]_n	DCA0	DCA1	DCA2	DCA3	DCA4	DCA5	DCA6	Test
-	64x	0	1	1	1	1	1	1	1	1	1	
		1	1	1	1	1	1	1	1	1	1	
	64x	0	0	1	1	1	1	1	1	1	1	QACS0 Single-bit switching ¹
		1	0	1	1	1	1	1	1	1	1	
	64x	0	1	1	1	1	1	1	1	1	1	
		1	1	1	1	1	1	1	1	1	1	
	64x	0	1	0	1	1	1	1	1	1	1	QACS1 Single-bit switching ¹
		1	1	0	1	1	1	1	1	1	1	
	64x	0	1	1	1	1	1	1	1	1	1	
		1	1	1	1	1	1	1	1	1	1	
-	64x	0	0	0	0	0	0	0	0	0	0	
		1	0	0	0	0	0	0	0	0	0	
	64x	0	1	0	0	0	0	0	0	0	0	QxCS0 Single-bit switching
		1	1	0	0	0	0	0	0	0	0	
	64x	0	0	0	0	0	0	0	0	0	0	
		1	0	0	0	0	0	0	0	0	0	
	64x	0	0	1	0	0	0	0	0	0	0	QxCS1 Single-bit switching
		1	0	1	0	0	0	0	0	0	0	
	64x	0	0	0	0	0	0	0	0	0	0	
		1	0	0	0	0	0	0	0	0	0	

NOTE 1 QBCS single-bit switching cannot be measured here due to output inversion, but can be measured in the patterns below with DCA = '0.

18.1 tQSK Specification Parameters and Test Conditions (cont'd)

Table 285 — tQSK_static QCA Measurement-Loop Pattern

[illegible]

[illegible]

Loop	Sub-Loop	Repeats (Cycles)	UI Number	DCS[0]_n	DCS[1]_n	DCA0	DCA1	DCA2	DCA3	DCA4	DCA5	DCA6	Test			
-	-	16x	0	1	1	1	1	1	1	1	1	1	QACS[1:0] SSO+ with QACA[13:0] static			
			1	1	1	1	1	1	1	1	1	1		1		
	1	16x	0	0	0	1	1	1	1	1	1	1		QACS[1:0] SSO+ with QACA[13:0] static		
			1	0	0	1	1	1	1	1	1	1			1	
		16x	0	1	1	1	1	1	1	1	1	1			QACS[1:0] SSO+ with QACA[13:0] static	
			1	1	1	1	1	1	1	1	1	1				1
	Run sub-loop 1 twice															
	2	16x	0	0	0	0	0	0	0	0	0	0		0	QBCS[1:0] SSO+ with QBCA[13:0] static	
			1	0	0	0	0	0	0	0	0	0		0		0
		16x	0	1	1	1	1	1	1	1	1	1		1		QBCS[1:0] SSO+ with QBCA[13:0] static
			1	1	1	1	1	1	1	1	1	1		1		
	Run sub-loop 2 twice															
	3	16x	0	0	1	0	0	0	0	0	0	0		0	QACA[13:0] SSO+ and QACS[1:0] static	
			1	0	1	0	0	0	0	0	0	0		0		0
		16x	0	0	1	1	1	1	1	1	1	1		1		QACA[13:0] SSO+ and QACS[1:0] static
			1	0	1	1	1	1	1	1	1	1		1		
	Run sub-loop 3 twice															
	4	16x	0	0	1	0	0	0	0	0	0	0		0	QBCA[13:0] SSO+ and QBCS[1:0] static	
			1	0	1	0	0	0	0	0	0	0		0		0
		16x	0	0	1	1	1	1	1	1	1	1		1		QBCA[13:0] SSO+ and QBCS[1:0] static
			1	0	1	1	1	1	1	1	1	1		1		
	Run sub-loop 4 twice															
	1	5	16x	0	0	1	1	0	0	0	0	0		0	QCA0 SSO-	
				1	0	1	0	0	0	0	0	0		0		0
16x			0	0	1	0	1	1	1	1	1	1	1	QCA0 SSO-		
			1	0	1	1	1	1	1	1	1	1	1			1
Run sub-loop 5 twice																
Repeat loop 1 by swapping the highlighted pattern for each of DCA1 through DCA6 to test QCA1 through QCA6																
2	6	16x	0	0	1	0	0	0	0	0	0	0	QCA7 SSO-			
			1	0	1	1	0	0	0	0	0	0		0		
		16x	0	0	1	1	1	1	1	1	1	1		1	QCA7 SSO-	
			1	0	1	0	1	1	1	1	1	1		1		1
Run sub-loop 6 twice																

Table 286 — tQSK_dynamic Measurement-Loop Pattern (cont'd)

Loop	Sub-Loop	Repeats (Cycles)	UI Number	DCS[0]_n	DCS[1]_n	DCA0	DCA1	DCA2	DCA3	DCA4	DCA5	DCA6	Test
Repeat loop 2 by swapping the highlighted pattern for each of DCA1 through DCA6 to test QCA8 through QCA13													
-	-	16x	0	1	1	1	1	1	1	1	1	1	
			1	1	1	1	1	1	1	1	1	1	
	7	16x	0	1	0	1	1	1	1	1	1	1	QACS[1:0] and QBSC[1:0] SSO-
			1	1	0	1	1	1	1	1	1	1	
		16x	0	0	1	1	1	1	1	1	1	1	
			1	0	1	1	1	1	1	1	1	1	
			Run sub-loop 7 twice										

19 Reference to other Applicable JEDEC Standards and Publications

- JEP95, JEDEC Registered and Standard Outlines for Solid State and Related Products
- JEP104, Reference Guide to Letter Symbols for Semiconductor Devices
- JESD21-C, Configuration for Solid State Memories
- JESD8-11A.01, 1.5 V +/- 0.1 V (Normal Range) and 0.9 V - 1.6 V (Wide Range) Power Supply Voltage and Interface Standard for Nonterminated Digital Integrated Circuits
- JESD79-5, DDR5 SDRAM
- MO-361A, Package Mechanical Outline
- I3C Basic, Specification for I3C Basic Version 1.0 – 19 July 2018
- JESD403-1, JEDEC Module Sideband Bus (SidebandBus)
- JS-001-2017, Joint JEDEC/ESDA Standard for Electrostatic Discharge Sensitivity Test – Human Body Model (HBM) – Component Level
- JS-002-2018, ANSI/ESDA/JEDEC Joint Standard for Electrostatic Discharge Sensitivity Testing – Charged Device Model (CDM) – Device Level



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